

# **2011 16th International Solid-State Sensors, Actuators and Microsystems Conference**

## **(TRANSDUCERS 2011)**

**Beijing, China  
5-9 June 2011**

**Volume 1  
Pages 1-501**



**IEEE Catalog Number: CFP11SSA-PRT  
ISBN: 978-1-4577-0157-3**



The 16th International Conference on  
Solid-State Sensors, Actuators and Microsystems

TABLE OF CONTENTS

Volume 1 / M1.001-T2D.003

MONDAY, JUNE 6, 2011

**OPENING CEREMONY** 08:30 - 09:45

**PLENARY I** 10:15 - 10:55

**M001 NEW TRENDS OF MEMS/NEMS BASED ON  
HETEROGENEOUS PROCESS INTEGRATION -  
TOWARDS LIFE/GREEN INNOVATION**

Hiroyuki Fujita  
CIRMM, The University of Tokyo, Tokyo, JAPAN

.....1

**PLENARY II** 10:55 - 11:35

**M002 VACUUM MICROSYSTEMS FOR ENERGY  
CONVERSION AND OTHER APPLICATIONS**

Roger T. Howe  
Dept. of Electrical Engineering, Stanford University,  
Stanford, California, USA

.....7

**PLENARY III** 11:35 - 12:15

**M003 MICROFLUIDIC SOLUTIONS FOR  
MINIATURIZATION, INTEGRATION,  
AUTOMATION AND PARALLELIZATION OF  
TESTS ON COMMERCIALY AVAILABLE  
INSTRUMENTS**

R. Zengerle<sup>1,2,3</sup>, D. Mark<sup>1</sup>, D. Kossel, G. Roth<sup>1,2</sup>, and F.  
von Stetten<sup>1,2</sup>

<sup>1</sup>HSG-IMIT, Wilhelm-Schickard-Straße 10, D-78052  
Villingen-Schwenningen, Germany

<sup>2</sup>Laboratory for MEMS Applications, Department of  
Microsystems Engineering - IMTEK, University of  
Freiburg, Georges-Koehler-Allee 106, D-79110

Freiburg, Germany

<sup>3</sup>BIOSS-Centre for Biological Signalling Studies,  
University of Freiburg, D-79110 Freiburg, Germany

.....12

**POSTER SESSION I** 13:15 - 16:15

**Mechanical/Physical Sensors and Microsystems**

**M3P.001 PHASE-LOCKED DRIVE LOOP WITH AMPLITUDE  
REGULATION BASED ON PHASE-SHIFTING FOR  
GYROSCOPES**

T. Northemann<sup>1</sup>, M. Maurer<sup>1</sup>, S. Rombach<sup>1</sup> and Y.  
Manoli<sup>1,2</sup>

<sup>1</sup>Fritz Huettinger Chair of Microelectronics, Department  
of Microsystems Engineering – IMTEK University of  
Freiburg, Germany

<sup>2</sup>HSG-IMIT - Institute of Micromachining and  
Information Technology, Villingen-Schwenningen,  
Germany

.....16

**M3P.002 DESIGN OF T-SHAPE VECTOR HYDROPHONE  
BASED ON MEMS**

Linggang Guan<sup>1,2</sup>, Guojun Zhang<sup>1</sup>, Chenyang  
Xue<sup>1,2</sup>, Wendong Zhang<sup>1,2</sup>, Jijun Xiong<sup>1,2</sup>, Jiao  
Xu<sup>2</sup>

<sup>1</sup>Science and Technology on Electronic Test &  
Measurement Laboratory, Taiyuan, China

<sup>2</sup>Key Laboratory of Instrument Science & Dynamic  
Measurement (North University of China), Ministry of  
Education, Taiyuan, China

.....20

**M3P.003 A CMOS CAPACITIVE PRESSURE SENSOR CHIP  
FOR FINGERPRINT DETECTION**

Yung-Shih Hsiung<sup>1</sup>, and Michael S.-C. Lu<sup>1,2</sup>

<sup>1</sup>Department of Electrical Engineering and <sup>2</sup>Institute of  
NanoEngineering and Microsystems,

National Tsing Hua University, Hsinchu, Taiwan, R.O.C.

.....24

<b>M3P.004</b>	<b>GAAS/INXGA1-XAS/GAAS/ALAS RESONANT TUNNELING DIODES FOR NOVEL MEMS GYROSCOPE APPLICATION</b> Lishuang Liu, Jun Liu*, Yunbo Shi, Ruirong Wang, Rui Zhao, Jun Tang <i>National Key Laboratory for Electronic Measurement Technology, North University of China, Taiyuan, Shanxi Province, China</i>	28
<b>M3P.005</b>	<b>A WIDEBAND ANTI-HIGH-OVERLOAD THERMOELECTRIC MICROWAVE POWER SENSOR BASED ON GAAS MMIC TECHNOLOGY</b> D.B. Wang and X.P. Liao <i>Key Laboratory of MEMS of Ministry of Education, Southeast University, Nanjing, Jiangsu province, China</i>	32
<b>M3P.006</b>	<b>A 3-AXIS ACCELEROMETER AND STRAIN SENSOR SYSTEM FOR BUILDING INTEGRITY MONITORING</b> J. Santana <sup>1</sup> , R. van den Hoven <sup>1</sup> , C. van Liempd <sup>1</sup> , M. Colin <sup>2</sup> , N. Saillen <sup>3</sup> and C. Van Hoof <sup>1,4</sup> <sup>1</sup> <i>imec-Holst Centre, Eindhoven, The Netherlands</i> <sup>2</sup> <i>MEMSCAP, Grenoble, France</i> <sup>3</sup> <i>Thermo Fisher Scientific, Enschede, The Netherlands</i> <sup>4</sup> <i>IMEC, Leuven, Belgium</i>	36
<b>M3P.007</b>	<b>A NEW LOW CONSUMPTION 3D COMPASS USING INTEGRATED MAGNETS AND PIEZORESISTIVE NANO-GAUGES</b> D. Ettelt <sup>1</sup> , P. Rey <sup>1</sup> , M. Savoye <sup>1</sup> , C. Coutier <sup>1</sup> , M. Cartier <sup>1</sup> , O. Redon <sup>1</sup> , M. Audoin <sup>1</sup> , A. Walther <sup>1</sup> , P. Robert <sup>1</sup> , Y. Zhang <sup>2</sup> , F. Dumas-Bouchiat <sup>2</sup> , N.M. Dempsey <sup>2</sup> and J. Delamare <sup>3</sup> <sup>1</sup> <i>CEA-LETI, MINATEC Campus, 17 rue des Martyrs - 38054 Grenoble Cedex 9, FRANCE</i> <sup>2</sup> <i>Institut Néel, CNRS/UJF, 25 rue des Martyrs - 38042 Grenoble Cedex 9, FRANCE</i> <sup>3</sup> <i>G2Elab, 961 rue Houille Blanche - 38402 Saint Martin d'Hères, FRANCE</i>	40
<b>M3P.008</b>	<b>OUT-OF-PLANE AXIS SOI MEMS GYROSCOPE WITH INITIALLY DISPLACED VERTICAL SENSING COMB</b> D. Maeda, H. Jeong, C. Takubo, M. Degawa, K. Yamanaka, M. Shoji and Y. Goto <i>Hitachi, Ltd., Central Research Laboratory, Tokyo, Japan</i>	44
<b>M3P.009</b>	<b>ELECTRICAL PERFORMANCE OPTIMIZATION OF A SILICON-BASED EUV PHOTODIODE WITH NEAR-THEORETICAL QUANTUM EFFICIENCY</b> L. Shi, L. K. Nanver, <sup>1</sup> C. Laubis, <sup>1</sup> F. Scholze and S. Nihtianov <i>Delft University of Technology, Delft, the Netherlands</i> <sup>1</sup> <i>Physikalisch-Technische Bundesanstalt (PTB), Berlin, Germany</i>	48
<b>M3P.010</b>	<b>A NEW N/MEMS-BASED NONVOLATILE CIRCUIT</b>	52
<b>M3P.011</b>	<b>CYLINDER-SHAPED THERMAL INERTIAL FORCE SENSOR FOR WEARABLE FABRIC SENSOR SYSTEMS</b> Shingo Kitamura <sup>1</sup> , Masaharu Ishikawa <sup>1</sup> , Mitsuhiro Shikida <sup>2</sup> , and Kazuo Sato <sup>3</sup> <sup>1</sup> <i>Dept. of Mechanical Engineering, Nagoya University, Nagoya, Japan</i> <sup>2</sup> <i>Center for Micro-Nano Mechatronics, Nagoya University, Nagoya, Japan</i> <sup>3</sup> <i>Dept. of Micro-Nano Systems Engineering, Nagoya University, Nagoya, Japan</i>	56
<b>M3P.012</b>	<b>HIGH BANDWIDTH ELECTRON TUNNELING TRANSDUCER USING FREQUENCY DOWNMIXING READOUT OF NANOMECHANICAL MOTION</b> M. R. Kan <sup>1,2</sup> , E. Finley <sup>1</sup> , D.C. Fortin <sup>2</sup> , M. R. Freeman <sup>1,2</sup> and W. K. Hiebert <sup>1,2*</sup> <sup>1</sup> <i>National Institute for Nanotechnology, NRC Canada, Edmonton, Alberta, Canada</i> <sup>2</sup> <i>Department of Physics, University of Alberta, Edmonton, Alberta, Canada</i>	60
<b>M3P.013</b>	<b>ATTACHED-TYPE FLEXIBLE FLOW SENSOR FOR AIR CONDITIONING NETWORK SYSTEMS</b> Kazuhiro Yoshikawa <sup>1</sup> , Satoshi Iwai <sup>2</sup> , Mitsuhiro Shikida <sup>3</sup> , and Kazuo Sato <sup>1</sup> <sup>1</sup> <i>Dept. of Micro-Nano Systems Engineering, Nagoya University, Nagoya, Japan</i> <sup>2</sup> <i>Dept. of Mechanical Engineering, Nagoya University, Nagoya, Japan</i> <sup>3</sup> <i>Center for Micro-Nano Mechatronics, Nagoya University, Nagoya, Japan</i>	64
<b>M3P.014</b>	<b>A CMOS WIRELESS TWO-AXIS DIGITAL ACCELEMETER USING BONDWIRE INERTIAL SENSING</b> Y.-T. Liao, J. Shi, and B. Otis <i>Electrical Engineering Department, University of Washington, Seattle, USA</i>	68
<b>M3P.015</b>	<b>DAMPING CHARACTERISTICS OF A MICROMACHINED PIEZOELECTRIC DIAPHRAGM-BASED PRESSURE SENSOR FOR UNDERWATER APPLICATIONS</b> C.W. Tan <sup>1,2</sup> , A.G.P. Kottapalli <sup>2</sup> , Z.H. Wang <sup>2</sup> , X. Ji <sup>2</sup> , J.M. Miao <sup>2*</sup> , G. Barbastathis <sup>1,3</sup> and M. Triantafyllou <sup>1,3</sup> <sup>1</sup> <i>Center for Environmental Sensing and Modeling, SMART Centre, SINGAPORE</i> <sup>2</sup> <i>School of Mechanical and Aerospace Engineering, Nanyang Technological University, SINGAPORE</i> <sup>3</sup> <i>Department of Mechanical Engineering, Massachusetts</i>	68

- Institute of Technology, MA, USA*  
..... 72
- M3P.016 COMPACT ELECTRODE DESIGN FOR IN-PLANE ACCELEROMETER ON SOI WITH REFILLED ISOLATION TRENCH**  
Jin Xie, Rahul Agarwal, Youhe Liu, Julius Minglin Tsai and Nagarajan Ranganathan  
*The Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), Singapore*  
..... 76
- M3P.017 MICROFLUIDIC MICROSYSTEM FOR MAGNETIC SENSING OF NANOPARTICLES WITH GIANT MAGNETO-IMPEDANCE TECHNOLOGY**  
M. Denoual<sup>1</sup>, M. Harnois<sup>2</sup>, S. Saez<sup>1</sup>, C. Dolabdjian<sup>1</sup> and V. Senez<sup>2</sup>  
<sup>1</sup>*University of Caen Basse-Normandie GREYC-ENSICAEN, Caen, France*  
<sup>2</sup>*University of Lille Nord de France, IEMN, Lille, France*  
..... 80
- M3P.018 FIRST HIGH-G MEASUREMENT BY THERMAL ACCELEROMETERS**  
A. Garraud\*, P. Combette, J.M. Gosalbes, B. Charlot and A. Giani  
*Institut d'Electronique du Sud - Université Montpellier 2 - CNRS UMR 5412, Montpellier, FRANCE*  
..... 84
- M3P.019 EFFECT OF KNUDSEN NUMBER ON MAXIMUM RESPONSE OF A THERMAL CONDUCTIVITY DETECTOR**  
B.C. Kaanta<sup>1</sup>, H. Chen<sup>2</sup>, and X. Zhang<sup>1\*</sup>  
<sup>1</sup>*Boston University, Boston, MA, USA*  
<sup>2</sup>*Schlumberger Doll Research, Cambridge, MA, USA*  
..... 88
- M3P.020 THREE DIMENSIONAL PHOTOACOUSTIC IMAGING USING A MONOLITHIC CMOS MEMS CAPACITIVE ULTRASONIC SENSOR**  
Meng-Lin Li<sup>1</sup>, Po-Hsun Wang<sup>1</sup>, Pei-Liang Liao<sup>2</sup>, and Michael S.-C. Lu<sup>1,2</sup>  
<sup>1</sup>*Department of Electrical Engineering, <sup>2</sup>the Institute of NanoEngineering and Microsystems, National Tsing Hua University, Hsinchu, Taiwan*  
..... 92
- M3P.021 AN AERODYNAMICALLY EFFICIENT SPHERE ANEMOMETER WITH INTEGRATED HOT-FILM SENSORS FOR 2-D ENVIRONMENTAL AIRFLOW MONITORING**  
X.M. Jing<sup>1</sup>, J. Y. Lu<sup>1</sup>, J.M. Miao<sup>1\*</sup>, H. Hans<sup>1,2</sup>, H. A. Rahman<sup>1</sup>, S. S. Pan<sup>1,2</sup>, L. Norford<sup>2,3</sup>  
<sup>1</sup>*School of Mechanical and Aerospace Engineering, Nanyang Technological University, Singapore*  
<sup>2</sup>*Center for Environmental Sensing and Modeling (CENSAM), Singapore-MIT Alliance for Research and Technology (SMART) Centre, Singapore*  
<sup>3</sup>*Department of Architecture, Massachusetts Institute of Technology, Cambridge, MA, USA*  
..... 96
- M3P.022 A FILTER – LESS MULTI – WAVELENGTH FLUORESCENCE DETERCTOR**
- H. Nakazawa<sup>1,2,\*</sup>, K. Yamasaki<sup>1,\*</sup>, K. Takahashi<sup>1,3</sup>, M. Ishida<sup>1,4</sup>, and K. Sawada<sup>1,3,4</sup>  
<sup>1</sup>*Integrated Circuit and Sensor System Group, Toyohashi University of Technology, Aichi 441-8580, Japan*  
<sup>2</sup>*Research Fellow of the Japan Society for the Promotion of Science, Tokyo 102-8472 Japan*  
<sup>3</sup>*Core Research Evolutional Science and Technology, JST, Tokyo 102-8666, Japan*  
<sup>4</sup>*Electronics-Inspired Interdisciplinary Research Institute, TUT, Aichi 441-8580, Japan*  
<sup>\*</sup>*both authors contributed equally to this work*  
..... 100
- M3P.023 MULTI-PARAMETERS DECOUPLING METHOD WITH LAMB WAVE SENSOR FOR IMPROVING THE SELECTIVITY OF LABEL-FREE LIQUID DETECTION**  
Lianqun Zhou<sup>1,2,3,4</sup>, Ming Xuan<sup>1,4</sup>, Yihui Wu<sup>1,4,\*</sup>, Jean-François Manceau<sup>3</sup> and François Bastien<sup>3</sup>  
<sup>1</sup>*Changchun Institute of Optics, Fine Mechanics and Physics, Chinese Academy of Sciences, Changchun, China*  
<sup>2</sup>*Graduate University of Chinese Academy of Sciences, Beijing, China*  
<sup>3</sup>*MN2S Department, FEMTO-ST Institute, CNRS, Université de Franche-Comté, Besançon, France*  
<sup>4</sup>*Suzhou Institute of Biomedical Engineering and Technology, Chinese Academy of Sciences, Suzhou, China*  
..... 104
- M3P.024 A FLEXIBLE INTEGRATED MICROMACHINED HOT-FILM SENSOR ARRAY FOR MEASURING SURFACE FLOW VECTOR**  
R. Y. Que<sup>1</sup>, R. Zhu<sup>1\*</sup>, Q. Z. Wei<sup>1</sup>, and Z. Cao<sup>1</sup>  
<sup>1</sup>*State Key Laboratory of Precision Measurement Technology and Instruments, Department of Precision Instruments and Mechanology, Tsinghua University, Beijing, CHINA*  
..... 108
- M3P.025 A HIGH-SENSITIVE ULTRA-THIN MEMS CAPACITIVE PRESSURE SENSOR**  
Y. Zhang, R. Howver, B. Gogoi\* and N. Yazdi  
*Evigia Systems, Inc., Ann Arbor, Michigan, USA*  
<sup>\*</sup>*Currently with HVVi Semiconductors, Inc., Phoenix, Arizona, USA*  
..... 112
- M3P.026 ZERO TEMPERATURE COEFFICIENT GAS-SEALED PRESSURE SENSOR USING MECHANICAL TEMPERATURE COMPENSATION**  
X.C. Hao<sup>1</sup>, Y.G. Jiang<sup>1</sup>, H. Takao<sup>1,3</sup>, K. Maenaka<sup>1,2</sup>, T. Fujita<sup>1,2</sup>, and K. Higuchi<sup>1</sup>  
<sup>1</sup>*Maenaka Human-Sensing Fusion Project, JST, shosha 2167, Himeji, Hyogo, Japan*  
<sup>2</sup>*Department of Electrical Engineering and Computer Science, University of Hyogo, Himeji, Hyogo, Japan*  
<sup>3</sup>*Micro-Nano Struct. Device Integrated Res. Center, Kagawa University, Takamatsu, Kagawa, Japan*  
..... 116

## Chemical Sensors and Microsystems

### M3P.027 HYDROGEN SENSOR BASED ON PALLADIUM NANOTUBE ARRAYS FABRICATED BY NOVEL LOW-TEMPERATURE HYDROTHERMAL SYNTHESIS

M.A. Lim<sup>1</sup>, D. Kim<sup>1</sup>, C-O. Park<sup>2</sup>, Z. Li<sup>3</sup>, and I. Park<sup>1,\*</sup>

<sup>1</sup>Department of Mechanical Engineering & KI for the NanoCentury, KAIST, Daejeon, South Korea

<sup>2</sup>Department of Materials Science and Engineering, KAIST, Daejeon, South Korea

<sup>3</sup>Intelligent Infrastructure Lab, HP Laboratory, Palo Alto, CA, USA

120

### M3P.028 TURN-ON LASING SENSORY MECHANISM FOR VAPOR DETECTION OF AMINES WITH METALLOPHENYLPORPHRIN DOPED POLYFLUORENE

C.M. Deng<sup>1,2</sup>, C. He<sup>1,2</sup>, L.Q. Shi<sup>1,2</sup>, Y.Y. Fu<sup>1</sup>, D.F. Zhu<sup>1</sup>, H.M. Cao<sup>1</sup>, Q.G. He<sup>1</sup>, and J.G. Cheng<sup>1</sup>

<sup>1</sup>State Key Laboratory of Transducer Technology, Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, Shanghai, China

<sup>2</sup>Graduate School of the Chinese Academy of Sciences, Beijing, China

124

### M3P.029 ANALYSIS OF C1 AND C2 HYDROCARBON GAS MIXTURES USING MINIATURIZED GAS CHROMATOGRAPHY AND SNO2 GAS DETECTORS

A. Sklorz<sup>\*1</sup>, A. Schu<sup>1</sup> and W. Lang<sup>1,2</sup>

<sup>1</sup>Institute for Microsensors, -actuators and -systems (IMSAS), University of Bremen, Bremen, Germany

<sup>2</sup>FWBI Friedrich-Wilhelm-Bessel Forschungsgesellschaft mbH, Bremen, Germany

128

### M3P.030 MICROMECHANICAL OLFATORY SYSTEM FOR SENSITIVE AND SELECTIVE DETECTION OF EXPLOSIVES

K.S. Hwang<sup>1</sup>, M.H. Lee<sup>1</sup>, J.K. Han<sup>1</sup>, T.S. Kim<sup>1</sup> and J.Y. Kang<sup>1</sup>

<sup>1</sup>Korea Institute of Science and Technology (KIST), Seoul, Republic of KOREA

132

### M3P.031 SENSING CHARACTERISTICS OF RNA OLIGOMER COATED SWNT GAS SENSORS

Y. Liu<sup>1</sup>, M. Chen<sup>2</sup>, M.L. Wang<sup>3</sup>, and M. R. Dokmeci<sup>1</sup>

<sup>1</sup>ECE, Northeastern University, Boston, MA, USA

<sup>2</sup>Point Loma Nazarene University, San Diego, CA, USA

<sup>3</sup>CEE, Northeastern University, Boston, MA, USA

136

### M3P.032 A MINIATURIZED NETWORKED SENSOR FOR TRACE EXPLOSIVES

L. Song<sup>1,3</sup>, L. He<sup>2,3</sup>, L. Cui<sup>1</sup> and W. Hu<sup>3</sup>

<sup>1</sup>The Technical Manuscript Design Group, City, STATE/Province, COUNTRY

<sup>2</sup>The Scientific Paper Formatting Initiative, Beijing, China

<sup>3</sup>Laboratory for Abstract Submissions, Nanjing, China

140

### M3P.033 MIXED-POTENTIAL TYPE NOX SENSOR USING STABILIZED ZIRCONIA AND CR2O3-WO3 NANOCOMPOSITES

Quan Diao, Xishuang Liang<sup>\*</sup>, Jianguo Li, Shiqi Yang, Chengguo Yin and Geyu Lu<sup>\*</sup>

State Key Laboratory on Integrated Optoelectronics, College of Electronic Science and Engineering, Jilin University, 2699 Qianjin Street, Changchun 130012, China

146

### M3P.034 HIGH-PERFORMANCE OF PLANAR NO2 SENSOR USING STABILIZED ZIRCONIA AND NIO SENSING ELECTRODE SYNTHESIZED BY MICROWAVE AT HIGH TEMPERATURE

Shiqi Yang, Xishuang Liang<sup>\*</sup>, Jianguo Li, Quan Diao, Han Zhang and Geyu Lu<sup>\*</sup>

State Key Laboratory on Integrated Optoelectronics, College of Electronic Science and Engineering, Jilin University, 2699 Qianjin Street, Changchun 130012, China

150

### M3P.035 IMPROVEMENT IN SELECTIVITY OF NO2 SENSORS BASED ON WO3 THIN FILMS WITH MNO2 FILTERS DEPOSITED BY RADIO FREQUENCY SPUTTERING

C. Zhang<sup>1</sup>, A. Boudiba<sup>1</sup>, C. Navio<sup>2</sup>, M.-G. Olivier<sup>1</sup>, R. Snyders<sup>2,3</sup>, M. Debliquy<sup>1</sup>

<sup>1</sup>Service de Science des Matériaux, Faculté Polytechnique, Université de Mons, Mons, Belgium

<sup>2</sup>Plasma Surface Interaction Chemistry, CIRMAP, Université de Mons, Mons, Belgium

<sup>3</sup>Materia Nova Research Centre, Mons, Belgium

154

### M3P.036 UV-ENHANCED ROOM TEMPERATURE GAS SENSOR BASED ON HOLLOW SPHERE SNO2-TIO2

J.B. Sun, J. Xu, Y.S. Yu, Y. Guan, F.M. Liu<sup>\*</sup>, G.Y. Lu<sup>\*</sup>

State Key Laboratory on Integrated Optoelectronics Jilin University Region;

College of Electronic Science and Engineering, Jilin University, Changchun, PR CHINA

158

### M3P.037 DMMP VAPOR DETECTION WITH 50NM THICK ALN FILMS BASED MICROCANTILEVERS

P. Ivaldi<sup>1</sup>, J. Abergel<sup>1</sup>, H. Blanc<sup>1</sup>, E. Colinet<sup>1</sup>, E.B. Myers<sup>2</sup>, M.L. Roukes<sup>2</sup>, P. Robert<sup>1</sup>, P. Andreucci<sup>1</sup>, S. Hentz<sup>1\*</sup>, E. Defay<sup>1</sup>

<sup>1</sup>CEA-LETI, MINATEC Campus, Grenoble, France

<sup>2</sup>Kavli Nanoscience Institute, California Institute of Technology, Pasadena, California USA

- .....162
- M3P.038 NOVEL PALLADIUM NANOROD ELECTRODE ENSEMBLE FOR ELECTROCHEMICAL EVALUATION OF HYDROGEN ADSORPTION**  
Y.T. Chuang, S.P. Ju, and C.H. Lin  
*Department of Mechanical and Electro-Mechanical Engineering National Sun Yat-sen University, Kaohsiung, Taiwan*
- .....166
- M3P.039 HYDROGEN GAS SENSING PERFORMANCE OF A Pt/GRAPHENE/SiC DEVICE**  
M. Shafiei<sup>1,2</sup>, K. Shin<sup>3</sup>, J. Yu<sup>1</sup>, S. H. Han<sup>3</sup>, J. W. Jong<sup>4</sup>, N. Motta<sup>2</sup>, J. du Plessis<sup>5</sup>, W. Wlodarski<sup>1</sup>  
<sup>1</sup>*Sensor Technology Laboratory, RMIT University, Melbourne, Australia*  
<sup>2</sup>*School of Engineering Systems, Queensland University of Technology (QUT), Brisbane, Australia*  
<sup>3</sup>*Department of Chemistry and Graphene Research Institute, Korea*  
<sup>4</sup>*Department of Nano-Science and Technology and Graphene Research Institute, Korea*  
<sup>5</sup>*School of Applied Sciences, RMIT University, Melbourne, Australia*
- .....170
- M3P.040 NASICON-BASED POTENTIOMETRIC CL2 SENSOR USING CR2O3 SENSING ELECTRODE**  
Han Zhang, Xishuang Liang\*, Jianguo Li, Geyu Lu\*  
*State Key Laboratory on Integrated Optoelectronics, College of Electronic Science and Engineering, Jilin University, 2699 Qianjin Street, Changchun 130012, China*
- .....174
- M3P.041 THIN FILM GAS SENSOR FOR DETECTION OF TOXIC GASES FROM MICROBIAL**  
Sang-Do Han<sup>1</sup>, and Y.-S. Sohn<sup>2</sup>  
<sup>1</sup>*Korea Institute of Energy Research, Energy Conversion and Storage Research Center, Daejeon, 305-343, Korea*  
<sup>2</sup>*Catholic University of Daegu, Gyeongsan-si, Gyeongbuk, 702-701 Korea*
- .....178

## Bio-Sensors and Bio-Microsystems

- M3P.042 A FULLY INTEGRATED, HIGH-THROUGHPUT, MULTI-PARAMETRIC FLOW CYTOMETRY CHIP USING "MICROFLUIDIC DRIFTING" BASED THREE-DIMENSIONAL (3D) HYDRODYNAMIC FOCUSING**  
Xiaole Mao<sup>1,2</sup>, Ahmad Ahsan Nawaz<sup>1</sup>, and Tony Jun Huang<sup>1,2</sup>  
<sup>1</sup>*Department of Engineering Science and Mechanics, The Pennsylvania State University, University, PA, 16801 US*  
<sup>2</sup>*The Department of Bioengineering, The Pennsylvania State University, University, PA, 16801 US*
- .....182

- M3P.043 RECORDING OF NEURAL ACTIVITY OF MOUSE RETINAL GANGLION CELLS BY MEANS OF AN INTEGRATED HIGH-DENSITY MICROELECTRODE ARRAY**  
I.L. Jones<sup>1</sup>, M. Fiscella<sup>1</sup>, U. Frey<sup>1</sup>, D. Jäckel<sup>1</sup>, J. Müller<sup>1</sup>, B. Roscic<sup>1</sup>, R. Streichan<sup>1</sup>, A. Hierlemann<sup>1</sup>  
<sup>1</sup>*Bio Engineering Laboratory, ETH Zurich, Basel, Switzerland*
- .....186
- M3P.044 PATHOGEN DETECTION USING MICROFLUIDIC BEAD-BASED POLYMERASE CHAIN REACTION**  
J.P. Hilton<sup>1</sup>, T. Nguyen<sup>1</sup>, M. Barbu<sup>2</sup>, R. Pei<sup>2</sup>, M. Stojanovic<sup>2</sup>, Q. Lin<sup>1</sup>  
<sup>1</sup>*Dept. of Mechanical Engineering, Columbia University, New York, USA*  
<sup>2</sup>*Dept. of Medicine, Columbia University, New York, USA*
- .....190
- M3P.045 PARALLEL FOCUSING AND SWITCHING OF LEAKAGE FLUX FROM MAGNETIC LOOP FOR ON-CHIP PATTERNING OF MAGNETICALLY LABELED CELLS**  
J. Kunishida, W. Tonomura, J. Sato and S. Konishi  
*Ritsumeikan University, Shiga, JAPAN*
- .....194
- M3P.046 PARYLENE MICROPROBES WITH ENGINEERED STIFFNESS AND SHAPE FOR IMPROVED INSERTION**  
Daniel Egert, Rebecca L. Peterson and Khalil Najafi  
*Center for Wireless Integrated Microsystems (WIMS), University of Michigan, Ann Arbor, USA*
- .....198
- M3P.047 MECHANICAL AND ELECTRICAL EVALUATION FOR THE LONG-TERM STABILITY OF IMPLANTED 3D RETINAL MICROELECTRODE**  
S. Hong, S. Lee, H. Yoo, J. Ahn, S. Park, K. Koo, and D. Cho\*  
*Automation and Systems Research Institute (ASRI)/Inter-university Semiconductor Research Center (ISRC), School of Electrical Engineering and Computer Sciences, Seoul National University, Seoul, Korea*
- .....202
- M3P.048 REUSABLE HIGH-FREQUENCY ELECTRODELESS QCM BIOSENSOR WITH A BARE QUARTZ RESONATOR EMBEDDED IN A SILICON MICROCHANNEL**  
Fumihito Kato<sup>1</sup>, Shintaro Nishikawa<sup>1</sup>, Taiji Yanagida<sup>1</sup>, Hirotsugu Ogi<sup>\*1,2</sup>, Masahiko Hirao<sup>1</sup>  
<sup>1</sup>*Graduate School of Engineering Science, Osaka University, Osaka, Japan*  
<sup>2</sup>*Japan Science and Technology Agency, PRESTO, Saitama, Japan*
- .....206
- M3P.049 INTEGRATED MICROFLUIDIC**

**LOOP-MEDIATED-ISOTHERMAL-AMPLIFICATION SYSTEMS FOR RAPID ISOLATION AND DETECTION OF AQUACULTURE PATHOGENS**

Wen-Hsin Chang<sup>1</sup>, Sung-Yi Yang<sup>1</sup>, Chih-Hung Wang<sup>1</sup>, Ming-An Tsai<sup>2</sup>, Pei-Chyi Wang<sup>2,3</sup>, Shih-Chu Chen<sup>2,4</sup>, Tzong-Yueh Chen<sup>5</sup>, and Gwo-Bin Lee<sup>1\*</sup>

<sup>1</sup>Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan

<sup>2</sup>Department of Veterinary medicine, National Pingtung University of Science and Technology, Pingtung, Taiwan

<sup>3</sup>Department of Tropical Agriculture and International Cooperation, National Pingtung University of Science and Technology, Pingtung, Taiwan

<sup>4</sup>Graduate Institute of Animal Vaccine, National Pingtung University of Science and Technology, Pingtung, Taiwan

<sup>5</sup>Institute of Biotechnology, National Cheng Kung University, Tainan

.....210

**Medical Microsystems**

**M3P.050 EASY AND STABLE LIPID BILAYER**

**FORMATION: A DROPLETS- CONTACTING-METHOD IN PARYLENE MICROPORES FOR MULTIPLE ION CHANNEL RECORDINGS**

Yutaro Tsuji<sup>1,3</sup>, Ryuji Kawano<sup>1</sup>, Toshihisa Osaki<sup>1</sup>, Hiroataka Sasaki<sup>1</sup>, Norihisa Miki<sup>1,3</sup>, and Shoji Takeuchi<sup>1,2</sup>

<sup>1</sup>Kanagawa Academy of Science and Technology, Kanagawa, Japan

<sup>2</sup>Institute of Industrial Science, The University of Tokyo, Tokyo, Japan

<sup>3</sup>Keio University, Kanagawa, Japan

.....214

**M3P.051 AN INTEGRATED LOBULE-MIMETIC LIVER CHIP FOR TESTING HEPATOTOXICITY**

Y. J. Chu<sup>1</sup>, T. H. Punde<sup>2</sup>, S. M. Yang<sup>3</sup>, V. P. Srinivasu<sup>1</sup>, S. Shilpa<sup>1</sup>, R. J. Chen<sup>1</sup>, C. H. Liu<sup>1\*</sup>

<sup>1</sup>Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan, R.O.C.

<sup>2</sup>Institute of NanoEngineering and Microsystems, National Tsing Hua University, Hsinchu, Taiwan, R.O.C.

<sup>3</sup>Department of Electrophysics, National Chiao Tung University, Taiwan, R.O.C.

.....218

**M3P.052 MICROFLUIDIC DEVICE TO PERFORM IMPEDOMETRIC DETECTION OF ACTIVATED PARTIAL THROMBOPLASTIN TIME OF BLOOD**

B. Ramaswamy<sup>1</sup>, Y.T. Yeh<sup>2</sup>, and S.Y. Zheng<sup>2</sup>

<sup>1</sup>Department of Electrical Engineering

<sup>2</sup>MINIBio Lab, Department of Bioengineering, The Pennsylvania State University, University Park, Pennsylvania, U.S.A

.....222

**M3P.053 A HIGH-PERFORMANCE MICROSYSTEM FOR ISOLATING VIABLE CIRCULATING TUMOR**

**CELLS**

X.J. Zheng<sup>1</sup>, L.S.L. Cheung<sup>1</sup>, J.A. Schroeder<sup>2</sup>, L. Jiang<sup>1,3</sup>, and Y. Zohar<sup>1,4</sup>

<sup>1</sup>Dept. Aerospace and Mechanical Engineering

<sup>2</sup>Dept. Molecular and Cellular Biology

<sup>3</sup>College of Optical Sciences

<sup>4</sup>Dept. Biomedical Engineering, The University of Arizona, Tucson, Arizona, USA

.....226

**Microfluidics**

**M3P.054 FINGER-POWERED MICRODROPLET GENERATOR**

K. Iwai, A. T. Higa, R. D. Sochol, and L. Lin  
Mechanical Engineering Department, Berkeley Sensor and Actuator Center, University of California, Berkeley, USA

.....230

**M3P.055 ON-CHIP GELATION OF TEMPORALLY CONTROLLED ALGINATE MICRODROPLETS**

D.-H. Lee, W. Lee, E. Um, and J.-K. Park  
Department of Bio and Brain Engineering, KAIST, Daejeon, REPUBLIC OF KOREA

.....234

**M3P.056 HIGH-PERFORMANCE PROTEIN PRECONCENTRATOR USING MICROCHANNEL-INTEGRATED NAFION STRIP**

H. Yang, M. Shen, V. Sivagnanam and M. A. M. Gijs

Laboratory of Microsystems, École Polytechnique Fédérale de Lausanne, Lausanne, SWITZERLAND

.....238

**M3P.057 OPTICAL-DRIVEN VORTEX AS A MICROPARTICLE CONCENTRATOR**

S. M. Yang<sup>1</sup>, T. H. Punde<sup>2</sup>, Y. J. Chu<sup>3</sup>, T. M. Yu<sup>1</sup>, M. H. Liu<sup>4</sup>, L. Hsu<sup>1</sup>, and C. H. Liu<sup>3\*</sup>

<sup>1</sup>Department of Electrophysics, National Chiao Tung University, Taiwan, R.O.C.

<sup>2</sup>Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Taiwan, R.O.C.

<sup>3</sup>Department of Power Mechanical Engineering, National Tsing-Hua University, Taiwan, R.O.C.

<sup>4</sup>SINONAR Company, Taiwan, R.O.C

.....242

**M3P.058 MARANGONI-DRIVEN MICROMOTOR IN LIQUID MEDIUM**

E. Hendarto<sup>1</sup> and Y.B. Gianchandani  
Department of Electrical Engineering and Computer Science, University of Michigan 1301 Beal Ave, Ann Arbor, MI 48109, USA.

.....246

**M3P.059 AN ELECTROSTATICALLY ACTUATED PARYLENE MICROVALVE FOR LAB-ON-A-CHIP APPLICATIONS**

Ender Yıldırım<sup>1,2</sup>, Haluk Kūlah<sup>3,4</sup>, and M.A. Sahir Arıkan<sup>1,4</sup>

- <sup>1</sup>*METU, Department of Mechanical Engineering, Ankara, TURKEY*
- <sup>2</sup>*Cankaya University, Department of Mechanical Engineering, Ankara, TURKEY*
- <sup>3</sup>*METU, Department of Electrical and Electronics Engineering, Ankara, TURKEY*
- <sup>4</sup>*METU-MEMS Research and Applications Center, Ankara, TURKEY*
- .....250
- M3P.060 A NOVEL NARROW MIST SPRAY DEVICE USING SURFACE ACOUSTIC WAVE WITH A CHANNEL**  
 Atsushi Yabe, Yuichiro Hamate, Sumito Nagasawa, and Hiroki Kuwano  
*Department of Nanomechanics in Tohoku University, Sendai, Miyagi, JAPAN*
- .....254
- M3P.061 HIGH-YIELD BLOOD PLASMA SEPARATION BY MODULATING INERTIAL MIGRATION IN A CONTRACTION-EXPANSION ARRAY MICROCHANNEL**  
 M. G. Lee<sup>1</sup>, S. Choi<sup>1</sup>, H.-J. Kim<sup>2</sup>, H. K. Lim<sup>1,3</sup>, J.-H. Kim<sup>3</sup>, N. Huh<sup>3</sup>, and J.-K. Park<sup>1</sup>  
<sup>1</sup>*Department of Bio and Brain Engineering, KAIST, Daejeon, REPUBLIC OF KOREA*  
<sup>2</sup>*Department of Hematology, Catholic Blood and Marrow Transplantation Center, Seoul St. Mary's Hospital, The Catholic University of Korea College of Medicine, Seoul, REPUBLIC OF KOREA*  
<sup>3</sup>*Bio Lab., SAIT, Samsung Electronics Co. Ltd., Yongin-Si, REPUBLIC OF KOREA*
- .....258
- M3P.062 MEMS SILICON-BASED RESISTOJET MICRO-THRUSTER FOR ATTITUDE CONTROL OF NANO-SATELLITES**  
 M. Mihailovic<sup>1</sup>, T.V. Mathew<sup>2</sup>, J.F. Creemer<sup>1</sup>, B.T.C. Zandbergen<sup>2</sup> and P.M. Sarro<sup>1</sup>  
<sup>1</sup>*Delft Institute of Microsystems and Nanoelectronics, Delft University of Technology, Delft, the Netherlands*  
<sup>2</sup>*Chair Space Systems Engineering, Delft University of Technology, Delft, the Netherlands*
- .....262
- M3P.063 ROLLING, ALIGNING, AND TRAPPING DROPLETS ON A LASER BEAM USING MARANGONI OPTOFLUIDIC TWEEZERS**  
 G.K. Kurup<sup>1</sup> and Amar S. Basu<sup>1,2</sup>  
<sup>1</sup>*Department of Electrical and Computer Engineering*  
<sup>2</sup>*Department of Biomedical Engineering Wayne State University, Detroit MI, USA*
- .....266
- M3P.064 A HYBRID ELECTROKINETIC BIOPROCESSOR FOR STATIC AND DYNAMIC PATHOGEN MANIPULATION IN PHYSIOLOGICAL SAMPLES**  
 Jian Gao<sup>1,2</sup>, Mandy L. Y. Sin<sup>2</sup>, and Pak Kin Wong<sup>2,3,4,\*</sup>  
<sup>1</sup>*Chemical Engineering, Shandong Polytechnic University, Jinan, China*  
<sup>2</sup>*Aerospace and Mechanical Engineering, University of*
- Arizona, Tucson, USA*
- <sup>3</sup>*Biomedical Engineering IDP, University of Arizona, Tucson, USA*
- <sup>4</sup>*Bio5 Institute, University of Arizona, Tucson, USA*
- .....270
- M3P.065 SIZE FRACTIONATION OF PRIMARY MUSCLE CELLS USING HYDRODYNAMICS IN MICROCHANNELS**  
 K. Funakoshi<sup>1</sup>, Y. Akiyama<sup>1</sup>, T. Hoshino<sup>1</sup>, K. Morishima<sup>1,2</sup>  
<sup>1</sup>*Grad. School of Bio-Applications & Systems Engineering, Tokyo Univ. of Agri. & Tech., Tokyo, Japan,*  
<sup>2</sup>*Dep. of Mech. Systems Engineering, Tokyo Univ. of Agri. & Tech., Tokyo, Japan*
- .....274
- M3P.066 2-DIMENSIONAL SEPARATION OF BIOMIMETIC PARTICLES BY STOPPED-FLOW CENTRIFUGO-MAGNETOPHORESIS**  
 J. Siegrist, L. Zavattoni, R. Burger, and J. Ducreé\*  
*Biomedical Diagnostics Institute, National Centre for Sensor Research, School of Physics, Dublin City University, IRELAND*
- .....278
- M3P.067 UNTETHERED MICROROBOT ACTUATED BY AN ELECTROMAGNETIC FIELD WITH AN ACOUSTICALLY OSCILLATING BUBBLE FOR BIO/MICRO-OBJECT MANIPULATION**  
 J. O. Kwon, J. S. Yang, and S. K. Chung  
*Department of Mechanical Engineering, Myongji University, Yongin 449-728, South Korea*
- .....282
- M3P.068 MICROEDDY DESIGN AND APPLICATION FOR SINGLE CELL TRAPPING AND MONITORING**  
 V.H. Lieu, T.A. House, J.T. Crawford and D.T. Schwartz  
*Department of Chemical Engineering, University of Washington, Seattle, Washington, United States*
- .....286
- M3P.069 IN-SITU CLOSED LOOP HYDROGEL MEMBRANE FORMATION BY ONE STEP STAMPING**  
 Eunpyo Choi<sup>1</sup> and Jungyul Park<sup>1\*</sup>  
<sup>1</sup>*Department of Mechanical Engineering, Sogang University, Seoul, Korea*
- .....290
- M3P.070 A MULTIPLEXED MICROFLUIDIC IMPEDANCE SENSOR FOR HIGH THROUGHPUT ANALYSIS OF MICROPARTICLES**  
 Ashish V. Jagtiani and Jiang Zhe\*  
*Department of Mechanical Engineering, The University of Akron, Akron, OH, USA 44325*
- .....294
- M3P.071 HIGH-EFFICIENCY BLOOD SEPARATION UTILIZING SPIRAL FILTRATION MICROCHANNEL WITH GRADUALLY VARIED WIDTH**  
 Y.R. Ju<sup>1</sup>, Z.X. Geng<sup>1,2,3\*</sup>, L.Q. Zhang<sup>1</sup>, W. Wang<sup>1</sup>

and Z.H. Li<sup>1\*</sup>

<sup>1</sup>National Key Laboratory of Nano/Micro Fabrication Technology, Institute of Microelectronics, Peking University, Beijing, China

<sup>2</sup>School of Information Engineering, Minzu University of China, Beijing, China

<sup>3</sup>Engineering Research Center for Semiconductor Integrated Technology Institute of Semiconductors, Chinese Academy of Sciences, Beijing, China

298

**M3P.072 A DOUBLE TRAPPED SINGLE CELL CONTACT AND INTERACTION SYSTEM VIA MOVABLE POLY (ETHYLENE GLYCOL) DIACRYLATE (PEG-DA) MICROSTRUCTURE FOR IMMUNE ANALYSIS**

Ling-Yi Ke<sup>1</sup>, Yu-Shih Chen<sup>2,3</sup>, Zong-Keng Kuo<sup>3</sup> and Cheng-Hsien Liu<sup>1,2</sup>

<sup>1</sup>Department of Power Mechanical Engineering, <sup>2</sup>Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, Taiwan, R.O.C.

<sup>3</sup>Biomedical Engineering Research Lab, Industrial Technology Research Institute, Hsinchu, Taiwan, R.O.C.

302

**M3P.073 MICROFLUIDIC VALVES BASED ON TiO<sub>2</sub> COATING WITH TUNABLE SURFACE WETTABILITY BETWEEN SUPERHYDROPHILIC AND SUPERHYDROPHOBIC**

T. Zhang, M. Zhang, and T. Cui<sup>\*</sup>  
Department of Mechanical Engineering, University of Minnesota, Minneapolis, MN 55455, USA

306

**M3P.074 FLUORESCENCE ENHANCEMENT VIA SINGLE-CORE LIQUID WAVEGUIDES IN MICROFLUIDIC CHANNELS**

H. Huang<sup>1,2\*</sup>, X. M. Ji<sup>1</sup>, J. Zhou<sup>1</sup>, T. J. Huang<sup>2</sup>, and Y. P. Huang<sup>1\*</sup>

<sup>1</sup>ASIC and System State Key Lab, Department of Microelectronics, Fudan University, Shanghai, China

<sup>2</sup>Department of Engineering Science and Mechanics, The Pennsylvania State University, University Park, PA, USA

310

**M3P.075 LASER-ACTUATED MICRO-VALVES AND MICRO-PUMPS**

Aoqun Jian, Kai Zhang, Yu Wang, and Xuming Zhang<sup>\*</sup>

Department of Applied Physics, Hong Kong Polytechnic University, Hong Kong, P. R. China

314

**M3P.076 MICRO-LIQUID HANDLING ON PAPER ANALYSIS CHIP TRIGGERED BY INK-JET DROPLET**

S. Okabe<sup>1,2</sup>, K. Sakamoto<sup>1</sup>, Y. Murakami<sup>1,2</sup>, T. Ishikawa<sup>1,2</sup> and R. Miyake<sup>1,2</sup>

<sup>1</sup>Hiroshima University, 1-4-2 Kagamiyama, Higashi-Hiroshima, JAPAN

<sup>2</sup>JST, CREST, Tokyo, JAPAN

318

**M3P.077 LIGHT-DIRECTED MIGRATION OF D. DISCOIDEUM SLUGS IN MICROCHANNELS**

J. Kim<sup>\*1</sup>, H. Ennis<sup>2</sup>, T. Nguyen<sup>1</sup>, R. Kessin<sup>3</sup>, M. Stojanovic<sup>2</sup>, and Q. Lin<sup>1</sup>

Departments of Mechanical Engineering<sup>1</sup>, Medicine<sup>2</sup>, and Anatomy and Cell Biology<sup>3</sup>, Columbia University, New York, NY 10027, USA

322

**M3P.078 A MINIATURIZED OPTICALLY-INDUCED FLUORESCENCE-ACTIVATED CELL SORTER**

S. M. Yang<sup>1</sup>, M. Y. Ku<sup>1</sup>, T. H. Punde<sup>2</sup>, R. J. Chen<sup>3</sup>, S. Y. Tseng<sup>1</sup>, T. M. Yu<sup>1</sup>, H. P. Huang<sup>1</sup>, M. H. Liu<sup>4</sup>, L. Hsu<sup>1</sup>, and C. H. Liu<sup>3</sup>

<sup>1</sup>Department of Electrophysics, National Chiao Tung University, Taiwan, R.O.C.

<sup>2</sup>Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Taiwan, R.O.C.

<sup>3</sup>Department of Power Mechanical Engineering, National Tsing-Hua University, Taiwan, R.O.C.

<sup>4</sup>SINONAR Company, Taiwan, R.O.C.

326

**M3P.079 DIODE CHARACTERISTIC OF ELECTROLYTE-OXIDE-SEMICONDUCTOR STRUCTURE FOR POTENTIAL CHEMICAL AND BIOLOGICAL APPLICATIONS**

Y.L. Zhang, G.C. Sun, and W.G. Wu<sup>\*</sup>

National Key Laboratory of Science and Technology on Micro/Nano Fabrication, Institute of Microelectronics, Peking University, Beijing 100871, P. R. China

330

**Materials, Fabrication and Packaging Technologies**

**M3P.080 LOW-TEMPERATURE ZERO-LEVEL PACKAGING TECHNIQUE USING PHOTOSENSITIVE FILM TYPE PERMX POLYMER**

S. Seok, J. Kim, N. Rolland, P.A. Rolland  
IEMN/CNRS 8520, Villeneuve d'Ascq CEDEX, France

334

**M3P.081 RELIABILITY OF MICRO-HOTPLATES ON POLYIMIDE FOIL**

J. Courbat, M. Barbieri, D. Briand, and N.F. de Rooij  
Ecole Polytechnique Fédérale de Lausanne (EPFL), Institute of Microengineering (IMT), Sensors, Actuators and Microsystems Laboratory (SAMPLAB), Neuchâtel, Switzerland

338

**M3P.082 ELECTRICAL CONNECTION USING SUBMICRON POROUS GOLD BUMPS FOR WAFER-LEVEL PACKAGING OF MEMS USING ANODICALLY-BONDABLE LTCC WAFER**

Shuji Tanaka<sup>1\*</sup>, Mamoru Mohri<sup>2</sup>, Toshinori

- Ogashiwa<sup>3</sup>, Hideyuki Fukushi<sup>1</sup>, Katsunao Tanaka<sup>3</sup>,  
Daisuke Nakamura<sup>2</sup>, Takashi Nisimori<sup>3</sup>,  
Masayoshi Esashi<sup>1</sup>  
<sup>1</sup>Tohoku University, Sendai, Miyagi, Japan  
<sup>2</sup>Nikko Company, Hakusan, Ishikawa, Japan  
<sup>3</sup>Tanaka Kikinzoku Kogyo, Hiratsuka, Kanagawa,  
Japan  
.....342
- M3P.083 MATERIAL OPTIMIZATION OF  
PHOSPHORUS-DOPED POLYCRYSTALLINE  
SILICON GERMANIUM FOR MINIATURIZED  
THERMOELECTRIC GENERATOR**  
Z. Wang<sup>1</sup>, J. Su<sup>1</sup>, Y. van Andel<sup>1</sup>, H. Nguyen<sup>2</sup>, R. J.  
M. Vullers<sup>1</sup>  
<sup>1</sup>Imec / Holst Centre, High Tech Campus 31, 5656AE,  
Eindhoven, the Netherlands  
<sup>2</sup>Dept. MTM, Katholieke Universiteit Leuven, B-3000,  
Leuven, Belgium  
.....346
- M3P.084 MONOCRYSTALLINE THIN-FILM WAFERLEVEL  
ENCAPSULATION OF MICROSYSTEMS USING  
POROUS SILICON**  
A. Prümm<sup>1</sup>, K.-H. Kraft<sup>1</sup>, P. Gottschling<sup>1</sup>, M.  
Ahles<sup>1</sup>, S. Armbruster<sup>1</sup>, M. Metz<sup>1</sup>, J. N.  
Burghartz<sup>2</sup>  
<sup>1</sup>Robert Bosch GmbH – Engineering Sensor Technology  
Center, Reutlingen, GERMANY  
<sup>2</sup>Institute for Microelectronics Stuttgart (IMS CHIPS),  
Stuttgart, GERMANY  
.....350
- M3P.085 BLACK SILICON WITH SUB-PERCENT  
REFLECTIVITY: INFLUENCE OF THE 3D  
TEXTURIZATION GEOMETRY**  
K. N. Nguyen<sup>1</sup>, D. Abi-Saab<sup>1</sup>, P. Basset<sup>1</sup>, E.  
Richalot<sup>2</sup>, F. Marty<sup>1</sup>, D. Angelescu<sup>1</sup>, Y.  
Leprince-Wang<sup>3</sup>, T. Bourouina<sup>1</sup>  
<sup>1</sup>Université Paris-Est, ESYCOM, ESIEE Paris,  
Noisy-le-Grand, France  
<sup>2</sup>Université Paris-Est, ESYCOM, UMLV, Noisy-le-Grand,  
France  
<sup>3</sup>Université Paris-Est, LPMDI, Noisy-le-Grand, France  
.....354
- M3P.086 INCREASE IN MECHANICAL STRENGTH BY  
SCALLOPING REMOVAL**  
Kayo Hamaguchi<sup>1</sup>, Hirotaka Hida<sup>2</sup>, Mitsuhiro  
Shikida<sup>3</sup>, and Kazuo Sato<sup>2</sup>  
<sup>1</sup>Dept. of Mechanical Engineering, Nagoya University,  
Nagoya, Japan  
<sup>2</sup>Dept. of Micro-Nano Systems Engineering, Nagoya  
University, Nagoya, Japan  
<sup>3</sup>Center for Micro-Nano Mechatronics, Nagoya  
University, Nagoya, Japan  
.....358
- M3P.087 ENHANCED DYNAMIC ELECTROMECHANICAL  
PROPERTIES OF ELECTROPHORESIS  
ASSEMBLED CARBON NANOTUBE-POLYMER  
PIEZOELECTRIC TRANSDUCERS**  
D. Zhang and T. Cui  
Department of Mechanical Engineering, University of  
Minnesota, Minneapolis, Minnesota, USA  
.....362
- M3P.088 LOW TEMPERATURE PYREX/SILICON WAFER  
BONDING VIA A SINGLE INTERMEDIATE  
PARYLENE LAYER**  
A.T. Ciftlik and M.A.M. Gijs  
Laboratory of Microsystems, École Polytechnique  
Fédérale de Lausanne, CH-1015 Lausanne, Switzerlan  
.....366
- M3P.089 CONTINUOUS PHOTOLITHOGRAPHY SYSTEM  
AND TECHNOLOGY FOR FIBER SUBSTRATE**  
Y. Zhang<sup>\*1,2</sup>, J. Lu<sup>1,2</sup>, A.Ohtomo<sup>2,3</sup>, H. Mekar<sup>1,2</sup>,  
and T. Itoh<sup>1,2</sup>  
<sup>1</sup>NEDO BEANS Project, Macro BEANS Center,  
Tsukuba, Ibaraki, Japan  
<sup>2</sup>National Institute of Advanced Industrial Science and  
Technology (AIST), Tsukuba, Ibaraki, Japan  
<sup>3</sup>Toshiba Machine Co., Ltd, Numazu, Shizuoka, Japan  
.....370
- M3P.090 A GENETIC ALGORITHM BASED KINETIC  
MONTE CARLO SIMULATION FOR THE  
EVOLUTION OF COMPLEX SURFACE IN  
ANISOTROPIC WET ETCHING**  
Y. Xing<sup>1</sup>, M. A. Gosálvez<sup>2</sup>, M. Tian<sup>1</sup> and K. Sato<sup>3</sup>  
<sup>1</sup>Laboratory for Micro-Nano Medical Device, Dept. of  
Mechanical Eng, Southeast University, Nanjing, China  
<sup>2</sup>Dept. Materials Phys., Univ. of the Basque Country  
(UPV-EHU, CFM-CSIC, DIPC), San Sebastian, Spain  
<sup>3</sup>Dept. of Micro-Nano Systems Engineering, Nagoya  
University, Nagoya 464-8603, Japan  
.....374
- M3P.091 HIGH DENSITY 256-CHANNEL CHIP  
INTEGRATION WITH FLEXIBLE  
PARYLENE POCKET**  
Jay Han-Chieh Chang, Ray Huang and  
Yu-Chong Tai  
California Institute of Technology, CA, USA  
.....378
- M3P.092 WAFER-LEVEL TWO-STEP BONDING PROCESS  
FOR COMBINED SENSOR WITH TWO  
DIFFERENT PRESSURE CHAMBERS**  
T.Aono<sup>1</sup>, K. Suzuki<sup>1</sup>, A. Koide<sup>1</sup>, H. Jeong<sup>2</sup>, M.  
Degawa<sup>2</sup>, K. Yamanaka<sup>2</sup>, and M. Hayashi<sup>3</sup>  
<sup>1</sup>Mechanical Engineering Research Laboratory, Hitachi,  
Ltd., Ibaraki, Japan  
<sup>2</sup>Central Research Laboratory, Hitachi, Ltd., Tokyo,  
Japan  
<sup>3</sup>Hitachi Automotive System, Ltd., Ibaraki, Japan  
.....382
- M3P.093 SELF-ASSEMBLY AND TRANSFERRING OF  
PHOTORESIST AS PLANAR LAYER FOR  
FABRICATION OF TSV AND FREE STANDING  
BEAMS**  
Z. Y. Wu, H. Yang, C. G. Dou, Y. H. Wu, X. X. Li  
and Y. L. Wang  
State Key Laboratories of Transducer Technology,  
Science and Technology on Micro-system Laboratory,

Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, Shanghai, China

386

**M3P.094 ADHESION-ENHANCING SURFACE TREATMENTS FOR PARYLENE DEPOSITION**

Jay Han-Chieh Chang, Bo Lu and Yu-Chong Tai  
California Institute of Technology, CA, US

390

**M3P.095 PRECISE CELL TRAPPING WITH STRUCTURE-CONFINED DIELECTROPHORESIS**  
S. M. Yang<sup>1</sup>, T. H. Punde<sup>2</sup>, H. P. Chen<sup>3</sup>, C. W. Lin<sup>3</sup>, S. Shilpa<sup>3</sup>, V. P. Srinivasu<sup>3</sup>, Y. T. Lu<sup>4</sup>, L. Hsu<sup>1</sup>, and C. H. Liu<sup>3\*</sup>

<sup>1</sup>Department of Electrophysics, National Chiao Tung University, Taiwan, R.O.C.

<sup>2</sup>Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Taiwan, R.O.C.

<sup>3</sup>Department of Power Mechanical Engineering, National Tsing Hua University, Taiwan, R.O.C.

<sup>4</sup>Department of Medical Research, Mackay Memorial Hospital, Taipei, Taiwan, R.O.C.

394

**M3P.096 LOW-COST FABRICATION OF PMMA AND PMMA BASED MAGNETIC COMPOSITE CANTILEVERS**  
M. Suter<sup>1</sup>, Y. Li<sup>1</sup>, G.A. Sotiriou<sup>2</sup>, A. Teleki<sup>2</sup>, S.E. Pratsinis<sup>2</sup> and C. Hierold<sup>1</sup>

<sup>1</sup>Micro and Nanosystems, <sup>2</sup>Particle Technology Laboratory, Department of Mechanical and Process Engineering, ETH Zurich, 8092 Zurich, SWITZERLAND

398

**M3P.097 A TRANSFER METHOD FOR COMPLEX STRUCTURES FABRICATED ON NON-PLANAR SURFACES**

X Zeng<sup>1</sup>, C.-C. Huang<sup>1</sup>, and H. Jiang<sup>1,2,3,\*</sup>

<sup>1</sup>Department of Electrical and Computer Engineering, University of Wisconsin - Madison, Madison, WI, USA

<sup>2</sup>Eye Research Institute, University of Wisconsin - Madison, Madison, WI, USA

<sup>3</sup>Materials Science Program, University of Wisconsin - Madison, Madison, WI, USA

402

**M3P.098 A BROADBAND 3D PACKAGE FOR RF MEMS DEVICES UTILIZING THROUGH SILICON VIAS (TSV)**

Y.Y. Lim, B.T. Chen, A.B. Yu and J.L. Shi  
Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), 11 Science Park Road, Singapore Science Park II, Singapore

406

**M3P.099 A SINGLE-WAFER-BASED SINGLE-SIDED BULK-MICROMACHINING TECHNIQUE FOR HIGH-YIELD AND LOW-COST VOLUME PRODUCTION OF PRESSURE SENSORS**

Jiachou Wang and Xinxin Li  
State Key Lab of Transducer Technology, and, Science and Technology on Microsystem Lab, Shanghai Institute

of Microsystem and Information Technology, Chinese Academy of Sciences, CHINA

410

**M3P.100 THE INTEGRATION OF CNTS-BASED FLEXIBLE TACTILE SENSOR AND FLEXIBLE CIRCUIT BY POLYMER MOLDING PROCESS**

Chih-Fan Hu<sup>1</sup>, Wang-Shen Su<sup>3</sup>, and Weileun Fang<sup>1,2,3</sup>

<sup>1</sup>Dept. of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, TAIWAN

<sup>2</sup>Inst. of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, TAIWAN

<sup>3</sup>National Nano Device Laboratories, Hsinchu, TAIWAN

414

**M3P.101 LOW-STRESS WAFER-LEVEL TRANSFER BONDING OF POLYMER LAYERS USING FLOATATION**

J.M. Karlsson, T. Haraldsson, C.F. Carlborg, W. van der Wijngaart

Microsystem Technology Lab, KTH Royal Institute of Technology, Stockholm, SWEDEN

418

**Theory, Design and Test Methodology**

**M3P.102 A PARYLENE-LED WINGBEATING INDICATOR FOR VISUAL REMOTE SENSING**

L.J. Yang<sup>1,2</sup>, I.C. Huang<sup>1</sup>, Y.S. Chen<sup>1</sup>, W.T. Tang<sup>3</sup>, and A.B. Wang<sup>4</sup>

<sup>1</sup>Tamkang University, Tamsui, New Taipei City, Taiwan

<sup>2</sup>National Applied Research Laboratories, Taipei, Taiwan

<sup>3</sup>National Taiwan Sport University, Taoyuan, Taiwan

<sup>4</sup>National Taiwan University, Taipei, Taiwan

422

**M3P.103 ENGINEERING APPLICATION OF MEMS VECTOR HYDROPHONE AND SELF-ADAPTING ROOT-MUSIC ALGORITHM**

Peng Wang<sup>1,3</sup>, Guo-jun Zhang<sup>1,2</sup>, Chen-yang Xue<sup>1,2</sup>, Wen-dong Zhang<sup>1,2</sup> and Ji-jun Xiong<sup>1,2</sup>

<sup>1</sup>Key Laboratory of Instrumentation Science & Dynamic Measurement, North University of China, Taiyuan, China

<sup>2</sup>Science and Technology on Electronic Test & Measurement Laboratory, North University of China, Taiyuan, China

<sup>3</sup>School of Science, North University of China, Taiyuan, China

426

**M3P.104 CAPACITIVE DETECTION OF NANOLITER DROPLETS ON THE FLY - INVESTIGATION OF ELECTRIC FIELD DURING DROPLET FORMATION USING CFD-SIMULATION**

K. Mutschler<sup>1</sup>, A. Ernst<sup>3</sup>, N. Paust<sup>2</sup>, R. Zengerle<sup>1,2</sup> and P. Koltay<sup>1,3</sup>

- <sup>1</sup>Laboratory for MEMS Applications, IMTEK, University of Freiburg, Germany  
<sup>2</sup>HSG-IMIT - Institut für Mikro- und Informationstechnik, Villingen-Schwenningen, Germany  
<sup>3</sup>BioFluidix GmbH, Georges-Köhler-Allee 106, 79110 Freiburg, Germany  
.....430
- M3P.105 TOWARDS MEASUREMENT OF THE CASIMIR FORCE BETWEEN PARALLEL PLATES SEPARATED AT SUB-MICRON DISTANCE**  
M.B.S. Nawazuddin<sup>1</sup>, T.S.J. Lammerink<sup>1</sup>, R.J. Wiegerink<sup>1</sup>, J.W. Berenschot<sup>1</sup>, M. de Boer<sup>1</sup> and M.C. Elwenspoek<sup>1,2</sup>  
<sup>1</sup>Transducers Science and Technology Group, MESA+ Research Institute, University of Twente, P.O. Box 217, 7500 AE Enschede, the Netherlands  
<sup>2</sup>Fellow, FRIAS, Albert-Ludwigs University, Albertstr. 19, 79104 Freiburg, Germany  
.....434
- M3P.106 THE INVESTIGATION OF POINT DEFECT MODES OF PHONONIC CRYSTAL FOR HIGH Q RESONANCE**  
F. Li<sup>1</sup>, J. Liu<sup>1,2</sup>, and Y.H. Wu<sup>1</sup>  
<sup>1</sup>State Key Laboratory of Applied Optics Changchun Institute of Optics, Fine Mechanics and Physics, Chinese Academy of Sciences, Changchun, China  
<sup>2</sup>Graduate University of Chinese Academy of Sciences, Beijing, China  
.....438
- M3P.107 DYNAMIC OPTIMIZATION OF VALVELESS MICROPUMP**  
Y.B. Deng<sup>1,2</sup>, Y.H. Wu<sup>1</sup>, M. Xuan<sup>1</sup>, Jan G. Korvink<sup>3,4</sup>, and Z.Y. Liu<sup>1</sup>  
<sup>1</sup>Institute of Optics, Fine Mechanics and Physics, Chinese Academy of Sciences, Changchun, China  
<sup>2</sup>Graduate University of Chinese Academy of Sciences, Beijing, China  
<sup>3</sup>Department of Microsystems Engineering (IMTEK), University of Freiburg, Freiburg, Germany  
<sup>4</sup>Freiburg Institute of Advanced Studies (FRIAS), University of Freiburg, Germany  
.....442
- M3P.108 TIME-DEPENDENT CELL MEMBRANE DAMAGE UNDER MECHANICAL TENSION: EXPERIMENTS AND MODELING**  
Bo Lu, Jay Han-Chieh Chang and Yu-Chong Tai  
California Institute of Technology, Pasadena, CA, US  
.....446
- M3P.109 USE OF A NEW ANISOTROPIC ETCHING SIMULATOR ON QUARTZ CRYSTAL**  
M. Zhao, H. Oigawa, J. Wang, J. Ji, T. Ueda  
Graduate school of Information, Production and System, WASEDA University, Kitakyushu, Japan  
.....450
- M3P.110 CHARACTERISTICS OF INVERTED PYRAMIDAL MICRODISCHARGE DEVICES OPERATING IN CHF3 AND CHF3/AR FOR MASKLESS**

#### MICROPLASMA ETCHING

L. Wen<sup>1\*</sup>, Z. Yuan<sup>1</sup>, L. L. Cheng<sup>1</sup>, L. W. He<sup>1</sup>, H. Wang<sup>2</sup>, J. R. Chu<sup>1</sup>

<sup>1</sup>Department of Precision Machinery & Instrumentation, University of Science and Technology of China, Hefei, Anhui, 230026, China

<sup>2</sup>Department of Mechanical Engineering, Anhui Polytechnic University, Wuhu, Anhui, 241000, China

.....454

#### M3P.111 PULSED EVAPORATIVE TRANSIENT THERMOMETRY ON ISOLATED MICROSTRUCTURES

R. Xiao, and E. N. Wang<sup>\*</sup>

Device Research Laboratory, Department of Mechanical Engineering

Massachusetts Institute of Technology, Cambridge, MA, United States of America

.....458

### Actuators

#### M3P.112 MICRO-BEAM ACTUATOR BASED ON CONDUCTING INTERPENETRATING POLYMER NETWORKS: FROM PATTERNING PROCESS TO ACTUATION IN OPEN AIR

Alexandre Khaldi<sup>1,2</sup>, Cédric Plesse<sup>2</sup>, Caroline Soyer<sup>1</sup>, David Troadec<sup>1</sup>, Frédéric Vidal<sup>2</sup>, Eric Cattan<sup>1</sup>, Claude Chevrot<sup>2</sup> and Dominique Teyssié<sup>2</sup>

<sup>1</sup>IEMN CNRS UMR-8520, - Villeneuve d'Ascq, FRANCE

<sup>2</sup>LPPI, EA 2528, Cergy-Pontoise, FRANCE

.....462

#### M3P.113 A NOVEL SU-8 ELECTROTHERMAL MICROGRIPPER BASED ON TYPE SYNTHESIS OF KINEMATIC CHAIN METHOD

R. Zhang, J.K. Chu, and Z.P. Chen

Key Laboratory for Micro/Nano Technology and System of Liaoning Province, Dalian University of Technology, Dalian, China

.....466

#### M3P.114 DESIGN AND CHARACTERIZATION OF A LOW-VOLTAGE PIEZOELECTRICALLY ACTUATED POLYMER MEMBRANE

H. Feth<sup>1</sup>, M. Esch<sup>1</sup>, C. Mueller<sup>2</sup>, F. Thoma<sup>1</sup>, G. Biancuzzi<sup>1</sup>, T. Lemke<sup>1</sup>, F. Goldschmidtboeing<sup>1</sup> and P. Woias<sup>1</sup>

<sup>1</sup>Laboratory for Design of Microsystems, <sup>2</sup>Laboratory for Process Technology, Department of Microsystems Engineering (IMTEK), Albert-Ludwigs-University of Freiburg, Germany

.....470

#### M3P.115 A LATCHABLE HIGH-PRESSURE COMPOSITE VALVE ACTUATOR COMBINING PARAFFIN AND A LOW MELTING POINT ALLOY

S. Ogden, J. Jonsson, K. Hjort and G. Thornell

Department of Engineering Sciences, Uppsala University, SWEDEN

	474
<b>M3P.116 ELECTROMECHANICAL COUPLING OF POLYPYRROLE TRILAYER ACTUATORS</b>	
Ping Du, Xi Lin, and Xin Zhang	
<i>Department of Mechanical Engineering, Boston University, Boston, USA</i>	
	478
<b>M3P.117 A NOVEL MINIATURIZATION ACTUATOR USING A SYMMETRIC PIEZOELECTRIC PUSHER ELEMENT FOR POCKET SUN-TRACKING SYSTEM</b>	
S.C. Shen <sup>*1</sup> , P.C. Tsai <sup>1</sup> , C. T. Pan <sup>2</sup> , H.J. Huang <sup>1</sup> , J.C. Huang <sup>1</sup>	
<sup>1</sup> <i>Department of Systems and Naval Mechatronic Engineering, National Cheng Kung University, Tainan</i>	
<sup>2</sup> <i>Department of Mechanical and Electro-Mechanical Engineering, National Sun Yat-Sen University, Kaoshiung, Taiwan</i>	
	482
<b>M3P.118 GAN COMB-DRIBE ACTUATORS ON SI SUBSTRATE</b>	
T. Tanae <sup>1</sup> , H. Samashima <sup>1</sup> , and K. Hane <sup>1</sup>	
<sup>1</sup> <i>Tohoku University, Sendai, Japan</i>	
	486
<b>M3P.119 RAPID AND REPEATED BOLUS DRUG DELIVERY ENABLED BY HIGH EFFICIENCY ELECTROCHEMICAL BELLOWS ACTUATORS</b>	
R. Sheybani, H. Gensler, and E. Meng	
<i>Biomedical Microsystems Laboratory, University of Southern California, Los Angeles, CA, USA</i>	
	490
<b>M3P.120 CYMBAL TYPE PIEZO-POLYMER-COMPOSITE ACTUATORS FOR ACTIVE CANCELLATION OF FLOW INSTABILITIES ON AIRFOILS</b>	
D. Haller <sup>1</sup> , A. Paetzold <sup>2</sup> , N. Goldin <sup>2</sup> , S. Neissl, F. Goldschmidtboeing <sup>1</sup> , W. Nitsche <sup>2</sup> , R. King <sup>2</sup> , and P. Woias <sup>1</sup>	
<sup>1</sup> <i>Department of Microsystems Engineering, IMTEK, University of Freiburg, Germany</i>	
<sup>2</sup> <i>Technical University of Berlin, Germany</i>	
	494
<b>M3P.121 A MEMS MICROGRIPPER WITH CHANGEABLE GRIPPING TIPS</b>	
B.K. Chen and Y. Sun	
<i>University of Toronto, Canada</i>	
	498

## RF MEMS, Resonators, and Oscillators

<b>M3P.122 CAPACITIVE FREQUENCY TUNING OF ALN MICROMECHANICAL RESONATORS</b>	
B. Kim, R.H. Olsson III, K.E. Wojciechowski	
<i>Sandia National Laboratories, Albuquerque, NM, United States of America</i>	
	502
<b>M3P.123 INFLUENCE OF THE A-F EFFECT ON THE TEMPERATURE STABILITY OF SILICON</b>	

## MICROMECHANICAL RESONATORS

H.K. Lee<sup>1\*</sup>, R. Melamud<sup>1</sup>, S.A. Chandorkar<sup>1</sup>, Y.Q. Qu<sup>1</sup>, J.C. Salvia<sup>2</sup>, B. Kim<sup>1</sup>, M.A. Hopcroft, and T.W. Kenny

<sup>1</sup>*Department of Mechanical Engineering, Stanford University, Stanford, CA, USA*

<sup>2</sup>*Department of Electrical Engineering, Stanford University, Stanford, CA, USA*

506

## M3P.124 VERIFICATION OF THE PHASE-NOISE MODEL FOR MEMS OSCILLATORS OPERATING IN THE NONLINEAR REGIME

H.K. Lee<sup>1\*</sup>, P.A. Ward<sup>2</sup>, A.E. Duwel<sup>2</sup>, J.C. Salvia<sup>3</sup>, Y.Q. Qu<sup>1</sup>, R. Melamud<sup>1</sup>, S.A. Chandorkar<sup>1</sup>, M.A. Hopcroft<sup>1</sup>, B. Kim<sup>1</sup>, and T.W. Kenny<sup>1</sup>

<sup>1</sup>*Department of Mechanical Engineering, Stanford University, Stanford, CA, USA*

<sup>2</sup>*Charles Stark Draper Laboratory, Cambridge, MA, USA*

<sup>3</sup>*Department of Electrical Engineering, Stanford University, Stanford, CA, USA*

510

## M3P.125 MICRO DISK RESONATOR WITH ON-DISK PIEZOELECTRIC THIN FILM TRANSDUCERS FOR INTEGRATED MEMS UBIQUITOUS APPLICATIONS

J.Lu, Y.Zhang, T.Itoh, and R.Maeda

*Research Center for Ubiquitous MEMS and Micro Engineering (UMEMSME),*

*National Institute of Advanced Industrial Science and Technology (AIST), Tsukuba, Ibaraki, JAPAN*

514

## M3P.126 NOVEL MEMS OSCILLATOR USING IN-PLANE DISK RESONATOR WITH SENSING PLATFORM AND ITS MASS SENSING CHARACTERISTICS

M. Konno<sup>1</sup>, T. Ikehara<sup>1</sup>, S. Murakami<sup>1</sup>, R. Maeda<sup>1</sup>, M. Kimura<sup>2</sup>, T. Fukawa<sup>2</sup>, T. Mihara<sup>3</sup>

<sup>1</sup>*National Institute of Advanced Industrial Science and Technology (AIST), Tsukuba, Japan*

<sup>2</sup>*Faculty of Textile Science and Technology, Shinshu University, Ueda, Japan*

<sup>3</sup>*Future Creation Laboratory, Olympus Corporation, Hachioji, Japan*

518

## M3P.127 AN EWOD DRIVEN MILLIMETER-WAVE PHASE SHIFTER USING A MOVABLE ULTRASOFT METALIZED PDMS GROUND PLANE

Sami Hage-Ali<sup>1a</sup>, Nicolas Tiercelin<sup>1a</sup>, Florian Lapierre<sup>2</sup>, Yovan Orlic<sup>1a</sup>, Maxime Harnois<sup>2</sup>, Vincent Thomy<sup>2</sup>, Vladimir Preobrazhensky<sup>1a,b</sup>, Philippe Pernod<sup>1a</sup> and Philippe Coquet<sup>1a,2</sup>

<sup>1</sup>*Joint International Laboratory LEMAC:*

<sup>a)</sup>*Institute for Electronics, Microelectronics and Nanotechnology, IEMN UMR CNRS 8520, ECLille, PRES Université Lille Nord de France, 59651 Villeneuve d'Ascq, France*

<sup>b)</sup>*Wave Research Center, GPI RAS, 38 Vavilov str., Moscow, 119991, Russia*

<sup>2</sup>BioMEMS group, Institute for Electronics,  
Microelectronics and Nanotechnology, IEMN UMR  
CNRS 8520, PRES Université Lille Nord de France,  
59652 Villeneuve d'Ascq, France

.....522

**M3P.128** **PIEZOELECTRIC ALN MEMS RESONATORS WITH  
HIGH COUPLING COEFFICIENT**

Lynn Khine, Jeffrey B.W. Soon, and Julius M.  
Tsai

*The Institute of Microelectronics, A\*STAR (Agency for  
Science, Technology and Research), 11 Science Park  
Road, Singapore Science Park II, Singapore 117685*

.....526

**M3P.129** **AN ABSORPTIVE FILTER USING MICROFLUIDIC  
SWITCHABLE METAMATERIALS**

B. Dong<sup>1,3</sup>, W. M. Zhu<sup>1</sup>, Y. H. Fu<sup>1</sup>, J. M. Tsai<sup>2</sup>, H.  
Cai<sup>2</sup>, D. L. Kwong<sup>2</sup>, E. P. Li<sup>3</sup>, E. Rius<sup>4</sup> and A. Q.  
Liu<sup>1</sup>

<sup>1</sup>*School of Electrical and Electronic Engineering,  
Nanyang Technological University, Singapore 639798*

<sup>2</sup>*Institute of Microelectronics, A\*STAR (Agency for  
Science, Technology and Research) 11 Science Park  
Road, Singapore Science Park II, Singapore 117685*

<sup>3</sup>*Institute of High Performance Computing, A\*STAR  
(Agency for Science, Technology and Research)  
1 Fusionopolis Way, Singapore 138632*

<sup>4</sup>*Laboratoire des Sciences et Techniques de  
l'Information, de la Communication et de la  
Connaissance (Lab-STICC), University of Brest, Brest  
29238, France*

.....530

## Optical MEMS

**M3P.130** **MODE-SELECTIVE OPTICAL FILTERING AND  
WAVELENGTH-SELECTIVE SWITCHING  
THROUGH FABRY-PEROT CAVITY WITH  
CYLINDRICAL REFLECTORS**

M. Malak, N. Pavy, F. Marty and T. Bourouina  
*Université Paris-Est, laboratoire ESYCOM, ESIEE  
Paris, Noisy-le-Grand, FRANCE*

.....534

**M3P.131** **SPECKLE REDUCTION IN LASER DISPLAYS  
USING A MEMS TANDEM MODULATOR**

G. M. Ouyang<sup>1</sup>, Z. M. Tong<sup>1</sup>, M. N. Akram<sup>1</sup>, V.  
Kartashov<sup>2</sup>, K. Y. Wang<sup>1</sup>, and X. Y. Chen<sup>1</sup>

<sup>1</sup>*Faculty of Science and Engineering, Vestfold  
University College, N-3103 Tonsberg, Norway*

<sup>2</sup>*poLight AS, N-3192 Horten, Norway*

.....538

**M3P.132** **A NOVEL ELECTROMAGNETIC  
MICROACTUATOR WITH LATERAL  
MAGNETO-STATIC FORCE FOR SCANNING  
MICROMIRROR DEVICE**

Tenghsien Lai<sup>1</sup> and Chingfu Tsou<sup>2</sup>

<sup>1</sup>*Ph. D. Program in Electrical and Communications  
Engineering, Feng Chia University*

<sup>2</sup>*Department of Automatic Control Engineering, Feng  
Chia University, Taichung, Taiwan, R.O.C.*

.....542

**M3P.133** **MICROMACHINED ARRAY-TYPE MIRAU  
INTERFEROMETER FOR MEMS METROLOGY**

C. Gorecki<sup>1</sup>, S. Bargiel<sup>1</sup>, J. Albero<sup>1</sup>, N. Passilly<sup>1</sup>,  
C. Rousselot<sup>1</sup>, U. Zeitner<sup>2</sup>, and K. Gastingner<sup>3</sup>

<sup>1</sup>*Dep. MN2S, FEMTO-ST (UMR CNRS  
6174/UFC/ENSMM/UTBM), 25000 Besançon,  
FRANCE*

<sup>2</sup>*Dep. Microoptical Systems, Fraunhofer IOF, 07745  
Jena, GERMANY*

<sup>3</sup>*SINTEF ICT, 7465 Trondheim, NORWAY*

.....546

**M3P.134** **A THERMAL TUNABLE BULK-MICROMACHINED  
OPTICAL FILTER**

Sihua Li<sup>1,2</sup>, Shaolong Zhong<sup>1</sup>, Jing Xu<sup>1</sup> and  
Yaming Wu<sup>1</sup>

<sup>1</sup>*State Key Laboratory of Transducer Technology,  
Shanghai Institute of Microsystem and Information  
Technology, Chinese Academy of Sciences, Shanghai,  
China*

<sup>2</sup>*Graduate university of the Chinese Academy of  
Sciences, Beijing, China*

.....550

**M3P.135** **MICRO-MIRRORS CONNECTED IN SERIES FOR  
LOSS-MECHANISM STUDY AND LOW-VOLTAGE  
OPERATION**

S. Kotani, H.M. Chu, T. Sasaki, and K. Hane  
*Tohoku University, Sendai, Japan*

.....554

**M3P.136** **DESIGN, FABRICATION, AND VACUUM PACKAGE  
PROCESS FOR HIGH PERFORMANCE  
OF 2D SCANNING MEMS MICROMIRROR**

H.M. Chu, T. Sasaki, K. Hane

*Department of Nanomechanics, Tohoku University,  
Sendai, Miyagi, Japan*

.....558

**M3P.137** **A NOVEL DUAL SCREEN PROJECTION SYSTEM  
USING BALANCE-TYPE MICROMIRROR WITH  
PIEZOELECTRIC ACTUATOR**

M.T. Shih<sup>1</sup>, S.C. Shen<sup>1\*</sup>, S.J. Chang<sup>2</sup>, H. J.  
Huang<sup>1</sup>

<sup>1</sup>*Department of Systems and Naval Mechatronic  
Engineering, National Cheng Kung University, Tainan,  
Taiwan*

<sup>2</sup>*Department of Mechanical Engineering, National  
Yunlin University of Science and Technology, Yunlin,  
Taiwan*

.....562

**M3P.138** **NOVEL ULTRA-LIGHTWEIGHT AND  
HIGH-RESOLUTION MEMS X-RAY OPTICS FOR  
SPACE ASTRONOMY**

I. Mitsuishi<sup>1</sup>, Y. Ezoe<sup>2</sup>, K. Ishizu<sup>2</sup>, T. Moriyama<sup>2</sup>,  
M. Mita<sup>1</sup>, N. Y. Yamasaki<sup>1</sup>, K. Mitsuda<sup>1</sup>, M.  
Horade<sup>3</sup>,

S. Sugiyama<sup>3</sup>, R. Riveros<sup>4</sup>, H. Yamaguchi<sup>4</sup>, Y.  
Kanamori<sup>5</sup>, K. Morishita<sup>6</sup>, K. Nakajima<sup>6</sup> and R.

	Maeda <sup>7</sup> <sup>1</sup> ISAS/JAXA, <sup>2</sup> Tokyo Metropolitan University, <sup>3</sup> Ritsumeikan University, <sup>4</sup> University of Florida, <sup>5</sup> Tohoku University, <sup>6</sup> Kyoto University, <sup>7</sup> AIST .....566
<b>M3P.139</b>	<b>VARIFOCAL SCANNING MICRO-MIRROR FABRICATED FROM SILICON-ON-INSULATOR WAFER</b> T. Sasaki and K. Hane <i>Department of Nanomechanics, Tohoku University, Sendai, Japan</i> .....570
<b>M3P.140</b>	<b>METAL-BASED PIEZOELECTRIC MEMS SCANNER MIRRORS COMPOSED OF PZT THIN FILMS ON TITANIUM SUBSTRATES</b> Shuhei Matsushita, Isuku Kanno, Ryuji Yokokawa and Hidetoshi Kotera <i>Kyoto University, Kyoto, Japan</i> .....574
<b>M3P.141</b>	<b>PROCESS OPTIMIZATION AND PERFORMANCE ANALYSIS OF AN ELECTROSTATICALLY ACTUATED VARIFOCAL LIQUID LENS</b> A. Pouydebasque <sup>1</sup> , S. Bolis <sup>1</sup> , C. Bridoux <sup>1</sup> , F. Jacquet <sup>1</sup> , S. Moreau <sup>1</sup> , E. Sage <sup>1</sup> , D. Saint-Patrice <sup>1</sup> , C. Bouvier <sup>1</sup> , C. Kopp <sup>1</sup> , N. Sillon <sup>1</sup> , S. Fanget <sup>1</sup> and E. Vigier-Blanc <sup>2</sup> <sup>1</sup> CEA-Leti, MINATEC Campus, 17 Avenue des Martyrs, F-38054 Grenoble, France <sup>2</sup> ST Microelectronics, 12, rue Jules Horowitz, F-38019 Grenoble, France .....578
<b>M3P.142</b>	<b>A NANO-OPTO-MECHANICAL PRESSURE SENSOR</b> X. Zhao <sup>1,2,3</sup> , J. M. Tsai <sup>3</sup> , H. Cai <sup>3</sup> , X. M. Ji <sup>2</sup> , J. Zhou <sup>2</sup> , M. H. Bao <sup>2</sup> , Y. P. Huang <sup>2</sup> , D. L. Kwang <sup>3</sup> and A. Q. Liu <sup>1</sup> <sup>1</sup> School of Electrical & Electronic Engineering, Nanyang Technological University, Singapore 639798 <sup>2</sup> School of Information Science and Technology, Fudan University, Shanghai 200433, China <sup>3</sup> Institute of Microelectronics, A*STAR (Agency for Science, Technology and Research) 11 Science Park Road, Singapore Science Park II, Singapore 117685 .....582
<b>M3P.143</b>	<b>HOLLOW CORE MOEMS BRAGG GRATING MICROPHONE FOR DISTRIBUTED AND REMOTE SENSING</b> K. Reck <sup>1</sup> , C. Østergaard <sup>1</sup> , E. V. Thomsen <sup>1</sup> and O. Hansen <sup>1,2</sup> <sup>1</sup> DTU Nanotech, Technical University of Denmark, Kgs. Lyngby, DK-2800, Denmark <sup>2</sup> Center for Individual Nanoparticle Functionality, CINF, Technical University of Denmark .....586
<b>M3P.144</b>	<b>2D IMAGING WITH 1D LED ARRAY INTEGRATED FR4 ACTUATOR</b> Y.D. Gokdel, B.Sarioglu, and A.D. Yalcinkaya <i>Bogazici University, Dept. Electrical and Electronics Engineering, Bebek, 34342, Istanbul, TURKEY</i>

	.....590
<b>M3P.145</b>	<b>MICRO-OPTO-MECHANICAL TECHNOLOGY FOR THE FABRICATION OF HIGHLY MINIATURIZED FIBER-OPTIC ULTRASONIC DETECTORS</b> L. Belsito <sup>1</sup> , F. Mancarella <sup>1</sup> , M. Ferri <sup>1</sup> , A. Roncaglia <sup>1</sup> , E. Biagi <sup>2</sup> , S. Cerbai <sup>2</sup> , L. Masotti <sup>2</sup> , G. Masetti <sup>3</sup> , and N. Speciale <sup>3</sup> <sup>1</sup> Institute of Microelectronics and Microsystems, CNR, Bologna, Italy <sup>2</sup> Electronics and Telecommunications Department, University of Florence, Florence, Italy <sup>3</sup> Electronics, Computer Science and Systems Department, University of Bologna, Bologna, Italy .....594
<b>M3P.146</b>	<b>CONTINUOUS MEMBRANE DEFORMABLE MIRROR FOR ADAPTIVE OPTICS USING BIMORPH SPRING</b> T. Wu <sup>1</sup> , M. Akiyama <sup>2</sup> , and K. Hane <sup>1</sup> <sup>1</sup> Department of Nanomechanics, Tohoku University, Sendai 980-8579, Japan <sup>2</sup> Astronomical Institute, Tohoku University, Sendai 980-8578, Japan .....598

**Nanoscale Materials and Fabrication,  
Devices and Systems**

<b>M3P.147</b>	<b>FORMATION OF SILICON NANO TIPS USING POST SAM-BASED WET ETCHING</b> B. Tang and K. Sato <i>Department of Micro-Nano Systems Engineering, Nagoya University, Nagoya, Japan</i> .....602
<b>M3P.148</b>	<b>HIGH-PERFORMANCE SURFACE- TENSION-DRIVEN CAPILLARY PUMPING BASED ON LAYER-BY-LAYER SELF ASSEMBLY OF TiO2 NANOPARTICLES</b> T. Zhang and T. Cui <i>Department of Mechanical Engineering, University of Minnesota, Minneapolis, MN 55455, USA</i> .....606
<b>M3P.149</b>	<b>GOLD MEMBRANES WITH LARGE ARRAYS OF SUB-<math>\mu</math>m HOLES FABRICATED BY WAFER-SCALE NANOSPHERE LITHOGRAPHY</b> M. J. K. Klein <sup>1,2</sup> , R. Eckert <sup>1</sup> , M. Guillaumée <sup>1</sup> , L. A. Dunbar <sup>1</sup> , H. Heinzelmänn <sup>1</sup> , J. Brugger <sup>2</sup> and R. Pugin <sup>1</sup> <sup>1</sup> Nanotechnology and Life Sciences, CSEM S.A., Neuchâtel, SWITZERLAND <sup>2</sup> Microsystems Laboratory LMIS1, EPFL-STI-IMT, Lausanne, SWITZERLAND .....610
<b>M3P.150</b>	<b>ENHANCED ELECTRO-MECHANICAL PERFORMANCE OF TiO2 NANO-PARTICLE MODIFIED POLYDIMETHYLSILOXANE (PDMS) AS ELECTROACTIVE POLYMERS</b> G. M. Ouyang, K. Y. Wang, and X. Y. Chen

- .....614
- M3P.151 ELECTRICAL INSULATION OF CARBON NANOTUBE SEPARATION COLUMNS FOR MICROCHIP ELECTROCHROMATOGRAPHY**  
K.B. Mogensen, M. Chen, K. Molhave, P. Boggild, and J.P. Kutter  
*The Technical University of Denmark (DTU), 2800 Kgs. Lyngby, DENMARK*  
.....618
- M3P.152 TECHNOLOGY AND CHARACTERISTICS OF MICROHUMIDITY SENSORS**  
S.A. Krutovertsev, A.E. Tarasova, L.S. Krutovertseva, M.V. Chuprin, O.M. Ivanova, Yu.S. Sazhinev  
*JSC "Ecological sensors and systems", Moscow, Russia*  
.....621
- M3P.153 SUSPENDED CARBON NANOTUBE THIN FILM STRUCTURES WITH HIGH DEGREE OF ALIGNMENT FOR NEMS SWITCH APPLICATIONS**  
Dongjin Lee<sup>1</sup>, Zhijiang Ye<sup>1</sup>, Stephen A. Campbell<sup>2</sup>, and Tianhong Cui<sup>1\*</sup>  
<sup>1</sup>*Department of Mechanical Engineering, University of Minnesota, Minneapolis, U.S.A.*  
<sup>2</sup>*Department of Electrical and Computer Engineering, University of Minnesota, Minneapolis, U.S.A.*  
.....625
- M3P.154 MEASUREMENT OF SHEAR STRESS BETWEEN SINGLE-WALL CARBON NANOTUBES AND SUBSTRATES USING NEMS DEVICES**  
H.Y. Pan<sup>1,3</sup>, Y.C. Wu<sup>2,3</sup>, P.J. Ryan<sup>2,3</sup>, G.G. Adams<sup>2,3</sup>, N.E. McGruer<sup>1,3</sup>  
<sup>1</sup>*Electrical and Computer Engineering, Northeastern University, Boston, Massachusetts, USA*  
<sup>2</sup>*Mechanical and Industrial Engineering, Northeastern University, Boston, Massachusetts, USA*  
<sup>3</sup>*Center for High-rate Nanomanufacturing, Northeastern University, Boston, Massachusetts, USA*  
.....629
- M3P.155 A NEW PLATFORM FOR ASSEMBLY OF CARBON NANOTUBES ON NANO SENSORS BY UTILIZING OPTICALLY-INDUCED DIELECTROPHORESIS AND DIELECTROPHORESIS**  
Pei-Fang Wu<sup>1</sup> and Gwo-Bin Lee<sup>2\*</sup>  
<sup>1</sup>*Department of Engineering Science, National Cheng Kung University, Tainan, Taiwan*  
<sup>2</sup>*Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan*  
.....633
- M3P.156 GROWTH OF HORIZONTALLY ALIGNED CARBON NANOTUBES FROM DESIGNATED SIDEWALLS OF DRIE-ETCHED SILICON TRENCH**  
Jingyu Lu, Jianmin Miao\*, and Ting Xu  
*School of Mechanical and Aerospace Engineering, Nanyang Technological University, Singapore*  
.....637

- M3P.157 WAFER-LEVEL FABRICATION OF NANOSCALE PATTERNED SAPPHIRE SUBSTRATES WITH BROADBAND OPTICAL TRANSMITTANCE**  
Yu-Sheng Lin, and J. Andrew Yeh  
*Institute of NanoEngineering and MicroSystems, National Tsing-Hua University, Hsinchu, Taiwan*  
.....641
- M3P.158 DIELECTRIC CONSTANTS OF PDMS NANOCOMPOSITES USING CONDUCTING POLYMER NANOWIRES**  
Ping Du, Xi Lin, and Xin Zhang  
*Department of Mechanical Engineering, Boston University, Boston, MA, USA*  
.....645
- M3P.159 VERTICAL SILICON NANO-PILLAR FOR NON-VOLATILE MEMORY**  
V.X.H. Leong<sup>1</sup>, E.J. Ng<sup>1,2</sup>, J.B.W. Soon<sup>1,3</sup>, N. Singh<sup>1</sup>, N. Shen<sup>1</sup>, T. Myint<sup>1</sup>, V. Pott<sup>1</sup>, J.M. Tsai<sup>1</sup>  
<sup>1</sup>*Institute of Microelectronics, A\*STAR(Agency for Science, Technology and Research), SINGAPORE*  
<sup>2</sup>*Department of Mechanical Engineering, Stanford University, Stanford, CA, USA*  
<sup>3</sup>*Department of Electrical & Computer Engineering, National University of Singapore, SINGAPORE*  
.....649
- M3P.160 MICROPARTICLE TRAPPING AND MANIPULATION BY OPTICAL FORCE IN DOUBLE COUPLED RING RESONATOR (DCRR) VIA WAVELENGTH TUNING**  
Y. F. Yu<sup>1</sup>, H. Cai<sup>2</sup>, J. F. Tao<sup>1</sup>, T. Bourouina<sup>2</sup> and A. Q. Liu<sup>1</sup>  
<sup>1</sup>*School of Electrical & Electronic Engineering, Nanyang Technological University, Singapore 639798*  
<sup>2</sup>*Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), 11 Science Park Road, Singapore Science Park II, Singapore 117685*  
<sup>3</sup>*Ecole Supérieure d'Ingénieurs en Electronique et Electrotechnique (ESIEE), University of Paris Est, Paris 93162*  
.....653

## Energy and Power MEMS

- M3P.161 A SELF-SUSTAINING PYROELECTRIC ENERGY HARVESTER UTILIZING SPATIAL THERMAL GRADIENTS**  
S. K. T. Ravindran<sup>1</sup>, T. Huesgen<sup>1,2</sup>, M. Kroener<sup>1</sup>, P. Woias<sup>1</sup>  
<sup>1</sup>*Laboratory for Design of Microsystems, Department of Microsystems Engineering – IMTEK, University of Freiburg, Georges-Koehler-Allee 102, D-79110, Freiburg, Germany.*  
<sup>2</sup>*Currently at ABB Schweiz AG, Baden-Dättwil, Switzerland*  
.....657
- M3P.162 A FLAT HIGH PERFORMANCE MICRO ENERGY HARVESTER BASED ON A SERPENTINE COIL**

**WITH A SINGLE WINDING**

C. Cepnik, U. Wallrabe  
*University of Freiburg – IMTEK, Department of  
Microsystems Engineering, Graduate School Micro  
Energy Harvesting, Laboratory for Microactuators,  
Germany*

661

**M3P.163 A MICRO ENERGY HARVESTER WITH 3D WIRE  
BONDED MICROCOILS**

C. Cepnik, U. Wallrabe  
*University of Freiburg – IMTEK, Department of  
Microsystems Engineering, Graduate School Micro  
Energy Harvesting, Laboratory for Microactuators,  
Germany*

665

**M3P.164 THERMAL ENERGY HARVESTING USING SHAPE  
MEMORY/PIEZOELECTRIC COMPOSITES**

G.A. Lebedev<sup>1,2,3</sup>, B.V. Gusarov<sup>1,3</sup>, B. Viala<sup>1,2</sup>, J.  
Delamare<sup>3</sup>, O. Cugat<sup>3</sup>, T. Lafont<sup>3</sup> and D.I.  
Zakharov<sup>3,4</sup>

<sup>1</sup>CEA, LETI, MINATEC Campus, Grenoble, France

<sup>2</sup>SPINTEC, UMR 8191, CEA/CNRS/UJF, INAC,  
Grenoble, France

<sup>3</sup>G2Elab, Grenoble Electrical Engineering Lab,  
CNRS-UJF-INPG, St Martin d'Hères, France

<sup>4</sup>Institut Néel, CNRS-UJF, Grenoble, France

669

**M3P.165 A NEW APPROACH OF A SHAPE-OPTIMIZED  
PIEZOELECTRIC MEMS GENERATOR FOR  
FLUID-ACTUATED ENERGY SCAVENGING**

I. Kuehne<sup>\*1</sup>, J. Seidel<sup>2</sup>, M. Schreiter<sup>1</sup>, H. Seidel<sup>3</sup>,  
and A. Frey<sup>1</sup>

<sup>1</sup>Siemens AG, Corporate Technology, Corporate  
Research and Technologies, Munich, Germany

<sup>2</sup>Munich University of Applied Sciences, Department of  
Precision- and Micro-Engineering, Engineering Physics,  
Munich, Germany

<sup>3</sup>Saarland University, Chair of Micromechanics,  
Microfluidics/Microactuators, Saarbruecken, Germany

671

**M3P.166 POWER SWITCH SYSTEM BASED ON  
MICROELECTROMECHANICAL SWITCH**

B. Li, C. Keimel, G. Claydon, J. Park, A.D.  
Corwin, and M. Aimi  
*GE Global Research Center, Niskayuna, New York,  
USA*

675

**M3P.167 SCREEN PRINTED PZT/PZT THICK FILM  
BIMORPH MEMS CANTILEVER DEVICE FOR  
VIBRATION ENERGY HARVESTING**

R. Xu<sup>1</sup>, A. Lei<sup>1</sup>, T.L. Christiansen<sup>1</sup>, K. Hansen<sup>2</sup>,  
M. Guizzetti<sup>2</sup>, K. Birkelund<sup>1</sup>, E.V. Thomsen<sup>1</sup> and  
O. Hansen<sup>1,3</sup>

<sup>1</sup>Department of Micro- and Nanotechnology, Technical  
University of Denmark, DTU Nanotech, Building 345  
East, DK-2800 Kongens Lyngby, Denmark

<sup>2</sup>Meggitt Sensing Systems, DK-3490 Kvistgaard,  
Denmark

<sup>3</sup>CINF, Center for Individual Nanoparticle  
Functionality, Technical University of Denmark

679

**M3P.168 PIEZOELECTRIC MEMS ENERGY HARVESTING  
MODULE BASED ON NON-RESONANT  
EXCITATION**

Alexander Frey<sup>1\*</sup>, Julian Seidel<sup>2</sup>, Matthias  
Schreiter<sup>1</sup> and Ingo Kuehne<sup>1</sup>

<sup>1</sup>Siemens AG, Corporate Technology, Corporate  
Research & Technologies, Munich, Germany

<sup>2</sup>Munich University of Applied Sciences, Munich,  
Germany

683

**M3P.169 NON-CONTACT REPULSIVE-FORCE EXCITATION  
FOR HIGHLY ENDURABLE WIDE**

**FREQUENCY-RANGE ENERGY-HARVESTING**  
Yongliang Yang, Qiaochu Tang, and Xinxin Li  
*State Key Lab of Transducer Technology, and, Science  
and Technology on Microsystem Lab, Shanghai Institute  
of Microsystem and Information Technology, Chinese  
Academy of Sciences, CHINA*

687

**M3P.170 PASSIVE-SELF-TUNABLE VIBRATIONAL ENERGY  
HARVESTER**

S.E. Jo, M.S. Kim, and Y.J. Kim  
*School of Mechanical Engineering, Yonsei University,  
Seoul, Republic of Korea*

691

**ORAL SESSIONS**

16:15 - 18:00

**SESSION I(1) – Inertial Sensors**

**M4A.001 ULTRA-HIGH PRECISION MEMS  
ACCELEROMETER**

Y. Dong, P. Zwahlen, A. M. Nguyen, R. Frosio, F.  
Rudolf  
*Colibrys (Switzerland) Ltd, Neuchâtel, Switzerland*

695

**M4A.002 A REEL-TO-REEL COMPATIBLE PRINTED  
ACCELEROMETER**

N. Klejwa, R.G. Hennessy, J.-W.P. Chen and R.T.  
Howe  
*Department of Electrical Engineering, Stanford  
University, Stanford, CA, USA*

699

**M4A.003 MONOLITHIC-INTEGRATED SILICON  
BULK-MICROMACHINED ACCELEROMETER  
AND PRESSURE-SENSOR FOR  
TIRE-PRESSURE-MONITORING-SYSTEM (TPMS)  
APPLICATION**

Jiachou Wang and Xinxin Li  
*State Key Lab of Transducer Technology, and, Science  
and Technology on Microsystem Lab,  
Shanghai Institute of Microsystem and Information  
Technology, Chinese Academy of Sciences, CHINA*

- .....703
- M4A.004 A FOURTH ORDER UNCONSTRAINED  $\Sigma$  CAPACITIVE ACCELEROMETER**  
 Uğur Sönmez<sup>1\*</sup>, Haluk Külah<sup>1,2</sup>, and Tayfun Akin<sup>1,2</sup>  
<sup>1</sup>Department of Electrical and Electronics Engineering, METU, Ankara, Turkey  
<sup>2</sup>METU-MEMS Center, Ankara, Turkey  
 .....707
- M4A.005 CARBON NANOTUBES-INTEGRATED INERTIAL SWITCH FOR RELIABLE DETECTION OF THRESHOLD ACCELERATION**  
 J. -I. Lee, Y. Song, H.-K. Jung, J. Choi, Y. Eun and J. Kim\*  
 School of Mechanical Engineering, Yonsei University, Seoul, KOREA  
 ..... 711
- M4A.006 SENSITIVITY LINEARIZATION TECHNIQUE FOR A TIME BASED MEMS ACCELEROMETER**  
 R.A. Dias<sup>1</sup>, R.F. Wolffenbuttel<sup>2</sup>, E. Cretu<sup>3</sup>, and L.A. Rocha<sup>1</sup>  
<sup>1</sup>University of Minho, Guimaraes, Portugal  
<sup>2</sup>Delft University of Technology, Delft, Netherlands  
<sup>3</sup>University of British Columbia, Vancouver, Canada  
 .....715
- M4A.007 MEMS ULTRASONIC TRANSDUCERS FOR HIGHLY SENSITIVE DOPPLER VELOCITY SENSOR FOR LOW VELOCITY MEASUREMENT**  
 Lingtao Wang<sup>1</sup>, Youngki Choe<sup>1</sup>, Shih-Jui Chen<sup>1</sup>, Lukas Baumgartel<sup>2</sup>, and Eun Sok Kim<sup>1</sup>  
<sup>1</sup>Department of Electrical Engineering, University of Southern California, Los Angeles, CA, USA  
<sup>2</sup>Department of Physics, University of Southern California, Los Angeles, CA, USA  
 ..... 719

## SESSION I(2) - Power MEMS

- M4B.001 AMORPHOUS SILICON-COATED CNT FOREST FOR ENERGY STORAGE APPLICATIONS**  
 A. Kozinda, Y. Jiang, and L. Lin  
 Berkeley Sensor and Actuator Center and Mechanical Engineering Department, University of California at Berkeley, Berkeley, California, USA  
 .....723
- M4B.002 A HIERARCHICAL APPROACH FOR THE FABRICATION OF THREE-DIMENSIONAL MICROBATTERY ELECTRODES**  
 K. Gerasopoulos<sup>1,2,3\*</sup>, E. Pomerantseva<sup>1,3\*</sup>, M. McCarthy<sup>7\*\*</sup>, J. Culver<sup>5\*</sup>, C. Wang<sup>6\*</sup> and R. Ghodssi<sup>1,2,3,4\*</sup>  
<sup>1</sup>MEMS Sensors and Actuators Laboratory,  
<sup>2</sup>Department of Materials Science and Engineering,  
<sup>3</sup>The Institute for Systems Research, <sup>4</sup>Department of Electrical and Computer Engineering  
<sup>5</sup>Department of Plant Sciences and Landscape Architecture, <sup>6</sup>Department of Chemical and

Biomolecular Engineering, <sup>7</sup>Department of Mechanical Engineering and Mechanics, Drexel University  
 .....727

- M4B.003 POWER ENHANCEMENT OF MICRO THERMOELECTRIC GENERATORS BY MICRO FLUIDIC HEAT TRANSFER PACKAGING**  
 N.Z. Wojtas<sup>1</sup>, E. Schwyter<sup>1,2</sup>, W. Glatz<sup>2</sup>, S. Kühne<sup>1</sup>, W. Escher<sup>3</sup> and C. Hierold<sup>1</sup>  
<sup>1</sup>Micro and Nanosystems, ETH Zurich, Zurich, Switzerland  
<sup>2</sup>greenTEG GmbH, Zurich, Switzerland  
<sup>3</sup>Zurich Research Laboratory, IBM Research GmbH, Rüschlikon, Switzerland  
 .....731
- M4B.004 ENERGY HARVESTING FROM A ROTATING GEAR USING AN IMPACT TYPE PIEZOELECTRIC MEMS SCAVENGER**  
 P. Janphuang, D. Isarakorn, D. Briand, and N.F. de Rooij  
 Ecole Polytechnique Fédérale de Lausanne (EPFL), Institute of Microengineering (IMT), Sensors, Actuators and Microsystems Laboratory (SAMLAB), Neuchâtel, Switzerland  
 .....735
- M4B.005 DESIGN, MODELING, FABRICATION AND CHARACTERIZATION OF AN ELECTRET-BASED MEMS ELECTROSTATIC ENERGY HARVESTER**  
 G. Altena<sup>1,\*</sup>, D. Hohlfeld<sup>2</sup>, R. Elfrink<sup>1</sup>, M.H. Goedbloed<sup>1</sup> and R. van Schaijk<sup>1</sup>  
<sup>1</sup>imec/Holst Centre, Eindhoven, The Netherlands  
<sup>2</sup>Reutlingen University, Reutlingen, Germany  
 .....739
- M4B.006 GREEN VEHICLE SHOCK ABSORBER: MICROMACHINED WAVY SHAPED PIEZOELECTRIC CUSHION ENERGY HARVESTER AND ITS POWER GENERATING DEMONSTRATION BASED ON REAL NAVIGATION**  
 Guo-Hua Feng and Min-Yiang Tsai  
 Department of Mechanical Engineering, National Chung Cheng University, Chiayi, Taiwan  
 .....743
- M4B.007 LARGE ARRAY ELECTROSPUN PVDF NANOGENERATORS ON A FLEXIBLE SUBSTRATE**  
 Jiyoung Chang and Liwei Lin  
 Department of Mechanical Engineering, Berkeley Sensor and Actuator Center, University of California at Berkeley, Berkeley, CA USA  
 .....747

## SESSION I(3) - Cell Handling & Analysis

- M4C.001 SPECIFIC CELL CAPTURE AND TEMPERATURE-MEDIATED RELEASE USING SURFACE-IMMOBILIZED APTAMERS IN A MICROFLUIDIC DEVICE**

Jing Zhu<sup>1</sup>, ThaiHuu Nguyen<sup>1</sup>, Renjun Pei<sup>2</sup>,  
Milan Stojanovic<sup>2</sup> and Qiao Lin<sup>1</sup>  
<sup>1</sup>Department of Mechanical Engineering, Columbia  
University, New York, NY, USA  
<sup>2</sup>Department of Medicine, Columbia University, New  
York, NY, USA

.....751

**M4C.002 SINGLE CELL REAL TIME SECRETION ASSAY  
USING AMORPHOUS FLUOROPOLYMER  
MICROWELL ARRAY**

Y. Shirasaki<sup>1,2</sup>, A. Nakahara<sup>2</sup>, N. Shimura<sup>1</sup>, M.  
Yamagishi<sup>1</sup>, J. Mizuno<sup>2</sup>, O. Ohara<sup>1,3</sup> and S.  
Shoji<sup>2</sup>

<sup>1</sup>RCAI, RIKEN, Kanagawa, Japan

<sup>2</sup>WASEDA Univ., Tokyo, Japan

<sup>3</sup>Kazusa DNA Res. Inst., Chiba, Japan

.....755

**M4C.003 MEMS MASS SENSORS WITH UNIFORM  
SENSITIVITY FOR MONITORING CELLULAR  
APOPTOSIS**

K. Park<sup>\*1,2</sup>, L. Millet<sup>\*1,2</sup>, N. Kim<sup>3</sup>, H. Li<sup>3</sup>, K. J.  
Hsia<sup>2,3,4</sup>, N. R. Aluru<sup>2,3,5</sup> and R. Bashir<sup>1,2,4</sup>

<sup>1</sup>Department of Electrical and Computer Engineering,

<sup>2</sup>Micro and Nanotechnology Laboratory, <sup>3</sup>Department

of Mechanical Science and Engineering, <sup>4</sup>Department

of Bioengineering, <sup>5</sup>Beckman Institute of Advanced

Science and Technology, University of Illinois at

Urbana-Champaign, Urbana, Illinois 61801, USA

\* authors contributed equally

.....759

**M4C.004 MECHANICAL STIMULATOR OF CULTURED  
VASCULAR ENDOTHELIAL CELL FOR  
INVESTIGATION OF DRUG PERMEABILITY OF  
BLOOD VESSEL**

A. Shunori<sup>1</sup>, K. Shimizu<sup>2,3</sup>, M. Hashida<sup>2,4</sup>, and  
S. Konishi<sup>1,2,3</sup>

<sup>1</sup>Department of Micro System Technology, Ritsumeikan  
University, Japan

<sup>2</sup>Institute for Innovative NanoBio Drug Discovery and  
Development, Kyoto University, Japan

<sup>3</sup>Ritsumeikan-Global Innovation Research  
Organization, Ritsumeikan University, Japan

<sup>4</sup>Department of Drug Delivery Research, Kyoto  
University, Japan

.....763

**M4C.005 PULSATILE SHEAR STRESS AND HIGH GLUCOSE  
CONCENTRATIONS INDUCED REACTIVE  
OXIGEN SPECIES PRODUCTION IN  
ENDOTHELIAL CELLS**

J. Q. Yu<sup>1</sup>, L. K. Chin<sup>1</sup>, Y. Fu<sup>1</sup>, T. Yu<sup>2</sup>, K. Q. Luo<sup>2</sup>  
and A. Q. Liu<sup>1</sup>

<sup>1</sup>School of Electrical & Electronic Engineering

<sup>2</sup>School of Chemical & Biomedical

Engineering, Nanyang Technological University,  
Singapore 639798

.....767

**M4C.006 PROTOZOON CLASSIFICATIONS BASED ON SIZE,  
SHAPE AND REFRACTIVE INDEX USING ON-CHIP**

**IMMERSION REFRACTOMETER**

L. K. Chin<sup>1</sup>, T. C. Aji<sup>2</sup>, P. H. Yap<sup>2</sup> and A. Q. Liu<sup>1</sup>

<sup>1</sup>School of Electrical & Electronic Engineering,  
Nanyang Technological University, Singapore 639798

<sup>2</sup>Defence Medical & Environmental Institute, DSO  
National Laboratories, Singapore 117510

.....771

**M4C.007 DIAGNOSTIC DEVICE FOR COW MASTITIS  
BASED ON THE DETECTION OF SUPEROXIDE  
SECRETED FROM NEUTROPHILS**

S. Kimura, J. Fukuda, and H. Suzuki

Graduate School of Pure and Applied Sciences,  
University of Tsukuba, Tsukuba, JAPAN

.....775

**SESSION I(4) - Chemical Sensors I**

**M4D.001 INTEGRATED SILICON-BASED CHEMICAL  
MICROSYSTEM FOR PORTABLE SENSING  
APPLICATIONS**

K.S. Demirci<sup>1,2</sup>, L.A. Beardslee<sup>1</sup>, S. Truax<sup>1</sup>, J.-J.  
Su<sup>1</sup>, O. Brand<sup>1</sup>

<sup>1</sup>School of Electrical and Computer Engineering,  
Georgia Institute of Technology, Atlanta, GA, USA

<sup>2</sup>currently at: Texas Instruments Inc., Dallas, TX, USA

.....779

**M4D.002 FREQUENCY-MULTIPLEXED COMBINATORY  
MASS SENSING WITH SINGLE DATA LINE FROM  
MULTIPLE INTEGRATED FILM BULK ACOUSTIC  
RESONATORS**

S.J. Chen, A. Lin, L. Wang and E.S. Kim

University of Southern California, Los Angeles, USA

.....783

**M4D.003 ULTRA-LOW POWER PALLADIUM-COATED  
MEMS RESONATORS FOR HYDROGEN  
DETECTION UNDER AMBIENT CONDITIONS**

J. Henriksson, L. G. Villanueva, and J. Brugger

Microsystems Laboratory, École Polytechnique Fédérale  
de Lausanne (EPFL), Lausanne, Switzerland

.....787

**M4D.004 LOCALLY SYNTHESIZED METAL OXIDE  
NANOWIRE-DEVICES AND THEIR GAS SENSING  
APPLICATIONS**

D. Kim<sup>1</sup>, M. A. Lim<sup>1</sup>, D. Yang<sup>1</sup>, Z. Li<sup>2</sup>, C.O.  
Park<sup>3</sup>, and I. Park<sup>1</sup>

<sup>1</sup>Department of Mechanical Engineering & KI for the  
NanoCentury, KAIST, Daejeon, Korea

<sup>2</sup>Intelligent Infrastructure Laboratory, Hewlett  
Packard Laboratory, Palo Alto, CA, USA

<sup>3</sup>Department of Materials Science and Engineering,  
KAIST, Daejeon, Korea

.....791

**M4D.005 SINGLE CHIP NANOTUBE SENSORS FOR  
CHEMICAL AGENT MONITORING**

Y. Liu<sup>1</sup>, C.-L. Chen<sup>2</sup>, V. Agarwal<sup>3</sup>, S. Sonkusale<sup>3</sup>,  
M. L. Wang<sup>1</sup>, M. R. Dokmeci<sup>1</sup>

<sup>1</sup>Northeastern University, Boston, MA, USA

<sup>2</sup>University of California Los Angeles, Los Angeles, CA, USA

<sup>3</sup>Tufts University, Medford, MA, USA

.....795

**M4D.006 FIELD TESTING OF A RUGGED MEMS GAS CHROMATOGRAPH PROTOTYPE: SELECTIVE ANALYSIS OF TRACE-LEVEL TCE VAPORS IN CONTAMINATED HOMES**

S. K. Kim<sup>1,2</sup>, H. Chang<sup>1,2</sup>, J. G. Bryant<sup>1,2</sup>, D. R. Burris<sup>4</sup> and E. T. Zellers<sup>1,2,3\*</sup>

<sup>1</sup>Center for Wireless Integrated MicroSystems (WIMS),

<sup>2</sup>Departments of Environmental Health Sciences and

<sup>3</sup>Chemistry, University of Michigan, Ann Arbor, Michigan, USA

<sup>4</sup>Integrated Science and Technology, Inc., 228 Harrison Avenue, Panama City, FL 32401

.....799

**M4D.007 A PRESSURE PROGRAMMABLE GAS CHROMATOGRAPHY MICROSYSTEM UTILIZING MOTIONLESS KNUDSEN PUMP, FIBER-INTEGRATED OPTICAL DETECTOR, AND SILICON MICROMACHINED SEPARATION COLUMN**

Jing Liu, Naveen K. Gupta, Xudong Fan, Kensall D. Wise, and Yogesh B. Gianchandani  
Engineering Research Center for Wireless Integrated Microsystems, University of Michigan, Ann Arbor, MI 48109

.....803

## TUESDAY, June 7, 2011

### ORAL SESSIONS 08:30 - 10:00

#### SESSION II(1) – CMOS-MEMS

**T1A.001 Invited Speaker**

**MEMS TECHNOLOGY DEVELOPMENT AND MANUFACTURING IN A CMOS FOUNDRY**

CM Liu, Bruce C.S. Chou, Robert Chin-Fu Tsai, Nick Y.M. Shen, Benior SF Chen, Emerson CW Cheng, Hsiao Chin Tuan, Alex Kalnitsky, Sean Cheng, Chung-Hsien Lin, Tien-Kan Chung, Kuei-Sung Chang, Yi-Shao Liu  
Taiwan Semiconductor Manufacturing Company, Hsin-Chu, Taiwan

.....807

**T1A.002 A 400×400µm<sup>2</sup> 3-AXIS CMOS-MEMS ACCELEROMETER WITH VERTICALLY INTEGRATED FULLY-DIFFERENTIAL SENSING ELECTRODES**

Ming-Han Tsai<sup>1</sup>, Yu-Chia Liu<sup>1</sup>, Chih-Ming Sun<sup>1</sup>, Chuanwei Wang<sup>2</sup>, Chun-Wen Cheng<sup>3</sup>, and Weileun Fang<sup>1,2\*</sup>

<sup>1</sup>Institute of NanoEngineering and MicroSystems,

National Tsing Hua University, Hsinchu, Taiwan

<sup>2</sup>Power Mechanical Engineering Department, National Tsing Hua University, Hsinchu, Taiwan

<sup>3</sup>Taiwan Semiconductor Manufacturing Company, Hsinchu, Taiwan

.....811

**T1A.003 INTEGRATION AND PACKAGING TECHNOLOGY OF MEMS-ON-CMOS TACTILE SENSOR FOR ROBOT APPLICATION USING MOLDED THICK BCB LAYER AND BACKSIDE-GROOVED ELECTRICAL CONNECTION**

M. Makihata<sup>1</sup>, S. Tanaka<sup>1</sup>, M. Muroyama<sup>1</sup>, S. Matsuzaki<sup>1</sup>, H. Yamada<sup>2</sup>, T. Nakayama<sup>2</sup> U. Yamaguchi<sup>2</sup>,

K. Mima<sup>2</sup>, Y. Nonomura<sup>3</sup>, M. Fujiyoshi<sup>3</sup> and M. Esashi<sup>1</sup>

<sup>1</sup>Tohoku University, JAPAN, <sup>2</sup>Toyota Motor Corp., JAPAN and <sup>3</sup>Toyota Central R&D Labs., Inc., JAPAN

.....815

**T1A.004 A DIFFERENTIAL DIFFERENCE AMPLIFIER WITH AUTOMATIC GAIN SELECTION AS READOUT INTERFACE FOR CMOS STRESS SENSORS IN ORTHODONTIC BRACKETS**

M. Kuhl<sup>1</sup>, P. Gieschke<sup>1</sup>, O. Paul<sup>1</sup>, Y. Manoli<sup>1,2</sup>

<sup>1</sup>University of Freiburg, Department of Microsystems Engineering (IMTEK), Freiburg, Germany

<sup>2</sup>HSG-IMIT, Villingen-Schwenningen, Germany

.....819

**T1A.005 A FRENKEL-POOLE MODEL OF DIELECTRIC CHARGING IN CMOS MEMS**

K.L. Dorsey<sup>1</sup> and G.K. Fedder<sup>1,2,3</sup>

<sup>1</sup>Department of Electrical and Computer Engineering, Carnegie Mellon University, Pittsburgh, PA, USA

<sup>2</sup>The Robotics Institute, Carnegie Mellon University, Pittsburgh, PA, USA

<sup>3</sup>Institute for Complex and Engineered Systems, Carnegie Mellon University, Pittsburgh, PA, USA

.....823

#### SESSION II(2) – RF-MEMS

**T1B.001 Invited Speaker**

**2×2 MIMO, MULTI-MODE, WIDEBAND TRANSCIEVER SYSTEM FOR WORLDWIDE-WIMAX (IEEE 802.16E) / WLAN (IEEE 802.11N) APPLICATIONS**

K. Chun<sup>1,\*</sup>, S. Kang<sup>1</sup>, Y. Jang<sup>1</sup>, Y. E. Kim<sup>2</sup>, J. Lee<sup>3</sup>, I. S. Song<sup>2</sup>, J. H. Yi<sup>4</sup>, B. H. Kim<sup>5</sup>, B. Lee<sup>6</sup>, and H. C. Kim<sup>7</sup>

<sup>1</sup>ISRC, Electrical Engineering and Computer Science, Seoul National University, Seoul, KOREA

<sup>2</sup>Samsung Electronics Co., LTD., Kyunggi-do, KOREA

<sup>3</sup>Future Communications IC Inc., Kyunggi-Do, KOREA

<sup>4</sup>Yujeong Systems Co., Seoul, KOREA

<sup>5</sup>Electronics Engineering, Catholic University of Daegu, Gyeongbuk, KOREA

<sup>6</sup>Mechatronics Engineering, Korea University of

Technology and Education, Chungnam, KOREA  
<sup>7</sup>Electrical Engineering, University of Ulsan, Ulsan,  
KOREA

827

**T1B.002** **RF MEMS SWITCHES INTEGRATED WITH SEALED SUSPENDED COPLANAR WAVEGUIDES FOR RECONFIGURABLE RF CIRCUITS**  
K. Kuwabara, K. Takagahara, H. Morimura and Y. Sato  
*NTT Microsystem Integration Laboratories, NTT Corporation, Kanagawa, JAPAN*

832

**T1B.003** **VOLTAGE PROGRAMMABLE DUAL-BAND BANDPASS/BANDSTOP FILTER RESPONSE IN A SINGLE MICRO-ELECTRO-MECHANICAL DEVICE**  
X. Zou<sup>1\*</sup>, J. Yan<sup>1</sup> and A. A. Seshia<sup>1</sup>  
Nanoscience Centre, Department of Engineering, University of Cambridge, Cambridge, United Kingdom

836

**T1B.004** **NANO-ELECTROMECHANICAL STORAGE ELEMENT FOR A LOW POWER COMPLIMENTARY LOGIC ARCHITECTURE USING PZT RELAYS**  
Robert M. Proie Jr.<sup>1,2</sup>, Ronald G. Polcawich<sup>2</sup>, Jeffrey S. Pulskamp<sup>2</sup>, Tony Ivanov<sup>2</sup>, Mona Zaghoul<sup>1</sup>  
<sup>1</sup>The George Washington University, Washington, DC 20052, USA  
<sup>2</sup>US Army Research Laboratory, Adelphi, MD 20783-1197, USA

840

**T1B.005** **SPONTANEOUS OSCILLATION DUE TO CHARGING EFFECT IN MEMS RF SWITCHES**  
Y.-C. Chen<sup>1</sup>, T. Ishida<sup>2</sup>, H. Toshiyoshi<sup>2,3</sup>, R. Chen<sup>1</sup>, and H. Fujita<sup>2</sup>  
<sup>1</sup>PME, National Tsing Hua University, Hsinchu, Taiwan  
<sup>2</sup>IIS, the University of Tokyo, Tokyo, Japan  
<sup>3</sup>RCAST, the University of Tokyo, Tokyo, Japan

844

### SESSION II(3) – Wet Assembly

**T1C.001** **Invited Speaker**  
**PROGRAMMABLE SELF-ASSEMBLY FOR MICROSYSTEM INTEGRATION**  
J. H. Hoo<sup>1</sup>, K. S. Park<sup>1</sup>, R. Baskaran<sup>1,2</sup>, K. F. Böhringer<sup>1</sup>  
<sup>1</sup>Department of Electrical Engineering, University of Washington, Seattle, USA  
<sup>2</sup>Components Research, Intel Corporation, USA

848

**T1C.002** **LOW TEMPERATURE ENCAPSULATION OF NANOCHANNELS WITH WATER INSIDE**  
C. Shen<sup>\*</sup>, V.R.S.S. Mokkalapati, F. Santagata, A. Bossche, P.M. Sarro  
*DIMES - ECTM, Delft University of Technology, Delft,*

*the Netherlands*

854

**T1C.003** **ELECTRO-WETTING ENHANCED BONDING STRENGTH**  
Rong Cheng, Kewei Jiang, Xinxin Li<sup>\*</sup>  
*State Key Lab of Transducer Technology, and, Science and Technology on Microsystem Lab, Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, CHINA*

858

**T1C.004** **POLYMERIC DROPLET DEPOSITION AND SELF-RELEASE FORMING MICRO PARTS ON HETEROGENEOUS SURFACES**  
K.Z. Tu and C.T. Chen<sup>\*</sup>  
*μ FOS Laboratory, Department of Mechanical Engineering, National Kaohsiung University of Applied Sciences, Kaohsiung, TAIWAN, Republic of China*

862

**T1C.005** **ORIENTATION-SPECIFIC SELF-ASSEMBLY AT AIR-WATER INTERFACE USING MAGNETIC FIELD**  
K.S. Park<sup>1</sup>, R. Baskaran<sup>1,2</sup>, K.F. Böhringer<sup>1</sup>  
<sup>1</sup>Department of Electrical Engineering, University of Washington, Seattle, USA  
<sup>2</sup>Components Research, Intel Corporation, USA

866

### SESSION II(4) – Biomolecular Sensing

**T1D.001** **Invited Speaker**  
**NANOBIODEVICE BASED SINGLE MOLECULE AND CELL SENSING FOR CANCER DIAGNOSIS AND IN VIVO IMAGING FOR STEM CELL THERAPY**  
Y. Baba<sup>1,2</sup>  
<sup>1</sup>Department of Applied Chemistry, School of Engineering, Nagoya University  
*FIRST Research Center for Innovative Nanobiodevice, Nagoya University*  
*Department of Advanced Medical Science, School of Medicine, Nagoya University, Nagoya, Japan*  
<sup>2</sup>Health Research Institute, National Institute of Advanced Industrial Science and Technology (AIST), Takamatsu, Japan

870

**T1D.002** **NANOPORE DNA SENSORS IN CMOS WITH ON-CHIP LOW-NOISE PREAMPLIFIERS**  
J. Rosenstein<sup>1</sup>, V. Ray<sup>2</sup>, M. Drndic<sup>2</sup>, and K. L. Shepard<sup>1</sup>  
<sup>1</sup>Department of Electrical Engineering, Columbia University, New York, New York, USA  
<sup>2</sup>Department of Physics, University of Pennsylvania, Philadelphia, Pennsylvania, USA

874

**T1D.003** **DNA MICROARRAYS IMMOBILIZED ON UNMODIFIED PLASTICS IN A MICROFLUIDIC**

**BIOCHIP FOR RAPID TYPING OF AVIAN INFLUENZA VIRUS**

Y. Sun<sup>1</sup>, I.R. Perch-Nielsen<sup>1</sup>, M. Dufva<sup>1</sup>, D. Sabourin<sup>1</sup>, D.D. Bang<sup>2</sup>, J. Høgberg<sup>2</sup>, M. Bu<sup>1</sup> and A. Wolff<sup>1</sup>

<sup>1</sup>DTU Nanotech, Department of Micro- and Nanotechnology, Technical University of Denmark, Kgs. Lyngby, DENMARK

<sup>2</sup>DTU Vet, National Veterinary Institute, Technical University of Denmark, Aarhus, DENMARK

878

**T1D.004 ULTRA-SENSITIVE CARBON NANOTUBES FOR SINGLE-MOLECULE DETECTION OF DNA HYBRIDIZATION KINETICS USING CONDUCTANCE-BASED CORRELATION SPECTROSCOPY**

S. Sorgenfrei<sup>1</sup>, C.-Y. Chiu<sup>2</sup>, C. Nuckolls<sup>2</sup>, K. Shepard<sup>1</sup>

<sup>1</sup>Department of Electrical Engineering, Columbia University, New York, New York, USA

<sup>2</sup>Department of Chemistry, Columbia University, New York, New York, USA

882

**T1D.005 MOTOR PROTEIN MOTION ALONG MICROTUBULES FOR MOLECULAR DETECTION**

M.C. Tarhan<sup>1</sup>, R. Yokokawa<sup>2</sup>, H. Qiu<sup>1</sup>, S.L. Karsten<sup>3</sup> and H. Fujita<sup>1</sup>

<sup>1</sup>CIRMM, The University of Tokyo, Tokyo, JAPAN

<sup>2</sup>Kyoto University, Kyoto, JAPAN

<sup>3</sup>University of California Los Angeles, Los Angeles, CA, USA

886

**ORAL SESSIONS**

10:30 - 12:15

**SESSION III(1) – Physical Sensors I**

**T2A.001 SINGLE CHIP FLOW SENSING SYSTEM WITH A DYNAMIC FLOW RANGE OF MORE THAN 4 DECADES**

T.S.J. Lammerink<sup>1</sup>, J.C. Lötters<sup>1,2</sup>, R.J. Wiegerink<sup>1</sup>, J. Groenesteijn<sup>1,2</sup>, J. Haneveld<sup>1,2</sup>

<sup>1</sup>MESA+ Institute for Nanotechnology, University of Twente, The Netherlands

<sup>2</sup>Bronkhorst High-Tech BV, Ruurlo, The Netherlands

890

**T2A.002 CAPACITIVE ABSOLUTE PRESSURE SENSOR WITH INDEPENDENT ELECTRODE AND MEMBRANE SIZES FOR IMPROVED FRACTIONAL CAPACITANCE CHANGE**

Chia-Fang Chiang<sup>1</sup>, Andrew B. Graham<sup>2</sup>, Matthew W. Messana<sup>1</sup>, J. Provine<sup>1</sup>, Daniela T. Buchman<sup>1</sup>, Gary J. O'Brien<sup>2</sup>, and Thomas W. Kenny<sup>1</sup>

<sup>1</sup>Stanford University, Stanford, CA, USA

<sup>2</sup>Robert Bosch LLC, Research and Technology Center, Palo Alto, CA, USA

894

**T2A.003 BAROMETRIC PRESSURE CHANGE MEASUREMENT**

N. Minh-Dung, H. Takahashi, K. Matsumoto and I. Shimoyama

The University of Tokyo, Japan

898

**T2A.004 SAW-PIRANI VACUUM SENSOR WITH A NEW FUNCTIONING MODE AND A FAST RESPONSE TIME**

D. Mercier<sup>1</sup>, G. Bordel<sup>1</sup>, P. Brunet-Manquat<sup>1</sup>, S. Verrun<sup>1</sup>, O. Elmazria<sup>2</sup>, F. Sarry<sup>2</sup>, B. Belgacem<sup>3</sup>, J. Bounouar<sup>4</sup>

<sup>1</sup>CEA-LETI-MINATEC, 17 Rue des Martyrs 38054 Grenoble Cedex 9, France

<sup>2</sup>Institut Jean Lamour, UMR 7198 CNRS-Nancy University 54506, France

<sup>3</sup>SENSEOR, 18 Rue Alain Savary 25000 Besançon, France

<sup>4</sup>ADIXEN, Alcatel Vacuum Technology France, 740009 Annecy, France

902

**T2A.005 A HIGHLY SENSITIVE FLEXIBLE PRESSURE AND SHEAR SENSOR ARRAY FOR MEASUREMENT OF GROUND REACTIONS IN PEDESTRIAN NAVIGATION**

R. Surapaneni, K. Park, M.A. Suster, D.J. Young and C. H. Mastrangelo

University of Utah, Salt Lake City, UT, USA

906

**T2A.006 MINIATURE ULTRASOUND ACOUSTIC IMAGING DEVICES USING 2-D PMUTS ARRAY ON EPITAXIAL PZT/SrRuO<sub>3</sub>/Pt/γ-AI<sub>2</sub>O<sub>3</sub>/Si STRUCTURE**

Daisuke Akai<sup>1</sup>, Takahiro Yogi<sup>2</sup>, Ikuo Kamja<sup>2</sup>, Yasuyuki Numata<sup>2</sup>, Katsuya Ozaki<sup>2</sup>, Kazuaki Sawada<sup>2</sup>, Nagaya Okada<sup>3</sup>, Kazuki Higuchi<sup>3</sup>, and Makoto Ishida<sup>1,2</sup>

<sup>1</sup>Electronics-Inspired Interdisciplinary Research Institute (EIRIS), Toyohashi University of Technology, JAPAN

<sup>2</sup>Department of Electrical and Electronic Information Engineering, Toyohashi University of Technology, JAPAN

<sup>3</sup>Honda Electronics Co. Ltd., Toyohashi, JAPAN

910

**T2A.007 IN SITU WAFER-LEVEL POLARIZATION OF ELECTRET FILMS IN MEMS ACOUSTIC SENSOR ARRAYS**

M. Kranz<sup>1</sup>, M.G. Allen<sup>2</sup>, and T. Hudson<sup>3</sup>

<sup>1</sup>Stanley Associates, Huntsville, AL, USA

<sup>2</sup>Georgia Institute of Technology, Atlanta, GA, USA

<sup>3</sup>U.S. Army AMRDEC, Huntsville, AL, USA

914

**SESSION III(2) – Resonators & Oscillators**

**T2B.001 ONE-DIMENSIONAL LINEAR ACOUSTIC**

- BANDGAP STRUCTURES FOR PERFORMANCE ENHANCEMENT OF ALN-ON-SILICON MICROMECHANICAL RESONATORS**  
L. Sorenson, J.L. Fu, and F. Ayazi  
*Georgia Institute of Technology, Atlanta, Georgia, USA*  
.....918
- T2B.002 A 1.75 GHz PIEZOELECTRICALLY-TRANSDUCED SIC LATERAL OVERMODED BULK ACOUSTIC-WAVE RESONATOR**  
Songbin Gong, Nai-Kuei Kuo, and Gianluca Piazza  
*Penn Micro and Nano Systems Lab, University of Pennsylvania, Philadelphia, PA, USA*  
..... 922
- T2B.003 HIGH PERFORMANCE BULK MODE GALLIUM NITRIDE RESONATORS AND FILTERS**  
V.J.Gokhale<sup>1</sup>, J.Roberts<sup>2</sup>, and M.Rais-Zadeh<sup>1</sup>  
<sup>1</sup>*University of Michigan, Ann Arbor, Michigan, USA*  
<sup>2</sup>*Nitronex Corporation, Durham, North Carolina, USA*  
..... 926
- T2B.004 ENGINEERING OF ACOUSTIC METAMATERIALS WITH APPLICATION TO MEMS BAW RESONATORS**  
X. Rottenberg, R. Jansen, P. Verheyen, R. Van Hoof, A. Verbist and H.A.C. Tilmans  
*Imec v.z.w., Kapeldreef 75, B-3001 Leuven, Belgium*  
..... 930
- T2B.005 HIGH-Q, LARGE-STOPBAND-REJECTION INTEGRATED CMOS-MEMS OXIDE RESONATORS WITH EMBEDDED METAL ELECTRODES**  
Yu-Chia Liu<sup>1</sup>, Ming-Han Tsai<sup>1</sup>, Wen-Chien Chen<sup>2</sup>, Sheng-Shian Li<sup>1,2</sup>, and Weileun Fang<sup>1,2</sup>  
<sup>1</sup>*Inst. of NanoEngineering and MicroSystems and*<sup>2</sup>*Dept. of Power Mechanical Engineering National Tsing Hua University, Hsinchu, Taiwan*  
..... 934
- T2B.006 VERY HIGH FREQUENCY DOUBLE-ENDED TUNING FORK NANO-MECHANICAL FIN-FET RESONATOR**  
S.T. Bartsch, D. Grogg, A. Lovera, D. Tsamados, and A.M. Ionescu  
*Ecole Polytechnique Fédérale de Lausanne – EPFL Nanoelectronic Devices Laboratory Lausanne, SWITZERLAND*  
.....938
- T2B.007 ENCAPSULATED MECHANICALLY COUPLED FULLY-DIFFERENTIAL BREATHE-MODE RING FILTERS WITH ULTRA-NARROW BANDWIDTH**  
S. Wang, S. A. Chandorkar, A. B. Graham, M. W. Messana, J. Salvia, and T.W. Kenny  
*Stanford University, Stanford, California, USA*  
..... 942

**SESSION III(3) –Bioprobes & Biodevices**

- T2C.001 HIGH-Q IN-PLANE RESONANCE-MODE**

- CANTILEVER BIO/CHEMICAL SENSOR FOR REAL-TIME DETECTION IN LIQUIDS**  
Y.H. Tao, C.Z. Wei, H.T. Yu, P.C. Xu, T.G. Xu, B. Xiong, Xinxin Li\*  
*State Key Lab of Transducer Technology, and, Science and Technology on Microsystem Lab, Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, CHINA*  
..... 946

- T2C.002 SEMIPERMEABLE PARYLENE MEMBRANE AS AN ARTIFICIAL BRUCH'S MEMBRANE**  
Bo Lu<sup>1</sup>, Zhao Liu<sup>1</sup>, Laura Liu<sup>2,3</sup>, Danhong Zhu<sup>2,3</sup>, David Hinton<sup>2,3</sup>, Biju Thomas<sup>2</sup>, Mark S. Humayun<sup>2,3</sup> and Yu-Chong Tai<sup>1</sup>  
<sup>1</sup>*California Institute of Technology, Pasadena, CA, USA*  
<sup>2</sup>*Doheny Eye Institute, Los Angeles, CA, USA*  
<sup>3</sup>*University of Southern California, Los Angeles, CA, USA*  
..... 950

- T2C.003 LABEL-FREE REAL TIME IMAGING OF NEURAL COMMUNICATION USING ACETYLCHOLINE IMAGE SENSOR**  
Shoko TAKENAGA<sup>1</sup>, Yui TAMAI<sup>1</sup>, Kengo HIRAI<sup>1</sup>, Kazuhiro TAKAHASHI<sup>1,2</sup>, Takashi SAKURAI<sup>2,3</sup>, Susumu TERAOKAWA<sup>2,3</sup>, Makoto ISHIDA<sup>1,2</sup>, Koichi OKUMURA<sup>1,2</sup> and Kazuaki Sawada<sup>1,2</sup>  
<sup>1</sup>*Department of Electrical and Electronic Information Engineering, Toyohashi University of Technology, Toyohashi, Japan*  
<sup>2</sup>*JST CREST, Tokyo, Japan*  
<sup>3</sup>*Hamamatsu University School of Medicine, Hamamatsu, Japan*  
..... 954

- T2C.004 NEW CLASS OF CHRONIC RECORDING MULTICHANNEL NEURAL PROBES WITH POST-IMPLANT SELF-DEPLOYED SATELLITE RECORDING SITES**  
Daniel Egert and Khalil Najafi  
*Center for Wireless Integrated Microsystems (WIMS) University of Michigan, Ann Arbor, MI, USA*  
..... 958

- T2C.005 MULTILAYER PHASED MICROCOIL ARRAY FOR MAGNETIC RESONANCE IMAGING**  
O. G. Gruschke<sup>1,\*</sup>, L. Clad<sup>2</sup>, N. Baxan<sup>3</sup>, K. Kratt<sup>2</sup>, M. Mohammadzadeh<sup>3</sup>, D. von Elverfeldt<sup>3</sup>, A. Peter<sup>1</sup>, J. Hennig<sup>3</sup>, V. Badilita<sup>2</sup>, U. Wallrabe<sup>2</sup>, and J. G. Korvink<sup>1,4</sup>  
<sup>1</sup>*Lab. of Simulation, Dept. of Microsystems Engineering - IMTEK, University of Freiburg, Germany*  
<sup>2</sup>*Lab. for Microactuators, Dept. of Microsystems Engineering- IMTEK, University of Freiburg, Germany*  
<sup>3</sup>*University Medical Center, Dept. of Radiology Medical Physics, Freiburg, Germany*  
<sup>4</sup>*Freiburg Institute for Advanced Studies-FRIAS, University of Freiburg, Germany*  
.....962

**T2C.006 A FLEXIBLE FISH-BONE-SHAPED NEURAL PROBE STRENGTHENED BY BIODEGRADABLE SILK COATING FOR ENHANCED BIOCOMPATIBILITY**  
Fan Wu, Maesoon Im, and Euisik Yoon  
*Center for Wireless Integrated Microsystem  
Department of Electrical Engineering and Computer  
Science, University of Michigan, Ann Arbor, MI, USA*  
..... 966

**T2C.007 A MEMS DIFFERENTIAL AFFINITY SENSOR FOR CONTINUOUS GLUCOSE DETECTION**  
X. Huang<sup>1</sup>, J. Oxsher<sup>2</sup>, C. LeDuc<sup>3</sup>, Y. Ravussin<sup>3</sup>,  
Q. Wang<sup>2</sup>, D. Accili<sup>4</sup>, R. Leibel<sup>3</sup> and Q. Lin<sup>1\*</sup>  
*Departments of <sup>1</sup>Mechanical Engineering, <sup>3</sup>Pediatrics  
and <sup>4</sup>Medicine, Columbia University, New York,  
NY, USA;  
<sup>2</sup>Chemistry and Biochemistry Department, University of  
South Carolina, Columbia, SC, USA*  
.....970

### SESSION III(4) – Wafer Level Process

**T2D.001 WAFER-LEVEL THIN FILM VACUUM PACKAGES FOR MEMS USING NANOPOROUS ANODIC ALUMINA MEMBRANES**  
J. Zekry<sup>1,2\*</sup>, D.S. Tezcan<sup>1</sup>, J.-P. Celis<sup>2</sup>, R. Puers<sup>1,2</sup>,  
C. Van Hoof<sup>1,2</sup>, and H.A.C. Tilmans<sup>1</sup>  
*<sup>1</sup>Imec, Kapeldreef 75, B-3001 Leuven, Belgium  
<sup>2</sup>Katholieke Universiteit Leuven, Leuven, Belgium*  
..... 974

**T2D.002 DIRECT WAFER BONDING OF ATOMIC LAYER DEPOSITED TiO<sub>2</sub> AND Al<sub>2</sub>O<sub>3</sub> THIN FILMS**  
R. L. Puurunen<sup>1</sup>, T. Suni<sup>1,2</sup>, O. Ylivaara<sup>1</sup>, H.  
Kondo<sup>3</sup>, M. Ammar<sup>4</sup>, T. Ishida<sup>2</sup>, H. Fujita<sup>2</sup>, A.  
Bosseboeuf<sup>4</sup>, S. Zaima<sup>3</sup>, H. Kattelus<sup>1</sup>  
*<sup>1</sup>VTT Technical Research Centre of Finland, Espoo,  
FINLAND  
<sup>2</sup>Institute of Industrial Science (IIS), University of  
Tokyo, Tokyo, JAPAN  
<sup>3</sup>Nagoya University (NU), Nagoya, JAPAN  
<sup>4</sup>Institut d'Electronique Fondamentale (IEF),  
Université Paris Sud 11, CNRS, Orsay, FRANCE*  
.....978

**T2D.003 A WAFER-LEVEL POLY-SIGE-BASED THIN FILM PACKAGING TECHNOLOGY DEMONSTRATED ON**

**A SOI-BASED HIGH-Q MEM RESONATOR**  
Ph. Helin<sup>\*</sup>, A. Verbist, J. De Coster, B. Guo, S.  
Severi, A. Witvrouw, L. Haspeslagh and H.A.C.  
Tilmans  
*Imec, Kapeldreef 75, B-3001, Leuven, Belgium  
Y. Naito, K. Nakamura and K. Onishi  
Advanced Devices Development Center, Panasonic  
Corporation, 1006 Kadoma, Kadoma City, Osaka  
571-8501 Japan*  
.....982

**T2D.004 WAFER LEVEL PACKAGING BASED ON AU-AU BONDING FOR A CMOS COMPATIBLE THERMAL WIND SENSOR**  
Ziqiang Dong, Ming Qin, Jingjing Chen, Yukun  
Qin, and Qing-An Huang<sup>\*</sup>  
*Key Laboratory of MEMS of the Ministry of Education,  
Southeast University, Nanjing, CHINA*  
..... 986

**T2D.005 INVESTIGATIONS OF THERMOCOMPRESSION BONDING WITH THIN METAL LAYERS**  
J. Froemel<sup>1,3</sup>, M. Baum<sup>1</sup>, M. Wiemer<sup>1</sup>, F.  
Roscher<sup>1</sup>, M. Haubold<sup>1</sup>, C. Jia<sup>2</sup>, T. Gessner,<sup>1,2,3</sup>  
*<sup>1</sup>Fraunhofer ENAS, Chemnitz, GERMANY  
<sup>2</sup>Chemnitz University of Technology, Chemnitz,  
Germany  
<sup>3</sup>WPI Advanced Institute for Materials Research, Tohoku  
University, Sendai, JAPAN*  
.....990

**T2D.006 CONFORMAL COATING OF POLY(GLYCIDYL METHACRYLATE) AS A LITHOGRAPHIC POLYMER BY INITIATED CHEMICAL VAPOR DEPOSITION**  
S. Yoshida<sup>1</sup>, T. Kobayashi<sup>2</sup>, M. Kumano<sup>2</sup>, and M.  
Esashi<sup>1</sup>  
*<sup>1</sup>WPI Advanced Institute for Materials Research,  
Tohoku University, Sendai, Japan  
<sup>2</sup>Graduate School of Engineering, Tohoku University,  
Sendai, Japan*  
.....994

**T2D.007 HEATED MEMBRANES PREVENT CLOGGING OF APERTURES IN NANOSTENCIL LITHOGRAPHY**  
S.Q. Xie<sup>1</sup>, V. Savu<sup>1</sup> and J. Brugger<sup>1</sup>  
*<sup>1</sup>Microsystems Laboratory, Ecole Polytechnique  
Fédérale de Lausanne (EPFL), Lausanne, Switzerland*  
..... 998

Mechanical/Physical Sensors and Microsystems

- T3P.001 IMPROVEMENT OF CMOS-MEMS ACCELEROMETER USING POST-CMOS SELECTIVE ELECTROPLATING TECHNIQUE**  
 Yu-Chia Liu<sup>1</sup>, Ming-Han Tsai<sup>1</sup>, Tsung-Lin Tang<sup>2</sup>, and Weileun Fang<sup>1,2</sup>  
<sup>1</sup>*Inst. of NanoEngineering and MicroSystems and* <sup>2</sup>*Dept. of Power Mechanical Engineering National Tsing Hua University, Hsinchu, Taiwan*  
 .....1002
- T3P.002 MONOLITHIC PRESSURE+ACCELERATION SENSOR WITH SELF-TEST FUNCTION FOR RELIABLE & LOW-COST TIRE-PRESSURE-MONITORING-SYSTEM (TPMS) APPLICATIONS**  
 C.Z. Wei<sup>1,2</sup>, W. Zhou<sup>1</sup>, Q. Wang<sup>1</sup>, Xinxin Li<sup>1,2</sup>  
<sup>1</sup>*State Key Lab of Transducer Technology, and, Science and Technology on Microsystem Lab, Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, CHINA*  
<sup>2</sup>*Graduate School of Chinese Academy of Sciences, Beijing, China*  
 .....1006
- T3P.003 AN SOI 3-AXIS ACCELEROMETER WITH A ZIGZAG-SHAPED Z-ELECTRODE FOR DIFFERENTIAL DETECTION**  
 M. Fujiyoshi<sup>1</sup>, Y. Nonomura<sup>1</sup>, H. Funabashi<sup>1</sup>, Y. Omura<sup>1</sup>, T. Akashi<sup>1</sup>, Y. Hata<sup>1</sup>, H. Yamada<sup>2</sup>, and M. Esashi<sup>3</sup>  
<sup>1</sup>*Toyota Central R&D labs., Inc., Aichi, Aichi, Japan*  
<sup>2</sup>*Toyota Motor Corporation, Toyota, Aichi, Japan*  
<sup>3</sup>*Tohoku University, Sendai, Miyagi, Japan*  
 ..... 1010
- T3P.004 PIEZOELECTRIC SWITCH TO ACTIVATE EVENT-DRIVEN WIRELESS SENSOR NODE BY SEVERAL HZ OF VIBRATION**  
 T. Kobayashi<sup>1,3</sup>, H. Okada<sup>1,3</sup>, V. Z. Gang<sup>1</sup>, R. Maeda<sup>1</sup>, T. Masuda<sup>2,3</sup>, and T. Itoh<sup>1,3</sup>  
<sup>1</sup>*National Institute of Advanced Industrial Science and Technology (AIST), Tsukuba, Ibaraki, Japan*  
<sup>2</sup>*The University of Tokyo, Bunkyo, Tokyo, Japan,*  
<sup>3</sup>*JST-CREST, Kawaguchi, Saitama, Japan*  
 .....1014
- T3P.005 MEMS SENSOR WITH GIANT PIEZORESISTIVE EFFECT USING METALLSEMICONDUCTOR HYBRID STRUCTURE**  
 H.-D. Ngo<sup>\*1</sup>, T. Tekin<sup>1</sup>, T.-C. Vu<sup>1</sup>, M. Fritz<sup>1</sup>, W. Kurniawan<sup>1</sup>, B. Mukhopadhyay<sup>1</sup>, A. Kolitsch<sup>2</sup>, M. Schiffer<sup>3</sup>, K.-D. Lang<sup>1</sup>  
<sup>1</sup>*Research Center of Microperipheric Technologies,*

- Microsensors and Actuator Technology*  
 Gustav-Meyer-Allee 25, TiB 4/2-1, Technical University Berlin, GERMANY  
<sup>2</sup>*Forschungszentrum Dresden-Rossendorf Institute of Ion Beam Physics and Materials Research, Dresden, GERMANY*  
<sup>3</sup>*TDK-EPCOS Corporation, 14532 Stansdorf, GERMANY*  
 .....1018
- T3P.006 TRANSPARENT TOUCH PANEL WITH CONDUCTIVE LIQUID CHANNEL STRUCTURE**  
 Koji Asano<sup>1</sup>, Gakuto Kita<sup>1</sup>, Mitsuhiro Shikida<sup>2</sup>, and Kazuo Sato<sup>1</sup>  
<sup>1</sup>*Dept. of Micro-Nano Systems Engineering, Nagoya University, Nagoya, Japan*  
<sup>2</sup>*Center for Micro-Nano Mechatronics, Nagoya University, Nagoya, Japan*  
 .....1022
- T3P.007 DESIGN AND IMPLEMENTATION OF A NOVEL CMOS MEMS CONDENSER MICROPHONE WITH CORRUGATED DIAPHRAGM**  
 Chien-Hsin Huang<sup>1,2</sup>, Ming-Han Tsai<sup>3</sup>, Chien-Hsing Lee<sup>4</sup>, Tsung-Min Hsieh<sup>4</sup>, Jhy-Cheng Liou<sup>4</sup>, Li-Che Chen<sup>2</sup>, Ming-Chuen Yip<sup>1</sup>, and Weileun Fang<sup>1</sup>  
<sup>1</sup>*Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan*  
<sup>2</sup>*United Microelectronics Corp., Hsinchu, Taiwan*  
<sup>3</sup>*Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, Taiwan*  
<sup>4</sup>*Solid State System Corporation (3S), Hsinchu, Taiwan*  
 .....1026
- T3P.008 PRESSURE SENSOR USING NANO-OPTO-MECHANICAL SYSTEMS (NOMS)**  
 X. Zhao<sup>1,2,3</sup>, J. M. Tsai<sup>3</sup>, H. Cai<sup>3</sup>, X. M. Ji<sup>2</sup>, J. Zhou<sup>2</sup>, M. H. Bao<sup>2</sup>, Y. P. Huang<sup>2</sup>, D. L. Kwang<sup>3</sup> and A. Q. Liu<sup>1†</sup>  
<sup>1</sup>*School of Electrical & Electronic Engineering, Nanyang Technological University, Singapore 639798*  
<sup>2</sup>*School of Information Science and Technology, Fudan University, Shanghai 200433, China*  
<sup>3</sup>*Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research) 11 Science Park Road, Singapore Science Park II, Singapore 117685*  
 .....1030
- T3P.009 A HIGH SENSITIVITY SOI ELECTRIC-FIELD SENSOR WITH NOVEL COMB-SHAPED MICROELECTRODES**  
 Pengfei Yang<sup>1,2</sup>, Chunrong Peng<sup>1</sup>, Haiyan Zhang<sup>1,2</sup>, Shiguo Liu<sup>1</sup>, Dongming Fang<sup>1</sup>, and Shanhong Xia<sup>1\*</sup>  
<sup>1</sup>*State Key Laboratory of Transducer Technology, Institute of Electronics, Chinese Academy of Sciences, Beijing 100190, P.R.China*  
<sup>2</sup>*Graduate School of the Chinese Academy of Sciences Beijing 100039, P.R.China*

- .....1034
- T3P.010 SELF-CLEANING MASS CALIBRATION OF A THERMOGRAVIMETRIC DEVICE USING A THIN FILM MOLYBDENUM**  
E. Iervolino<sup>1,2</sup>, L. Mele<sup>2</sup>, F. Santagata, A. W. van Herwaarden<sup>1</sup>, W. van der Vlist<sup>2</sup>, J. F. Creemer<sup>2</sup>, P. M. Sarro<sup>2</sup>  
<sup>1</sup>*Sensor Integration, Distributieweg 28, 2645 EJ Delfgauw, The Netherlands (NL) [www.sensor.nl]*  
<sup>2</sup>*Delft University of Technology, DIMES, Feldmannweg 17, 2628 CT, NL [www.dimes.tudelft.nl]*
- .....1038
- T3P.011 THEORETICAL ANALYSIS ON GYROSCOPIC EFFECT IN SURFACE ACOUSTIC WAVES**  
Wen Wang, Jiuling Liu  
*Institute of acoustics, Chinese Academy of Sciences, Beijing, 100190, P. R. China*
- .....1042
- T3P.012 A ROBUST MICRO MECHANICAL-LATCH SHOCK SWITCH WITH LOW CONTACT RESISTANCE**  
C. H. Chung, R.-P. Ma, Y.-C. Shieh, W. Hsu  
*Department of Mechanical Engineering, National Chiao Tung University, Taiwan*
- .....1046
- T3P.013 A NOVEL INTEGRATED TRANSPARENT FLEXIBLE TACTILE SENSOR**  
Tsun-Yi Chen<sup>1</sup>, Yung-Chen Wang<sup>1</sup>, Cheng-Yao Lo<sup>2</sup>, and Rongshun Chen<sup>1,2</sup>  
<sup>1</sup>*Department of Power Mechanical Engineering, National Tsing Hua University, Taiwan*  
<sup>2</sup>*Institutes of NanoEngineering and MicroSystems, National Tsing Hua University, Taiwan*
- .....1052
- T3P.014 FABRICATION AND TESTING OF A HIGH RESOLUTION EXTENSOMETER BASED ON RESONANT MEMS STRAIN SENSORS**  
M. Ferri<sup>1</sup>, L. Belsito<sup>1</sup>, F. Mancarella<sup>1</sup>, L. Masini<sup>1</sup>, A. Roncaglia<sup>1</sup>, J. Yan<sup>2</sup>, A. A. Seshia<sup>2</sup>, J. Zalesky<sup>3</sup>, and K. Soga<sup>2</sup>  
<sup>1</sup>*Institute of Microelectronics and Microsystems, CNR, Bologna, Italy*  
<sup>2</sup>*Department of Engineering, University of Cambridge, Cambridge, United Kingdom*  
<sup>3</sup>*Czech Technical University in Prague, Faculty of Civil Engineering, Prague, Czech Republic*
- .....1056
- T3P.015 MICRO-CANTILEVERS FOR NON-DESTRUCTIVE CHARACTERIZATION OF NANOGRASS UNIFORMITY**  
Dirch H. Petersen<sup>1</sup>, Fei Wang<sup>1</sup>, Mikkel B. Olesen<sup>1</sup>, Rafal Wierzbicki<sup>1</sup>, Michael S. Schmidt<sup>1</sup>, Peter F. Nielsen<sup>2</sup>, Peter Boggild<sup>1</sup>, Ole Hansen<sup>1, 3</sup>, and Kristian Mølhave<sup>1</sup>.  
<sup>1</sup>*DTU Nanotech, Technical University of Denmark, Building 345E, DK-2800 Kgs. Lyngby, Denmark*  
<sup>2</sup>*CAPRES A/S, Scion-DTU, Building 373, DK-2800 Kgs. Lyngby, Denmark*  
<sup>3</sup>*CINF - Center for Individual Nanoparticle*
- .....1060
- T3P.016 IN-PROCESS PARAMETER CALIBRATION OF THERMOELECTRICAL FLOW SENSORS WITH MONOLITHIC INTEGRATED CHANNEL**  
M. Kropp<sup>1</sup>, E. Brauns<sup>1</sup>, C. Sosna<sup>2</sup> and W. Lang<sup>1</sup>  
<sup>1</sup>*Institute for Microsensors, -actuators and -systems (IMSAS), University of Bremen, Bremen, Germany*  
<sup>2</sup>*Diehl Gas Metering GmbH, Ansbach, Germany*
- .....1064
- T3P.017 AN IN-PLANE COBALT-NICKEL MICRORESONATOR SENSOR WITH MAGNETIC ACTUATION AND READOUT**  
O. Ergeneman<sup>1</sup>, P. Eberle<sup>1</sup>, M. Suter<sup>2</sup>, G. Chatzipirpiridis<sup>1</sup>, K. M. Sivaraman<sup>1</sup>, S. Pané<sup>1</sup>, C. Hierold<sup>2</sup>, and B. J. Nelson<sup>1</sup>  
<sup>1</sup>*Institute of Robotics and Intelligent Systems, ETH Zurich, Zurich, SWITZERLAND*  
<sup>2</sup>*Micro and Nano Systems, ETH Zurich, Zurich, SWITZERLAND*
- .....1068
- T3P.018 ALN BASED PIEZOELECTRIC FORCE SENSOR FOR ENERGY AUTONOMOUS SENSOR SYSTEMS**  
D. Feili, M. Barra, M. Ziegler and, H. Seidel  
*Saarland University, Department of Mechatronics, 66123 Saarbrücken, GERMANY*
- .....1072
- T3P.019 A CMOS COMPATIBLE POLYCRYSTALLINE SILICON-GERMANIUM BASED PIEZORESISTIVE PRESSURE SENSOR**  
P. Gonzalez<sup>1,2</sup>, B. Guo<sup>1</sup>, S. Severi<sup>1</sup>, K. De Meyer<sup>1,2</sup>, and A. Witvrouw<sup>1</sup>  
<sup>1</sup>*Interuniversity Electronic Center (IMEC), Leuven, Belgium*  
<sup>2</sup>*Katholieke Universiteit Leuven, Leuven, Belgium*
- .....1076
- T3P.020 DEVELOPMENT OF A STRAIN SENSOR FOR ROLLING CONTACT LOADS**  
C. Winkelmann, O. Woitschach, E.-M. Meyer and W. Lang  
*University of Bremen, Institute for Microsensors, -actuators and -systems, Bremen, Germany*
- .....1080
- T3P.021 AC CHARACTERISATION OF THERMAL FLOW SENSOR WITH FLUID CHARACTERISATION FEATURE**  
C. J. Hepp<sup>1</sup>, F. T. Krogmann<sup>1</sup>, J. Polak<sup>1</sup>, M. M. Lehmann<sup>1</sup>, G. A. Urban<sup>2</sup>  
<sup>1</sup>*Innovative Sensor Technology AG, Wattwil, SWITZERLAND*  
<sup>2</sup>*Laboratory for Sensors, Department of Microsystems Engineering (IMTEK), University of Freiburg, Freiburg, GERMANY*
- .....1084
- T3P.022 NOVEL METHOD FOR GATED INDUCTIVE READOUT FOR HIGHLY SENSITIVE AND LOW COST VISCOSITY AND DENSITY SENSORS**  
P. Rust, J. Dual  
*Functionality, NanoDTU, Denmark*

Institute of Mechanical Systems, Department of  
Mechanical and Process Engineering, ETH  
Zurich, Tammenstrasse 3, CH-8092 Zurich,  
SWITZERLAND

.....1088

**T3P.023 MODULATED ELECTRO-MECHANICAL  
CONTINUOUS-TIME  
LOWPASS SIGMA-DELTA-MODULATOR FOR  
MICROMACHINED GYROSCOPES**

S. Rombach<sup>1</sup>, T. Northemann<sup>1</sup>, M. Maurer<sup>1</sup>, M.  
Dienger<sup>2</sup> and Y. Manoli<sup>2</sup>

<sup>1</sup>Fritz Huettinger Chair of Microelectronics, Department  
of Microsystems Engineering - IMTEK, University of  
Freiburg, Germany

<sup>2</sup>HSG-IMIT Institute of Micromachining and Information  
Technology, Villingen-Schwenningen, Germany

.....1092

**T3P.024 DEFLECTION AMPLIFICATION MECHANISM IN A  
CAPACITIVE ACCELEROMETER**

I. Zeimpekis, I. Sari, M. Kraft

Nano Research Group, ECS, University of Southampton,  
Southampton, United Kingdom

.....1096

**T3P.025 NOVEL SINGLE-DEVICE "XOR" AND "AND"  
GATES FOR HIGH SPEED, VERY LOW POWER LSI  
MECHANICAL PROCESSORS**

Faisal K. Chowdhury<sup>1</sup>, Karumbaiah N.  
Chappanda<sup>1</sup>, Daniel Saab<sup>2</sup>, & Massood  
Tabib-Azar<sup>1</sup>

<sup>1</sup>University of Utah, Salt Lake City, Utah, USA

<sup>2</sup>Case Western Reserve University, Cleveland, Ohio,  
USA

.....1100

**T3P.026 DESIGN AND IMPLEMENTATION OF AN  
EXTREMELY LARGE PROOF-MASS CMOS-MEMS  
CAPACITIVE TILT SENSOR FOR SENSITIVITY AND  
RESOLUTION IMPROVEMENT**

Chun-I Chang<sup>1</sup>, Ming-Han Tsai<sup>1</sup>, Yu-Chia Liu<sup>1</sup>,  
Chih-Ming Sun<sup>3</sup>, and Weileun Fang<sup>1,2</sup>

<sup>1</sup>Institute of NanoEngineering and MicroSystems,  
National Tsing Hua University, HsinChu, Taiwan

<sup>2</sup>Department of Power Mechanical Engineering,  
National Tsing Hua University, HsinChu, Taiwan

<sup>3</sup>PixArt Imaging Inc, Hsinchu, Taiwan

.....1104

**T3P.027 MEASUREMENT OF THE MAGNITUDE AND  
DIRECTION OF MAGNETIC FIELD BY A  
MICROMACHINED CANTILEVER**

J. Chen, M. Qin, and Q.A. Huang\*

Key Laboratory of MEMS of the Ministry of Education,  
Southeast University, Nanjing 210096, CHINA

.....1108

**Chemical Sensors and Microsystems**

**T3P.028 ON THE RELATIVE SENSITIVITY OF  
MASS-SENSITIVE CHEMICAL MICROSENSORS**

L.A. Beardslee<sup>1</sup>, S. Truax<sup>1</sup>, J.-J. Su<sup>1</sup>, S.M.

Heinrich<sup>2</sup>, F. Josse<sup>3</sup>, O. Brand<sup>1</sup>

<sup>1</sup>School of Electrical and Computer Engineering,  
Georgia Institute of Technology, Atlanta, GA, USA

<sup>2</sup>Department of Civil and Environmental Engineering,  
Marquette University, Milwaukee, WI, USA

<sup>3</sup>Department of Electrical and Computer Engineering,  
Marquette University, Milwaukee, WI, USA

.....1112

**T3P.029 A RESONANT CANTILEVER SENSOR FOR  
MONITORING AIRBORNE NANOPARTICLES**

H. S. Wasisto<sup>1\*</sup>, S. Merzsch<sup>1</sup>, A. Stranz<sup>1</sup>, A. Waag<sup>1</sup>,  
I. Kirsch<sup>2</sup>, E. Uhde<sup>2</sup>, T. Salthammer<sup>2</sup> and E.  
Peiner<sup>1</sup>

<sup>1</sup>Institute of Semiconductor Technology (IHT), TU  
Braunschweig, Braunschweig, Germany

<sup>2</sup>Fraunhofer - WKI, Material Analysis and Indoor  
Chemistry, Braunschweig, Germany

.....1116

**T3P.030 GOLD NANOPARTICLES IMMOBILIZED QUARTZ  
CRYSTAL MICROBALANCE BIOCHIP WITH  
ULTRASONIC STANDING WAVE ENHANCEMENT  
FOR REAL-TIME SENSING PROTEIN-LIGAND  
INTERACTION**

Guo-Hua Feng\* and Shu-Xiang Yang

Department of Mechanical Engineering National Chung  
Cheng University, Chiayi, Taiwan

.....1120

**T3P.031 OZONE SENSOR USING ZNO BASED FILM BULK  
ACOUSTIC RESONATOR**

Z. Wang<sup>1</sup>, X. Qiu<sup>2</sup>, R. Tang<sup>2</sup>, J. Oiler<sup>2</sup>, J. Zhu<sup>2</sup>, H.  
Huang<sup>2</sup>, H. Wang<sup>2</sup>, J. Shi<sup>1</sup> and H. Yu<sup>2</sup>

<sup>1</sup>Wuhan University, Wuhan, China

<sup>2</sup>Arizona State University, Tempe, USA

.....1124

**T3P.032 MEASURING THE FREQUENCY RESOLUTION OF  
A MULTI DEGREE OF FREEDOM RESONATOR  
FOR MASS DETECTION**

K.M. Moran and K.L. Turner

Dept. of Mechanical Engineering, UCSB, Santa Barbara,  
CA, USA

.....1128

**T3P.033 PH MEASUREMENTS WITH ZNO BASED SURFACE  
ACOUSTIC WAVE RESONATOR**

R. Tang<sup>1</sup>, X. Qiu<sup>1</sup>, J. Zhu<sup>1</sup>, J. Oiler<sup>2</sup>, H. Huang<sup>1</sup>, H.  
Wang<sup>2</sup> and H. Yu<sup>1,2,\*</sup>

<sup>1</sup>School of Electrical, Computer and Energy Engineering,  
Arizona State University, Tempe, AZ 85287

<sup>2</sup>School of Earth and Space Exploration, Arizona State  
University, Tempe, AZ 85287

.....1132

**T3P.034 CO2 MEASUREMENT USING AN ALN/SI SAW  
SENSOR**

S. Fanget, H. Grange, F. Palancade, G. Ganuchaud,  
M. Matheron, S. Charlot, T. Bordy, T. Hoang, P.  
Rey, D. Mercier, P. Brunet-Manquat and P. Robert  
CEA-Leti, MINATEC Campus, 17 Rue des Martyrs -  
38054 GRENOBLE Cedex 9, FRANCE

.....1136

**T3P.035 SURFACE ACOUSTIC WAVE GAS SENSOR FOR MONITORING LOW CONCENTRATION AMMONIA**  
T.H. Lin<sup>1</sup>, Y.T. Li<sup>1</sup>, H.C.Hao<sup>1</sup>, I.C. Fang<sup>1</sup>, C.M. Yang<sup>2</sup>, and D.J. Yao<sup>1</sup>

<sup>1</sup>Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, Taiwan

<sup>2</sup>Department of Chemistry, National Tsing Hua University, Hsinchu, Taiwan

.....1140

**T3P.036 ADVANCES IN POLYMER-COATED SURFACE ACOUSTIC WAVE GAS SENSOR**

Shitang He, Wen Wang, Shunzhou Li, and Minghua Liu

Institute of Acoustics, Chinese Academy of Sciences, Beijing, CHINA

.....1144

**T3P.037 A MICROFABRICATED PRECONCENTRATING DEVICE FOR EXHALED BREATH ANALYSIS**

M. Li<sup>1</sup>, S. Biswas<sup>2</sup>, M. H. Nantz<sup>2</sup>, R. M. Higashi<sup>2,3,4</sup> and X. A. Fu<sup>\*1</sup>

<sup>1</sup>Department of Chemical Engineering

<sup>2</sup>Department of Chemistry

<sup>3</sup>Center for Regulatory and Environmental Analytical Metabolomics (CREAM)

<sup>4</sup>James Graham Brown Cancer Center University of Louisville, Kentucky, USA

.....1148

**T3P.038 FLEXIBLE POLYMER HUMIDITY SENSOR FABRICATED BY INKJET PRINTING**

E. Starke\*, A. Türke, M. Krause, and W.-J. Fischer  
Technische Universität Dresden, Institute of Semiconductors and Microsystems, 01062 Dresden, Germany

.....1152

**T3P.039 A TEXTILE INTEGRATED SENSOR SYSTEM FOR MONITORING HUMIDITY AND TEMPERATURE**

T. Kinkeldei, C. Zysset, K.H. Cherenack and G. Tröster

Swiss Federal Institute of Technology Zurich, Wearable Computing Lab, Zurich, Switzerland

.....1156

**T3P.040 FEM MODELING SAW HUMIDITY SENSOR BASED ON ZNO/IDTS/ALN/SI STRUCTURES**

D.T. Phan and G.S. Chung

School of Electrical Engineering, University of Ulsan, San 29, Mugeodong, Namgu, Ulsan, KOREA

.....1160

**T3P.041 RAPID HORMONE IMMUNOSENSOR WITH FLUID CONTROL MECHANISM**

M. Yamaguchi<sup>1</sup>, Y. Matsuda<sup>1</sup>, S. Yoshikawa<sup>1</sup>, M. Sasaki<sup>1</sup>, Y. Imai<sup>2</sup>, D. Niwa<sup>2</sup>, and V. Shetty<sup>3</sup>

<sup>1</sup>Iwate University, Morioka, Iwate, Japan

<sup>2</sup>Rohm Co., Ltd., Kyoto, Japan

<sup>3</sup>University of California, Los Angeles, CA, USA

.....1164

**T3P.042 FLUORENE-THIOPHENE-BASED THIN-FILM FLUORESCENT CHEMOSENSOR FOR METHAMPHETAMINE VAPOR**

Y.Y. Fu<sup>1</sup>, L.Q. Shi<sup>1</sup>, D. F. Zhu<sup>1</sup>, C. He<sup>1,2</sup>, D. Wen<sup>1,2</sup>, C.M. Deng<sup>1,2</sup>, Q.G. He<sup>1</sup>, H. M. Cao<sup>1</sup>, J. G. Cheng<sup>1</sup>

<sup>1</sup>State Key Laboratory of Transducer Technology, Shanghai Institute of Microsystem and Information Technology, Chinese Academy of Sciences, Shanghai, China

<sup>2</sup>Graduate School of the Chinese Academy of Sciences, Beijing, China

.....1168

## Bio-Sensors and Bio-Microsystems

**T3P.043 LOCALIZED ELECTROPORATION OF MOUSE EMBRYO USING DIELECTRIC GUIDES**

E. Mazari<sup>1</sup>, M. Mantelet<sup>1</sup>, J. Irazzo<sup>2</sup>, A. Perea-Gomez<sup>2</sup>, and C. Gosse<sup>1</sup>

<sup>1</sup>Laboratoire de Photonique et de Nanostructures, LPN-CNRS, Marcoussis, France

<sup>2</sup>Institut Jacques Monod, Université Paris 7 - CNRS, Paris, France

.....1172

**T3P.044 RAPID ON-SITE MEASUREMENT OF THE FRESHNESS OF RICE ON A MICRO ELECTROCHEMICAL DEVICE**

E. Koyachi<sup>1</sup>, K. Kojima<sup>1</sup>, T. Satake<sup>2</sup>, and H. Suzuki<sup>1</sup>

<sup>1</sup>Graduate School of Pure and Applied Sciences, University of Tsukuba, Tsukuba, Ibaraki, JAPAN

<sup>2</sup>Graduate School of Life and Environmental Sciences, University of Tsukuba, Tsukuba, Ibaraki, JAPAN

.....1176

**T3P.045 AN ALL-DIGITAL, TIME-GATED 128X128 SPAD ARRAY FOR ON-CHIP, FILTER-LESS FLUORESCENCE DETECTION**

Y. Maruyama and E. Charbon

Circuits and Systems, Delft University of Technology, Delft, The Netherlands

.....1180

**T3P.046 MAGNETIC MICROHEATERS FOR CELL SEPARATION, MANIPULATION, AND LYSING**

Angelo Gaitas<sup>1,2</sup>, Paddy French<sup>2</sup>

<sup>1</sup>PicoCal Inc., 333 Parkland Plaza, Ann Arbor, Michigan, USA

<sup>2</sup>EI/EWI-DIMES, Delft University of Technology, Mekelweg 4 2628CD Delft, the Netherlands

.....1184

**T3P.047 MULTI-SITE ELECTRORETINOGRAM RECORDINGS INSIDE ISOLATED MOUSE RETINA USING FLEXIBLE SPATIALLY ARRANGED MICROELECTRODE PROBES**

Wataru Tonomura<sup>1</sup>, Shun Taga<sup>1</sup>, Chieko Koike<sup>1,2</sup> and Satoshi Konishi<sup>1</sup>

<sup>1</sup>Ritsumeikan University, Kusatsu, Shiga, JAPAN

<sup>2</sup>PRESTO, JST, Kawaguchi, Saitama, JAPAN

.....1188

**T3P.048 A MICRO DEVICE FOR IMPEDANCE AND MECHANICAL CHARACTERIZATION OF**

## BIOLOGICAL CELLS

Jian Chen\*, Yi Zheng\*, Qingyuan Tan, Yan Liang Zhang, Jason Li, Steve To, and Yu Sun\*\*  
*Advanced Micro and Nanosystems Lab, University of Toronto, Canada*

.....1192

### T3P.049 LOW COST AND HIGH SPECIFIC ANESTHETIC BIOSENSORS WITH FUNCTIONALLY IMPRINTED NANOCAVITIES ON POLYMER FILMS

Chien-Chong Hong<sup>1</sup>, Chih-Chung Lin<sup>2</sup>, Chian-Lang Hong<sup>2</sup>, and Po-Hsiang Chang<sup>1</sup>

<sup>1</sup>*BioMEMS and NanoBiosystems Lab, Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan*

<sup>2</sup>*Department of Anesthesia, Chang Gung Memorial Hospital, Linkou, Taiwan*

.....1196

### T3P.050 HIGH-DENSITY MICROELECTRODE ARRAY SYSTEM AND OPTIMAL FILTERING FOR CLOSED-LOOP EXPERIMENTS

David Jäckel, Jan Müller, Muhammad Usman Khalid, Urs Frey, Douglas Bakkum, Andreas Hierlemann

*ETH Zurich, Department of Biosystems Science and Engineering, 4058 Basel, Switzerland*

.....1200

### T3P.051 EVALUATION OF THE PACKAGING AND ENCAPSULATION RELIABILITY IN FULLY INTEGRATED, FULLY WIRELESS 100 CHANNEL UTAH SLANT ELECTRODE ARRAY (USEA): IMPLICATIONS FOR LONG TERM FUNCTIONALITY

A. Sharma<sup>1</sup>, L. Rieth<sup>1</sup>, P. Tathireddy<sup>1</sup>, R. Harrison<sup>1,2</sup>, H. Oppermann<sup>3</sup>, M. Klein<sup>3</sup>, M. Töpfer<sup>3</sup>, E. Jung<sup>3</sup>, R. Normann<sup>2</sup>, G. Clark<sup>2</sup> and F. Solzbacher<sup>1,2</sup>

<sup>1</sup>*Dept. of Electrical and Computer Engineering, Univ. of Utah, Salt Lake City, Utah, 84112, USA*

<sup>2</sup>*Dept. of Bioengineering, Univ. of Utah, Salt Lake City, Utah, 84112, USA*

<sup>3</sup>*Fraunhofer Institute for Reliability and Microintegration, 13355 Berlin, Germany*

.....1204

## Medical Microsystems

### T3P.052 WIRELESS RECHARGING OF BATTERY OVER LARGE DISTANCE FOR IMPLANTABLE BLADDER PRESSURE CHRONIC MONITORING

M.A. Suster and D.J. Young

*University of Utah, Salt Lake City, Utah, USA*

.....1208

### T3P.053 FLEXIBLE MICRO-TACTILE SENSOR FOR NORMAL AND SHEAR ELASTICITY MEASUREMENTS

P. Peng<sup>1</sup>, R. Rajamani<sup>1</sup>, and X. Yu<sup>2</sup>

<sup>1</sup>*University of Minnesota, Minneapolis, Minnesota, USA*

<sup>2</sup>*University of Minnesota, Duluth, Minnesota, USA*

.....1212

### T3P.054 DEVELOPMENT OF A MICROFLUIDIC DEVICE WITH MICROCANTILEVER ARRAY FOR PROBING SINGLE CANCER CELL MECHANICS

T. I. Yin<sup>1\*</sup>, Y. Zhao<sup>1</sup>, C. F. Lin<sup>2</sup>, H. H. Tsai<sup>2</sup>, Y. Z. Juang<sup>2</sup>, G. A. Urban<sup>1</sup>

<sup>1</sup>*IMTEK, University of Freiburg, Freiburg, Germany*

<sup>2</sup>*National Chip Implementation Center, National Applied Research Laboratories, Hsinchu, Taiwan*

.....1216

### T3P.055 ANIMAL EXPERIMENTAL STUDY ON THE NERVE ROOT RETRACTION WITH A SILICON PRESSURE SENSOR

Xing Liu<sup>1</sup>, Qing-An Huang<sup>1</sup>, Ming Qin<sup>1</sup>, Hui Chen<sup>2</sup>, and Darrin Young<sup>3</sup>

<sup>1</sup>*Key Laboratory of MEMS of the Ministry of Education, Southeast University, Nanjing 210096, China*

<sup>2</sup>*Medical College, Southeast University, Nanjing 210009, China*

<sup>3</sup>*Department of Electrical and Computer Engineering, University of Utah, Salt Lake City UT 84112, USA*

.....1220

### T3P.056 INDIVIDUALLY-ADDRESSABLE PARYLENE MICRONEEDLE ARRAYS WITH INTEGRATED MICROCHANNELS FOR RETINAL PROSTHESIS STUDY

H. Tu, Y. Li, P. Finlayson, R. Iezzi, and Y. Xu  
*Wayne State University, Detroit, MI, USA*

.....1224

### T3P.057 PRELIMINARY THERMAL CHARACTERIZATION OF A FULLY-PASSIVE WIRELESS BACKSCATTERING NEURO-RECORDING MICROSYSTEM

H. N. Schwerdt<sup>1</sup>, W. Xu<sup>1</sup>, S. Shekhar<sup>1</sup>, F. A. Miranda<sup>2</sup>, J. Chae<sup>1</sup>

<sup>1</sup>*Arizona State University, School of Electrical, Computer, and Energy Engineering, Tempe, AZ, USA*

<sup>2</sup>*NASA Glenn Research Center, Cleveland, OH, USA*

.....1228

### T3P.058 A FABRY-PÉROT PRESSURE SENSOR FABRICATED ON LEFT VENTRICULAR ASSIST DEVICE FOR HEART FAILURE IMPLANT

M. D. Zhou<sup>1</sup>, C. Yang<sup>2</sup>, Z. Liu<sup>2</sup>, J. P. Cysyk<sup>3</sup>, and S. Y. Zheng<sup>1</sup>

<sup>1</sup>*Department of Bioengineering,*

<sup>2</sup>*Department of Electrical Engineering, Pennsylvania State University University Park, Pennsylvania, U. S. A.*

<sup>3</sup>*Department of Surgery, College of Medicine, Pennsylvania State University, Hershey, Pennsylvania, U. S. A.*

.....1232

## Microfluidics

### T3P.059 AN INTEGRATED MICROFLUIDIC SYSTEM FOR INTERSTITIAL FLUID TRANSDERMAL EXTRACTION

H.X. Yu<sup>1,2</sup>, D.C. Li<sup>1</sup>, R.C. Roberts<sup>2</sup>, W.S. Liang<sup>1</sup>,

- K.X. Xu<sup>1</sup>, and N.C. Tien<sup>2</sup>  
<sup>1</sup>State Key Laboratory of Precision Measuring Technology and Instruments, Tianjin University, China  
<sup>2</sup>Department of Electrical Engineering & Computer Science, Case Western Reserve University, USA  
.....1236
- T3P.060 ACOUSTIC TWEEZERS: ACHIEVING QUASI-DYNAMIC MICROPARTICLE PATTERNING USING TUNABLE SURFACE ACOUSTIC WAVES**  
Xiaoyun Ding, Jinjie Shi, Sz-Chin Steven Lin, Shahrzad Yazdi, Brian Kiraly, and Tony Jun Huang  
Department of Engineering Science and Mechanics, The Pennsylvania State University, University Park, PA 16802 US  
.....1240
- T3P.061 A MICROFLUIDIC CONTROL SYSTEM WITH RE-USABLE MICROPUMP/VALVE ACTUATOR AND INJECTION MOULDED DISPOSABLE POLYMER LAB-ON-A-SLIDE**  
Minqiang Bu, Ivan R. Perch-Nielsen, Yi Sun, and Anders Wolff  
Department of Micro and Nanotechnology (DTU Nanotech), Technical University of Denmark, Kgs. Lyngby, DK-2800, DENMARK  
.....1244
- T3P.062 DIGITAL LIQUID-LIQUID MICROEXTRACTION**  
Y.-W. Hsu<sup>1</sup>, C.-H. Chen<sup>1</sup>, and S.-K. Fan<sup>1,2</sup>  
<sup>1</sup>Department of Mechanical Engineering, National Chiao Tung University, Hsinchu, Taiwan  
<sup>2</sup>Department of Materials Science and Engineering, National Chiao Tung University, Hsinchu, Taiwan  
.....1248
- T3P.063 DYNAMIC EFFECTS OF DROPLET IMPINGEMENT ON NANOTEXTURED SURFACE FOR HIGH EFFICIENT SPRAY COOLING**  
C. Lin<sup>1\*</sup>, C.J. Chen<sup>1</sup>, C.C. Chieng<sup>1</sup>, and F.G.Tseng<sup>1,2</sup>  
<sup>1</sup>Department of Engineering and System Science, National Tsing Hua University, Taiwan, R.O.C  
<sup>2</sup>Division of Mechanics, Research Center for Applied Sciences, Academia Sinica, Taiwan, R.O.C.  
.....1252
- T3P.064 OPTIMIZATION OF LIQUID DIELECTROPHORESIS (L-DEP) BASED DEVICES TOWARDS CONDUCTIVE BIOLOGICAL LIQUIDS HANDLING**  
B. Daunay<sup>1</sup>, P. Lambert<sup>1</sup>, L. Jalabert<sup>1</sup>, D. Collard<sup>1</sup> and H. Fujita<sup>2</sup>  
<sup>1</sup>LIMMS-CNRS/IIS, UMI2820, The University of Tokyo  
<sup>2</sup>CIRMM, IIS, The University of Tokyo  
.....1256
- T3P.065 MILLILITER-TO-MICROLITER PLATFORM FOR ON-DEMAND LOADING OF AQUEOUS AND NON-AQUEOUS DROPLETS TO DIGITAL MICROFLUIDICS**  
G.J. Shah<sup>1</sup>, H.-J. Ding<sup>1</sup>, S. Sadeghi<sup>1</sup>, S. Chen<sup>2</sup>, C.-J. Kim<sup>3</sup> and R.M. van Dam<sup>1,2</sup>  
<sup>1</sup>Crump Institute for Molecular Imaging and Dept. of Molecular & Medical Pharmacology  
<sup>2</sup>Bioengineering Dept.  
<sup>3</sup>Mechanical and Aerospace Engineering Dept., UCLA, Los Angeles CA 90095, USA  
.....1260
- T3P.066 CONDUCTOMETRIC AND OPTICAL SENSING OF STIMULI SENSITIVE HYDROGELS INSIDE MICROFLUIDIC CHANNELS**  
T. Guan<sup>1</sup>, F. Ceysens<sup>1</sup>, and R. Puers<sup>1</sup>  
<sup>1</sup>KULeuven, dept. ESAT-MICAS, Leuven, BELGIUM  
.....1264
- T3P.067 DEPOSITION OF CARBON NANOPARTICLES USING OPTICALLY INDUCED DIELECTROPHORESIS FORCE**  
S.E. Wang<sup>1,2</sup>, Z.L. Dong<sup>1</sup>, Y.L. Qu<sup>1</sup>, G.B. Lee<sup>1,3</sup>, and W.J.Li<sup>1,4</sup>  
<sup>1</sup>State Key Laboratory of Robotics, Shenyang Institute of Automation, CAS, Shenyang, China  
<sup>2</sup>The Graduate University of the Chinese Academy of Sciences, China  
<sup>3</sup>Dept. of Engineering Science, NCKU, Taiwan  
<sup>4</sup>Centre for Micro and Nano Systems, CUHK, Hong Kong  
.....1268
- T3P.068 DYNAMICALLY CONTROLLABLE CONCENTRATION GRADIENT GENERATOR FOR STUDYING CELLULAR RESPONSE TO CHEMICAL INSTIGATION**  
R.J. Chen<sup>1</sup>, S. Shilpa<sup>1</sup>, V. P. Srinivasu<sup>1</sup>, S.M. Yang<sup>2</sup>, Y.J.Chu<sup>1</sup> and C.H. Liu<sup>1</sup>  
<sup>1</sup>Microsystems and Control Laboratory, Power Mechanical Engineering Department, NTHU, Hsinchu, Taiwan, R.O.C.  
<sup>2</sup>Department of Electrophysics, National Chiao Tung University, Taiwan, R.O.C.  
.....1272
- T3P.069 ROTATIONALLY CONTROLLED CENTRIFUGO-PNEUMATIC VALVING UTILIZING DISSOLVABLE FILMS**  
R. Gorkin, C. Nwankire, J. Siegrist, R. Burger, J. Gaughran, and J. Ducreé  
Biomedical Diagnostics Institute, National Centre for Sensor Research, School of Physical Sciences, Dublin City University, Ireland  
.....1276
- T3P.070 FOCUSING MICROPARTICLES IN A MICROFLUIDIC CHANNEL WITH FERROFLUIDS**  
Taotao Zhu<sup>1</sup>, Rui Cheng<sup>2</sup>, and Leidong Mao<sup>2</sup>  
<sup>1</sup>Department of Chemistry, Nanoscale Science and Engineering Center  
<sup>2</sup>Faculty of Engineering, Nanoscale Science and Engineering Center  
University of Georgia, Athens, Georgia 30602, USA  
.....1280
- T3P.071 PLANAR ON-CHIP FLOW CYTOMETER USING EVANESCENT WAVES BASED ON LIQUID TOTAL INTERNAL REFLECTION (L-TIR)**  
H. Huang<sup>1,2\*</sup>, X. M. Ji<sup>1</sup>, J. Zhou<sup>1</sup>, T. J. Huang<sup>2</sup>, and

Y. P. Huang<sup>1\*</sup>  
<sup>1</sup>ASIC and System State Key Lab, Department of Microelectronics, Fudan University, Shanghai, China  
<sup>2</sup>Department of Engineering Science and Mechanics, The Pennsylvania State University, University Park, PA, USA  
..... 1284

**T3P.072 FRICTIONAL DRAG REDUCTION IN MICROCHANNEL USING SLIP ON CONVEX AIR BUBBLES NATURALLY FORMED IN A SPECIFIED A CAVITY**  
B.H. Kwon<sup>1</sup>, H.H. Kim<sup>1</sup>, K. Park<sup>1</sup>, J.H. Park<sup>1</sup>, D.G. Choi<sup>2</sup>, and J.S. Go<sup>1</sup>  
<sup>1</sup>School of Mechanical Engineering, Pusan National University, Busan, South Korea  
<sup>2</sup>Center for Nanoscale Mechatronics & Manufacturing, Korea Institute of Machinery & Materials, Daejeon, South Korea  
..... 1288

**T3P.073 A MICROFLUIDIC MIXER BASED ON PARALLEL, HIGH-SPEED CIRCULAR MOTION OF INDIVIDUAL MICROBEADS IN A ROTATING MAGNETIC FIELD**  
Z-C. Peng<sup>\*,†</sup>, P. Hesketh<sup>‡</sup>, W. Mao<sup>‡</sup>, A. Alexeev<sup>‡</sup>, W. Lam<sup>\*,1</sup>  
<sup>\*</sup>Emory - Georgia Tech Joint Department of Biomedical Engineering, Atlanta, Georgia, USA  
<sup>†</sup>School of Mechanical Engineering, Georgia Institute of Technology, Atlanta, Georgia, USA  
<sup>1</sup>Department of Pediatrics, Emory University School of Medicine, Atlanta, Georgia, USA  
..... 1292

**T3P.074 ACTIVE SURFACE TENSION DRIVEN MICROPUMP USING DROPLET/MENISCUS PRESSURE GRADIENT**  
R. Shabani<sup>1</sup> and H.J. Cho<sup>1,2</sup>  
<sup>1</sup>Department of Mechanical, Materials and Aerospace Engineering, University of Central Florida Orlando, Florida, USA  
<sup>2</sup>School of Advanced Materials Science and Engineering, Sungkyunkwan University, Suwon, Korea  
..... 1296

**T3P.075 OPTOELECTRONIC TWEEZERS INTEGRATION WITH MULTILAYER MICROFLUIDIC DEVICE USING SWNT EMBEDDED PDMS MEMBRANE ELECTRODE**  
K.-W. Huang<sup>1</sup>, S. Sattar<sup>2</sup>, and P.Y. Chiou<sup>1</sup>  
<sup>1</sup>Department of Mechanical and Aerospace Engineering, University of California at Los Angeles, USA  
<sup>2</sup>Department of Bioengineering, University of California at Los Angeles, USA  
..... 1300

**T3P.076 WIRELESSLY ACTUATED MICROVALVE SYSTEM USING INDUCTION HEATING AND ITS THERMAL EFFECT ON THE MICROFLUIDIC SYSTEM**  
Seung-Ki Baek<sup>1</sup>, Yong-Kyu 'YK' Yoon<sup>2</sup>, and Jung-Hwan Park<sup>3\*</sup>  
<sup>1</sup>Electrical Engineering and <sup>3</sup>College of Bionano

Technology, Kyungwon University, Republic of Korea  
<sup>2</sup>Electrical and Computer Engineering, University of Florida, USA  
..... 1304

**T3P.077 A BISTABLE SHAPE MEMORY MICROVALVE FOR THREE-WAY CONTROL**  
C. Megnin, J. Barth, and M. Kohl  
Karlsruhe Institute of Technology (KIT)  
Institute of Microstructure Technology (IMT), Karlsruhe, GERMANY  
..... 1308

**T3P.078 HIGH-SPEED DELIVERY OF MICROBEADS IN MICROCHANNEL USING MAGNETICALLY DRIVEN MICROTOOL**  
L. Feng<sup>1,3</sup>, M. Hagiwara<sup>1</sup>, Huseyin Uvet<sup>1</sup>, Y. Yamanish<sup>2</sup>, T. Kawahara<sup>1</sup>, K. Kosuge<sup>3</sup>, F. Arai<sup>1,4</sup>  
<sup>1</sup>Department of Micro-Nano Systems Engineering, Nagoya University, Furo-cho, Chikusa-ku, Nagoya, 464-8603, Japan  
<sup>2</sup>JST PRESTO, Japan  
<sup>3</sup>Department of Bioengineering and Robotics, Tohoku University, Sendai, Japan  
<sup>4</sup>Seoul National University, Seoul, Korea  
..... 1312

**T3P.079 HIGH THROUGHPUT SEPARATION OF BLOOD CELLS BY USING HYDRODYNAMICS AND MAGNETOPHORESIS**  
H. K. Seo<sup>1</sup>, D. H. Kang<sup>1</sup>, H. R. Ahn<sup>1</sup>, H. O. Kim<sup>2</sup>, and Y. J. Kim<sup>1</sup>  
<sup>1</sup>School of Mechanical Engineering, Yonsei University, Seoul, South Korea  
<sup>2</sup>Department of Laboratory Medicine, Yonsei University, Seoul, South Korea  
..... 1316

**T3P.080 A MICROFLUIDIC "TREADMILL" FOR SPERM SELECTIVE TRAPPING ACCORDING TO MOTILITY CLASSIFICATION**  
T. Qiu<sup>1,2</sup>, C. Han<sup>1,2</sup>, R. Ma<sup>1,2</sup>, L. Xie<sup>1,2</sup>, Z. Li<sup>1,2</sup>, K. Su<sup>3</sup>, L. Wang<sup>2</sup>, G. Huang<sup>1,2</sup>, J. Wang<sup>3</sup>, J. Qiao<sup>4</sup>, W. Xing<sup>1,2,\*</sup>, J. Cheng<sup>1,2,\*</sup>  
<sup>1</sup>Department of Biomedical Engineering, School of Medicine, Tsinghua University, Beijing, China  
<sup>2</sup>National Engineering Research Center for Beijing Biochip Technology, Beijing, China  
<sup>3</sup>Shanxi Key Laboratory of Ecological Animal Science and Environmental Medicine, Shanxi Agricultural University, Taigu, Shanxi, China  
<sup>4</sup>Center of Reproduction Medicine, Department of Obstetrics and Gynecology, Third Hospital of Peking University, Beijing, China  
..... 1320

**Materials, Fabrication and Packaging Technologies**

**T3P.081 COMB-DRIVE III-NITRIDE MICRO MIRROR FABRICATED BY FAST ATOM BEAM ETCHING**  
Y. J. Wang<sup>1,2</sup>, T. Sasaki<sup>2</sup>, T. Wu<sup>2</sup>, F.R. Hu<sup>2</sup>, K. Hane<sup>2</sup>

<sup>1</sup>Institute of Communication Technology, Nanjing University of Posts and Telecommunications, Nanjing, Jiang-Su 210003, People's Republic of China

<sup>2</sup>Department of Nanomechanics, Tohoku University, Sendai 980-8579, Japan

..... 1324

**T3P.082 FABRICATION OF MICROPATTERNS ON CHANNEL SIDEWALLS USING STRAINRECOVERY PROPERTY OF A SHAPE-MEMORY POLYMER**

\*Anirban Chakraborty, Xinchuan Liu and Cheng Luo

*Mechanical and Aerospace Engineering, University of Texas at Arlington, Arlington, TX 76019 USA*

..... 1328

**T3P.083 ROOM-TEMPERATURE REACTIVE BONDING BY USING NANO SCALE MULTILAYER SYSTEMS**

J. Braeuer<sup>1\*</sup>, J. Besser<sup>1</sup>, M. Wiemer<sup>1</sup> and T. Gessner<sup>1,2</sup>

<sup>1</sup>Fraunhofer Institute for Electronic Nano Systems, Chemnitz, Germany

<sup>2</sup>Chemnitz University of Technology, Chemnitz, Germany

..... 1332

**T3P.084 LASER ANNEALED SIGE DEVICES FOR MEMS APPLICATIONS AT TEMPERATURES BELOW 250°C**

J. El-Rifai<sup>1,2,3</sup>, S. Sedky<sup>2,4</sup>, R. Van Hoof<sup>1</sup>, S. Severi<sup>1</sup>, D. Lin<sup>1</sup>, R. Puers<sup>1,3</sup>, C. Van Hoof<sup>1,3</sup> and A. Witvrouw<sup>1</sup>

<sup>1</sup>imec, Leuven, Belgium

<sup>2</sup>YJ-Science and Technology Research Center, AUC, New Cairo, Egypt

<sup>3</sup>Katholieke Universiteit Leuven, Leuven, Belgium

<sup>4</sup>Physics Department, The American University in Cairo (AUC), New Cairo, Egypt

..... 1336

**T3P.085 PLASMA ENHANCED BONDING OF POLYDIMETHYLSILOXANE (PDMS) WITH PARYLENE**

P. Rezai, P. R. Selvaganapathy\* and G. R. Wohl

*Department of Mechanical Engineering, McMaster University, Hamilton, ON, CANADA*

..... 1340

**T3P.086 SILICON RETAINER RING INTEGRATION IN MICRO-TURBINE WITH THRUST BALL BEARING SUPPORT MECHANISM**

R. J. Hergert<sup>1,2</sup>, B. Hanrahan<sup>2,3</sup>, A. S. Holmes<sup>1</sup>, and R. Ghodssi<sup>2</sup>

<sup>1</sup>Optical and Semiconductor Devices Group, Department of Electrical and Electronics Engineering, Imperial College London, UK

<sup>2</sup>MEMS Sensors and Actuators Laboratory, Department of Electrical and Computer Engineering, Institute for Systems Research, University of Maryland College Park, MD, USA

<sup>3</sup>The US Army Research Laboratory, Adelphi, MD, USA

..... 1344

**T3P.087 TRANSFER TECHNOLOGY OF PYROLYZED**

**POLYMER ONTO LOW THERMAL TOLERANCE SUBSTRATE**

T. Kobayashi, A. Akazawa, Y. Furuno, W. Tonomura and S. Konishi

*Ritsumeikan University, Kusatsu, Shiga, JAPAN*

..... 1348

**T3P.088 NOVEL POST-PROCESS GAP REDUCTION TECHNOLOGY OF HIGH ASPECT RATIO MICROSTRUCTURES UTILIZING MICRO WELDING**

M. Nowack<sup>1</sup>, S. Leidich<sup>2</sup>, D. Reuter<sup>1,2</sup>, S. Kurth<sup>2</sup>, M. Kuchler<sup>2</sup>, A. Bertz<sup>1,2</sup> and T. Gessner<sup>1,2</sup>

<sup>1</sup>Chemnitz University of Technology, Center for Microtechnologies, Chemnitz, Germany

<sup>2</sup>Fraunhofer Institute for Electronic Nano Systems, Chemnitz, Germany

..... 1352

**T3P.089 INKJET PRINTING ON PAPER FOR THE REALIZATION OF HUMIDITY AND TEMPERATURE SENSORS**

J. Courbat, Y.B. Kim, D. Briand, and N.F. de Rooij

*Ecole Polytechnique Fédérale de Lausanne (EPFL), Institute of Microengineering (IMT), Sensors, Actuators and Microsystems Laboratory (SAMLAB), Neuchâtel, Switzerland*

..... 1356

**T3P.090 ROOM-TEMPERATURE WAFER-LEVEL VACUUM SEALING BY COMPRESSION OF HIGH-SPEED WIRE BONDED GOLD BUMPS**

M. Antelius, A. C. Fischer, N. Roxhed, G. Stemme and F. Niklaus

*KTH Royal Institute of Technology, Stockholm, SWEDEN*

..... 1360

**T3P.091 A STUDY OF SURFACE DIFFUSION OF METALS IN TUNGSTEN FOR NEMS APPLICATIONS**

Karumbaiah N.Chappanda, Abhishek Mathur<sup>1</sup> and Massood Tabib-Azar<sup>1,2</sup>

<sup>1</sup>Department of electrical and computer engineering

<sup>2</sup>Department of bioengineering, University of Utah, Salt Lake City, Utah, USA

..... 1364

**T3P.092 CRACK PROPAGATION DIRECTION CONTROL FOR CRACK-LESS SOLDER BONDING USING AL/NI FLASH HEATING TECHNIQUE**

T. Namazu<sup>1,2</sup>, K. Ohtani<sup>1</sup>, K. Yoshiki<sup>1</sup>, and S. Inoue<sup>1</sup>

<sup>1</sup>Department of Mechanical and Systems Engineering, University of Hyogo, Himeji, Japan

<sup>2</sup>JST PRESTO, Japan Science and Technology Agency, Saitama, Japan

..... 1368

**T3P.093 DISPENSE AND SELF-PLANARIZATION PROCESS ON A MODIFIED SURFACE FOR MULTIPLE HEIGHT 3-D MICROFABRICATION**

Jungkwun 'J.K.' Kim<sup>1, 2</sup>, Pitfee Jao<sup>2</sup>, Cheolbok Kim<sup>2</sup>, and Yong-Kyu 'YK' Yoon<sup>1, 2</sup>

<sup>1</sup>State University of New York at Buffalo, Buffalo, NY,

USA

<sup>2</sup>University of Florida, Gainesville, FL, USA

..... 1372

**T3P.094 INFLUENCE OF THERMAL TREATMENT ON MECHANICAL CHARACTERISTICS OF AL-SI-CU THIN FILMS EVALUATED BY BIAXIAL TENSILE TESTING**

M. Fujii<sup>1</sup>, T. Namazu<sup>1,2</sup>, K. Yoshiki<sup>1</sup>, and S. Inoue<sup>1</sup>

<sup>1</sup>Department of Mechanical and Systems Engineering, University of Hyogo, JAPAN

<sup>2</sup>JST PRESTO, Japan Science and Technology Agency, Saitama, Japan

..... 1376

**T3P.095 REFINED SI-CMOS-MEMS PROCESS USING AOE, DRIE AND PREFORM BONDING**

Y.-J. Fang<sup>1</sup>, T. Mukherjee<sup>1</sup>, and G.K. Fedder<sup>1,2,3</sup>

<sup>1</sup>Department of Electrical and Computer Engineering,

<sup>2</sup>The Robotics Institute,

<sup>3</sup>Institute for Complex Engineered Systems, Carnegie Mellon University, Pittsburgh, PA, USA 15213

..... 1380

**T3P.096 LOW-TEMPERATURE SEALING FOR OPTICAL MICROSYSTEM PACKAGES USING AU-AU SURFACE ACTIVATED BONDING IN ATMOSPHERIC PRESSURE ENVIRONMENT**

S. Yamamoto<sup>1</sup>, E. Higurashi<sup>2</sup>, T. Suga<sup>1</sup>, R. Sawada<sup>3</sup>

<sup>1</sup>Department of Precision Engineering, School of Engineering, The University of Tokyo, Tokyo, Japan

<sup>2</sup>Research Center for Advanced Science and Technology, The University of Tokyo, Tokyo, Japan

<sup>3</sup>Department of Mechanical Engineering, Faculty of Engineering, Kyushu University, Fukuoka, Japan

..... 1384

**T3P.097 EFFICIENT SOLUTION TO SELECTIVE WET ETCHING OF ULTRA-THICK COPPER SACRIFICIAL LAYER WITH HIGH SELECTIVE ETCHING RATIO**

Y.B. Wu<sup>1,2</sup>, G.F. Ding<sup>1\*</sup>, H. Wang<sup>1</sup> and C.C. Zhang<sup>1</sup>

<sup>1</sup>National Key Lab of Nano/Micro Fabrication Technology, Key Lab for Thin Film and Micro fabrication of the Ministry of Education, Institute of Micro and Nano Science and Technology, Shanghai Jiao Tong University, Shanghai, China

<sup>2</sup>Power Electronics Business Unit, Zhuzhou CSR Times Electric Co., Ltd., Zhuzhou, Hunan, China

..... 1388

**T3P.098 ELECTRODEPOSITION AND CHARACTERIZATION OF CONIMNP PERMANENT MAGNET ARRAYS FOR MEMS APPLICATIONS**

Xuming Sun<sup>1</sup>, Student Member IEEE, Quan Yuan<sup>1</sup>, Student Member IEEE, Dongming Fang<sup>2</sup>, Member IEEE, and Haixia Zhang<sup>1\*</sup>, Senior Member IEEE

<sup>1</sup>National Key Laboratory of Science and Technology on Micro/Nano Fabrication, Institute of Microelectronics, Peking University, Beijing 100871, China

<sup>2</sup>State Key Laboratory of Transducer Technology,

Institute of Electronics,

Chinese Academy of Sciences, Beijing 100190, China

..... 1392

**T3P.099 A POLYMER STACKING PROCESS WITH 3D ELECTRICAL ROUTINGS FOR FLEXIBLE TEMPERATURE SENSOR ARRAY AND ITS HETEROGENEOUS INTEGRATION**

Wang-Shen Su<sup>1</sup>, Chang-Hung Chen<sup>2</sup>, Chih-Chun Lee<sup>3</sup>, Yu-Cheng Lin<sup>4</sup>, and Weileun Fang<sup>1,2,3</sup>

<sup>1</sup>National Nano Device Laboratories, Hsinchu, Taiwan

<sup>2</sup>Power Mechanical Eng. Dept.,<sup>3</sup>NEMS Inst., National Tsing Hua Univ., Hsinchu, Taiwan

<sup>4</sup>Dept. of Engineering Science, National Cheng Kung Univ., Tainan, Taiwan

..... 1396

**T3P.100 THE SENSITIVITY OF STICTION PERFORMANCE TO SURFACE CHEMISTRY UNDER VARIOUS HUMIDITY REGIMES**

Firas Sammoura<sup>1,2,3</sup> and Ken Yang<sup>2</sup>

<sup>1</sup>Masdar Institute of Science and Technology, Abu Dhabi, UAE

<sup>2</sup>MEMS/Sensors Division, Analog Devices, Wilmington, MA 01887

<sup>3</sup>Technology and Development Program, Massachusetts Institute of Technology, Cambridge, MA02139

..... 1400

**Theory, Design and Test Methodology**

**T3P.101 DESIGN OF PRECISION LIGHT INTENSITY MODULATION FOR LIGHT-ADDRESSABLE POTENTIOMETRIC SENSOR**

W. Zhang, Y. Zhao, D. Ha, W. Cai and P. Wang  
Zhejiang University, Hangzhou, Zhejiang Province, CHINA

..... 1404

**T3P.102 THIN FILM THERMAL CONDUCTIVITY METROLOGY USING PHOTOLUMINESCENCE OF QUANTUM DOTS**

X. Liu<sup>\*</sup>, X.M. Wu, and T.L. Ren

<sup>1</sup>Institute of Microelectronics, Tsinghua University, Beijing 100084, China

<sup>2</sup>Tsinghua National Laboratory of Information Science and Technology, Tsinghua University, Beijing 100084, China

..... 1408

**T3P.103 A NOVEL STRESS ISOLATION GUARD RING DESIGN FOR THE IMPROVEMENT OF THREE-AXIS PIEZORESISTIVE ACCELEROMETER**

Hsieh-Shen Hsieh<sup>1,2</sup>, Heng-Chung Chang<sup>1,2</sup>, Chih-Fan Hu<sup>1</sup>, Chao-Lin Cheng<sup>1</sup>, Weileun Fang<sup>1</sup>

<sup>1</sup>Power Mech. Eng. Dept National Tsing Hua University, Hsinchu, Taiwan

<sup>2</sup>MEMS/MST R&D Department, Research Center, Delta Electronics, Inc., Taoyuan, Taiwan

..... 1412

**T3P.104 MODELING OF THE ELASTIC MODULUS OF CRYSTALLINE SILICON BASED ON A LATTICE**

## DYNAMICS APPROACH

Weiwei Zhang, Hong Yu, and Qing-An Huang\*  
Key Laboratory of MEMS of Ministry of Education,  
Southeast University,  
Nanjing 210096, CHINA  
.....1416

- T3P.105 ASSESSING POLYMER SORPTION KINETICS USING MICROMACHINED RESONATORS**  
J.-J. Su<sup>1</sup>, C. Carron<sup>1</sup>, S. Truax<sup>1</sup>, K.S. Demirci<sup>1,2</sup>,  
L.A. Beardslee<sup>1</sup>, O. Brand<sup>1</sup>  
<sup>1</sup>School of Electrical and Computer Engineering,  
Georgia Institute of Technology, Atlanta GA, USA  
<sup>2</sup>currently at: Texas Instruments Inc., Dallas, TX, USA  
.....1420

- T3P.106 NONLINEAR AIR DRAG DAMPING OF TORSIONAL MICROSCANNERS**  
W. O. Davis  
MicroVision, Inc., Redmond, WA, USA  
.....1424

- T3P.107 MICROFLUIDIC FLOW METER AND VISCOMETER UTILIZING FLOW-INDUCED VIBRATION ON AN OPTIC FIBER CANTILEVER**  
Po-Yau Ju<sup>1</sup>, Chien-Hsiung Tsai<sup>2</sup>, Lung-Ming Fu<sup>2</sup>  
and Che-Hsin Lin<sup>1,\*</sup>  
<sup>1</sup>National Sun Yat-sen University, Kaohsiung, Taiwan  
<sup>2</sup>National Pingtung University of Science and Technology,  
Pingtung, Taiwan  
.....1428

- T3P.108 EFFECT OF LOADING RATES ON POLYMER MICROPILLAR BASED FORCE TRANSDUCERS**  
Ping Du, Xiaoyu Zheng, I-Kuan Lin, and Xin Zhang  
Department of Mechanical Engineering, Boston University, Boston, MA, USA  
.....1432

- T3P.109 DESIGN AND EXPERIMENTS OF A NANO-OPTO-MECHANICAL SWITCH USING EIT-LIKE EFFECTS OF COUPLED-RING RESONATOR**  
M. Ren<sup>1,2</sup>, Y. F. Yu<sup>1</sup>, J. M. Tsai<sup>2</sup>, H. Cai<sup>2</sup>, W. M. Zhu<sup>1</sup>, D. L. Kwong<sup>2</sup> and A. Q. Liu<sup>1</sup>  
<sup>1</sup>School of Electrical & Electronic Engineering,  
Nanyang Technological University, Singapore 639798  
<sup>2</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research) 11 Science Park Road, Singapore Science Park II, Singapore 117685  
.....1436

- T3P.110 A NOVEL, SIMPLE, AND Q-INDEPENDENT SELF OSCILLATION LOOP DESIGNED FOR VIBRATORY MEMS GYROSCOPES**  
B. Eminoglu<sup>1</sup>, S.E. Alper<sup>2</sup>, and T. Akin<sup>1,2</sup>  
<sup>1</sup>Middle East Technical University, Department of Electrical and Electronics Eng., Ankara, TURKEY  
<sup>2</sup>METU-MEMS Research and Application Center, Ankara, TURKEY  
.....1440

## Actuators

- T3P.111 WALKING OF A MAGNETICALLY BIPEDAL MICROROBOT**  
T.D. Chiang<sup>1</sup>, C.F. Fong<sup>1</sup>, G.L. Jiang<sup>1</sup>, C.W. Hong<sup>1</sup>,  
H.C. Liu<sup>2</sup> and M.T. Hou<sup>1,\*</sup>  
<sup>1</sup>Department of Mechanical Engineering, National United University, Miaoli, Taiwan  
<sup>2</sup>Department of Mechanical Engineering, China University of Science and Technology, Taipei, Taiwan  
.....1444

- T3P.112 CONTROL OF THE RADIAL MOTION OF A SELF-PROPELLED MICROBOAT THROUGH A SIDE RUDDER**  
\*L. Qiao, D. Xiao, F.K. Lu and C. Luo  
Mechanical and Aerospace Engineering, University of Texas at Arlington, Arlington, TX, USA  
.....1448

- T3P.113 RAPID PROTOTYPING OF 3D MICROSTRUCTURES BY DIRECT PRINTING OF LIQUID METAL AT TEMPERATURES UP TO 500°C USING THE STARJET TECHNOLOGY**  
N. Lass<sup>1</sup>, A. Tropmann<sup>1</sup>, A. Ernst<sup>2</sup>, R. Zengerle<sup>1</sup> and P. Koltay<sup>1,2</sup>  
<sup>1</sup>Laboratory for MEMS Applications, IMTEK, University of Freiburg, Germany  
<sup>2</sup>BioFluidix GmbH, Georges Köhler Allee 106, 79110 Freiburg Germany  
.....1452

- T3P.114 CHARACTERIZATION OF THE 2ND GENERATION MAGNETIC MICROBEARING WITH INTEGRATED STABILIZATION FOR FRICTIONLESS DEVICES**  
V. Badilita\*, S. Rzesnik, K. Kratt, and U. Wallrabe  
Laboratory for Microactuators, Dept. of Microsystems Engineering – IMTEK, University of Freiburg, Germany  
.....1456

- T3P.115 MONODISPERSE MICROPARTICLE GENERATION FROM AQUEOUS SOLUTIONS**  
A. Tropmann<sup>1</sup>, N. Lass<sup>1</sup>, N. Paust<sup>2</sup>, C. Ziegler<sup>1</sup>, R. Zengerle<sup>1,2</sup> and P. Koltay<sup>1,3</sup>  
<sup>1</sup>Laboratory for MEMS Applications, IMTEK, University of Freiburg, Germany  
<sup>2</sup>HSG-IMIT – Institut fuer Mikro- und Informationstechnik, Villingen-Schwenningen, Germany  
<sup>3</sup>BioFluidix GmbH, Georges-Koehler-Allee 106, 79110 Freiburg, Germany  
.....1460

- T3P.116 INTEGRATED THIN-FILM PIEZOELECTRIC TRAVELING WAVE ULTRASONIC MOTORS**  
G. L. Smith<sup>1</sup>, R. Q. Rudy<sup>1,2</sup>, D. L. DeVoe<sup>2</sup>, and R. G. Polcawich<sup>1</sup>  
<sup>1</sup>U.S. Army Research Laboratory, Adelphi, MD, USA  
<sup>2</sup>University of Maryland, College Park, USA  
.....1464

- T3P.117 A NANO-OPTO-MECHANICAL ACTUATOR DRIVEN BY OPTICAL RADIATION FORCE**  
X. Zhao<sup>1,2,3</sup>, J. M. Tsai<sup>3</sup>, H. Cai<sup>3</sup>, X. M. Ji<sup>2</sup>, J. Zhou<sup>2</sup>,  
M. H. Bao<sup>2</sup>, Y. P. Huang<sup>2</sup>, D. L. Kwang<sup>3</sup> and A.

Q.Liu<sup>1</sup>  
<sup>1</sup>School of Electrical & Electronic Engineering,  
 Nanyang Technological University, Singapore 639798  
<sup>2</sup>School of Information Science and Technology, Fudan  
 University, Shanghai 200433, China  
<sup>3</sup>Institute of Microelectronics, A\*STAR (Agency for  
 Science, Technology and Research)  
 .....1468

**T3P.118 DISPOSABLE MICROFLUIDIC VACUUM MODULES  
 USING INDUCTIVELY-TRIGGERED  
 TRANSFORMATIVE POLYMERS FOR  
 POINT-OF-CARE DIAGNOSTICS**

Chien-Chong Hong<sup>1</sup>, Cheng-Han Tsai<sup>1</sup>, Szu-Ying  
 Chen<sup>1</sup> and Chie-Pein Chen<sup>2</sup>  
<sup>1</sup>BioMEMS and NanoBiosystems Lab, Department of  
 Power Mechanical Engineering, National Tsing Hua  
 University, Hsinchu, Taiwan  
<sup>2</sup>Department of Obstetrics and Gynecology, Mackay  
 Memorial Hospital, Taipei, Taiwan  
 .....1472

**T3P.119 A HYBRID VERTICAL COMB-DRIVE ACTUATOR  
 SUPPORTED BY FLEXIBLE PDMS SUSPENSIONS**

M. Lee<sup>1</sup>, Y.-C. Chen<sup>2</sup>, C. Chang<sup>1</sup>, M. Hou<sup>3</sup> and  
 R.Chen<sup>1,2</sup>  
<sup>1</sup>Institute of NanoEngineering and MicroSystems,  
 National Tsing Hua University, Hsinchu, Taiwan  
<sup>2</sup>Department of Power Mechanical Engineering  
 National Tsing Hua University, Hsinchu, Taiwan  
<sup>3</sup>Department of Mechanical Engineering, National  
 United University, Miaoli, Taiwan  
 .....1476

**T3P.120 SILICON LINKAGE WITH NOVEL COMPLIANT  
 MECHANISM FOR PIEZOELECTRIC ACTUATION  
 OF AN INTRAOCULAR IMPLANT**

Th. Martin<sup>1</sup>, U. Gengenbach<sup>1</sup>, P. Ruther<sup>2</sup>, O. Paul<sup>2</sup>,  
 G. Brethauer<sup>1</sup>  
<sup>1</sup>Karlsruhe Institute of Technology, Institute for Applied  
 Computer Science, Germany  
<sup>2</sup>Department of Microsystems Engineering (IMTEK),  
 University of Freiburg, Germany  
 .....1480

**T3P.121 THERMALLY-ACTUATED HIGH SPEED DROPLET  
 MANIPULATION PLATFORM**

E. Yakhshi-Tafti, R. Kumar, and H. J. Cho  
 Department of Mechanical, Materials and Aerospace  
 Engineering, University of Central Florida Orlando,  
 Florida, USA  
 .....1484

**RF MEMS, Resonators, and Oscillators**

**T3P.122 WIDEBAND TUNABLE LOVE WAVE FILTER USING  
 ELECTROSTATICALLY-ACTUATED MEMS  
 VARIABLE CAPACITORS INTEGRATED ON  
 LITHIUM NIOBATE**

T. Yasue<sup>1</sup>, T. Komatsu<sup>2</sup>, N. Nakamura<sup>2</sup>, K.  
 Hashimoto<sup>2</sup>, H. Hirano<sup>1</sup>, M. Esashi<sup>1</sup> and S.  
 Tanaka<sup>1\*</sup>

<sup>1</sup>Tohoku University, Sendai, JAPAN  
<sup>2</sup>Chiba University, Chiba, JAPAN

.....1488

**T3P.123 SYNCHRONIZED OSCILLATION IN MICRO  
 MECHANICALLY COUPLED OPPOSITE C-SHAPED  
 CANTILEVER-BASED OSCILLATOR SYSTEM**

Mamoru Nakajima<sup>1</sup>, Dong F. Wang<sup>1</sup>, Tsuyoshi  
 Ikehara<sup>2</sup>, and Ryutaro Maeda<sup>2</sup>  
<sup>1</sup>Micro Engineering & Micro Systems Laboratory,  
 Ibaraki University (College of Eng.), Hitachi, Japan  
<sup>2</sup>Ubiquitous MEMS & Micro Engineering Research  
 Center (UMEMSME), AIST, Tsukuba, Japan  
 .....1492

**T3P.124 PIEZOELECTRIC MICRO-SCALE TUNING FORK  
 RESONATORS FOR SENSING APPLICATIONS**

M. Gil<sup>1</sup>, T. Manzaneque<sup>1</sup>, J. Hernando-García<sup>1</sup>, A.  
 Ababneh<sup>2</sup>, H. Seidel<sup>3</sup>, J. L. Sánchez-Rojas<sup>1</sup>  
<sup>1</sup>Dpto. de Ingeniería Eléctrica, Electrónica,  
 Automática y Comunicaciones, ETSI Industriales,  
 Campus Universitario UCLM, 13071 Ciudad Real,  
 Spain.  
<sup>2</sup>Yarmouk University, Electronic Engineering  
 Department, Hijawi Faculty for Engineering  
 Technology, Jordan.  
<sup>3</sup>Chair of Micromechanics,  
 Microfluidics/Microactuators,  
 Faculty of Natural Sciences and Technology II,  
 Saarland University, D-66123 Saarbrücken, Germany  
 .....1496

**T3P.125 CMOS-MEMS TRANSVERSE-MODE SQUARE  
 PLATE RESONATOR WITH HIGH Q AND LOW  
 MOTIONAL IMPEDANCE**

Ming-Huang Li<sup>1</sup>, Wen-Chien Chen<sup>2</sup>, and  
 Sheng-Shian Li<sup>1,2</sup>  
<sup>1</sup>Inst. of NanoEngineering and MicroSystems, 2Dept. of  
 Power Mechanical Engineering  
 National Tsing Hua University, Hsinchu, Taiwan  
 .....1500

**T3P.126 A TUNABLE LASER USING DOUBLE-RING  
 RESONATOR EXTERNAL CAVITY VIA  
 FREE-CARRIER DISPERSION EFFECT**

M. Ren<sup>1,2</sup>, H. Cai<sup>2</sup>, J. M. Tsai<sup>2</sup>, W. M. Zhu<sup>1</sup>, D. L.  
 Kwong<sup>2</sup> and A. Q. Liu<sup>1</sup>  
<sup>1</sup>School of Electrical & Electronic Engineering,  
 Nanyang Technological University, SINGAPORE  
 639798  
<sup>2</sup>Institute of Microelectronics, A\*STAR (Agency for  
 Science, Technology and Research)  
 .....1504

**T3P.127 A DRY ETCHING METHOD USING  
 DOUBLE-LAYERED ETCHING MASK FOR  
 MODULATING SHAPE OF DEEP-ETCHED QUARTZ  
 SURFACE**

T. Abe<sup>1</sup>, Y. Itasaka<sup>2</sup>  
<sup>1</sup>Niigata University, Niigata, Japan  
<sup>2</sup>Tohoku University, Sendai, Japan  
 .....1508

**T3P.128 QUALITY FACTOR ENHANCEMENT IN LAMB**

**WAVE RESONATORS UTILIZING ALN PLATES WITH CONVEX EDGES**

Chih-Ming Lin<sup>1\*</sup>, Yun-Ju Lai<sup>1</sup>, Ting-Ta Yen<sup>1</sup>, Jin-Chen Hsu<sup>2</sup>, Yung-Yu Chen<sup>3</sup>, Debbie G. Senesky<sup>1</sup>, and Albert P. Pisano<sup>1</sup>

<sup>1</sup>Department of Mechanical Engineering, University of California, Berkeley, California, USA

<sup>2</sup>Department of Mechanical Engineering, National Yunlin University of Sci. & Tech., Yunlin, Taiwan

<sup>3</sup>Department of Mechanical Engineering, Tatung University, Taipei, Taiwan

..... 1512

**T3P.129 A STATE-CONVERTING INLINE RF MEMS POWER SENSOR USING GAAS MMIC TECHNOLOGY**

Zhiqiang Zhang, Xiaoping Liao<sup>\*</sup>, and Lei Han

Key Laboratory of MEMS of Ministry of Education, Southeast University, Nanjing 210096, China

..... 1516

**T3P.130 LATERALLY-EXCITED SILICON BULK ACOUSTIC RESONATORS WITH SIDEWALL ALN**

R. Tabrizian and F. Ayazi

School of Electrical and Computer Engineering, Georgia Institute of Technology, Atlanta, Georgia, USA

..... 1520

**Optical MEMS**

**T3P.131 A MONOLITHIC MEMS MICHELSON INTERFEROMETER FOR FTIR SPECTROSCOPY**

Jinhong Kim and Erik R. Deutsch

Block MEMS LLC, Marlborough, Massachusetts, United States

..... 1524

**T3P.132 A NOVEL VACUUM-PACKAGED LOW-POWER SCANNING MIRROR WITH INCLINED 3D-SHAPED WINDOW**

U. Hofmann, H.J. Quenzer, C. Eisermann, J. Janes, C. Schroeder, B. Jensen, J. Hagge, F. Soerensen, F. Senger, D. Vick, O. Schwarzelbach, L. Ratzmann, T. Giese, B. Wagner, W. Benecke

<sup>1</sup>Fraunhofer Institute for Silicon Technology ISIT, Itzehoe, GERMANY

..... 1527

**T3P.133 TUNABLE PHOTONIC CRYSTAL WITH 50 NANOMETER TUNING RANGE AND 100 MILLISECOND RESPONSE TIME**

C.T. Chan and J.A. Yeh

Institute of NanoEngineering and MicroSystems, National Tsing-Hua University, Hsinchu, Taiwan

..... 1531

**T3P.134 CAVITY OPTOMECHANICAL SENSORS**

H. Miao<sup>1, 2</sup>, K. Srinivasan<sup>1</sup>, M. T. Rakherl, M. Davanco<sup>1, 2</sup> and V. Aksyuk<sup>1</sup>

<sup>1</sup>Center for Nanoscale Science and Technology, National Institute of Standards and Technology, Gaithersburg, MD, USA

<sup>2</sup>Maryland Nanocenter, University of Maryland, College

Park, MD, USA

..... 1535

**T3P.135 AN APODIZED SURFACE GRATING COUPLER ENABLING THE FABRICATION OF SILICON PHOTONIC NANOWIRE SENSOR CIRCUITS IN ONE LITHOGRAPHY STEP**

K.B. Gylfason, M. Antelius, and H. Sohlström

Microsystem Technology Laboratory, KTH – Royal Institute of Technology, SWEDEN

..... 1539

**T3P.136 TRANSMISSIVE COLOR SHIFT THROUGH LAYERED SUB-WAVELENGTH GRATINGS BASED ON PLASMON ENHANCED COUPLING**

T. Lee<sup>1</sup>, A. Higo<sup>1</sup>, H. Fujita<sup>2</sup>, Y. Nakano<sup>1</sup>, and H. Toshiyoshi<sup>1, 2</sup>

<sup>1</sup>Research Center for Advanced Science and Technology, The University of Tokyo, Tokyo, JAPAN

<sup>2</sup>Institute of Industrial Science, The University of Tokyo, Tokyo, JAPAN

..... 1542

**T3P.137 INTEGRATED TRACKING AND FOCUSING MICRO LENS ACTUATORS BASED ON SILICON BULK MICROMACHINING**

P. Li<sup>1, 2\*</sup>, T. Sasaki<sup>1</sup>, L.F. Pan<sup>2</sup>, and K. Hane<sup>1</sup>

<sup>1</sup>Department of Nanomechanics, Tohoku University, Sendai, Japan

<sup>2</sup>Department of Precision Instruments and Mechanology, Tsinghua University, Beijing, China

..... 1546

**T3P.138 BISTABLE OPTOFLUIDIC ATTENUATOR WITH INTEGRATED ELECTROWETTING ACTUATION AND HIGH DYNAMIC RANGE**

P. Müller, A. Kloss, W. Mönch, and H. Zappe

Department of Microsystems Engineering – IMTEK, University of Freiburg, Freiburg, GER

..... 1550

**T3P.139 LOW POWER PECVD SIC DELAY LINES FOR OPTICAL COHERENCE TOMOGRAPHY IN THE VISIBLE**

G. Pandraud<sup>1\*</sup>, L. Mele<sup>1</sup>, B. Morana<sup>1</sup>, E. Margallo-Balbás<sup>2</sup>, P.J. French<sup>3</sup> and P.M. Sarro<sup>1</sup>

<sup>1</sup>DIMES-ECTM, Delft University of Technology, Delft, The Netherlands

<sup>2</sup>Medlumics S.I., Madrid, Spain

<sup>3</sup>DIMES-EI, Delft University of Technology, Delft, The Netherlands

..... 1554

**T3P.140 ADAPTIVE PIEZOELECTRIC AXICON MIRRORS FOR HIGH POWER FEMTOSECOND LASER APPLICATIONS**

J. Brunne<sup>1</sup>, R. Grunwald<sup>2</sup> and U. Wallrabe<sup>1</sup>

<sup>1</sup>University of Freiburg - IMTEK, Department of Microsystems Engineering, Laboratory for Microactuators, Freiburg, Germany

<sup>2</sup>Max Born Institute for Nonlinear Optics and Short Pulse Spectroscopy, Berlin, Germany

..... 1558

**T3P.141 TEMPORAL MODULATION OF X-RAYS USING**

**MEMS MICROMIRRORS DEEPKISHORE**

Mukhopadhyay<sup>1</sup>, Donald Walko<sup>2</sup>, Il Woong Jung<sup>1</sup>,  
Jin Wang<sup>2</sup>, Gopal Shenoy<sup>2</sup> and Danie<sup>1</sup> López<sup>1</sup>

<sup>1</sup>Center for Nanoscale Materials, Argonne National  
Laboratory, Argonne, IL, USA

<sup>2</sup>Advanced Photon Source, Argonne National  
Laboratory, Argonne, IL, USA

.....1562

**T3P.142 MULTIFUNCTIONAL OPTICAL MEMS SENSOR  
PLATFORM FOR WIRELESS OPTICAL SENSOR  
NETWORKS**

C. Pang<sup>1</sup>, M. Yu<sup>1\*</sup>, X.M. Zhang<sup>2</sup>, A.K. Gupta<sup>1</sup>,  
and K.M. Bryden<sup>3</sup>

<sup>1</sup>Department of Mechanical Engineering, University of  
Maryland, College Park, USA

<sup>2</sup>Department of Applied Physics, Hong Kong Polytechnic  
University, Hong Kong, China

<sup>3</sup>Department of Mechanical Engineering, Iowa State  
University, Ames, USA

.....1566

**T3P.143 1-D ELECTRO-OPTIC BEAM STEERING DEVICE**

Wei-Chih Wang<sup>1,2</sup>, Chi Leung Tsui<sup>1</sup>, and Menglu  
Wu<sup>1</sup>

<sup>1</sup>Department of Mechanical Engineering,

<sup>2</sup>Department of Electrical Engineering, University of  
Washington, Seattle, WA, 98195, USA

.....1570

**T3P.144 DESIGN AND FABRICATION OF MECHANICAL  
RESONANCE BASED SCANNING ENDOSCOPE**

K. Gu<sup>1</sup>, C.-C. Lee<sup>3</sup>, W. Cui<sup>1</sup>, M. Wu and W.-C.  
Wang<sup>1,2\*</sup>

<sup>1</sup>Department of Mechanical Engineering, University of  
Washington, Seattle, Washington, USA

<sup>2</sup>Department of Electrical Engineering, University of  
Washington, Seattle, Washington, USA

<sup>3</sup>School of Science and Engineering, Teesside University,  
Middlesbrough, UK

.....1574

**T3P.145 SILICON BULKMICROMACHINED  
PIEZOELECTRICALLY ACTUATED CORNER CUBE  
RETROREFLECTOR**

J.C. Park<sup>1</sup>, J.Y. Park<sup>1</sup>, J. Y. Won<sup>2</sup>, D.H. Kim<sup>2</sup>, and  
J. Park<sup>1</sup>

<sup>1</sup>Department of Electronic Engineering, Kwangwoon  
University, Seoul, Korea

<sup>2</sup>Program for Nanomedical Science and Technology,  
Yonsei University, Seoul, Korea

.....1578

**T3P.146 A MICRO CAMERA UTILIZING A MICROLENS  
ARRAY FOR MULTIPLE VIEWPOINT IMAGING**

B. Aldalalil<sup>1</sup>, C. Li<sup>1</sup>, L. Zhang<sup>2,3</sup>, and H. Jiang<sup>1,3</sup>

<sup>1</sup>Department of Electrical and Computer Engineering,  
University of Wisconsin-Madison, Madison, WI,  
USA

<sup>2</sup>Department of Computer Science, University of  
Wisconsin-Madison, Madison, WI, USA

<sup>3</sup>Eye Research Institute, University of  
Wisconsin-Madison, WI, USA

.....1582

**T3P.147 INDIRECT WAVELENGTH SELECTIVE INFRARED  
EMITTER USING SURFACE PLASMON  
POLARITON**

K. Masuno<sup>1</sup>, T. Sawada<sup>1</sup>, S. Kumagai<sup>1</sup>, and M.  
Sasaki<sup>1</sup>

<sup>1</sup>Toyota Technological Institute, Nagoya, Aichi, Japan

.....1586

**Nanoscale Materials And Fabrication,  
Devices and Systems**

**T3P.148 IC COMPATIBLE TOP DOWN PROCESS FOR  
SILICON NANOWIRE FET ARRAYS WITH THREE  
{100} SURFACES FOR (BIO) CHEMICAL SENSING**

T.S.Y. Moh<sup>1, 2</sup>, Y. Maruyama<sup>3</sup>, C. Shen<sup>1</sup>, G.  
Pandraud<sup>1</sup>, L.C.P.M. de Smet<sup>2</sup>, H.D. Tong<sup>4</sup>, C. van  
Rijn<sup>4</sup>, E.J.R. Sudhölter<sup>2</sup> and P.M. Sarro<sup>1</sup>

Delft University of Technology, The Netherlands.

<sup>1</sup>Delft Institute of Microsystems and Nanoelectronics,

<sup>2</sup>Department of Chemical Engineering, Nano Organic  
Chemistry,

<sup>3</sup>Circuits and Systems,

<sup>4</sup>Nanosens, The Netherlands

.....1590

**T3P.149 LIGHT-ACTUATED CNT-DOPED ELASTOMER  
BLISTERS TOWARDS BRAILLE DOTS**

C.J. Camargo<sup>1\*</sup>, N. Torras<sup>1</sup>, H. Campanella<sup>1</sup>, J.E.  
Comrie<sup>2</sup>, E.M. Campo<sup>3</sup>, K. Zinoviev<sup>1</sup>, E.M.  
Terentjev<sup>2</sup> and J.Esteve<sup>1</sup>

<sup>1</sup>Instituto de Microelectrónica de Barcelona IMB-CNM  
(CSIC), Bellaterra, Barcelona, SPAIN

<sup>2</sup>Cavendish Laboratory, University of Cambridge,  
Cambridge CB3 0HE, UK

<sup>3</sup>Laboratory for Research on the Structure of Matter,  
University of Pennsylvania, Philadelphia PA, USA

.....1594

**T3P.150 CHEMORESISTIVITY OF SOLID STATE LAYERS  
OF PORPHYRIN NANOTUBES**

E. Martinelli<sup>1</sup>, F. Dini<sup>1</sup>, D. Monti<sup>2</sup>, G. Pomarico<sup>2</sup>,  
R. Paolesse<sup>2,3</sup>, C. Di Natale<sup>1,3</sup>

<sup>1</sup>Department of Electronic Engineering, University of  
Rome Tor Vergata, Rome, Italy

<sup>2</sup>Department of Chemical Science and Technology,  
University of Rome Tor Vergata, Rome, Italy

<sup>3</sup>CNR – IDASC, Rome, Italy

.....1598

**T3P.151 MAGNETORESISTANCE BEHAVIORS OF  
UNDOPED AND N-DOPED GRAPHENE GROWN BY  
CVD METHOD**

W.R. Wang<sup>1,3</sup>, Y.X. Zhou<sup>1,3</sup>, T. Li<sup>1\*</sup>, M.F. Wang<sup>2</sup>,  
X.M. Xie<sup>2</sup>, Y.L. Wang<sup>1</sup>

<sup>1</sup>State Key Laboratories of Transducer Technology,  
Science and Technology on Microsystem Laboratory,

<sup>2</sup>State Key Laboratory of Functional Materials for  
Informatics, Shanghai Institute of Microsystem and  
Information Technology, Chinese Academy of Science,  
Shanghai, China

<sup>3</sup>Graduate School of Chinese Academy of Sciences, Beijing, China

..... 1602

**T3P.152 DIAGNOSTIC OF MICROPLASMA REACTOR FOR SCANNING PLASMA ETCHING**

H. Wang<sup>1,2</sup>, Y.H. Tong<sup>1,2</sup>, L. Wen<sup>3</sup> and Z. Li<sup>1,2</sup>

<sup>1</sup>School of Mechanical and Automotive Engineering, Anhui Polytechnic University, Wuhu, Anhui, China

<sup>2</sup>Anhui Key Laboratory of Advanced Numerical Control & Servo Technology, Wuhu, Anhui, China

<sup>3</sup>Department of Precision Machinery and Precision Instrumentation, University of Science and Technology of China, Hefei, China

..... 1606

**T3P.153 ELECTROSTATIC GATING OF ION AND MOLECULE TRANSPORT THROUGH A NANOCHANNEL-ARRAY MEMBRANE**

\*G. Pardon and W. van der Wijngaart

Microsystem Technology Lab, KTH Royal Institute of Technology, Stockholm, SWEDEN

..... 1610

**T3P.154 FUNCTIONALIZATION OF CERAMIC LIPOSOMAL NANOPARTICLES, CERASOMES, WITH ANTIBODIES**

M.T. Stamm<sup>1</sup>, Z. Zha<sup>1,2</sup>, L. Jiang<sup>1</sup>, Z. Dai<sup>2</sup>, and Y. Zohar<sup>1</sup>

<sup>1</sup>The University of Arizona, Tucson, Arizona, USA

<sup>2</sup>Harbin Institute of Technology, Harbin, China

..... 1614

**T3P.155 3D MICROELECTRODE BASED ON INTEGRATED MICRO AND NANO ARCHITECTURES**

J.Z. Sun<sup>1</sup>, Y. Li<sup>1,2</sup>, C. Bian<sup>1</sup>, J.H. Tong<sup>1</sup>, H.P. Dong<sup>1</sup>, H. Zhang<sup>1</sup>, Q.Y. Chen<sup>1,2</sup>, S.H. Xia<sup>1</sup>

<sup>1</sup>State Key Laboratory of Transducer Technology, Institute of Electronics, Chinese Academy of Sciences, Beijing, China

<sup>2</sup>Graduate University of Chinese Academy of Sciences, Beijing, China

..... 1618

**T3P.156 FABRICATION OF PLASMA PROBE FOR CHEMICAL VAPOR DEPOSITION**

Wen Yuan, Karumbaiah H. Chappanda and Massood Tabib-Azar

University of Utah, Salt Lake City, UT, USA

..... 1622

**T3P.157 PLASTIC DEFORMATION OF MICROSTRUCTURES USING CARBON NANOTUBES FILM AS LATCHING SURFACE**

Y. Eun, J.-I. Lee, J. Choi, Y. Song and J. Kim\*

School of Mechanical Engineering, Yonsei University, Seoul, KOREA

..... 1626

**T3P.158 FABRICATION OF 3-D HYBRID POLYMER-MAGNETITE NANOSTRUCTURES WITH GEOMETRIC SHAPE ANISOTROPY**

Z. Liu<sup>1</sup>, F. Herrault<sup>2</sup>, S.-H. Kim<sup>2</sup>, D. G. Bucknall<sup>1</sup> and M. G. Allen<sup>2</sup>

<sup>1</sup>School of Materials Science and Engineering, Georgia

Institute of Technology, GA, USA, 30332

<sup>2</sup>School of Electrical and Computer Engineering, Georgia Institute of Technology, GA, USA, 30332

..... 1630

**T3P.159 NANO-PHOTONIC DISPLACEMENT SENSING MECHANISM**

Hongbin Yu<sup>1,2</sup>, Guangya Zhou<sup>1</sup>, Xiongyue Chew<sup>1</sup>, Sujeet K. Sinha<sup>2</sup>, and Fook Siong Chau<sup>1</sup>

<sup>1</sup>Micro/Nano Systems Initiative, Department of Mechanical Engineering, National University of Singapore, Singapore

<sup>2</sup>Material laboratory, Department of Mechanical Engineering, National University of Singapore, Singapore

..... 1634

**T3P.160 2D PHOTONIC CRYSTAL TM POLARIZER FABRICATED BY ONE-STEP COMBINED NANOIMPRINT AND PHOTOLITHOGRAPHY**

K.-H. Choi<sup>1\*</sup>, J. Huh<sup>2\*</sup>, Y. Cui<sup>1</sup>, B.-K. Ju<sup>2</sup>, W. Hu<sup>1</sup>, and J.-B. Lee<sup>1</sup>

<sup>1</sup>The University of Texas at Dallas, Richardson, Texas, U.S.A.

<sup>2</sup>Korea University, Seoul, Republic of Korea

\*These authors contributed equally to this work

..... 1638

## Energy and Power MEMS

**T3P.161 BIOCOMPATIBLE ALN-BASED PIEZO ENERGY HARVESTERS FOR IMPLANTS**

N. Heidrich<sup>1,2</sup>, F. Knöbber<sup>1,2</sup>, R.E. Sah<sup>1</sup>, W. Pletschen<sup>1</sup>, S. Hampl<sup>3</sup>, V. Cimalla<sup>1</sup>, and V. Lebedev<sup>1</sup>

<sup>1</sup>Fraunhofer Institute for Applied Solid State Physics, Freiburg, Germany

<sup>2</sup>IMTEK, University of Freiburg, Freiburg, Germany

<sup>3</sup>IMN MacroNano®, Ilmenau University of Technology, Ilmenau, Germany

..... 1642

**T3P.162 PHOTOVOLTAICALLY RECHARGEABLE FUEL CELL ACCUMULATOR FOR ENERGY SELF-SUFFICIENT MICROSYSTEMS**

D. Hertkorn<sup>1</sup>, C. Bretthauer<sup>1</sup>, F. Bükler<sup>1</sup>, B. Herr<sup>1</sup>, M. Müller<sup>1</sup>, F. Paul<sup>2</sup>, C. Müller<sup>1</sup>, J. Haußelt<sup>2</sup>, H. Reinecke<sup>1</sup>

Laboratory for Process Technology<sup>1</sup> and Laboratory for Materials Process Technology<sup>2</sup>, Department of Microsystems Engineering- IMTEK, University of Freiburg, GERMANY

..... 1645

**T3P.163 THINNED-PZT ON SOI PROCESS AND DESIGN OPTIMIZATION FOR PIEZOELECTRIC INERTIAL ENERGY HARVESTING**

Ethem Erkan Aktakka, Rebecca L. Peterson, and Khalil Najafi

Center for Wireless Integrated Microsystems (WIMS) University of Michigan, Ann Arbor, MI, USA

- ..... 1649
- T3P.164 HIGHLY SCALABLE AND SENSITIVE BROADBAND 1HZ ~ 1KHZ VIBRATED ENERGY HARVESTER WITH NOVEL SELF-ALTERNATION MAGNETIC-FLUX AND 3D COILS**  
 Y. S. Lai<sup>1</sup>, M. Q. Wei<sup>2</sup>, H. C. Lin<sup>1</sup>, Y. J. Cheng<sup>2</sup>, Y. B. Lin<sup>3</sup>, and C. H. Ho<sup>1</sup>  
<sup>1</sup>National Nano Device Laboratories, Hsinchu, Taiwan  
<sup>2</sup>National Chi Nan University, Nantou, Taiwan  
<sup>3</sup>National Center for Research on Earthquake Engineering, Taipei, Taiwan  
 ..... 1653
- T3P.165 MICROELECTROMAGNETIC ENERGY HARVESTER WITH INTEGRATED MAGNETS**  
 Q. Zhang<sup>1</sup>, S.J. Chen<sup>1</sup>, L. Baumgartel<sup>2</sup>, A. Lin<sup>1</sup> and E.S. Kim<sup>1</sup>  
<sup>1</sup>Department of Electrical Engineering, University of Southern California, Los Angeles, USA  
<sup>2</sup>Department of Physics, University of Southern California, Los Angeles, USA  
 ..... 1657
- T3P.166 HARVESTING TRAFFIC-INDUCED BRIDGE VIBRATIONS**  
 T. Galchev, J. McCullagh, R. L. Peterson, and K. Najafi  
 Center for Wireless Integrated Microsystems (WIMS)  
 University of Michigan, Ann Arbor, Michigan  
 48109-2122, USA  
 ..... 1661
- T3P.167 A MICRO INITIATOR REALIZED BY REACTIVE NI/AL NANOLAMINATES FOR MEMS APPLICATIONS**  
 X. Qiu<sup>1</sup>, R. Tang<sup>1</sup>, R. Liu<sup>2</sup>, S. Guo<sup>2</sup>, H. Yu<sup>1</sup>, <sup>3\*</sup>  
<sup>1</sup>School of Electrical, Computer and Energy Engineering, Arizona State University, Tempe, AZ 85287  
<sup>2</sup>Department of Mechanical Engineering, Louisiana State University, Baton Rouge, LA 70803  
<sup>3</sup>School of Earth and Space Exploration, Arizona State University, Tempe, AZ 85287  
 ..... 1665
- T3P.168 STUDY OF VIBRATION-INDUCED BROADBAND FLEXIBLE PIEZOELECTRIC ZNO MICRO-HARVESTER WITH STORAGE SYSTEM**  
 C.T. Pan<sup>1</sup>, Z.H. Liu<sup>1</sup>, Y.C. Chen<sup>2</sup>, W.T. Chang<sup>2</sup>, and Y.J. Chen<sup>1</sup>  
<sup>1</sup>Department of Mechanical and Electro-Mechanical Engineering, and Center for Nanoscience & Nanotechnology, National Science Council Core Facilities Laboratory for Nano-Science and Nano-Technology in Kaohsiung-Pingtung area, National Sun Yat-Sen University, Kaohsiung 804, Taiwan  
<sup>2</sup>Department of Electrical Engineering, National Sun Yat-Sen University, Kaohsiung 804, Taiwan  
 ..... 1669
- T3P.169 LIQUID-ENCAPSULATED ENERGY HARVESTER FOR LOW FREQUENCY VIBRATIONS**  
 L. Bu, X.M. Wu<sup>\*</sup>, X.H. Wang, and L.T. Liu  
 Institute of Microelectronics, Tsinghua University,

Beijing, China Tsinghua National Laboratory for Information Science and Technology, Beijing, China  
 ..... 1673

**ORAL SESSIONS** 16:15 - 18:00

**SESSION IV(1) –Acoustics, Damping and Vibration**

- T4A.001 SELF-POWERED HIGH SIGNAL-TO-NOISE RATIO ACOUSTIC EMISSION SENSOR AND ITS DEMONSTRATION ON DETECTING DYNAMIC FRICTION VARIATION**  
 Guo-Hua Feng<sup>\*</sup> and Min-Yiang Tsai  
 Department of Mechanical Engineering, National Chung Cheng University, Chiayi, Taiwan  
 ..... 1677
- T4A.002 AN ACTIVE MATRIX ARRAYED MICROPHONE WITH ACOUSTIC BANDWIDTH RESPONSE**  
 Y.J. Hsu and I. Kymissis  
 Department of Electrical Engineering, Columbia University, New York City, New York, U. S.A  
 ..... 1681
- T4A.003 NONLINEAR VIBRATION IN RESONANT SILICON BRIDGE PRESSURE SENSOR: THEORY AND EXPERIMENT**  
 Qingfeng Li<sup>1</sup>, Shangchun Fan<sup>1</sup>, Zhangyang Tang<sup>1</sup> and Weiwei Xing<sup>1</sup>  
<sup>1</sup>School of Instrument Science & Opto-electronics Engineering, BeiHang University, Beijing, CHINA  
 ..... 1685
- T4A.004 ANALYSIS OF ACOUSTIC RADIATION AND VISCOUS DAMPING ON THE VIBRATION OF PIEZOELECTRIC CIRCULAR MICRODIAPHRAGMS**  
 M. Olfatnia, A.G.P. Kottapalli, T. Xu, J. Miao, L. S. Ong  
 School of Mechanical and Aerospace Engineering, Nanyang Technological University, Singapore  
 ..... 1689
- T4A.005 MIXED-LEVEL MODELING OF SQUEEZE FILM DAMPING IN MEMS: SIMULATION AND PRESSURE-DEPENDENT EXPERIMENTAL VALIDATION**  
 M. Niessner<sup>1</sup>, G. Schrag<sup>1</sup>, J. Iannacci<sup>2</sup>, and G. Wachutka<sup>1</sup>  
<sup>1</sup>Institute for Physics of Electrotechnology, Munich University of Technology, Munich, Germany  
<sup>2</sup>MEMS Research Unit, Fondazione Bruno Kessler, Povo di Trento, Italy  
 ..... 1693
- T4A.006 SUBPIXEL TRANSLATION OF MEMS MEASURED BY DISCRETE FOURIER TRANSFORM ANALYSIS OF CCD IMAGES**  
 C. Yamahata<sup>1</sup>, E. Sarajlic<sup>2</sup>, M. Stranczl<sup>1</sup>, G.J.M. Krijnen<sup>3</sup>, and M.A.M. Gijs<sup>1</sup>  
<sup>1</sup>Laboratory of Microsystems, Ecole Polytechnique

Fédérale de Lausanne, Lausanne, SWITZERLAND  
<sup>2</sup>SmartTip B.V., Enschede, THE NETHERLANDS  
<sup>3</sup>Transducers Science & Technology, MESA+,  
University of Twente, Enschede, THE NETHERLANDS  
.....1697

- T4A.007 A NOVEL TEST METHOD FOR SIMULTANEOUS MEASUREMENT OF THERMAL CONDUCTIVITY, CTE, RESIDUAL STRESS AND YOUNG'S MODULUS OF SUSPENDED THIN FILMS USING A LASER DOPPLER VIBROMETER**  
J. De Coster, M. Lofrano, R. Jansen, X. Rottenberg, S. Severi, J. Borremans, G. Van der Plas, S. Donnay, H.A.C. Tilmans and I. De Wolf<sup>1</sup>  
*imec, Leuven, BELGIUM<sup>1</sup> also at Katholieke Universiteit Leuven, MTM, Leuven, BELGIUM*  
.....1701

#### SESSION IV(2) – Actuators

- T4B.001 A THREE-TERMINAL SINGLE-WALLED CARBON NANOTUBE THIN FILM MEMS SWITCH FOR DIGITAL LOGIC APPLICATIONS**  
Min-Woo Jang<sup>1</sup>, Chia-Ling Chen<sup>1</sup>, Walter E Partlo III<sup>2</sup>, Shruti R Patil<sup>1</sup>, Dongjin Lee<sup>3</sup>, Zhijang Ye<sup>3</sup>, David Lilja<sup>1</sup>, T. Andrew Taton<sup>2</sup>, Tianhong Cui<sup>3</sup> and Stephen A. Campbell<sup>1\*</sup>  
<sup>1</sup>Department of Electrical and Computer Engineering, University of Minnesota, Minneapolis, USA  
<sup>2</sup>Department of Chemistry, University of Minnesota, Minneapolis, USA  
<sup>3</sup>Department of Mechanical Engineering, University of Minnesota, Minneapolis, USA  
.....1705
- T4B.002 NANO-OPTO-MECHANICAL LINEAR ACTUATOR UTILIZING GRADIENT OPTICAL FORCE**  
H. Cai<sup>1</sup>, K. J. Xu<sup>2</sup>, J. M. Tsai<sup>1</sup>, G. Q. Lo<sup>1</sup>, D. L. Kwong<sup>1</sup> and A. Q. Liu<sup>2</sup>  
<sup>1</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research) 11 Science Park Road, Singapore Science Park II, Singapore 117685  
<sup>2</sup>School of Electrical and Electronic Engineering, Nanyang Technological University, Singapore 639798  
.....1709
- T4B.003 NOVEL TWEEZERS USING ACOUSTICALLY OSCILLATING TWIN BUBBLES**  
K. H. Lee, J. H. Lee, J. M. Won, and S. K. Chung  
*Department of Mechanical Engineering, Myongji University, Yongin 449-728, South Korea*  
.....1713
- T4B.004 HYGROSCOPIC BIOMIMETIC TRANSDUCERS MADE FROM CNT-HYDROGEL COMPOSITES**  
M. De Volder<sup>1</sup>, S. Tawfick<sup>2</sup>, D. Copic<sup>2</sup> and A.J. Hart<sup>2</sup>  
<sup>1</sup>IMEC, Heverlee, Belgium and KULeuven, Leuven - Belgium  
<sup>2</sup>The University of Michigan, Ann Arbor, MI – USA  
.....1717

- T4B.005 A FUNCTIONAL MICROPROBE INTEGRATED WITH SHARP TIP AND HUGE DEFLECTION CRANK-SLIDER STRUCTURAL CANTILEVER FOR VERSATILE INSTRUMENT**  
X. Chen and D.W. Lee\*  
*MEMS & Nanotechnology Laboratory, School of Mechanical Systems Engineering, Chonnam National University, Gwangju, Republic of Korea*  
.....1721
- T4B.006 3D OMNIDIRECTIONAL CONTROLLABLE ELASTIC IPMC TWEEZER WITH SELF-SENSING AND ADJUSTABLE CLAMPING FORCE ABILITIES FOR BIOMEDICAL APPLICATIONS**  
Guo-Hua Feng\* and Jen-Wei Tsai  
*Department of Mechanical Engineering, National Chung Cheng University, Chiayi, Taiwan*  
.....1725
- T4B.007 A MICRO ELECTROSTATIC LINEAR ACCELERATOR BASED ON ELECTROMAGNETIC LEVITATION**  
I. Sari and M. Kraft  
*School of Electronics and Computer Science, University of Southampton, Southampton, UK*  
.....1729

#### SESSION IV(3) – Nanofabrication & Nanodevices

- T4C.001 BIONANO CRYSTALLIZED POLY-SI FILM FOR INCREASING TENSILE STRESS IN MEMS/NEMS DEVICE STRUCTURES**  
S. Kumagai<sup>1,3\*</sup>, S. Miyachi<sup>1</sup>, I. Yamashita<sup>2,3</sup>, Y. Uraoka<sup>2,3</sup>, and M. Sasaki<sup>1,3</sup>  
<sup>1</sup>Dept. of Advanced Science and Technology, Toyota Technological Institute, Nagoya, Japan  
<sup>2</sup>Graduate School of Materials Science, Nara Institute of Science and Technology, Nara, Japan  
<sup>3</sup>CREST, Japan Science and Technology, Saitama, Japan  
.....1733
- T4C.002 THREE DIMENSIONAL NANOSCALE FABRICATION AND MODELING OF DYNAMIC MODE MULTIDIRECTIONAL UV LITHOGRAPHY**  
Jungkwun 'J.K.' Kim<sup>1, 2, 3</sup>, Xiaoyu Cheng<sup>2</sup>, David E.Senior<sup>2</sup>, Mark G. Allen<sup>3</sup>, and Yong-Kyu 'YK' Yoon<sup>1,2</sup>  
<sup>1</sup>State University of New York at Buffalo, Buffalo, NY, USA  
<sup>2</sup>University of Florida, Gainesville, FL, USA  
<sup>3</sup>Georgia Institute of Technology, Atlanta, GA, USA  
.....1737
- T4C.003 ELECTRICAL CATCHING AND TRANSFER OF NANOPARTICLES VIA NANOTIP SILICON PROBE ARRAYS**  
A. Goryu<sup>1</sup>, A. Ikedo<sup>1</sup>, M. Ishida<sup>1</sup> and T. Kawano<sup>1</sup>  
*<sup>1</sup>Toyohashi University of Technology, Toyohashi, Aichi, Japan*  
.....1741
- T4C.004 BIOASSISTED SELECTIVE-CAPTURE AND**

**RELEASE OF NANOPARTICLES TOWARD APPLICATION ON MICROFLUIDIC DEVICES**  
Y. Shimada<sup>1,\*</sup>, M. Suzuki<sup>2</sup>, M. Sugiyama<sup>1,2</sup>, I. Kumagai<sup>3</sup> and M. Umetsu<sup>2,3</sup>

<sup>1</sup>The University of Tokyo, Tokyo, Japan

<sup>2</sup>3D BEANS center, BEANS project, Tokyo, Japan

<sup>3</sup>Tohoku University, Sendai, Japan

.....1745

**T4C.005 LAYER-BY-LAYER DEPOSITION OF COLLOIDAL SEMICONDUCTOR NANOCRYSTALS FOR INTEGRATION OF INFRARED**

**PHOTON-DETECTORS ON 3D TOPOGRAPHY**

J. Wei<sup>1</sup>, Y. Gao<sup>2,3</sup>, A.J. Houtepen<sup>2</sup>, G. Pandraud<sup>1</sup>, P.M. Sarro<sup>1</sup>

<sup>1</sup>DIMES/Delft University of Technology, Delft, Netherlands

<sup>2</sup>Chemical Engineering/Delft University of Technology, Delft, Netherlands

<sup>3</sup>Kavli Institute of Nanoscience/Delft University of Technology, Delft, Netherlands

.....1749

**T4C.006 A NEMS OPTICAL SWITCH DRIVEN BY OPTICAL FORCE**

J. F. Tao<sup>1,2,3</sup>, H. Cai<sup>3</sup>, A. B. Yu<sup>3</sup>, Q. X. Zhang<sup>3</sup>, J. Wu<sup>2</sup>, K. Xu<sup>2</sup>, J. T. Lin<sup>2</sup>, G. Q. Lo<sup>3</sup>, D. L. Kwong<sup>3</sup> and A. Q. Liu<sup>1\*</sup>

<sup>1</sup>School of Electrical & Electronic Engineering, Nanyang Technological University, Singapore 639798

<sup>2</sup>Beijing University of Posts and Telecommunications, Beijing 100876, China

<sup>3</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), 11 Science Park Road, Singapore Science Park II, Singapore 117685

.....1753

**T4C.007 GATE-ALL-AROUND SINGLE-CRYSTALLINE SILICON NANOWIRE OPTICAL SENSOR**

B.M. Ziaei-Moayyed, B. Draper, and M. Okandan

Department of Advanced MEMS, Sandia National Laboratories, Albuquerque, NM, USA

.....1757

## SESSION IV(4) –Microfluidics I

**T4D.001 CONTINUOUS FLOW LAYER-BY-LAYER MICROBEAD FUNCTIONALIZATION VIA A MICROPOST ARRAY RAILING SYSTEM**

Ryan D. Sochol, Ryan Ruelos, Valerie Chang, Megan E. Dueck, Luke P. Lee, and Liwei Lin  
Berkeley Sensor and Actuator Center University of California, Berkeley, USA

.....1761

**T4D.002 IN-SITU GENERATION AND SHRINKAGE OF MONODISPERSE WATER-IN-OIL EMULSION FOR FEMTOLITER COMPARTMENTALIZATION USING CAPILLARY TRAPS**

Tianzhun Wu<sup>1,2</sup>, Hiroaki Suzuki<sup>2,3</sup>, and Tetsuya

Yomo<sup>2,3,4</sup>

<sup>1</sup>School of Physics and Engineering, Sun Yat-sen University, CHINA

<sup>2</sup>ERATO, JST, JAPAN

<sup>3</sup>Graduate School of Information Science and Technology, Osaka University, JAPAN

<sup>4</sup>Graduate School of Frontier Biosciences, Osaka University, JAPAN

.....1765

**T4D.003 AN ACTIVE GYROSCOPIC MAGNETIC MICROMIXER FOR RAPID FLUID MIXING IN DROPLET BASED MICROFLUIDIC SYSTEMS**

Yi Zhang<sup>1</sup> and Tza-Huei Wang<sup>2</sup>

<sup>1</sup>Department of Biomedical Engineering, Sidney Kimmel Comprehensive Cancer Center, Johns Hopkins University, Baltimore, MD, USA

<sup>2</sup>Department of Mechanical Engineering, Department of Biomedical Engineering, Sidney Kimmel

Comprehensive Cancer Center, Center of Cancer Nanotechnology Excellence at Johns Hopkins, Johns Hopkins University, Baltimore, MD, USA

.....1769

**T4D.004 HIGH-SPEED PULSED MIXING WITH HIGH-FREQUENCY SWITCHING OF MICROPUMP DRIVING AND ITS APPLICATION TO NANOPARTICLE SYNTHESIS**

K. Sugano, H. Yoshimune, A. Nakata, Y. Hirai, T. Tsuchiya, and O. Tabata

Department of Micro Engineering, Kyoto University, Kyoto, Japan

.....1773

**T4D.005 INERTIAL PARTICLE FOCUSING IN PARALLEL MICROFLUIDIC CHANNELS FOR HIGH-THROUGHPUT FILTRATION**

J. Hansson<sup>1</sup>, J.M. Karlsson<sup>2</sup>, T. Haraldsson<sup>2</sup>, W. van der Wijngaart<sup>2</sup>, A. Russom<sup>1</sup>

<sup>1</sup>Div. Cell Physics, Dept. Applied Physics, KTH Royal Institute of Technology, Stockholm, SWEDEN

<sup>2</sup>Microsystem Technology Lab, KTH Royal Institute of Technology, Stockholm, SWEDEN

.....1777

**T4D.006 A WAFER-LEVEL, HETEROGENEOUSLY INTEGRATED, HIGH FLOW SMA-SILICON GAS MICROVALVE**

H. Gradin, S. Braun, G. Stemme and W. van der Wijngaart

Microsystem Technology Lab, KTH Royal Institute of Technology, Stockholm, SWEDEN

.....1781

**T4D.007 A PASSIVE CHECK VALVE USING MICROSPHERES FOR LOW PRESSURE AND LOW FLOW RATE APPLICATIONS**

K. Ou, M. Chiao

Department of Mechanical Engineering, The University of British Columbia, Vancouver, BC, CANADA

.....1785

# WEDNESDAY, JUNE 8, 2011

## ORAL SESSIONS

08:30 - 10:00

### SESSION V(1) –3D Integration

#### W1A.001 Invited Speaker

##### MICROBALL BEARING TECHNOLOGY FOR MEMS DEVICES AND INTEGRATED MICROSYSTEMS

R. Ghodssi<sup>1</sup>, B. Hanrahan<sup>1,2</sup>, and M. Beyaz<sup>1</sup>  
<sup>1</sup>*MEMS Sensors and Actuators Laboratory (MSAL), Department of Electrical and Computer Engineering, Department of Materials Science and Engineering, Institute for Systems Research, University of Maryland, College Park, MD 20742, USA*  
<sup>2</sup>*U. S. Army Research Laboratory, Adelphi, MD 20783, USA*

1789

#### W1A.002 A NOVEL MEMS CONFIGURATION FOR THREE DIMENSIONAL FINE POSITIONING AND MECHANICAL FIXING OF A BALL LENS IN THE PACKAGING OF SILICON PHOTONICS

Q. X. Zhang<sup>1</sup>, Y. Du<sup>1,2</sup>, C.W. Tan<sup>1</sup>, J. Zhang<sup>1</sup>, M. B. Yu<sup>1</sup>, G. Q. Lo<sup>1</sup>, and D. L. Kwong<sup>1</sup>  
<sup>1</sup>*Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), Singapore*  
<sup>2</sup>*Dept. of Mechanical Engineering, National University of Singapore*

1795

#### W1A.003 DIE-LEVEL TSV FABRICATION PLATFORM FOR CMOS-MEMS INTEGRATION

Y. Temiz, M. Zervas, C. Guiducci, and Y. Leblebici  
*École Polytechnique Fédérale de Lausanne, Lausanne, SWITZERLAND*

1799

#### W1A.004 PLANAR MEMS RF CAPACITOR INTEGRATION

A. K. Stamper<sup>1</sup>, C. V. Jahnes<sup>2</sup>, S. R. Dupuis<sup>1</sup>, A. Gupta<sup>1</sup>, Z.-X. He<sup>1</sup>, R. T. Herrin<sup>1</sup>, S. E. Luce<sup>1</sup>, J. Maling<sup>1</sup>, D. R. Miga<sup>1</sup>, W. J. Murphy<sup>1</sup>, E. J. White<sup>1</sup>, S. J. Cunningham<sup>3</sup>, D. R. DeReus<sup>3</sup>, I. Vitomirov<sup>3</sup>, and A. S. Morris<sup>3</sup>  
<sup>1</sup>*IBM, Essex Junction, VT USA,*  
<sup>2</sup>*IBM, Yorktown Heights, NY USA*  
<sup>3</sup>*Wispry, Irvine, CA USA*

1803

### SESSION V(2) –Optofluidics

#### W1B.001 Invited Speaker

##### OPTOFLUIDICS

Demetri Psaltis

EPFL - Ecole Polytechnique Fédérale de Lausanne,

Lausanne, Switzerland

1807

#### W1B.002 CORTICAL BLOOD FLOW IMAGING WITH A PORTABLE MEMS BASED 2-PHOTON FLUORESCENCE MICROENDOSCOPE

W. Piyawattanametha<sup>1,3</sup>, O. Solgaard<sup>2</sup>, and M. J. Schnitzer<sup>1</sup>  
<sup>1</sup>*NECTEC, Pathumthani, Thailand 12120,* <sup>2</sup>*Edward L. Ginzton Laboratory, Stanford University, Stanford, CA 94305,* <sup>3</sup>*James H. Clark Center for Biomedical Engineering & Sciences, Stanford University, Stanford, CA 94305*

1809

#### W1B.003 PHOTOTHERMAL NANOBLADE FOR LARGE CARGO DELIVERY INTO MAMMALIAN CELLS

T.-H. Wu<sup>1,2</sup>, T. Teslaa<sup>2</sup>, S. Kalim<sup>2</sup>, C.T. French<sup>3</sup>, S. Moghadam<sup>3</sup>, R. Wall<sup>3</sup>, J.F. Miller<sup>3</sup>, O.N. Witte<sup>3</sup>, M.A. Teitell<sup>2</sup>, and P.-Y. Chiou<sup>1</sup>  
<sup>1</sup>*Department of Mechanical and Aerospace Engineering, University of California at Los Angeles (UCLA), Los Angeles, California, USA*  
<sup>2</sup>*Department of Pathology and Laboratory Medicine, UCLA, Los Angeles, California, USA*  
<sup>3</sup>*Department of Microbiology, Immunology and Molecular Genetics, UCLA, Los Angeles, California, USA*

1813

#### W1B.004 MULTISPECTRAL ANALYSIS OF CANCER CELLS USING QUANTUM DOT LEDS PATTERNED ON-CHIP

Ashwini Gopal, Zhiguo Wang, Kazunori Hoshino, Xiaojing Zhang  
*Department of Biomedical Engineering, The University of Texas at Austin, Austin, Texas, USA*

1817

#### W1B.005 PORTABLE ORAL CANCER DETECTION USING MINIATURE CONFOCAL IMAGING PROBE WITH LARGE FIELD OF VIEW

Youmin Wang, Milan Raj, H. Stan McGuff, TingShen, Xiaojing Zhang  
*Department of Biomedical Engineering, University of Texas at Austin, Austin, USA ; Department of Pathology, University of Texas Health Science Center San Antonio, Austin, USA; NanoLite Systems, Inc., Austin, TX, USA*

1821

### SESSION V(3) –Bioanalysis Tools

#### W1C.001 Invited Speaker

##### EFFICIENT AND HIGH-THROUGHPUT ELECTROPORATION CHIPS

Zhihong Li<sup>1</sup>, Zewen Wei<sup>1</sup>, Xueming Li<sup>1</sup>, Quan Du<sup>2</sup>, and Zicai Liang<sup>2</sup>

<sup>1</sup>*National Key Laboratory of Science and Technology on Micro/Nano Fabrication, Institute of Microelectronics, Peking University, China*

<sup>2</sup>*Institute of Molecular Medicine, Peking University, China*

1825

**WIC.002 MULTI-SITE MONITORING OF CHOLINE AND GLUTAMATE USING BIOSENSOR MICROPROBE ARRAYS IN COMBINATION WITH CMOS CIRCUITRY**

O. Frey<sup>1</sup>, J. Rothe<sup>1</sup>, M.K. Lewandowska<sup>1</sup>, P.D. van der Wal<sup>2</sup>, N.F. de Rooij<sup>2</sup>, and A. Hierlemann<sup>1</sup>

<sup>1</sup>Bio Engineering Laboratory, D-BSSE, ETH Zurich, Basel, SWITZERLAND

<sup>2</sup>Sensors, Actuators and Microsystems Laboratory, IMT, EPF Lausanne, Neuchatel, SWITZERLAND

1829

**WIC.003 A COMPACT HALL-EFFECT SENSOR ARRAY FOR THE DETECTION AND IMAGING OF SINGLE MAGNETIC BEADS IN BIOMEDICAL ASSAYS**

K. Skucha, P. Liu, M. Megens, J. Kim and B. Boser

University of California at Berkeley, Berkeley, California, USA

1833

**WIC.004 3D LOBULE-MIMETIC CHIP VIA POSITIVE DIELECTROPHORESIS FORCE WITH SINUSOIDAL SPACING POLY (ETHYLENE GLYCOL)-DIACRYLATE MICROWALLS**

Yu-Shih Chen<sup>1</sup>, Ling-Yi Ke<sup>2</sup>, and Cheng-Hsien Liu<sup>1,2</sup>

<sup>1</sup>Institute of NanoEngineering and MicroSystems,

<sup>2</sup>Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan, R.O.C.

1837

**WIC.005 RESIDUAL STRESS-FREE 100 MHZ PZT-BASED CONCAVE DIAPHRAGM RESONATOR FOR LABEL-FREE PROTEIN-LIGAND BIOSENSING WITH SELF-ENHANCING MECHANISM**

Guo-Hua Feng and Zhi-Dain Lin

Department of Mechanical Engineering, National Chung Cheng University, Chiayi, Taiwan

1841

**SESSION V(4) –Energy Harvesting**

**WID.001 Invited Speaker**

**MICROSYSTEMS FOR ENERGY HARVESTING**

K. Najafi, T. Galchev, E.E. Aktakka, R.L. Peterson, and J. McCullagh

Center for Wireless Integrated Microsystems (WIMS), University of Michigan, Ann Arbor, Michigan 48109-2122, USA

1845

**WID.002 A MICRO TESLA TURBINE FOR POWER GENERATION FROM LOW PRESSURE HEADS AND EVAPORATION DRIVEN FLOWS**

Vedavalli G. Krishnan<sup>1</sup>, Zohora Iqbal<sup>1</sup> and Michel M. Maharbiz<sup>1</sup>

<sup>1</sup>University of California Berkeley, CA., US

1851

**WID.003 DESIGN AND MICROFABRICATION OF**

**INTEGRATED MAGNETIC MEMS ENERGY HARVESTER FOR LOW FREQUENCY APPLICATION**

Quan Yuan<sup>1</sup>, Student Member, IEEE, Xuming Sun<sup>1</sup>, Student Member, IEEE, Dong-Ming Fang<sup>2</sup>, Member, IEEE, Haixia Zhang<sup>1</sup>, Senior Member, IEEE

<sup>1</sup>National Key Laboratory of Science and Technology on Micro/Nano Fabrication, Institute of Microelectronics, Peking University, Beijing 100871, P. R. China.

<sup>2</sup>State Key Laboratory of Transducer Technology, Institute of Electronics, Chinese Academy of Sciences, Beijing 100190, China

1855

**WID.004 HIGHLY EFFICIENT PIEZOELECTRIC MICRO HARVESTER FOR LOW LEVEL OF ACCELERATION FABRICATED WITH A CMOS COMPATIBLE PROCESS**

M. Defosseux<sup>1</sup>, M. Allain<sup>1</sup>, P. Ivaldi<sup>2</sup>, E. Defay<sup>2</sup> and S. Basrour<sup>1</sup>

<sup>1</sup>TIMA Laboratory (CNRS-Grenoble INP-UJF), Grenoble, France

<sup>2</sup>CEA LETI Minatoc Campus, Grenoble, France

1859

**WID.005 A MILLIMETER-SIZED ELECTRET- ENERGY-HARVESTER WITH MICROFABRICATED HORIZONTAL ARRAYS AND VERTICAL PROTRUSIONS FOR POWER GENERATION ENHANCEMENT**

K. Ono, N. Sato, T. Shimamura, M. Ugajin, T. Sakata, S. Mutoh, and Y. Sato

NTT Microsystem Integration Laboratories, NTT Corporation, Atsugi, Kanagawa, Japan

1863

**ORAL SESSIONS**

10:30 – 12:15

**SESSION VI(1) –Materials for Nanodevices**

**W2A.001 STRUCTURAL AND THERMOELECTRIC CHARACTERIZATION OF INDIVIDUAL SINGLE CRYSTALLINE NANOWIRES**

Z. Wang<sup>1</sup>, M. Kroener<sup>1</sup>, and P. Woias<sup>1</sup>

<sup>1</sup>Laboratory for Design of Microsystems, Department of Microsystems Engineering – IMTEK, University of Freiburg, Germany

1867

**W2A.002 IMPLEMENTATION OF INDUCTIVE PROXIMITY SENSOR USING NANOPOROUS ANODIC ALUMINUM OXIDE LAYER**

Pei-Hsuan Lo<sup>1</sup>, Chitsung Hong<sup>1</sup>, Sung-Cheng Lo<sup>2</sup>, and Weileun Fang<sup>1,2</sup>

<sup>1</sup>Institute of NanoEngineering and MicroSystems,

<sup>2</sup>Department of Power Mechanical Engineering, National Tsing Hua University, Hsinchu, Taiwan

1871

- W2A.003 NANOCRYSTALLINE SiC METAL-SEMICONDUCTOR-METAL PHOTODETECTOR WITH ZnO NANOROD ARRAYS FOR HIGH-TEMPERATURE APPLICATIONS**  
Wei-Cheng Lien<sup>1,2,4</sup>, Dung-Sheng Tsai<sup>4</sup>, Shu-Hsien Chiu<sup>4</sup>, Debbie G. Senesky<sup>2,3</sup>, Roya Maboudian<sup>2</sup>, Albert P. Pisano<sup>1,2,3</sup>, Jr-Hau He<sup>4</sup>  
<sup>1</sup>Applied Science and Technology Program, University of California, Berkeley, CA 94709, USA  
<sup>2</sup>Berkeley Sensor and Actuator, University of California, Berkeley, CA 94709, USA  
<sup>3</sup>Department of Mechanical Engineering, University of California, Berkeley, CA 94709, USA  
<sup>4</sup>Institute of Photonics and Optoelectronics and Department of Electrical Engineering, National Taiwan University, Taipei 10617, Taiwan  
.....1875
- W2A.004 GRAPHITIZATION OF N-TYPE POLYCRYSTALLINE SILICON CARBIDE AND ITS APPLICATION FOR MICRO- SUPERCAPACITORS**  
F. Liu<sup>1,a,\*</sup>, A. Gutes<sup>1</sup>, C. Carraro<sup>1</sup>, J. Chu<sup>2</sup> and R. Maboudian<sup>1</sup>  
<sup>1</sup>Berkeley Sensor & Actuator Center and Department of Chemical and Biomolecular Engineering University of California, Berkeley, CA 94720, USA  
<sup>2</sup>Department of Precision Machinery and Precision Instrumentation, University of Science and Technology of China, Hefei, Anhui 230027, China  
.....1879
- W2A.005 A GRAPHENE-BASED MICROELECTRODE FOR RECORDING NEURAL SIGNALS**  
C.H. Chen<sup>1</sup>, C.T. Lin<sup>2</sup>, J.J. Chen<sup>1</sup>, W.L. Hsu<sup>1</sup>, Y.C. Chang<sup>1</sup>, S.R. Yeh<sup>1</sup>, L.J. Li<sup>2</sup>, and D.J. Yao<sup>1,\*</sup>  
<sup>1</sup>National Tsing Hua University, Hsinchu, TAIWAN  
<sup>2</sup>Academia Sinica, Taipei, TAIWAN  
.....1883
- W2A.006 REDUCING STICTION IN MICROELECTROMECHANICAL SYSTEMS BY NANOMETER-SCALE FILMS GROWN BY ATOMIC LAYER DEPOSITION**  
R.L. Puurunen<sup>1</sup>, A. Häärälä<sup>1</sup>, H. Ritala<sup>1</sup>, J. Dekker<sup>1</sup>, M. Kainlahti<sup>1</sup>, H. Pohjonen<sup>1</sup>, T. Suni<sup>1</sup>, J. Kiihamäki<sup>1</sup>, E. Santala<sup>2</sup>, M. Leskelä<sup>2</sup>, and H. Kattelus<sup>1</sup>  
<sup>1</sup>VTT Technical Research Centre of Finland, Espoo, FINLAND  
<sup>2</sup>University of Helsinki, Laboratory of Inorganic Chemistry, Helsinki, FINLAND  
.....1887
- W2A.007 NANOELECTROMECHANICAL SWITCHES BASED ON DIAMOND-ON-DIAMOND**  
M.Y. Liao, S. Hishita, and Y. Koide  
Sensor Materials Center, National Institute for Materials Science, Namiki 1-1, Tsukuba, Japan  
.....1891

- W2B.001 “MEMSEYE” FOR OPTICAL 3D TRACKING AND IMAGING APPLICATIONS**  
V. Milanović<sup>1</sup>, A. Kasturi<sup>1</sup>, N. Siu<sup>1</sup>, M. Radojčić<sup>2</sup>, and Y. Su<sup>2</sup>  
<sup>1</sup>Mirrorcle Technologies, Inc., Berkeley, California, United States  
<sup>2</sup>Adriatic Research Institute, Berkeley, California, United States  
.....1895
- W2B.002 HIGHLY EFFICIENT LED LENS BIOLOGICALLY INSPIRED FROM CUTICLE NANOSTRUCTURES OF FIREFLY LIGHT ORGANS**  
J.J. Kim, Y.S. Lee, and K.H. Jeong  
Department of Bio and Brain Engineering, Korea Advanced Institute of Science and Technology (KAIST), Daejeon, Korea  
.....1899
- W2B.003 OPTICAL MEASUREMENT OF STRAIN USING SCATTERING FROM NANOPARTICLE PAIRS ON ELASTOMER**  
T. Kan, K. Matsumoto, and I. Shimoyama  
The University of Tokyo, Tokyo, JAPAN  
.....1903
- W2B.004 MICROFABRICATION AND PACKAGING OF A RUBIDIUM VAPOR CELL AS A PLASMA LIGHT SOURCE FOR MEMS ATOMIC CLOCKS**  
V. Venkatraman, Y. Petremand, C. Affolderbach, G. Mileti, N. de Rooij, H. Shea  
LMTS, Ecole Polytechnique Federale de Lausanne, Switzerland; LTF, University of Neuchatel, Switzerland; SAMLAB, Ecole Polytechnique Federale de Lausanne, Switzerland  
.....1907
- W2B.005 ON-CHIP OPTICAL POWER MEASUREMENT BY OPTICAL FORCE**  
J. F. Tao<sup>1, 2, 3</sup>, H. Cai<sup>3</sup>, A. B. Yu<sup>3</sup>, W. M. Zhu<sup>1</sup>, Q. X. Zhang<sup>3</sup>, J. Wu<sup>2</sup>, K. Xu<sup>2</sup>, J. T. Lin<sup>2</sup>, G. Q. Lo<sup>3</sup>, D. L. Kwong<sup>3</sup> and A. Q. Liu<sup>1</sup>  
<sup>1</sup>School of Electrical & Electronic Engineering, Nanyang Technological University, Singapore 639798  
<sup>2</sup>Beijing University of Posts and Telecommunications, Beijing 100876, China  
<sup>3</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), 11 Science Park Road, Singapore Science Park II, Singapore 117685  
.....1911
- W2B.006 SPR PHOTO DIODE DETECTOR USING TRANSPORTATION PHENOMENON OF PHOTON AND ELECTRON COUPLING**  
Yoshiharu Ajiki<sup>1</sup>, Tetsuo Kan<sup>2</sup>, Kiyoshi Matsumoto<sup>2</sup>, and Isao Shimoyama<sup>2</sup>  
<sup>1</sup>Future Creation Laboratory, Olympus Corporation, Tokyo, JAPAN  
<sup>2</sup>Graduate School of Information Science and Technology, the University of Tokyo, Tokyo, JAPAN  
.....1915
- W2B.007 DEVELOPMENT OF A “FLIP GLASS SUBSTRATE” LED PACKAGE TECHNOLOGY FOR COLOR BIN**

#### YIELD AND VIEW ANGLE ENHANCEMENT

Chien-Lin Chang-Chien<sup>1</sup>, Yu-Che Huang<sup>1</sup>,  
Ming-Chuen Yip<sup>1</sup>, and Weileun Fang<sup>1,2</sup>

<sup>1</sup>Power Mechanical Engineering, <sup>2</sup>NEMS Inst., National  
Tsing Hua University, Hsinchu, Taiwan

.....1919

### SESSION VI(3) –Biomedical Microdevices

#### W2C.001 A MICROFLUIDIC BLOOD-CLOGGING VALVE FOR ON-CHIP BLOOD ANALYSIS

W. Shi, L.W. Guo, and YC. Tai

California Institute of Technology, Pasadena, CA, USA

.....1923

#### W2C.002 FULLY INTEGRATED DROPLET BASED POINT-OF-CARE PLATFORM FOR MOLECULAR DETECTION FROM CRUDE BIOSAMPLES

Yi Zhang<sup>1,2</sup>, Seungkyung Park<sup>3</sup>, Samuel Yang  
and Tza-Huei Wang<sup>1,2,4,5</sup>

<sup>1</sup>Department of Biomedical Engineering, <sup>2</sup>Sidney  
Kimmel Comprehensive Cancer Center, <sup>3</sup>Department of  
Emergency Medicine, <sup>4</sup>Department of Mechanical  
Engineering, <sup>5</sup>Center of Cancer Nanotechnology  
Excellence at Johns Hopkins, Johns Hopkins University

.....1927

#### W2C.003 ISOLATION OF TUMOR CELLS USING A NEW MICROFLUIDIC INCUBATOR WITH MOVING-WALL STRUCTURES

Ying-Hsin Chuang<sup>1</sup>, Lien-Yu Hung<sup>2</sup>, Keng-Fu  
Hsu<sup>3</sup>, Cheng-Yang Chou<sup>3</sup> and Gwo-Bin Lee<sup>2\*</sup>

<sup>1</sup>Department of Engineering Science, National Cheng  
Kung University, Tainan, Taiwan

<sup>2</sup>Department of Power Mechanical Engineering,  
National Tsing Hua University, Hsinchu, Taiwan

<sup>3</sup>Department of Obstetrics and Gynecology, National  
Cheng Kung University, Tainan, Taiwan

.....1931

#### W2C.004 TOWARDS QUANTIFICATION OF BIOCOMPATIBILITY: MONITORING IN-GROWTH BEHAVIOR OF BIOMATERIALS IN TISSUE WITH A MICROSENSOR IMPLANT

M. Kubon<sup>1</sup>, M. Moschallski<sup>1</sup>, T. Ensslen<sup>1</sup>, G.  
Link<sup>1</sup>, S. Werner<sup>1</sup>, C. Burkhardt<sup>1</sup>, H. Hartmann<sup>1</sup>,  
B. Schlosshauer<sup>1</sup>, G. Urban<sup>2</sup> and M. Stelzle<sup>1</sup>

<sup>1</sup>NMI Natural and Medical Institute at the University of  
Tuebingen, Reutlingen, Germany

<sup>2</sup>University of Freiburg, IMTEK, Laboratory of Sensors,  
Freiburg, Germany

.....1935

#### W2C.005 DISPOSABLE MICRO DEVICES FOR CLINICAL ICSI

X.P. Zhang, Z. Lu, and Y. Sun

Department of Mechanical and Industrial Engineering,  
University of Toronto, Canada

.....1938

#### W2C.006 A PARYLENE-BASED FLEXIBLE ELECTROPORATION CHIP APPLICABLE FOR IN

#### VIVO GENE AND SIRNA DELIVERY

Zewen Wei<sup>1\*</sup>, Yuanyu Huang<sup>2\*</sup>, Deyao Zhao<sup>2</sup>,  
Zicai Liang<sup>2</sup>, and Zhihong Li<sup>1</sup>

<sup>1</sup>National Key Laboratory of Science and Technology  
on Micro/Nano Fabrication, Institute of  
Microelectronics, Peking University, China

<sup>2</sup>Institute of Molecular Medicine, Peking University,  
China

.....1942

#### W2C.007 MICRO-AQUATIC-FARM: ON CHIP STIMULATION AND EVALUATION SYSTEM FOR MICROORGANISMS BY MAGNETICALLY DRIVEN MICROTOOLS

T. Kawahara<sup>1</sup>, M. Sugita<sup>1</sup>, M. Hagiwara<sup>1</sup>, Y.  
Yamanishi<sup>1,2</sup>, F. Arai<sup>1,3</sup>, H. Kawano<sup>4</sup>, I.  
Shihira-Ishikawa<sup>4</sup>, and A. Miyawaki<sup>4</sup>

<sup>1</sup>Nagoya University, Japan

<sup>2</sup>JST PRESTO, Japan

<sup>3</sup>Seoul National University, Korea

<sup>4</sup>RIKEN Brain Science Institute, Japan

.....1946

### SESSION VI(4) –Chemical Sensors II

#### W2D.001 TEMPERATURE DEPENDENCE OF VACUUM ENCAPSULATED RESONATORS FOR HUMIDITY MEASUREMENT

R.G. Hennessy, M. M. Shulaker, M. W. Messana,  
A.B. Graham, N. Klejwa, J. Provine, T.W. Kenny,  
and R. T. Howe

Stanford University, Stanford, CA, USA

.....1950

#### W2D.002 ENHANCED PERFORMANCE OF A CMOS INTERDIGITAL CAPACITIVE HUMIDITY SENSOR BY GRAPHENE OXIDE

Cheng-Long Zhao, Ming Qin, Wei-Hua Li, and  
Qing-An Huang\*

Key Laboratory of MEMS of the Ministry of Education,  
Southeast University, Nanjing 210096, China

.....1954

#### W2D.003 MEMS-BASED AC DIFFERENTIAL SCANNING CALORIMETRY

B. Wang and Q. Lin

Department of Mechanical Engineering, Columbia  
University, New York, NY 10027, USA

.....1958

#### W2D.004 ENHANCEMENT OF SENSITIVITY OF COULOMETRIC DETECTION USING A ONE-ELECTRODE SYSTEM

K. Ikemoto, K. Kojima, F. Sassa, M. Yokokawa,  
and H. Suzuki

Graduate School of Pure and Applied Sciences,  
University of Tsukuba, Tsukuba, JAPAN

.....1962

#### W2D.005 MULTIMODAL BIO – IMAGE SENSOR FOR REAL – TIME PROTON AND FLUORESCENCE IMAGING

H. Nakazawa<sup>1,2</sup>, M. Ishida<sup>1,3</sup>, and K. Sawada<sup>1,3,4</sup>

<sup>1</sup>*Integrated Circuit and Sensor System Group,  
Toyohashi University of Technology, Aichi 441-8580  
Japan*

<sup>2</sup>*Research Fellow of the Japan Society for the  
Promotion of Science, Tokyo 102-8472 Japan*

<sup>3</sup>*Electronics-Inspired Interdisciplinary Research  
Institute, TUT, Aichi 441-8580 Japan*

<sup>4</sup>*Core Research Evolutional Science and Technology,  
JST, Tokyo 102-8666, Japan*

.....1966

**W2D.006 MICROFLUIDIC SURFACE-ENHANCED RAMAN  
SCATTERING SENSORS FOR ONLINE  
MONITORING TRACE CHEMICAL MIXING AND  
REACTION**

H.Y. Mao, P.P. Lv and W.G. Wu\*

*National Key Laboratory of Science and Technology  
on Micro/Nano Fabrication, Institute of  
Microelectronics, Peking University, Beijing 100871,  
P. R. China*

.....1970

**W2D.007 NANOPARTICLE SELF-ASSEMBLY BASED  
TRIPETALOID ARRAYED STRUCTURES AS  
SURFACE-ENHANCED RAMAN SCATTERING  
SUBSTRATES**

C. Qian, W.X. Yu, W.G. Wu\*, Y.F. Wang, and H.Y.  
Mao

*National Key Laboratory of Science and Technology on  
Micro/Nano Fabrication, Institute of Microelectronics,  
Peking University, Beijing 100871, P. R. China*

.....1974

## Volume 3 / W3P.001-Th2D.007

### POSTER SESSION III

13:15 – 16:15

#### Mechanical/Physical Sensors and Microsystems

##### W3P.001 LIGHTWEIGHT BIOCOMPATIBLE PHYSICAL FILM-BASED SENSORS: POLYMERS

###### “SELF-METALLIZED” WITH ORGANIC MOLECULAR CONDUCTORS

Elena Laukhina,<sup>1,2\*</sup> Victor Lebedev,<sup>2</sup> Vladimir Laukhin,<sup>1,2,3</sup> Gerard Oncins,<sup>4</sup> Raphael Pfattner<sup>2</sup>  
Concepcio Rovira,<sup>1,2</sup> Jaume Veciana<sup>1,2</sup>

<sup>1</sup>CIBER de Bioingeniería, Biomateriales y Nanomedicina (CIBER-BBN), Spain

<sup>2</sup>Institut de Ciència de Materials de Barcelona (ICMAB-CSIC), Campus UAB, Bellaterra, Spain

<sup>3</sup>Institució Catalana de Recerca i Estudis Avançats (ICREA), Barcelona, Spain

<sup>4</sup>CCiTUB, Nanometric Techniques Unit, University of Barcelona, Spain

1978

##### W3P.002 POSFET TOUCH SENSOR WITH ON-CHIP ELECTRONIC MODULE FOR SIGNAL CONDITIONING

A. Adami<sup>1</sup>, R. S. Dahiya<sup>1</sup>, C. Collini<sup>1</sup>, D. Cattin<sup>2</sup>, and L. Lorenzelli<sup>1</sup>

<sup>1</sup>Bio-MEMS, Fondazione Bruno Kessler, Trento, ITALY

<sup>2</sup>University of Padova, Vicenza, ITALY

1982

##### W3P.003 A NOVEL MEMS TUNABLE IONIZATION SENSOR BASED ON PATTERNED FREESTANDING NICKEL NANOWIRES AND MOVING ELECTRODE

T. Walewyns and L. A. Francis

Electrical Engineering Department, Institute of Information and Communication Technologies, Electronics and Applied Mathematics, Université catholique de Louvain, Louvain-la-Neuve, Belgium

1986

##### W3P.004 CONTROL OF MEMS ON THE EDGE OF INSTABILITY

C.B.Burgner, W.S.Snyders, and K.L.Turner  
University of California, Santa Barbara, California, USA

1990

##### W3P.005 HIGH TEMPERATURE COMPATIBLE ALUMINUM NITRIDE RESONATING STRAIN SENSOR

F.T. Goericke<sup>1,\*</sup>, M.W. Chan<sup>1</sup>, G. Vigevani<sup>1</sup>, I. Izyumi<sup>h2</sup>, B.E. Boser<sup>2</sup>, and A.P. Pisano<sup>1</sup>

<sup>1</sup>Department of Mechanical Engineering, University of California, Berkeley, USA

<sup>2</sup>Department of Electrical Engineering, University of California, Berkeley, USA

1994

##### W3P.006 FABRICATION AND TESTING OF AN IONIC ELECTROSPRAY PROPULSION SYSTEM DEVICE WITH A POROUS NI TIP ARRAY

H.Q. Li, D.G. Courtney, P. Diaz Gomez Maqueo and P. Lozano

Massachusetts Institute of Technology, Cambridge, MA, USA

1998

##### W3P.007 ELECTRICAL COUPLING SUPPRESSING FOR A MICROGYROSCOPE USING ASCENDING FREQUENCY DRIVE WITH 2-DOF PID CONTROLLER

J.Cui, Z.Y. Guo, Z. Yang, Y.L. Hao, G.Z. Yan

Institute of Microelectronics, Peking University, Beijing, China

National Key Laboratory of Science and Technology on Micro/Nano Fabrication

2002

##### W3P.008 ANALYSIS OF ACCELERATION SENSITIVITY IN MEMS TUNING FORK GYROSCOPE

Thakur Praveen Singh, Koji Sugano, Toshiyuki Tsuchiya and Osamu Tabata

Department of Micro Engineering, Kyoto University, Kyoto, Japan

2006

##### W3P.009 ULTRASENSITIVE MASS SENSOR USING THE OUT-OF-PHASE VIBRATION EIGENSTATE OF INTERCOUPLED DUAL-MICROCANTILEVERS

J. Wang, B. Feng, C. Li, F.Q. Zhang, K. Ding and W.G. Wu\*

National Key Laboratory of Science and Technology on Micro/Nano Fabrication,

Institute of Microelectronics, Peking University, Beijing 100871, P. R. China

2010

##### W3P.010 WIRELESS PASSIVE SENSING APPLICATION USING A CAVITY LOADED EVANESCENT MODE HALF MODE SUBSTRATE INTEGRATED WAVEGUIDE RESONATOR

D. E. Senior<sup>1,2</sup>, X. Cheng<sup>1</sup>, P. Jao<sup>1</sup>, C. Kim<sup>1</sup>, J.K. Kim<sup>1</sup>, and YK Yoon<sup>1</sup>

<sup>1</sup>Department of Electrical Engineering, University of Florida, Gainesville, USA

<sup>2</sup>Department of Electrical and Electronic Engineering, Universidad Tecnológica de Bolivar, Colombia

2014

##### W3P.011 A MONOLITHICALLY INTEGRATED 3-AXIS THERMAL-CONVECTIVE ACCELEROMETER WITH A PNEUMATICALLY CURVED THERMOPILE-CANTILEVER FOR Z-AXIS SENSING

Quan Wang<sup>1,2</sup>, Xinxin Li<sup>1</sup>

<sup>1</sup>State Key Lab of Transducer Technology, Shanghai Institute of Microsystem and Information Technology,

Chinese Academy of Sciences, Shanghai 200050,  
CHINA

<sup>2</sup>School of Mechanical Engineering, Jiangsu University,  
Zhenjiang 212013, CHINA

.....2018

**W3P.012 DIFFERENTIAL PRESSURE DISTRIBUTION  
MEASUREMENT OF A FREE-FLYING BUTTERFLY  
WING**

H. Takahashi, K. Matsumoto and I. Shimoyama  
The University of Tokyo, Tokyo, Japan

.....2022

**W3P.013 SILICON CARBIDE PRESSURE SENSOR FOR  
HIGH TEMPERATURE AND HIGH PRESSURE  
APPLICATIONS: INFLUENCE OF SUBSTRATE  
MATERIAL ON PERFORMANCE**

Sheng Jin<sup>1</sup>, Srihari Rajgopal<sup>2</sup>, Mehran  
Mehregany<sup>2</sup>

<sup>1</sup>Materials Science and Engineering

<sup>2</sup>Electrical Engineering and Computer Science  
Case Western Reserve University, Cleveland, OH, USA

.....2026

**W3P.014 ACCELEROMETER USING MOSFET WITH  
MOVABLE GATE ELECTRODE:  
ELECTROPLATING THICK NICKEL PROOF MASS  
ON FLEXIBLE PARYLENE BEAM FOR  
ENHANCING SENSITIVITY**

S. Aoyagi<sup>1</sup>, M. Suzuki<sup>1</sup>, J. Kogure<sup>1</sup>, T. Kong<sup>1</sup>, R.  
Taguchi<sup>1</sup>, T. Takahashi<sup>1</sup>, S. Yokoyama<sup>2</sup>, and H.  
Tokunaga<sup>3</sup>

<sup>1</sup>Kansai University, Osaka, Japan

<sup>2</sup>Hiroshima University, Hiroshima, Japan

<sup>3</sup>M. T. C. Corp., Kanagawa, Japan

.....2030

**W3P.015 FLEXIBLE FORCE SENSOR MEASURING  
CHANGE IN CAPACITANCE DUE TO DIELECTRIC  
OIL DISPLACEMENT OUT OF DOMED POLYMER  
INTO SURROUNDING CHANNELS**

T. Takahashi<sup>1</sup>, M. Suzuki<sup>1</sup>, S. Iwamoto<sup>1</sup>, and S.  
Aoyagi<sup>1</sup>

<sup>1</sup>Kansai University, Osaka, Japan

.....2034

**W3P.016 NON-DEGENERATE PARAMETRIC  
AMPLIFICATION AND FILTERING IN  
BIOMIMETIC HAIR FLOW SENSORS**

H. Droogendijk\*, C. M. Bruinink, R. G. P. Sanders  
and G. J. M. Krijnen

MESA<sup>+</sup> Research Institute, University of Twente, THE  
NETHERLANDS

.....2038

**W3P.017 FORCE SENSOR FOR POWER TRANSFER  
BETWEEN THE HUMAN BODY AND THE  
ENVIRONMENT**

R.A. Brookhuis<sup>1</sup>, T.S.J. Lammerink<sup>1</sup>, R.J.  
Wiegerink<sup>1</sup>, M.J. de Boer<sup>1</sup> and M.C.  
Elwenspoek<sup>1,2</sup>

<sup>1</sup>Transducers Science and Technology Group, MESA+  
Research Institute, University of Twente, P.O. Box 217,  
7500 AE Enschede, the Netherlands

<sup>2</sup>Fellow, FRIAS, Albert-Ludwigs University, Albertstr.  
19, 79104 Freiburg, Germany

.....2042

**W3P.018 THIN FILM ENCAPSULATED SIGE  
ACCELEROMETER FOR MEMS ABOVE IC  
INTEGRATION**

L. Wen<sup>1</sup>, B. Guo<sup>2</sup>, L. Haspeslagh<sup>2</sup>, S. Severi<sup>2</sup>, A.  
Witvrouw<sup>2</sup>, R. Puers<sup>1</sup>

<sup>1</sup>ESAT-MICAS, K.U.Leuven, Kasteelpark Arenberg 10,  
Leuven B-3001, Belgium

<sup>2</sup>IMEC, Kapeldreef 75, Leuven B-3001, Belgium

.....2046

**W3P.019 PHOTODIODE WITH MICRO TEXTURE FOR  
IMPROVING SENSITIVITY AT LARGE ANGLE OF  
INCIDENCE FOR PARTICLE SENSORS**

A. Isozaki<sup>1,2</sup>, K. Kuwana<sup>1,2</sup>, Y. Tomimatsu<sup>1,3</sup> and T.  
Itoh<sup>1,4</sup>

<sup>1</sup>BEANS Laboratory, Tsukuba, Japan

<sup>2</sup>The University of Tokyo, Tokyo, Japan

<sup>3</sup>Seiko Instruments Inc., Chiba, Japan

<sup>4</sup>AIST, Tsukuba, Japan

.....2050

**W3P.020 ARTIFICIAL HAIR CELL WITH EMBEDDED  
PIEZORESISTIVE FORCE SENSORS**

Ji-Eun Han<sup>1</sup>, Dongil Kim<sup>2</sup> and Kwang-Seok Yun<sup>2</sup>

<sup>1</sup>Samsung Electronics, Giheung, Korea

<sup>2</sup>Department of Electronic Engineering, Sogang  
University, Seoul, Korea

.....2054

**W3P.021 THE SENSITIVITY ENHANCEMENT FOR THE  
RADIATION SENSOR BASED ON FILM BULK  
ACOUSTIC-WAVE RESONATOR**

J. Oiler<sup>1</sup>, X. Qiu<sup>1</sup>, J. Zhu<sup>1</sup>, R. Tang<sup>1</sup>, S.J. Chen<sup>2</sup>, H.  
Huang<sup>1</sup>, K. Holbert<sup>1</sup>, H. Barnaby<sup>1</sup>, and H. Yu<sup>1</sup>

<sup>1</sup>Arizona State University, Tempe, Arizona, USA

<sup>2</sup>University of Southern California, Los Angeles,  
California, USA

.....2058

**W3P.022 ALUMINUM NITRIDE PMUT BASED ON A  
FLEXURALLY-SUSPENDED MEMBRANE**

A. Guedes<sup>1\*</sup>, S. Shelton<sup>1</sup>, R. Przybyla<sup>2</sup>, I.  
Izyumin<sup>2</sup>, B. Boser<sup>2</sup> and D.A. Horsley<sup>1</sup>

<sup>1</sup>Berkeley Sensor & Actuator Center, University of  
California, Davis, CA, USA

<sup>2</sup>Berkeley Sensor & Actuator Center, University of  
California, Berkeley, CA, USA

.....2062

**W3P.023 A NOVEL MICRO-G, EXTENDED RANGE,  
SOI-MEMS PIEZORESISTIVE  
TIME-ACCELEROMETER OPERATING IN TWO  
DISTINCT TIME-BASED TRANSDUCTION MODES**

V. Rajaraman<sup>1</sup>, B.S. Hau<sup>1</sup>, L.A. Rocha<sup>2</sup>, R.A.  
Dias<sup>2</sup>, K.A.A. Makinwa<sup>1</sup> and R. Dekker<sup>1</sup>

<sup>1</sup>Dept. of Microelectronics, Fac. EEMCS, Delft  
University of Technology (TU Delft), The Netherlands

<sup>2</sup>I3N/IPC, School of Engineering, University of Minho,  
Guimarães, Portugal

.....2066

**W3P.024 A MICROMECHANICAL ULTRASONIC DISTANCE SENSOR WITH >1 METER RANGE**

Richard Przybyla<sup>1\*</sup>, Anita Flynn<sup>1</sup>, Vipul Jain<sup>1</sup>, Stefan Shelton<sup>2</sup>, André Guedes<sup>2</sup>, Igor Izyumin<sup>1</sup>, David Horsley<sup>2</sup>, and Bernhard Boser<sup>1</sup>

Berkeley Sensor and Actuator Center

<sup>1</sup>University of California, Berkeley, CA, USA

<sup>2</sup>University of California, Davis, CA, USA

.....2070

**Chemical Sensors and Microsystems**

**W3P.025 FLOW INSENSITIVE THERMAL CONDUCTIVITY DETECTOR FOR  $\mu$ GAS CHROMATOGRAPHY**

B.C. Kaanta<sup>1</sup>, H. Chen<sup>2</sup>, and X. Zhang<sup>1\*</sup>

<sup>1</sup>Boston University, Boston, MA, USA

<sup>2</sup>Schlumberger Doll Research, Cambridge, MA, USA

.....2074

**W3P.026 MICROFABRICATED ELECTROSPRAY IONIZATION CHIP WITH 60 TIPS FOR HIGH THROUGHPUT MASS SPECTROMETRIC ANALYSES**

L. Sainiemi<sup>1,2\*</sup>, T. Nissilä<sup>2,3</sup>, R. Kostianen<sup>2</sup>, R. A. Ketola<sup>3</sup> and S. Franssila<sup>1</sup>

<sup>1</sup>Department of Materials Science and Engineering, Aalto University School of Science and Technology, Helsinki, Finland

<sup>2</sup>Division of Pharmaceutical Chemistry, University of Helsinki, Helsinki, Finland

<sup>3</sup>Centre for Drug Research, University of Helsinki, Helsinki, Finland

.....2078

**W3P.027 A MEMS GAS CHROMATOGRAPH FOR RAPID DETERMINATIONS OF EXPLOSIVE MARKER COMPOUNDS**

E. T. Zellers<sup>1,2,3</sup>, G. Serrano<sup>1,2</sup>, H. Chang<sup>1,2</sup> and L.K. Amos<sup>1,3</sup>

<sup>1</sup>Center for Wireless Integrated MicroSystems (WIMS),

<sup>2</sup>Departments of Environmental Health Sciences,

<sup>3</sup>Chemistry, University of Michigan, Ann Arbor, Michigan, USA

.....2082

**W3P.028 MINIATURISED GAS CHROMATOGRAPHIC SYSTEM WITH METAL OXIDE GAS SENSOR ARRAY FOR FAST DETECTION OF OFF-FLAVOURS**

M.-L. Bauersfeld<sup>1</sup>, M. Bücking<sup>2</sup>, J. Bruckert<sup>2</sup>, J. Wöllenstein<sup>1</sup>

<sup>1</sup>Fraunhofer Institute for Physical Measurement Technique IPM, Freiburg, Germany

<sup>2</sup>Fraunhofer Institute for Molecular Biology and Applied Ecology IME, Schmallingenberg-Grafschaft, Germany

.....2086

**W3P.029 LOW-LEAKAGE GAS SAMPLE-INJECTION SYSTEM FOR GAS CHROMATOGRAPHY IN HARSH ENVIRONMENTS**

Kinda Nacheff<sup>1,2</sup>, Frédéric Marty<sup>1</sup>, Kamran Danaie<sup>2</sup>, Bertrand Bourlon<sup>2</sup>, Eric Donzier<sup>2</sup> and Tarik Bourouina<sup>1</sup>

<sup>1</sup>ESIEE-Université Paris Est, Noisy-le-Grand, FRANCE

<sup>2</sup>Schlumberger MEMS, Elancourt, FRANCE

.....2090

**W3P.030 DEVELOPMENT OF A NOVEL MICROPRECONCENTRATOR FOR MICRO GAS CHROMATOGRAPH**

W.-C. Tian<sup>1\*</sup>, H.-J. Shheen<sup>2</sup>, T.-H. Wu<sup>2</sup>, C.-J. Lu<sup>3</sup>, W.-R. Chen<sup>3</sup> and T.-Y. Wei<sup>2</sup>

<sup>1</sup>Department of Electrical Engineering, National Taiwan University, Taipei, Taiwan

<sup>2</sup>Institute of Applied Mechanics, National Taiwan University, Taipei, Taiwan

<sup>3</sup>Department of Chemistry, National Taiwan Normal University, Taipei, Taiwan

.....2094

**W3P.031 ELECTROLYTIC CHARGE INVERSION AT PROGRAMMABLE CMOS SENSOR INTERFACES**

Krishna Jayant, Mark R. Hartman, Joshua B. Phelps, Philip H. Gordon, Dan Luo, Lois Pollack and Edwin C. Kan

<sup>1</sup>Electrical and Computer Engineering,

<sup>2</sup>Applied and Engineering Physics, <sup>3</sup>Biological Engineering, Cornell University, Ithaca, NY, USA 14850

.....2098

**W3P.032 CYCLODEXTRIN-BASED MICRO NEUROTRANSMITTER SENSOR FOR SELECTIVE CATECHOLAMINE HORMONE DETECTION**

Jung-Hoon Yang<sup>1</sup>, Hyun Tae Kim<sup>1</sup>, Jung Woo Park<sup>2</sup>, and Hanseup Kim<sup>1</sup>

<sup>1</sup>Electrical and Computer Engineering,

<sup>2</sup>Mechanical Engineering, University of Utah, Salt Lake City, UT 84112-9206

.....2102

**W3P.033 DUAL PHOTONIC ELECTROCHEMICAL LAB ON A CHIP FOR LACTATE DETECTION IN CONTINUOUS FLOW MODE**

O. Ordeig<sup>1</sup>, P. Ortiz<sup>1</sup>, X. Muñoz-Berbel<sup>1</sup>, S. Demming<sup>2</sup>, S. Büttgenbach<sup>2</sup>, C.

Fernández-Sánchez<sup>1</sup> and A. Llobera<sup>1</sup>

<sup>1</sup>Instituto de Microelectronica de Barcelona (IMB-CNM, CSIC), Bellaterra, Spain

<sup>2</sup>Institut für Mikrotechnik, Braunschweig, Germany

.....2106

**W3P.034 J H J N [ UGP UKW KW ] QHRQVCUBWO 'KQ' F G VGEVKQ P TGCNK GF 'QP' HNWQTRP CVGF/J HQ4'DJ 'HNWQTRP' KO RNCPCVQIP 'QP' GHU**

Kuan-I Ho<sup>1</sup>, Tseng-Fu Lu<sup>1</sup>, Meng-Cin Su<sup>1</sup>,

Jer-Chyi Wang<sup>1,2</sup>, Chia-Ming Yang<sup>3</sup>, Dorota G. Pijanswska<sup>4</sup> and Chao-Sung Lai<sup>1,2,\*</sup>

<sup>1</sup>Department of Electronic Engineering, Chang Gung University, Tao-Yuan, Taiwan

<sup>2</sup>Biosensor Group, Biomedical Engineering Center, Chang Gung University, Tao-Yuan, Taiwan

<sup>3</sup>Inotera Memories, Inc., Tao-Yuan, Taiwan

<sup>4</sup>Nalecz Institute of Biocybernetics and Biomedical Engineering, Polish Academy of Sciences, Warsaw, Poland

.....2110  
**W3P.035 DESIGN OF WIRELESS SENSOR NODE BASED ON A NOVEL HYBRID CHEMICAL SENSOR FOR HEAVY METAL MONITORING**

W. Cai, H.X. Zhao, D.Ha, H.S. Guo, W. Zhang, and P. Wang

*Department of Biomedical Engineering, Zhejiang University, Hangzhou, Zhejiang, China*  
*Biosensor National Special Laboratory, Key Laboratory of Biomedical Engineering of Ministry of Education*

.....2114  
**W3P.036 FUNCTIONALIZATION OF NANOSCALED 2-NM-THICK ALD-HFO<sub>2</sub> LAYER BY RAPID THERMAL ANNEALING AND CF<sub>4</sub> PLASMA FOR LAPS NH<sub>4</sub><sup>+</sup> DETECTION**

Jung-Hsiang Yang<sup>1</sup>, Tseng-Fu Lu<sup>1</sup>, Jer-Chyi Wang<sup>1,2</sup>, Dorota G. Pijanswska<sup>3</sup>, Chi-Hang Chin<sup>4</sup>, Cheng-En Lue<sup>1</sup>, Chia-Ming Yang<sup>5</sup>, and Chao-Sung Lai<sup>1,2\*</sup>

<sup>1</sup>*Department of Electronic Engineering, Chang Gung University, Taoyuan, Taiwan*

<sup>2</sup>*Biosensor Group, Biomedical Engineering Center, Chang Gung University, Taoyuan, Taiwan*

<sup>3</sup>*Nalecz Institute of Biocybernetics and Biomedical Engineering, Polish Academy of Sciences, Warsaw, Poland*

<sup>4</sup>*Institute of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, Taiwan*

<sup>5</sup>*Inotera Memories, Inc., Taoyuan, Taiwan*

.....2118  
**W3P.037 A PHOTOVOLTAGE-BASED INTEGRATED SENSOR FOR NEPHROTOXICITY EVALUATION UNDER DRUG STIMULATION**

J. Wang, H. Yu, H. Cai, L.P. Du, Q.J. Liu, and P. Wang

*Biosensor National Special Laboratory, Key Lab of Biomedical Engineering of Education Ministry, Department of Biomedical Engineering, Zhejiang University, Hangzhou, 310027, P. R. China*

.....2122  
**W3P.038 VJ GQTGVIECN'CPF'GZRGTKD GP VCN R'XGUVH CVIQP'QHWVNTCJ K J 'UGPUW'KKW' 'QH Y CXGNGPI VJ /R'VGT'QI CVGF'UWTHCEG RNCUO QP 'TGUQP CPEG'UGP UQTU**

Q. Liu, Z.-M. Qi\*, Z. Zhang, and D.-F. Lu  
*State Key Laboratory of Transducer Technology, Institute of Electronics, Chinese Academy of Sciences, Beijing 100190, China*

.....2126  
**W3P.039 MULTI-WELL STRUCTURE FOR CELL CULTURE ON THE CHEMICAL IMAGING SENSOR**

K. Miyamoto<sup>1</sup>, T. Wagner<sup>1</sup>, M. J. Schöning<sup>2,3</sup>, and T. Yoshinobu<sup>1,4</sup>

<sup>1</sup>*Department of Electronic Engineering, Tohoku University, JAPAN*

<sup>2</sup>*Institute of Nano- and Biotechnologies, Aachen University of Applied Sciences, GERMANY*

<sup>3</sup>*Institute of Bio- and Nanosystems (IBN-2), Research*

*Centre Jülich, GERMANY*

<sup>4</sup>*Department of Biomedical Engineering, Tohoku University, JAPAN*

.....2130  
**W3P.040 FLEXIBLE ELECTROCHEMICAL IMAGING BY LIGHT-ADDRESSABLE POTENTIOMETRIC SENSOR WITH "ZOOM-IN" FUNCTIONALITY**

T. Wagner<sup>1</sup>, K. Miyamoto<sup>1</sup>, C.F. Werner<sup>2</sup>, M.J. Schöning<sup>2</sup> and T. Yoshinobu<sup>1,3</sup>

<sup>1</sup>*Department of Electronic Engineering, Tohoku University, Sendai, MIYAGI, JAPAN*

<sup>2</sup>*Institute of Nano- and Biotechnology, Aachen University of Applied Sciences, Jülich, NRW, GERMANY*

<sup>3</sup>*Department of Biomedical Engineering, Tohoku University, Sendai, MIYAGI, JAPAN*

**Bio-Sensors and Bio-Microsystems**

.....2133  
**W3P.041 STICTION-FREE POLY-SIGE RESONATORS FOR MONOLITHIC INTEGRATION OF BIOSENSORS WITH CMOS**

S. Lenci<sup>1</sup>, F. Pieri<sup>2</sup>, L. Haspeslagh<sup>1</sup>, J. De Coster<sup>1</sup>, S. Decoutere<sup>1</sup>, A. Maestre Caro<sup>1,3</sup>, S. Armini<sup>1</sup> and A. Witvrouw<sup>1</sup>

<sup>1</sup>*Imec, Leuven, Belgium*

<sup>2</sup>*University of Pisa, Pisa, Italy*

<sup>3</sup>*KULeuven, Leuven, Belgium*

.....2136  
**W3P.042 FLUORESCENT HYDROGEL FIBERS FOR LONG-TERM IN VIVO GLUCOSE MONITORING**

Y. J. Heo<sup>1,2</sup>, H. Shibata<sup>2,3</sup>, T. Okitsu<sup>2,4</sup>, T. Kawanishi<sup>2,3</sup>, and S. Takeuchi<sup>1,2</sup>

<sup>1</sup>*Institute of Industrial Science, The University of Tokyo, Tokyo, Japan*

<sup>2</sup>*Life BEANS Center, BEANS Project, Tokyo, Japan*

<sup>3</sup>*TERUMO Co. Headquarters, Kanagawa, Japan*

<sup>4</sup>*Kyoto University Hospital, Kyoto, Japan*

.....2140  
**W3P.043 COMPARISON OF EXTRACELLULAR SIGNALS BETWEEN GOLD AND CARBON NANOTUBES BASED MICROELECTRODE ARRAYS**

C.H. Chen, L.H. Chen, H.C. Su, S.C. Chuang, S.R. Yeh, T.R. Yew, Y.C. Chang and D.J. Yao\*

*National Tsing Hua University, Hsinchu, TAIWAN*

.....2144  
**W3P.044 A HIGH-THROUGHPUT FULLY-AUTOMATED MICROFLUIDIC LIVE CELL ARRAY FOR COMBINATION DRUG TREATMENT ANALYSIU' OF COLORECTAL CANCER CELLS "**

H. Wang<sup>1</sup>, J.Kim<sup>2</sup>, A. Jayaraman<sup>2,3</sup>, M. Cypert<sup>4</sup>, J. Hua<sup>4</sup>, M. Bittner<sup>4</sup>, and A. Han<sup>1,3\*</sup>

<sup>1</sup>*Department of Electrical and Computer Engineering, Texas A&M University, College Station, TX, USA*

<sup>2</sup>*Department of Chemical Engineering, Texas A&M University, College Station, TX, USA*

<sup>3</sup>*Department of Biomedical Engineering, Texas A&M*

University, College Station, TX, USA

<sup>4</sup>Translational Genomics Research Institute, Phoenix, AZ, USA

.....2148

**W3P.045 MICROENGINEERED IRON AND IRON-OXIDE CONTRAST AGENT PARTICLES FOR TUNABLE MULTISPECTRAL MAGNETIC RESONANCE IMAGING**

X. Wang<sup>1</sup>, S.W. Anderson<sup>2</sup>, and X. Zhang<sup>1</sup>

<sup>1</sup>Department of Mechanical Engineering, Boston University, Boston, MA, USA

<sup>2</sup>Department of Radiology, Boston Medical Center, Boston, MA, USA

.....2152

**W3P.046 THE EFFECT OF SEQUENCE LENGTH ON DNA DECORATED CNT GAS SENSORS**

Y. Liu<sup>1</sup>, M. Chen<sup>2</sup>, M. Mohebbi<sup>1</sup>, M.L. Wang<sup>3</sup>, and M. R. Dokmeci<sup>1</sup>

<sup>1</sup>ECE, Northeastern University, Boston, MA, USA

<sup>2</sup>Point Loma Nazarene University, San Diego, CA, USA

<sup>3</sup>CEE, Northeastern University, Boston, MA, USA

.....2156

**W3P.047 TEMPERATURE MODULATED EXCITATION AND PHASE SENSITIVE DETECTION TO SELECTIVELY IMAGE DNA SEQUENCES**

K. Zrelli<sup>1</sup>, E. Cavatore<sup>2</sup>, T. Barilero<sup>1</sup>, H. Berthoumieux<sup>1,3</sup>, V. Croquette<sup>2</sup>, T. Le Saux<sup>1</sup>, L. Jullien<sup>1</sup>, A. Lemarchand<sup>3</sup>, and C. Gosse<sup>4</sup>

<sup>1</sup>Département de Chimie, École Normale Supérieure – CNRS, Paris, France

<sup>2</sup>Laboratoire de Physique Statistique, École Normale Supérieure – CNRS, France

<sup>3</sup>Laboratoire de Physique Théorique de la Matière Condensée, Université Paris 6 – CNRS, France

<sup>4</sup>Laboratoire de Photonique et de Nanostructures, LPN-CNRS, Marcoussis, France

.....2160

**W3P.048 A NOVEL MICRONEEDLE-BASED NON-ENZYMATIC GLUCOSE SENSOR FOR PAINLESS DIABETES TESTING APPLICATION**

Y.-S. Yoon<sup>1</sup>, J. Kim<sup>1</sup>, K. Lee<sup>1</sup>, H. Song<sup>1,2</sup>, K. Yoo<sup>1,3</sup>, G. Lee<sup>1</sup> and J.-B. Lee<sup>1</sup>

<sup>1</sup>Department of Electrical Engineering, The University of Texas at Dallas, TX, USA

<sup>2</sup>Inje University, Gimhae, Korea

<sup>3</sup>Hanbat national University, Daejeon, Korea

.....2164

**W3P.049 CELL-BASED SURFACE ACOUSTIC WAVE RESONANT MICROSENSOR FOR DNA QUANTIFICATION**

Z. Rácz<sup>1</sup>, M. Cole<sup>1</sup>, J.W. Gardner<sup>1</sup>, S. Pathak<sup>1</sup>, M.D. Jordan<sup>2</sup>, and R.A.J. Challiss<sup>2</sup>

<sup>1</sup>Sensors Research Laboratory, University of Warwick, Coventry, UK

<sup>2</sup>Department of Cell Physiology and Pharmacology, University of Leicester, Leicester, UK

.....2168

**Medical Microsystems**

**W3P.050 A MEMS INTRAOCULAR ORIGAMI COIL**

Y. Zhao, M.S. Nandra, Y.C. Tai

California Institute of Technology, Pasadena, CA, USA

.....2172

**W3P.051 A WIRELESS AND BATTERYLESS MICROSYSTEM WITH IMPLANTABLE GRID ELECTRODE/3-DIMENSIONAL PROBE ARRAY FOR ECG AND EXTRACELLULAR NEURAL RECORDING ON RAT**

C.W. Chang<sup>1</sup>, Y.J. Chen<sup>1</sup>, S.H. Hung<sup>1</sup> and J.C. Chiou<sup>1,2</sup>

<sup>1</sup>National Chiao-Tung University, Hsinchu, Taiwan.

<sup>2</sup>China Medical University, Taichung, Taiwan

.....2176

**W3P.052 TEMPERATURE SENSING PROBE INTEGRATED WITH AN SU-8 FLEXIBLE RIBBON CABLE FOR HEART SURGERY APPLICATION**

Kuei-Shu Li<sup>1</sup>, Tzu-Yuan Chao<sup>1</sup>, Y. T. Cheng<sup>1</sup>, Jing-Kuang Chen<sup>2</sup> and Yih-Shang Chen<sup>3</sup>

<sup>1</sup>Department of Electronics Engineering, National Chiao Tung University, Hsinchu, Taiwan

<sup>2</sup>Department of Electrical and Computer Engineering, University of New Mexico, USA

<sup>3</sup>Department of Cardiovascular Surgery, National Taiwan University Hospital, Taipei, Taiwan

.....2180

**W3P.053 A NOVEL IMPLANTABLE SAW SENSOR FOR BLOOD PRESSURE MONITORING**

B. Liang<sup>1</sup>, L. Fang<sup>1</sup>, C.L. Tu<sup>1</sup>, C.C. Zhou<sup>1</sup>, X.J. Wang<sup>1</sup>, Q. Wang<sup>1</sup>, P. Wang<sup>1</sup>, X.S. Ye<sup>1\*</sup>

<sup>1</sup>Biomedical Sensors National Special Laboratory, College of Biomedical Engineering & Instrument

Science, Zhejiang University, Hangzhou, China

.....2184

**W3P.054 A PHOTOACOUSTIC IMAGER WITH INFRARED ILLUMINATION THROUGH THE CMUT CHIP**

M. Wang<sup>1</sup>, J. Chen<sup>1</sup>, Y.-H. Wang<sup>2</sup>, and P.-C. Li<sup>2,R</sup>, Bhandari<sup>1</sup>, S. Negi<sup>1</sup>, and F. Solzbacher<sup>1,2</sup>

<sup>1</sup>Blackrock Microsystems, Salt Lake City, Utah, USA

<sup>2</sup>University of Utah, Salt Lake City, Utah, USA

.....2188

**W3P.055 POST-OPERATIVE WIRELESS PLATFORM FOR IN-VIVO MONITORING AND TREATMENT**

D. Subbaiyan<sup>1</sup>, L.S. Pakula<sup>1</sup>, P.J. French<sup>1</sup>, J.F. Lange<sup>2</sup>, J. Jeekel<sup>2</sup>, G.J. Kleinrensink<sup>2</sup>, H.J.C. Sterenborg<sup>2</sup>, D.J. Robinson<sup>2</sup>, F. van Zaane<sup>2</sup>, J.G. Kaptein<sup>1</sup>, K. Tang<sup>1</sup>, G. Pandraud<sup>1</sup>, J. van Veen<sup>3</sup>, M. Draaijer<sup>4</sup> & K.A. Vakalopoulos<sup>2</sup>

<sup>1</sup>TU Delft, Delft, The Netherlands

<sup>2</sup>Erasmus Medical Center, Rotterdam, The Netherlands,

<sup>3</sup>TNO, Delft, The Netherlands,

<sup>4</sup>Fytogoras, Leiden, The Netherlands

.....2192

- W3P.056 A NOVEL SURFACE MODIFICATION METHOD TO ACHIEVE LOW IMPEDANCE NEURAL MICROELECTRODE ARRAYS**  
 R. Bhandari<sup>1</sup>, S. Negi<sup>1</sup>, and F. Solzbacher<sup>1,2</sup>  
<sup>1</sup>Blackrock Microsystems, Salt Lake City, Utah, USA  
<sup>2</sup>University of Utah, Salt Lake City, Utah, USA  
 .....2196

**Microfluidics**

- W3P.057 A CELL ELECTROPORATION AND VIABILITY MONITORING CHIP USING A SINGLE CHANNEL WITH MULTIPLE ELECTRIC FIELD ZONES**  
 Min-Ji Kim, Taeyoon Kim, and Young-Ho Cho  
 Cell Bench Research Center, Daejeon, Republic of Korea  
 .....2200
- W3P.058 SPECIFIC AND LABEL-FREE IMMUNOGLOBULIN G ANTIBODY DETECTION USING NANO POROUS HYDROGEL PHOTONIC CRYSTALS**  
 Eunpyo Choi<sup>1</sup>, Yuri Choi<sup>2</sup>, and Jungyul Park<sup>1,2\*</sup>  
<sup>1</sup>Department of Mechanical Engineering, Sogang University, Seoul, Korea  
<sup>2</sup>Interdisciplinary Program of Integrated Biotechnology, Sogang University, Seoul, Korea  
 .....2203
- W3P.059 A SUBMERSIBLE PIEZORESISTIVE MEMS LATERAL FORCE SENSOR FOR CELLULAR BIOMECHANICS APPLICATIONS**  
 M. Gnerlich, S.F. Perry, S. Tatic-Lucic  
 Lehigh University, Bethlehem, PA, USA  
 .....2207
- W3P.060 MANIPULATION OF ELECTRICAL CHARGE OF PROTEINS FOR SENSITIVE BIOSENSING USING FIELD-EFFECT TRANSISTORS**  
 T. Goda and Y. Miyahara  
 Institute of Biomaterials and Bioengineering, Tokyo Medical and Dental University  
 .....2211
- W3P.061 PCR ON A PDMS-BASED MICROCHIP WITH INTEGRATED BUBBLE REMOVAL**  
 J.M. Karlsson<sup>1</sup>, T. Haraldsson<sup>1</sup>, S. Laakso<sup>2</sup>, A. Virtanen<sup>2</sup>, M. Mäki<sup>2</sup>, G. Ronan<sup>3</sup>, and W. van der Wijngaart<sup>1</sup>  
<sup>1</sup>Microsystem Technology Lab, KTH Royal Institute of Technology, Stockholm, SWEDEN  
<sup>2</sup>Mobidiag OY, Helsinki, FINLAND  
<sup>3</sup>Farfield Group, Manchester, UNITED KINGDOM  
 .....2215
- W3P.062 TUNABLE SENSITIVITY AND LINEARITY OF SELF-ASSEMBLED CARBON NANOTUBE COMPOSITE BASED pH BIOSENSORS USING SILICA NANOPARTICLES**  
 Dongjin Lee and Tianhong Cui\*  
 Department of Mechanical Engineering, University of Minnesota, Minneapolis, MN 55455, U.S.A.  
 .....2219

- W3P.063 PATTERN GENERATION OF A MICROFLUIDIC-BASED BIOSENSOR TO DETECT C-REACTIVE PROTEIN USING THE COMPETITIVE PROTEIN ADSORPTION**  
 S. Choi, A. Lajevardi-khosh, and J. Chae  
 School of Electrical, Computer and Energy Engineering, Arizona State University, Tempe, Arizona, USA  
 .....2223
- W3P.064 ON-DEMAND MICRO ENCAPSULATION UTILIZING ON-CHIP SYNTHESIS OF SEMI-PERMEABLE ALGINATE-PLL CAPSULES**  
 S.C. Chang, J.J. Wang, C.W. Chang, and Y.C. Su\*  
 Department of Engineering and System Science National Tsing Hua University, Hsinchu, Taiwan  
 .....2227
- W3P.065 A WIRELESS LOVE WAVE BIOSENSOR PLATFORM FOR SIMULTANEOUS DETECTIONS OF TWO DIFFERENT BIOMOLECULES**  
 T. Song<sup>1</sup>, S.Y. Song<sup>2</sup>, H.C. Yoon<sup>2</sup> and K. Lee<sup>1</sup>  
<sup>1</sup>Department of Electrical and Computer Engineering, Ajou University, Suwon, S. Korea  
<sup>2</sup>Department of Molecular Science and Technology, Ajou University, Suwon, S. Korea  
 .....2231
- W3P.066 PLANT PATHOGEN SPORES GROW IN MICROFLUIDIC DROPLETS: A HIGH-THROUGHPUT APPROACH TO ANTIFUNGAL DRUG SCREENING**  
 Haifeng Yang<sup>1</sup>, Madan K. Bhattacharyya,<sup>2</sup> and Liang Dong<sup>1,\*</sup>  
<sup>1</sup>Department of Electrical and Computer Engineering, Iowa State University, Ames, Iowa, USA  
<sup>2</sup>Department of Agronomy, Iowa State University, Ames, Iowa, USA  
 .....2235
- W3P.067 PRECISE SAMPLE POSITIONING FOR MULTIPOINT IMMUNOASSAY USING NANOFLUIDIC PRECONCENTRATOR**  
 K. P. Liao<sup>1</sup>, K.B. Sung<sup>1</sup>, and W. -C. Tian<sup>1,\*</sup>  
<sup>1</sup>Department of Electrical Engineering, National Taiwan University, Taipei, Taiwan  
 .....2239
- W3P.068 POLYMER OPTO-MECHANICAL TRANSDUCER FOR ABNORMAL CELL CONTRACTION DIAGNOSTICS**  
 Xiaoyu Zheng, and Xin Zhang  
 Laboratory for Microsystems Technology, Department of Mechanical Engineering, Boston University, Boston, MA 02215, USA  
 .....2243
- W3P.069 CHEMICAL INDUCED IMPEDANCE SPECTROSCOPY FOR SINGLE CANCER CELL DETECTION**  
 Vaishnavi Srinivasaraghavan, Jeannine Strobl, Masoud Agah  
 VT MEMS Lab, Virginia Tech., Blacksburg, VA, USA  
 .....2247
- W3P.070 A 3-D CAPILLARY-ENDOTHELIUM-MIMETIC**

- MICROFLUIDIC CHIP FOR STUDYING THE EXTRAVASATION BEHAVIOUR OF NEUTROPHILS**  
Tushar H. Punde<sup>1</sup>, Wen-Hao Wu<sup>2</sup>, Po-Chen Shih<sup>2</sup>, Chien-Yu Fu<sup>3</sup>, Tsung-Pao Wang<sup>3</sup>, Long Hsu<sup>4</sup>, Hawn-You Chang<sup>3</sup>, Cheng-Hsien Liu<sup>2</sup>  
<sup>1</sup>Institute of NanoEngineering and Microsystems,  
<sup>2</sup>Department of Power Mechanical Engineering,  
<sup>3</sup>Institute of Molecular Medicine, National Tsing Hua University,  
<sup>4</sup>Department of Electrophysics, National Chiao Tung University, Hsinchu, Taiwan, R.O.C.  
.....2251
- W3P.071 A LATERALLY RESONATING GRAVIMETRIC SENSOR WITH UNIFORM MASS SENSITIVITY AND HIGH LINEARITY**  
D. E Eroglu<sup>1</sup>, E. Bayraktar<sup>1</sup>, and H. Kulah<sup>1,2</sup>  
<sup>1</sup>Department of Electrical & Electronics Engineering, METU, Ankara, TURKEY  
<sup>2</sup>METU-MEMS Research & Applications Center, Ankara, TURKEY  
.....2255
- W3P.072 ULTRASENSITIVE DIELECTRIC FILLED LAMÉ MODE BIOMASS SENSOR**  
Amir Heidari<sup>1,2</sup>, Yong-Jin Yoon<sup>2</sup>, Mi Kyoung Park<sup>1</sup>, Woo-Tae Park<sup>1</sup> and Julius Tsai Ming Lin<sup>1</sup>  
<sup>1</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), Singapore, 117685, Singapore,  
<sup>2</sup>Department of Mechanical and Aerospace Engineering, Nanyang Technological University, Singapore, 639798, Singapore  
.....2259
- W3P.073 NANOSLIT BIOSENSOR WITH SINGLE-PIXEL RESOLVED KINETICS CAPABILITY: FINITE ELEMENT METHOD AND EXPERIMENTAL RESULTS**  
T. Leichlé<sup>1,2\*</sup>, and C.F. Chou<sup>3\*\*</sup>  
<sup>1</sup>CNRS; LAAS, Toulouse, France  
<sup>2</sup>Université de Toulouse; UPS, INSA, INP, ISAE; LAAS, Toulouse, France  
<sup>3</sup>Institute of Physics, Academia Sinica, Taipei, Taiwan  
.....2263
- W3P.074 IMPROVING SENSITIVITY OF PHOTONIC CRYSTAL-BASED BIOSENSORS BY A CAVITY ARRANGEMENT**  
M.H. Nguyen<sup>1</sup>, W.C. Chiu<sup>2</sup>, M.C. Lee<sup>2</sup>, and F.G. Tseng<sup>1</sup>  
<sup>1</sup>Department of Engineering and System Science, National TsingHua University, Hsinchu, Taiwan, China  
<sup>2</sup>Department of Electrical Engineering, National TsingHua University, Hsinchu, Taiwan, China Nuclear Science, National TsingHua University, Hsinchu, Taiwan, China  
.....2267
- W3P.075 LABEL-FREE DNA DETECTION BASED ON SILICON NANOWIRES**  
A.R. Gao<sup>1,2</sup>, N. Lu<sup>3</sup>, X.L. Gao<sup>1</sup>, P.F. Dai<sup>1,2</sup>, T. Li<sup>1</sup>, Y.B. Gong<sup>1</sup>, C.H. Fan<sup>3</sup> and Y.L. Wang<sup>1</sup>  
<sup>1</sup>State Key Laboratories of Transducer Technology, Science and Technology on Micro-system Laboratory, Shanghai Institute of Microsystem and Information Technology, CAS, Shanghai, China  
<sup>2</sup>Graduate School of Chinese Academy of Sciences, Beijing, China  
<sup>3</sup>Shanghai Institute of Applied Physics, Chinese Academy of Sciences, Shanghai, China  
.....2271
- W3P.076 MAGNETICALLY ACTUATED CELLULAR STRAIN ASSESSMENT TOOL; A STUDY ON THE STRAIN INDUCED DIRECTIONAL MIGRATION OF HUMAN ENDOTHELIAL CELLS**  
F. Khademolhosseini and M. Chiao  
Dept. of Mechanical Engineering, University of British Columbia, Vancouver r, B.C., Canada  
.....2275
- W3P.077 A MICROFLUIDIC SENSOR CHIP WITH RENEWABLE IN-SITU COPPER MODIFIED MICROELECTRODE FOR CONTINUOUS MONITORING OF NITRATE**  
Y. Li<sup>1,2</sup>, J.Z. Sun<sup>1</sup>, C. Bian<sup>1</sup>, J.H. Tong<sup>1</sup> and S.H. Xia<sup>1</sup>  
<sup>1</sup>State Key Laboratory of Transducer Technology, Institute of Electronics, Chinese Academy of Sciences, Beijing, China  
<sup>2</sup>Graduate University of Chinese Academy of Sciences, Beijing, China  
.....2279
- W3P.078 A MICROFLUIDIC DEVICE FOR HIGH FREQUENCY CHARACTERIZATION OF FLUIDS UNDER HIGH DC ELECTRIC FIELDS**  
C.S. Song and P.S. Wang  
Department of Electrical & Computer Engineering, Clemson University, Clemson, SC 29634, USA  
.....2283
- W3P.079 PROGRAMABLE MICROFLUIDIC PROCESSOR WITH PUMPING AND COULOMETRIC DETECTING FUNCTIONS**  
F. Sassa, Y. AL-Zain, T. Ginoza, J. Fukuda, S. Miyazaki, and H. Suzuki  
Graduate School of Pure and Applied Sciences, University of Tsukuba, Tsukuba, Ibaraki, JAPAN  
.....2287
- W3P.080 MICRO TITRATION DEVICE AND ITS APPLICATION TO RICE FRESHNESS MEASUREMENT**  
X. L. Qiu<sup>1</sup>, F. Sassa<sup>2</sup>, D. Itoh<sup>2</sup>, T. Satake<sup>1</sup>, and H. Suzuki<sup>2</sup>  
<sup>1</sup>Graduate School of Life and Environmental Sciences, University of Tsukuba, Tsukuba, Ibaraki, JAPAN  
<sup>2</sup>Graduate School of Pure and Applied Sciences, University of Tsukuba, Tsukuba, Ibaraki, JAPAN  
.....2291

**Materials, Fabrication and  
Packaging Technologies**

- W3P.081 ISOTROPIC ETCHING OF 111 SCS FOR WAFER-SCALE MANUFACTURING OF PERFECTLY HEMISPHERICAL SILICON MOLDS**  
 Laura C. Fegely, David N. Hutchison, and Sunil A. Bhave  
 OxideMEMS Lab, Cornell University, Ithaca, NY, USA  
 .....2295
- W3P.082 EPOXY-LESS PACKAGING METHODS FOR ELECTRICAL CONTACT TO PARYLENE-BASED FLAT FLEXIBLE CABLES**  
 Christian A. Gutierrez, Curtis Lee, Brian Kim and Ellis Meng  
 University of Southern California, Department of Biomedical Engineering, Los Angeles, CA, USA  
 .....2299
- W3P.083 HERMETIC PACKAGING OF RESONATORS WITH VERTICAL FEEDTHROUGHS USING A GLASS-IN-SILICON REFLOW PROCESS**  
 R. M. Haque<sup>1</sup>, D. E. Serrano<sup>2</sup>, X. Gao<sup>2</sup>, A. N.-Shirazi<sup>2</sup>, V. Keesara<sup>3</sup>, F. Ayazi<sup>2,3</sup>, and K. D. Wise<sup>1</sup>  
<sup>1</sup>The University of Michigan, Ann Arbor, MI, USA  
<sup>2</sup>Georgia Institute of Technology, Atlanta, GA, USA  
<sup>3</sup>Qualtré Inc., Marlborough, MA, USA  
 .....2303
- W3P.084 INTEGRATION OF ORGANIC OPTO-ELECTROWETTING AND POLY(ETHYLENE) GLYCOL DIACRYLATE (PEGDA) MICROFLUIDICS FOR DROPLET MANIPULATION**  
 Tung-Ming Yu<sup>1</sup>, Shih-Mo Yang<sup>1</sup>, Chien-Yu Fu<sup>3</sup>, Ming-Huei Liu<sup>4</sup>, Long Hsuland Cheng-Hsien Liu<sup>2</sup>  
<sup>1</sup>Department of Electrophysics, National Chiao-Tung University, Hsinchu, Taiwan  
<sup>2</sup>Department of Power Mechanical Engineering, National Tsing-Hua University, Hsinchu, Taiwan  
<sup>3</sup>Institute of molecular medicine, National Tsing Hua University, Hsinchu, Taiwan  
<sup>4</sup>Sinonar Corp. , Hsinchu, Taiwan  
 .....2307
- W3P.085 BIO-INSPIRED 3D SELF-PATTERNING OF FUNCTIONAL COATINGS FOR PDMS MICROFLUIDICS**  
 Tianzhun Wu<sup>1,2</sup>, Hiroaki Suzuki<sup>2,3</sup>, and Tetsuya Yomo<sup>2,3,4</sup>  
<sup>1</sup>School of Physics and Engineering, Sun Yat-sen University, CHINA  
<sup>2</sup>ERATO, JST, JAPAN  
<sup>3</sup>Graduate School of Information Science and Technology, Osaka University, JAPAN  
<sup>4</sup>Graduate School of Frontier Biosciences, Osaka University, JAPAN  
 .....2311
- W3P.086 POLYMER MEMS FABRICATION PROCESS FOR SELF-ASSEMBLED MILLIMETER-WAVE ON-CHIP ANTENNAS**  
 S.-W. Lee and M. Parameswaran (Ash)<sup>1</sup>  
<sup>1</sup>Institute of Micromachine and Microfabrication Research (IMMR), School of Engineering Science, Simon Fraser University, Burnaby, B.C., Canada  
 .....2315
- W3P.087 SUPPRESSION OF WEAR IN CYCLICALLY LOADED POLYCRYSTALLINE SILICON MEMS VIA A THIN SILICON CARBIDE COATING**  
 I. Laboriante<sup>1</sup>, N. Klejwa<sup>2</sup>, A. Suwandi<sup>1</sup>, C. Carraro<sup>1</sup>, Roger T. Howe<sup>2</sup>, and R. Maboudian<sup>1</sup>  
<sup>1</sup>Department of Chemical and Biomolecular Engineering, University of California, Berkeley, CA, USA  
<sup>2</sup>Department of Electrical Engineering, Stanford University, Stanford, CA, USA  
 .....2319
- W3P.088 OUT-OF-PLANE ASSEMBLY OF 3D NEURAL PROBE ARRAYS USING A PLATFORM WITH SU-8-BASED THERMAL ACTUATORS**  
 S. Herwik, T. Holzhammer, O. Paul, and P. Ruther  
 Microsystem Materials Laboratory, Department of Microsystems Engineering, University of Freiburg, Freiburg, Germany  
 .....2323
- W3P.089 HIGH PERFORMANCE 18F- CONCENTRATION ELECTRODE FOR PET APPLICATION BY USING INTERDIGITATED MICROSTRUCTURE AND PYROLYZED POLYMER/GLASSY CARBON COMPOSITE**  
 A. Akazawa<sup>1</sup>, Y. Furuno<sup>1</sup>, H. Saiki<sup>2</sup>, E. Ozeki<sup>2</sup> and S. Konishi<sup>1</sup>  
<sup>1</sup>Department of Micro System Technology, Ritsumeikan University, Shiga, Japan  
<sup>2</sup>Technology Research Laboratory, Shimadzu Corporation, Kyoto, Japan  
 .....2327
- W3P.090 FABRICATION OF HIGH ASPECT RATIO CARBON NANOTUBE-CARBON COMPOSITE MICROSTRUCTURES BASED ON SILICON MOLDING TECHNIQUE**  
 Liang He<sup>1</sup>, Masaya Toda<sup>1</sup>, Yusuke Kawai<sup>1</sup>, Hidetoshi Miyashita<sup>2</sup>, Chuanyu Shao<sup>1</sup>, Mamoru Omori<sup>3</sup>, Toshiyuki Hashida<sup>3</sup>, and Takahito Ono<sup>1</sup>  
<sup>1</sup>Department of Mechanical Systems and Design, Tohoku University, Sendai, Miyagi, Japan  
<sup>2</sup>Microsystem Integration Center, Tohoku University, Sendai, Miyagi, Japan  
<sup>3</sup>Fracture and Reliability Research Institute, Tohoku University, Sendai, Miyagi, Japan  
 .....2331
- W3P.091 DIELECTROPHORESIS FORMATION OF ELLIPSOIDAL PDMS MICRO-LENS ARRAY DIAGONALLY ALIGNED ON FLEXIBLE MEMBRANE**  
 Y.-C. Wang, Y.-C. Tsai, W.-P. Shih

Department of Mechanical Engineering, National Taiwan University, Taipei, Taiwan

.....2335

**W3P.092 UV LASER DICING WITHOUT FAILURE CAUSED BY CONTAMINATION AND HEAT FOR THICK ANODICALLY BONDED SILICON/GLASS MEMS WAFERS**

D.B. Xiao<sup>1</sup>, X. Zhang<sup>1</sup>, Z.Q. Hou<sup>1</sup>, X.Z. Wu<sup>1</sup>, Z.H. Chen<sup>1</sup>, Y. Pan<sup>2</sup>, X.D. Wu<sup>2</sup>

<sup>1</sup>National University of Defense Technology, Changsha, Hunan, China

<sup>2</sup>Suzhou Delphi Laser Co., Suzhou, Jiangsu, China

.....2339

**W3P.093 PROGRAMMABLE MICROPATTERNING OF NANOFIBERS FOR FUNCTIONAL TISSUE ENGINEERING**

B. Kim, H. Borteh, H. Zeng and Y. Zhao

Laboratory for Biomedical Microsystems, Department of Biomedical Engineering

The Ohio State University, Columbus, Ohio, USA

.....2343

**W3P.094 RAPID NON-LITHOGRAPHY BASED FABRICATION PROCESS AND CHARACTERIZATION OF PARYLENE C BELLOWS FOR APPLICATIONS IN MEMS ELECTROCHEMICAL ACTUATORS**

H. Gensler, R. Sheybani, and E. Meng

University of Southern California, Los Angeles, California, USA

.....2347

**W3P.095 ANODICALLY-BONDABLE LTCC SUBSTRATES WITH NOVEL NANO-STRUCTURED ELECTRICAL INTERCONNECTION FOR MEMS PACKAGING**

Y.-C. Lin<sup>1</sup>, W.-S. Wang<sup>2</sup>, L.Y. Chen<sup>1</sup>, M.W. Chen<sup>1</sup>, T. Gessner<sup>1,3-4</sup> and M. Esashi<sup>1-2</sup>

<sup>1</sup>WPI Advanced Institute for Materials Research, Tohoku University, Sendai, JAPAN

<sup>2</sup>Micro System Integration Center, Tohoku University, Sendai, JAPAN

<sup>3</sup>Fraunhofer ENAS, Chemnitz, GERMANY

<sup>4</sup>Chemnitz University of Technology, Chemnitz, GERMANY

.....2351

**W3P.096 SIMPLE AND LOW-COST PATTERNING OF CARBON NANOTUBE ON PDMS FOR FLEXIBLE MEMS**

Dongil Kim<sup>1</sup>, Ji-Eun Han<sup>2</sup>, Hyunjin Park<sup>3</sup> and Kwang-Seok Yun<sup>1</sup>

<sup>1</sup>Department of Electronic Engineering, Sogang University, Seoul, Korea

<sup>2</sup>Samsung Electronics, Giheung, Korea

<sup>3</sup>Hanool Robotics, Bucheon, Korea

.....2355

**W3P.097 FABRICATION AND TESTING OF CVD DIAMOND SINGLE-MATERIAL MEMS RESONATORS WITH PIEZORESISTIVE DETECTION**

Zongliang Cao, and Dean M. Aslam

Micro and Nano Technology Lab, Department of

Electrical and Computer Engineering, Michigan State University, East Lansing, MI 48824

.....2359

**W3P.098 NOVEL ISOTROPIC AND ANISOTROPIC ETCHING OF MEMS STRUCTURES BY CONTROLLING THE DYNAMICS OF THE ETCHANT**

S.Negi<sup>1</sup>, R. Bhandari<sup>1</sup>, and F. Solzbacher<sup>2</sup>

<sup>1</sup>Blackrock Microsystems, Salt Lake City, UT, USA

<sup>2</sup>Department of Electrical and Computer Engineering, University of Utah, Salt Lake City, UT, USA

.....2362

**W3P.099 A MAGNETOSTATIC 2-AXIS MEMS SCANNER WITH I-SECTION RIB-REINFORCEMENT AND SLENDER PERMANENT MAGNET PATTERNS**

Hsin-Yu Huang<sup>1</sup>, Tsung-Lin Tang<sup>1</sup>, Wei-Lun Sung<sup>1</sup>, Hung-Yi Lin<sup>3</sup>, and Weileun Fang<sup>1,2</sup>

<sup>1</sup>Dept. of Power Mechanical Engineering,

<sup>2</sup>Inst. of NanoEngineering and MicroSystems, National Tsing Hua University, Hsinchu, Taiwan

<sup>3</sup>Touch Micro-system Technology Corporation, Taoyuan, Taiwan

.....2366

**W3P.100 THE FABRICATION OF 3D ASPHERICAL SILICON MICROLENSES USING A SHADOW MASK**

J. Zhu<sup>1</sup>, S. J. Chen<sup>2</sup>, C. Y. Lin<sup>3</sup>, J. Oiler<sup>1</sup>, H. Wang<sup>1</sup>, Y. C. Chen<sup>3</sup> and H. Yu<sup>1</sup>

<sup>1</sup>Arizona State University, Tempe, USA

<sup>2</sup>University of Southern California, Los Angeles, USA

<sup>3</sup>National Central University, Zhongli, R.O.China

.....2370

**W3P.101 MICROFLUIDIC CHANNELS FABRICATED USING A LITHOGRAPHY-FREE METHOD**

J. Pu<sup>1,2</sup>, R. Sochol<sup>2</sup>, Y. Jiang<sup>1</sup> and L. Lin<sup>2</sup>

<sup>1</sup>University of Electronic Science and Technology of China, Chengdu, Sichuan, China

<sup>2</sup>University of California at Berkeley, Berkeley, California, United States

.....2374

**Theory, Design and Test Methodology**

**W3P.102 INVESTIGATION OF TEMPORARY STICTION IN POLY-SIGE MICROMIRROR ARRAYS**

F.Z. Ling<sup>1, 3</sup>, J. De Coster<sup>1</sup>, W.Y. Lin<sup>1, 2</sup>, A. Witvrouw<sup>1</sup>, J-P.Celis<sup>1, 2</sup>, I. De Wolf<sup>1, 2</sup>

<sup>1</sup>imec, Leuven, Belgium

<sup>2</sup>Dept Metallurgy and Materials Engineering, KULeuven, Leuven, Belgium

.....2378

**W3P.103 COMPREHENSIVE DYNAMIC AND STABILITY ANALYSIS OF ELECTROSTATIC VIBRATION ENERGY HARVESTER (E-VEH)**

D. Galayko<sup>1</sup>, R. Guillemet<sup>2</sup>, A. Dudka<sup>1</sup>, P. Basset<sup>2</sup>

<sup>1</sup>LIP6, UPMC Universités Paris Sorbonne, Paris, France

<sup>2</sup>Université Paris-Est, ESYCOM, ESIEE Paris, Noisy-le-Grand, France

.....2382

- W3P.104 THE MINIMUM TIME ESTIMATION FOR INITIATING TUMOR-CELL ATTACHMENT**  
L.J. Yang<sup>1</sup>, C.W. Hsu<sup>1</sup>, and Y.C. Ou<sup>2,3</sup>  
<sup>1</sup>Department of Mechanical & Electromechanical Engineering, Tamkang University, Tamsui, Taiwan  
<sup>2</sup>Instrument Technology Research Center, National Applied Research Laboratories, Hsinchu, Taiwan  
<sup>3</sup>Biomedical Tech and Product Research Center, National Applied Research Laboratories, Hsinchu, Taiwan  
.....2386
- W3P.105 INTEGRATION AND INSTALLATION OF ON-SITE WATER-QUALITY MONITORING NETWORK BASED ON MODEL-BASED DESIGN TECHNIQUE**  
R. Miyake<sup>1,2</sup>, S. Okabe<sup>1,2</sup>, H. Tsudome<sup>2,3</sup>, Y. Endo<sup>2,3</sup>, K. Mawatar<sup>4</sup> and T. Kitamor<sup>4</sup>  
<sup>1</sup>Hiroshima University, Hiroshima, JAPAN  
<sup>2</sup>JST, CREST, JAPAN  
<sup>3</sup>Hitachi Plant technologies, Ltd., Tokyo, JAPAN  
<sup>4</sup>University of Tokyo, Tokyo, JAPAN  
.....2390
- W3P.106 MEMS RATE AND RATE-INTEGRATING GYROSCOPE CONTROL WITH COMMERCIAL SOFTWARE DEFINED RADIO HARDWARE**  
J. A. Gregory, J. Cho, K. Najafi  
Center for Wireless Integrated Microsystems (WIMS)  
The University of Michigan, Ann Arbor, MI, USA  
.....2394
- W3P.107 CMOS TEST CIRCUIT ARCHITECTURE FOR THE EXTRACTION OF FLUID PROPERTIES USING INTERDIGITATED ELECTRODES MICROSENSORS**  
S. Druart, N. André, D. Flandre and L.A. Francis  
Sensors, Microsystems and Actuators Laboratory of Louvain (SMALL), Electrical Engineering Department (ELEN), Institute of Information and Communication Technologies, Electronics and Applied Mathematics (ICTEAM), Université catholique de Louvain, Belgium  
.....2398
- W3P.108 ELECTRICALLY DRIVEN CMOS-MEMS NONLINEAR PARAMETRIC RESONATOR DESIGN USING A HIERARCHICAL MEMS CIRCUIT LIBRARY**  
Congzhong Guo<sup>1</sup>, Kahini M. Shah<sup>1</sup> and Gary K. Fedder<sup>1,2,3</sup>  
<sup>1</sup>Department of Electrical and Computer Engineering,  
<sup>2</sup>Institute for Complex Engineered Systems,  
<sup>3</sup>The Robotics Institute Carnegie Mellon University, Pittsburgh, Pennsylvania, USA  
.....2402
- W3P.109 DIRECT PICK AND PLACE OF CNT BUNDLES FOR STRAIN SENSING APPLICATIONS**  
P.B. Wang<sup>1,2</sup>, Y.Q. Jiang<sup>2</sup>, W. Li<sup>1</sup>, and L. Lin<sup>2</sup>  
<sup>1</sup>College of Engineering, China Agricultural University, Beijing, P. R. China  
<sup>2</sup>Department of Mechanical Engineering, University of California at Berkeley, USA  
.....2406

- W3P.110 ANALYTIC MODEL FOR PERTURBATION ANALYSIS IN COUPLED RESONATOR SYSTEM FOR ELECTRONIC NOISE APPLICATIONS**  
M.S. Hajhashemi and B. Bahreyni  
Integrated Multi-Transducer Systems Lab (IMuTS Lab), Simon Fraser University, Canada  
.....2410
- W3P.111 MEASUREMENT OF ADHESION FORCE AT ELEVATED TEMPERATURES IN MEMS USING THERMAL-STRUCTURAL ACTUATION**  
M. Shavezipur<sup>1</sup>, G.H. Li<sup>1,2</sup>, W. Gou<sup>1,3</sup>, C. Carraro<sup>1</sup>, R. Maboudian<sup>1</sup>  
<sup>1</sup>Department of Chemical and Biomolecular Engineering, University of California, Berkeley, California, USA  
<sup>2</sup>School of Materials Science and Engineering, Hefei University of Technology, Hefei, Anhui 230009, China  
<sup>3</sup>College of Water Conservancy and Hydropower Engineering, Hohai University, Nanjing, Jiangsu 210098, China  
.....2414

## Actuators

- W3P.112 THREE-AXIS TACTILE DISPLAY USING PDMS PNEUMATIC ACTUATOR FOR ROBOT-ASSISTED SURGERY**  
Eunhyup Doh<sup>1</sup> and Hyungkew Lee<sup>2</sup>, Joonah Park<sup>2</sup>, and Kwang-Seok Yun<sup>1</sup>  
<sup>1</sup>Department of Electronic Engineering, Sogang University, Seoul, Korea  
<sup>2</sup>Samsung Advanced Institute of Technology, Yongin, Korea  
.....2418
- W3P.113 BATCH FABRICATED BIDIRECTIONAL DIELECTRIC ELASTOMER ACTUATORS**  
Aaron P. Gerratt, Bavani Balakrisnan, Ivan Penskiy, and Sarah Bergbreiter\*  
Department of Mechanical Engineering and the Institute for Systems Research  
University of Maryland, College Park, MD, USA  
.....2422
- W3P.114 A DRUG-INJECTION SYSTEM WITH CHEMO-MECHANICAL ENERGY CONVERSION FOR ACTIVE FEEDBACK CONTROL OF GLUCOSE CONCENTRATION IN A BLOOD**  
Takahiro Arakawa<sup>1</sup>, Ryodai Kato<sup>2</sup>, Munkhjargal Munkhjargal<sup>2</sup>, Daishi Takahashi<sup>1</sup>, Hiroyuki Kudo<sup>1</sup>, Kohji Mitsubayashi<sup>1,2</sup>  
<sup>1</sup>Institute of Biomaterials and Bioengineering, Tokyo Medical and Dental University, Tokyo, Japan  
<sup>2</sup>Graduate School of Medical and Dental Sciences, Tokyo Medical and Dental University, Tokyo, Japan  
.....2426
- W3P.115 MICROFLUIDIC ACTUATORS BASED ON INFRARED-LIGHT RESPONSIVE PNIPAAm HYDROGEL NANOCOMPOSITE INCORPORATING**

**GRAPHENE-OXIDE**

Chi-Wei Lo<sup>1</sup>, Difeng Zhu<sup>2</sup>, and Hongrui Jiang<sup>1,2,3\*</sup>

<sup>1</sup>Materials Science Program, University of Wisconsin-Madison, WI 53706 USA.

<sup>2</sup>Department of Electrical and Computer Engineering, University of Wisconsin-Madison, WI 53706 USA

<sup>3</sup>Eye Research Institute, University of Wisconsin - Madison, Madison, WI 53706, USA

.....2430

**W3P.116 NI-BASED MICROVALVES FOR FLOW MODULATION: TOWARD ACTIVE COMBUSTION CONTROL**

C.W. Chang<sup>1</sup> and R.S. Okojie<sup>2</sup>

<sup>1</sup>ASRC Aerospace Corporation, Cleveland, OH, USA

<sup>2</sup>NASA Glenn Research Center, Cleveland, OH, USA

.....2434

**W3P.117 EFFICIENT ELECTROSTATIC INCHWORM MOTORS WITH SIMPLE CONTROL AND HIGH FORCE DENSITY**

Ivan Penskiy<sup>1</sup>, Aaron P. Gerratt<sup>1</sup> and Sarah Bergbreiter<sup>1,2,\*</sup>

<sup>1</sup>Mechanical Engineering, University of Maryland, College Park, Maryland, USA

<sup>2</sup>Institute for Systems Research, University of Maryland, College Park, Maryland, USA

.....2438

**W3P.118 CHEMICAL SWITCHING OF JELLYFISH-SHAPED MICRO ROBOT CONSISTING ONLY OF CARDIOMYOCYTE GEL**

R. Takemura, Y. Akiyama, T. Hoshino, and K. Morishima

Tokyo University of Agriculture and Technology, Tokyo, Japan

.....2442

**W3P.119 ACTIVE CMOS-MEMS CONDUCTIVE PROBES AND ARRAYS FOR TUNNELING-BASED ATOMIC-LEVEL SURFACE IMAGING**

Y. Zhang<sup>1</sup>, J. Wang<sup>1</sup>, S. Santhanam<sup>1</sup>, and G. K. Fedder<sup>1,2,3</sup>

<sup>1</sup>Department of Electrical and Computer Engineering

<sup>2</sup>The Institute for Complex Engineered Systems

<sup>3</sup>The Robotics Institute, Carnegie Mellon University, Pittsburgh, PA, USA

.....2446

**W3P.120 RESONANT STATOR ACTUATION OF GEAR COUPLED ULTRASONIC MOTORS**

S. Piratla and A. Lal

SonicMEMS Laboratory, Cornell University, Ithaca, USA

.....2450

**W3P.121 ALL-ELECTRIC PERISTALTIC VACUUM PUMP UTILIZING ELECTROMAGNETIC AND HYDRAULIC ACTUATION WITH A HIGHLY FLEXIBLE LATEX MEMBRANE**

Hyun Tae Kim<sup>1</sup>, Jung Woo Park<sup>2</sup>, and Hanseup Kim<sup>1</sup>

<sup>1</sup>Electrical and Computer Engineering,

<sup>2</sup>Mechanical Engineering, University of Utah, Salt Lake

City, UT 84112-9206, USA

.....2454

**RF MEMS, Resonators, and Oscillators**

**W3P.122 LORENTZ FORCE TRANSDUCTION FOR RF MICROMECHANICAL FILTERS**

S. Forouzanfar<sup>1</sup>, R. R. Mansour<sup>1</sup>, and E. M. Abdel-Rahman<sup>2</sup>

<sup>1</sup>Electrical & Computer Eng. and <sup>2</sup>Systems Design Eng. Departments of University of Waterloo, Canada

.....2458

**W3P.123 RELIABLE LOW-COST FABRICATION AND CHARACTERIZATION METHODS FOR MICROMECHANICAL DISK RESONATORS**

J. Xie<sup>1,2</sup>, Y. F. Liu<sup>1,2</sup>, H. Zhao<sup>1,2</sup>, J. L. Yang<sup>1,2,\*</sup>, and F. H. Yang<sup>1</sup>

<sup>1</sup>Institute of Semiconductors, Chinese Academy of Sciences, Beijing, China

<sup>2</sup>State Key Laboratory of Transducer Technology, Shanghai, China

.....2462

**W3P.124 A LONG-TERM RELIABILITY ANALYSIS OF A CREEP IMMUNE RF-MEMS TUNABLE CAPACITOR**

Etsuji Ogawa<sup>1</sup>, Kei Masunishi<sup>2</sup>, Tamio Ikehashi<sup>1</sup>, Tomohiro Saito<sup>1</sup>, Hiroaki Yamazaki<sup>1</sup>, Yasushi Tomizawa<sup>2</sup>, and Yoshiaki Sugizaki<sup>1</sup>

<sup>1</sup>Device Process Development Center, Corporate Research & Development Center, Toshiba Corporation, Yokohama, Japan

<sup>2</sup>Mechanical Systems Laboratory, Corporate Research & Development Center, Toshiba Corporation, Kawasaki, Japan

.....2466

**W3P.125 ELECTROTHERMALLY ACTUATED RF MEMS CAPACITIVE SWITCH WITH ATOMIC LAYER DEPOSITED (ALD) DIELECTRICS**

X.J. He<sup>1,2</sup>, Z.Q. Lv<sup>1</sup>, B. Liu<sup>1</sup>, and Z.H. Li<sup>1</sup>

<sup>1</sup>National Key Laboratory of Science and Technology on Micro/Nano Fabrication, Institute of Microelectronics, Peking University, Beijing, China

<sup>2</sup>Department of Electronic Science and Technology, School of Applied Sciences, Harbin University of Science and Technology, Harbin, China

.....2470

**W3P.126 FHHGTGPVKCN/RRW/RGQ QTGUUVKGN/UGPUGF USWCTG/GZVGP UQPCNO QF'GTGQP CVQT'HQT RCTCUB/EHGGFVJ TQW J'ECPEGNVCVQP**

Y. Xu<sup>1,2</sup> and J. E.-Y. Lee<sup>1,2</sup>

<sup>1</sup>Department of Electronic Engineering, City University of Hong Kong, Kowloon, Hong Kong, China

<sup>2</sup>State Key Laboratory of Millimeter Waves, City University of Hong Kong, Hong Kong, China

.....2474

**W3P.127 FHHGTGPV'UVKVP'O GEJ CPHO UR'NGEVTQUCVIE OGO UF GXKRGU'PCPQECNG'CT CEVK CVKQP**

**BASED ON ADHESION AND FRICTION MEASUREMENTS**

U. Zaghloul<sup>1,2,3\*</sup>, B. Bhushan<sup>3</sup>, P. Pons<sup>1,2</sup>, G. Papaioannou<sup>1,2,4</sup>, F. Coccetti<sup>1,2,5</sup>, and R. Plana<sup>1,2</sup>  
<sup>1</sup>CNRS; LAAS; 7 avenue du colonel Roche, F-31077  
Toulouse, France

<sup>2</sup>Université de Toulouse; UPS, INSA, INP, ISAE ; LAAS ;  
F-31077 Toulouse, France

<sup>3</sup>NLBB Laboratory, The Ohio State University,  
Columbus, OH 43210, USA

<sup>4</sup>University of Athens, Solid State Physics,  
Panepistimiopolis Zografos, Athens, Greece

<sup>5</sup>Novamems, 10 avenue De l'Europe, F-31520 Toulouse,  
France

.....2478

**W3P.128 MILLIMETER-WAVE FILTER USING NOVEL MICROMACHINED SUBSTRATE INTEGRATED WAVEGUIDE STRUCTURE WITH EMBEDDED SILICON VIAS IN BCB DIELECTRICS**

Lk-Jae Hyeon, Woo-Young Park, Sungjoon Lim and  
Chang-Wook Baek

School of Electrical and Electronics  
Engineering, Chung-Ang University(CAU), Seoul,  
Republic of Korea

.....2482

**W3P.129 ULTRA HIGH FREQUENCY PHONONIC CRYSTAL IN SILICON CARBIDE**

N. Kuo, S. Gong, and G. Piazza  
University of Pennsylvania, Philadelphia, Pennsylvania,  
USA

.....2486

**W3P.130 INDEPENDENT TUNING OF QUALITY FACTOR AND RESONANT FREQUENCY OF TORSIONAL MICRO-RESONATORS FOR TIMING AND SENSING APPLICATIONS**

M.A. Rasouli and B. Bahreyni  
Integrated Multi-Transducer Systems Lab, Simon Fraser  
University, Surrey, BC, CANADA

.....2490

**Optical MEMS**

**W3P.131 TUNABLE SOLID-BODY ELASTOMERIC DIFFRACTIVE LENS**

Y. Sun, S. Thiele, P. Liebetraut, W. Mönch and H.  
Zappe  
Department of Microsystems Engineering – IMTEK,  
University of Freiburg, Freiburg, GERMANY

.....2494

**W3P.132 NANOPLASMONIC PHOTOCONDUCTIVE ANTENNA FOR HIGH POWER TERAHERTZ EMISSION**

S. Park<sup>1</sup>, K. Jin<sup>1</sup>, J. Ye<sup>1</sup> and K.H. Jeong<sup>1</sup>  
<sup>1</sup>Dept. of Bio and Brain Engineering, Korea Advanced  
Institute of Science and Technology (KAIST), Daejeon,  
Korea

.....2498

**W3P.133 SILICON/III-V MATERIAL ACTIVE LAYER HETEROINTEGRATED VERTICAL PIN**

**WAVEGUIDE PHOTODIODE BY DIRECT BONDING**

Linghan Li<sup>\*</sup>, Akio Higo<sup>1</sup>, Ryo Takigawa<sup>1</sup>, Eiji  
Higurashi<sup>1</sup>, Masakazu Sugiyama<sup>2</sup> and Yoshiaki Nakano<sup>1</sup>

<sup>1</sup>Research Center for Advanced Science and Technology,  
The University of Tokyo, Japan

<sup>2</sup>Institute of Engineering Innovation, The University of  
Tokyo, Japan

.....2502

**W3P.134 TiO2 FREESTANDING THIN FILM AS EVANESCENT WAVEGUIDE SENSOR FOR BIOMEDICAL APPLICATION**

A. Purniawan<sup>1</sup>, G. Pandraud<sup>2</sup>, P. J. French<sup>1</sup> and P.M.  
Sarro<sup>2</sup>

<sup>1</sup>Electronic Instrumentation Laboratory (EI) – DIMES –  
TU Delft, THE NETHERLANDS

<sup>2</sup>Electronic Component, Technology and Materials  
(ECTM) – DIMES – TU Delft, THE NETHERLANDS

.....2506

**W3P.135 INCORPORATION OF POLYMER REFRACTIVE MICROLENS ARRAY FOR EFFICIENCY IMPROVEMENT OF CUINS2 QUANTUM DOT-BASED HYBRID PHOTOVOLTAIC CELLS**

M. Nam<sup>1</sup>, J. Park<sup>2</sup>, S. Kim<sup>2</sup>, and K. Lee<sup>1</sup>

<sup>1</sup>Department of Electrical and Computer Engineering,  
Ajou University, Suwon 443-749, Republic of Korea

<sup>2</sup>Department of Molecular Science and Technology,  
Ajou University, Suwon 443-749, Republic of Korea

.....2510

**W3P.136 SWITCHABLE PHOTONIC CRYSTALS BASED ON THE PHOTONIC DEFORMATIONS OF THE AZOBENZENE CONTAINING LIQUID CRYSTAL POLYMER**

Z. Yan<sup>1</sup>, Y.L. Yu<sup>1</sup>, and X.M. Ji<sup>\*2</sup>

<sup>1</sup>Department of Materials Science, Fudan University,  
Shanghai, China

<sup>2</sup>The State Key Laboratory of ASIC & System,  
Department of Microelectronics,  
Fudan University, Shanghai, China

.....2514

**W3P.137 A COMPACT PROJECTION SYSTEM ENABLING TOPOGRAPHICAL MEASUREMENTS FOR A MINIATURIZED SUBMERSIBLE EXPLORER**

J. Jonsson, M. Berglund, H. Kratz, H. Nguyen, and G.  
Thornell

Ångström Space Technology Centre, Department of  
Engineering Sciences, Uppsala University, SWEDEN

.....2518

**W3P.138 MEMS MIRRORS BASED ON CURVED CONCENTRIC ELECTROTHERMAL ACTUATORS WITH VERY SMALL LATERAL SHIFT AND TILT**

Lin Liu, Sagnik Pal, and Huikai Xie<sup>\*</sup>

Department of Electrical & Computer Engineering,  
University of Florida, Gainesville, FL, USA

.....2522

**W3P.139 A WIRELESS PAIRED EMITTER DETECTOR DIODE DEVICE AS AN OPTICAL SENSOR FOR**

**LAB-ON-A-DISC APPLICATIONS**

R. Gorkin<sup>1</sup>, M. Czugala<sup>2</sup>, C. Rovira-Borras<sup>2</sup>, J. Ducre<sup>1</sup>,  
D. Diamond<sup>2</sup> and F. Benito-Lopez<sup>2\*</sup>

<sup>1</sup>School of Physical Sciences

<sup>2</sup>CLARITY: Centre for Sensor Web Technology, National  
Centre for Sensor Research, Dublin City University,  
Dublin 9, IRELAND

.....2526

**W3P.140 ELECTROLUMINESCENCE FROM A  
FREESTANDING INTEGRABLE SINGLE ZNO  
QUANTUM DOT**

Cheng Jiang<sup>1</sup>; Norimasa Yoshimizu<sup>2</sup>; Jun Hyun Han<sup>1</sup>,  
Amit Lal<sup>2</sup>; Chung Hoon Lee<sup>2</sup>

<sup>1</sup>Marquette University, Milwaukee, WI, USA

<sup>2</sup>Cornell University, Ithaca, NY, USA

.....2530

**W3P.141 INTEGRATED SELF-ALIGNED TIPS FOR  
DISPERSION TUNING IN A PHOTONIC CRYSTAL  
MICRO-CAVITY**

S.M.C. Abdulla<sup>1\*</sup>, L.J. Kauppinen<sup>2</sup>, M. de Ridder<sup>2</sup> and  
G.J.M. Krijnen<sup>1</sup>

<sup>1</sup>Transducers Science and Technology Group and  
2Integrated Optical Microsystems Group,

MESA<sup>+</sup> Research Institute, University of Twente, The  
Netherlands

.....2534

**W3P.142 DUAL-BAND MEMS FABRY-PÉROT FILTER WITH  
TWO MOVABLE REFLECTORS FOR MID- AND  
LONG-WAVE INFRARED  
MICROSPECTROMETERS**

M. Meinig<sup>1</sup>, M. Ebermann<sup>2</sup>, N. Neumann<sup>2</sup>, S. Kurth<sup>1</sup>,  
K. Hiller<sup>3</sup>, T. Gessner<sup>1,3</sup>

<sup>1</sup>Fraunhofer ENAS, Chemnitz, Germany

<sup>2</sup>InfraTec GmbH, Dresden, Germany

<sup>3</sup>Chemnitz University of Technology, Chemnitz, Germany

.....2538

**W3P.143 MEMS SCANNER BASED HANDHELD  
FLUORESCENT HYPERSPECTRAL IMAGING  
SYSTEM**

Sheldon Bish, Youmin Wang, James W. Tunnell, and  
Xiaoqing Zhang

Department of Biomedical Engineering

The University of Texas at Austin, Austin TX, USA

.....2542

**W3P.144 A HIGH-SPEED ELECTROSTATIC  
DOUBLE-LAYERED VIBRATORY GRATING  
SCANNER WITH VERY HIGH OPTICAL  
RESOLUTION**

Yu Du<sup>1,2</sup>, Guangya Zhou<sup>1\*</sup>, Kelvin K.L. Cheo<sup>1</sup>, Qingxin  
Zhang<sup>2</sup>, Hanhua Feng<sup>2</sup>, and Fook Siong Chau<sup>1</sup>

<sup>1</sup>Micro and Nano System Initiative, Dgrctvo gpv'qhl'

Ogej cplectf Engineering, National Wpk&gt;udf 'qh  
Ukpi aporg. Ukpi cr qt g=

<sup>2</sup>Institute of Microelectronics, A\*STAR (Agency for  
Science, Technology and Research), Singapore

.....2546

**W3P.145 DESIGN AND FABRICATION OF 2D FAST  
ELECTROTHERMAL MICROMIRRORS WITH  
LARGE SCAN RANGE AND SMALL CENTER  
SHIFT**

Sagnik Pal and Huikai Xie

The Department of Electrical and Computer  
Engineering, University of Florida, Gainesville, FL,  
USA

.....2550

**W3P.146 POLYMER-DISPERSED LIQUID CRYSTALS LIGHT  
SHUTTER DRIVEN BY SURFACE ACOUSTIC  
WAVE**

Yan Jun Liu<sup>a</sup>, Xiaoyun Ding<sup>a</sup>, Sz-Chin Steven Lin<sup>a</sup>,  
Jinjie Shi<sup>a,b</sup>, and Tony Jun Huang<sup>a\*</sup>

<sup>a</sup>Department of Engineering Science and Mechanics,  
The Pennsylvania State University, University Park, PA  
16802, USA

<sup>b</sup>The DOW Chemical Company, Spring House  
Technology Center, Spring House, PA 19477, USA

.....2554

**W3P.147 ULTRA-COMPACT ELECTRO-THERMALLY  
TUNABLE PHOTONIC CRYSTAL PRISM FOR  
ON-CHIP OPTICAL ROUTER APPLICATION**

K.-H. Choi, Y. Cui, K. Liu, D. MacFarlane, and J.-B.  
Lee

The University of Texas at Dallas, Richardson, Texas,  
U.S.A.

.....2558

**Nanoscale Materials and Fabrication,  
Devices and Systems**

**W3P.148 AMBIPOLAR SI NANOWIRE FIELD EFFECT  
TRANSISTORS FOR LOW CURRENT AND  
TEMPERATURE SENSING**

D. Sacchetto, G. De Micheli, and Y. Leblebici

EPFL - Ecole Polytechnique Fédérale, Lausanne, Vaud,  
SWITZERLAND

.....2562

**W3P.149 CARBON NANOTUBE BASED MULTI-SPECTRUM  
INFRARED DETECTOR ARRAY**

H. Chen, N. Xi, L. Chen, and King W. C. Lai

Michigan State University, East Lansing, Michigan,  
USA

.....2566

**W3P.150 NANOGAP-CONTROLLABLE SELF-ASSEMBLY OF  
GOLD NANOPARTICLES USING NANOTRENCH  
TEMPLATE**

K. Sugano<sup>1</sup>, R. Hiraoka<sup>1</sup>, T. Tsuchiya<sup>1</sup>, O. Tabata<sup>1</sup>, M.  
Klaumünzer<sup>2</sup>, M. Voigt<sup>2</sup> and W. Peukert<sup>2</sup>

<sup>1</sup>Department of Micro Engineering, Kyoto University,  
Kyoto, Japan

<sup>2</sup>Institute of Particle Technology, Friedrich-Alexander  
University of Erlangen-Nürnberg, Erlangen, Germany

.....2570

**W3P.151 AXIALLY STRETCHED NANO-THICK  
PIEZORESISTIVE SILICON CLAMPED-BEAMS  
TO SENSE SPECIFIC-REACTION-INDUCED  
DOUBLE-SIDE SURFACE-STRESS WITH MUCH  
HIGHER SENSITIVITY THAN CANTILEVERS**

Ying Chen, Pengcheng Xu and Xinxin Li<sup>\*</sup>

State Key Lab of Transducer Technology, and, Science

- and Technology on Microsystem Lab, Shanghai  
Institute of Microsystem and Information Technology,  
Chinese Academy of Sciences, China  
.....2574
- W3P.152 DESIGN, FABRICATION AND HELIUM ION  
MICROSCOPE PATTERNING OF SUSPENDED  
NANOMECHANICAL GRAPHENE STRUCTURES  
FOR NEMS APPLICATIONS**  
M. Annamalai<sup>2</sup>, S. Mathew<sup>2</sup>, V. Viswanathan<sup>3</sup>, C.  
Fang<sup>3</sup>, D. S. Pickard<sup>3</sup>, M. Palaniapan<sup>1</sup>  
<sup>1</sup>Signal Processing & VLSI Lab  
<sup>2</sup>Centre for Integrated Circuit Failure Analysis &  
Reliability  
<sup>3</sup>Plasmonics & Advanced Imaging Technology Lab  
Department of Electrical and Computer Engineering  
National University of Singapore, Singapore  
.....2578
- W3P.153 EFFECT OF ELECTRON-BEAM IRRADIATION ON  
ELECTRICAL CHARACTERIZATION OF  
NANOWIRES IN SCANNING ELECTRON  
MICROSCOPE**  
Y. Zhang and Y. Sun  
University of Toronto, Ontario, Canada  
.....2582
- W3P.154 NANOPROBE ELECTRODES CUT BY PHYSICAL  
STRETCH OF PARYLENE-INSULATED CARBON  
NANOTUBE BRIDGES**  
A. Inaba, Y. Takei, T. Kan, K. Matsumoto, and I.  
Shimoyama  
The University of Tokyo, Tokyo, Japan  
.....2586
- W3P.155 DIRECT GROWTH OF SINGLE WALLED CARBON  
NANOTUBES ON PAPER**  
Q. Zhou<sup>1</sup>, K. Liu<sup>2</sup>, and L. Lin<sup>1,\*</sup>  
<sup>1</sup>Berkeley Sensor and Actuator Center, Department of  
Mechanical Engineering,  
<sup>2</sup>Department of Physics, University of California,  
Berkeley, CA, USA  
.....2590
- W3P.156 AN ULTRA-SENSITIVE NANOCOMPOSITE  
PRESSURE SENSOR PATTERNED IN A PDMS  
DIAPHRAGM**  
Chao-Xuan Liu<sup>1</sup> and Jin-Woo Choi<sup>1,2</sup>  
<sup>1</sup>Department of Electrical and Computer Engineering,  
Louisiana State University, Baton Rouge, LA 70803,  
USA  
<sup>2</sup>Center for Advanced Microstructures and Devices,  
Louisiana State University, Baton Rouge, LA 70806,  
USA  
.....2594
- W3P.157 LARGE-SURFACE-AREA 3D SELF-ASSEMBLED  
NANO-POROUS STRUCTURE FOR  
HIGH-SENSITIVITY GAS-SENSING**  
M. Abasaki<sup>1,2</sup>, K. Yamada<sup>1,2</sup>, S. Souma<sup>2</sup>, N.  
Moronuki<sup>1,3</sup>, M. Sugiyama<sup>1,4</sup>  
<sup>1</sup>BEANS Project, Tokyo, JAPAN  
<sup>2</sup>Fuji Electric Systems, Co., Ltd, Tokyo, JAPAN  
<sup>3</sup>Tokyo Metropolitan University, Tokyo, JAPAN  
<sup>4</sup>The University of Tokyo, Tokyo, JAPAN  
.....2598
- W3P.158 MULTI-SPACER TECHNIQUE FOR  
LOW-VOLTAGE, HIGH-ASPECT-RATIO LATERAL  
ELECTROSTATIC ACTUATORS**  
D. LEE, S. Mitra, R. T. Howe, and H.-S. P. Wong  
Electrical Engineering Department, Stanford University,  
Stanford, CA, USA  
.....2602
- W3P.159 DUAL SIDEWALL LATERAL  
NANOELECTROMECHANICAL RELAYS WITH  
BEAM ISOLATION**  
W. S. Lee, S. Chong, R. Parsa, J. Provine, D. Lee,  
S. Mitra, H.-S. P. Wong, R.T. Howe  
Electrical Engineering Dept., Stanford University,  
Stanford, CA, USA  
.....2606
- W3P.160 CMOS-MEMS ATOMIC FORCE MICROSCOPE**  
N. Sarkar<sup>1</sup>, R. R. Mansour<sup>1</sup>, O. Patange<sup>1</sup>, K.  
Trainor<sup>1</sup>  
<sup>1</sup>University of Waterloo, Waterloo, Ontario, Canada  
.....2610
- W3P.161 SILICON CARBIDE (SiC) MEMBRANE  
NANOMECHANICAL RESONATORS WITH  
MULTIPLE VIBRATIONAL MODES**  
A.C. Barnes<sup>1</sup>, R.C. Roberts<sup>1</sup>, N.C. Tien<sup>1</sup>, C.A.  
Zorman<sup>1\*</sup>, and Philip X.-L. Feng<sup>1\*</sup>  
<sup>1</sup>Electrical Engineering & Computer Science, Case  
Western Reserve University, Cleveland, OH 44106, USA  
.....2614

## Energy and Power MEMS

- W3P.162 A NOVEL ASSEMBLY METHOD FOR MICRO  
DIRECT METHANOL FUEL CELLS USING  
MULTI-LAYER BONDING TECHNIQUE**  
Y.M. Zhu, X.H. Wang, Y.A. Zhou, L.T. Liu  
Institute of Microelectronics, Tsinghua University,  
Beijing, China  
Tsinghua National Laboratory for Information Science  
and Technology, Beijing, China  
.....2618
- W3P.163 PIEZOELECTRIC PDMS FILMS FOR POWER  
MEMS**  
J.J. Wang, J.M. Hsieh, R.W. Tsai, and Y.C. Su  
Department of Engineering and System Science  
National Tsing Hua University, Hsinchu, Taiwan  
.....2622
- W3P.164 AGING CHARACTERISTICS OF ELECTRET USED  
IN A VIBRATION-BASED ELECTROSTATIC  
INDUCTION ENERGY HARVESTER**  
Y. Wada<sup>1</sup>, Y. Hamate<sup>1</sup>, S. Nagasawa<sup>1</sup>, H.  
Kuвано<sup>1</sup>  
<sup>1</sup>Tohoku University, Sendai, Miyagi, JAPAN  
.....2626
- W3P.165 VIBRATION-DRIVEN MEMS ENERGY  
HARVESTER WITH VACUUM UV-CHARGED**

**VERTICAL ELECTRETS**

K. Yamashita<sup>1,2\*</sup>, M. Honzumi<sup>1,2</sup>, K. Hagiwara<sup>1,3</sup>,  
Y. Iguchi<sup>3</sup>, and Y. Suzuki<sup>1,2</sup>

<sup>1</sup>Dept. of Mechanical Engineering, The University of  
Tokyo,

<sup>2</sup>G Device Center, BEANS Project,

<sup>3</sup>NHK Science & Technology Research Laboratories

.....2630

**W3P.166 ELECTRET BASED ENERGY HARVESTER USING A SHARED SI ELECTRODE**

K. Fujii<sup>1</sup>, T. Toyonaga<sup>1,2</sup>, T. Fujita<sup>1,2</sup>, Y. G. Jiang<sup>2</sup>,  
K. Higuchi<sup>2</sup> and K. Maenaka<sup>1,2</sup>

<sup>1</sup>University of Hyogo, Himeji, Hyogo, Japan

<sup>2</sup>JST ERATO Maenaka Human-Sensing Fusion Project,  
Himeji, Hyogo, Japan

.....2634

**W3P.167 INCREASED-BANDWIDTH, MEANDERING VIBRATION ENERGY HARVESTER**

D. F. Berdy<sup>1,3</sup>, B. Jung<sup>1</sup>, J. F. Rhoads<sup>2,3</sup>, and D.  
Peroulis<sup>1,2,3</sup>

<sup>1</sup>School of Electrical and Computer Engineering,  
Purdue University, West Lafayette, IN, 47907, USA

<sup>2</sup>School of Mechanical Engineering, Purdue University,  
West Lafayette, IN, 47907, USA

<sup>3</sup>Birck Nanotechnology Center, Purdue University, West  
Lafayette, IN, 47907, USA

.....2638

**W3P.168 FABRICATION OF HIGHLY DIELECTRIC NANO-BATIO3/EPOXY-RESIN COMPOSITE PLATE HAVING TRENCHES BY MOLD CASTING AND ITS APPLICATION TO CAPACITIVE ENERGY HARVESTING**

M. Suzuki<sup>1</sup>, N. Matsushita<sup>1</sup>, T. Hirata<sup>1</sup>, R.  
Yoneya<sup>1</sup>, J. Onishi<sup>1</sup>, T. Wada<sup>1</sup>, T. Takahashi<sup>1</sup>, T.  
Nishida<sup>2</sup>, Y. Yoshikawa<sup>2</sup>, and S. Aoyagi<sup>1</sup>

<sup>1</sup>Kansai University, Osaka, Japan

<sup>2</sup>ROHM Co., Ltd., Kyoto, Japan

.....2642

**W3P.169 EFFICIENT ENERGY HARVESTING FROM HUMAN MOTION USING WEARABLE PIEZOELECTRIC SHELL STRUCTURES**

Boram Yang and Kwang-Seok Yun

Department of Electronic Engineering, Sogang  
University, Seoul, Korea

.....2646

**W3P.170 A VIBRATION-BASED ELECTROMAGNETIC ENERGY HARVESTER SYSTEM WITH HIGHLY EFFICIENT INTERFACE ELECTRONICS**

Arian Rahimi<sup>1,2</sup>, Özge Zorlu<sup>2</sup>, Ali Muhtaroglu<sup>3</sup>,  
and Haluk Külah<sup>1,2</sup>

<sup>1</sup>METU, Department of Electrical and Electronics  
Engineering, Ankara, Turkey

<sup>2</sup>METU-MEMS Research and Application Center,  
Ankara, Turkey

<sup>3</sup>METU-NCC, Department of Electrical and Electronics  
Engineering, Güzelyurt, Mersin 10 Turkey

.....2650

**W3P.171 ELECTROSTATICALLY-DRIVEN ACTIVE SPACE****RADIATOR USING NEAR-FIELD THERMAL RADIATION**

Ai Ueno<sup>1</sup> and Yuji Suzuki<sup>1</sup>

<sup>1</sup>Dept. of Mechanical Engineering, The University of  
Tokyo Hongo, Bunkyo-ku, Tokyo 113-8656, Japan

.....2654

**W3P.172 EFFECT OF ILLUMINATION ON THERMIONIC EMISSION FROM MICROFABRICATED SILICON CARBIDE STRUCTURES**

J.-H.Lee<sup>1</sup>, I.Bargatin<sup>1</sup>, J. Provine<sup>1</sup>, F.Liu<sup>2</sup>, M.-K.  
Seo<sup>1</sup>, R. Maboudian<sup>2</sup>, M.L. Brongersma<sup>1</sup>, N.A.  
Melosh<sup>1</sup>, Z.X. Shen<sup>1</sup>, R.T. Howe<sup>1</sup>

<sup>1</sup>Stanford University, Stanford, CA, USA; <sup>2</sup>University of  
California, Berkeley, CA, USA

.....2658

**ORAL SESSIONS**

16:15 - 18:00

**SESSION VII(1) –Materials & Photonic Crystals****W4A.001 “BOTTOM-UP” THREE-DIMENSIONAL METAMATERIALS AT TERAHERTZ FREQUENCIES**

Kebin Fan, Andrew C. Strikwerda, Richard D.  
Averitt, and Xin Zhang

Boston University, Boston, Massachusetts, USA

.....2662

**W4A.002 3-D MICROCOILS AS A METAMATERIAL WITH ELECTRIC AND MAGNETIC RESPONSE**

K. Kratt<sup>1</sup>, S. Waselikowski<sup>2</sup>, V. Badilita<sup>1,\*</sup>, U.  
Wallrabe<sup>1</sup>, M. Walthert<sup>2</sup>, J. G. Korvink<sup>1,3</sup>

<sup>1</sup>Department of Microsystems Engineering (IMTEK)

<sup>2</sup>Freiburg Materials Research Center (FMF)

<sup>3</sup>Freiburg Institute for Advanced Studies (FRIAS)

University of Freiburg, Germany

.....2666

**W4A.003 A MICROMACHINED OPTICAL DELAY LINE BY SWITCHABLE METAMATERIALS**

W. M. Zhu<sup>1,3</sup>, J. F. Tao<sup>1</sup>, J. H. Teng<sup>2</sup>, X. H.  
Zhang<sup>2</sup>, H. Tanoto<sup>2</sup>, H. C. Guo<sup>2</sup>, Q. Y. Wu<sup>2</sup>, T.  
Bourouina<sup>3</sup> and A. Q. Liu<sup>1†</sup>

<sup>1</sup>School of Electrical & Electronic Engineering,

Nanyang Technological University

SINGAPORE 639798

<sup>2</sup>Institute of Microelectronics, A\*STAR (Agency for  
Science, Technology and Research), 11 Science Park  
Road, Singapore Science Park II, Singapore 117685

<sup>3</sup>School of Electrical & Electronic Engineering, ESIEE,  
Université Paris-Est, Paris 93162, FRANCE

.....2670

**W4A.004 ALL-OPTICAL PROGRAMMABLE PHOTONIC INTEGRATED CIRCUIT: AN OPTICAL ANALOGY TO ELECTRONIC FPGA**

Depeng Mao, Peng Liu, and Liang Dong

Department of Electrical and Computer Engineering,  
Iowa State University, Ames, Iowa, USA

.....2674

**W4A.005 ACOUSTIC SPEAKER BASED ON HIGH-EFFICIENCY BROADBAND NANO-PILLAR PHOTONIC CRYSTAL OPTO-THERMO-MECHANICAL MEMS EXCITATION**  
Yuerui Lu<sup>\*</sup>, and Amit La<sup>1</sup>  
*SonicMEMS Laboratory, School of Electrical and Computer Engineering  
Cornell University, Ithaca, NY*  
.....2678

**W4A.006 REFLECTANCE-BASED TiO<sub>2</sub> PHOTONIC CRYSTAL SENSORS**  
Y. Huang, G. Pandraud and P.M. Sarro  
*DIMES, Delft University of Technology, Delft, the Netherlands*  
.....2682

### SESSION VII(2) –Materials & Characterization

**W4B.001 NIFE-AAO NANOCOMPOSITE FOR PERFORMANCE ENHANCEMENT OF ON-CHIP SPIRAL INDUCTORS**  
Tzu-Yuan Chao, H. F. Hsu, K. M. Chen, and Y. T. Cheng  
*Microsystems Integration Laboratory, Department of Electronics Engineering & Institute of Electronics, National Chiao Tung University, Hsinchu, Taiwan*  
.....2686

**W4B.002 SPUTTERED MOLYBDENUM AS CONDUCTIVE MATERIAL FOR HIGH-TEMPERATURE MICROHOTPLATES**  
L. Mele<sup>1\*</sup>, F. Santagata<sup>1</sup>, E. Iervolino<sup>2</sup>, M. Mihailovic<sup>1</sup>, T. Rossi<sup>1</sup>, A.T. Tran<sup>1</sup>, H. Schellevis<sup>1</sup>, J.F. Creemer<sup>1</sup>, P.M. Sarro<sup>1</sup>  
<sup>1</sup>*Delft University of Technology, DIMES, Feldmannweg 17, 2628CT, Delft, The Netherlands (NL)*  
<sup>2</sup>*Sensor Integration, Distributieweg 28, 2645 EJ Delfgauw, The Netherlands (NL)*  
.....2690

**W4B.003 PIEZORESISTIVE BIOCOMPATIBLE MEMBRANES FOR FLEXIBLE PRESSURE SENSORS**  
Vladimir Laukhin,<sup>1,2,3</sup> Victor Lebedev,<sup>2</sup> Elena Laukhina,<sup>2,3\*</sup> Concepcio Rovira,<sup>2,3</sup> Jaume Veciana<sup>2,3</sup>  
<sup>1</sup>*Institució Catalana de Recerca i Estudis Avançats (ICREA), Barcelona, Spain*  
<sup>2</sup>*Institut de Ciència de Materials de Barcelona ICMA-B-CSIC, Campus UAB, Bellaterra, Spain*  
<sup>3</sup>*CIBER de Bioingeniería, Biomateriales y Nanomedicina (CIBER-BBN), Spain*  
.....2694

**W4B.004 CREEP OF PARYLENE-C FILM**  
Jeffrey Chun-Hui Lin<sup>1</sup>, Peigang Deng<sup>2</sup>, Gilbert Lam<sup>3</sup>, Bo Lu<sup>1</sup>, Yi-Kuen Lee<sup>2</sup>, Yu-Chong Tai<sup>1</sup>  
<sup>1</sup>*California Institute of Technology, Pasadena, CA, USA*  
<sup>2</sup>*Hong Kong University of Science and Technology, Hong Kong*

<sup>3</sup>*University of California, San Diego, CA, USA*  
.....2698

**W4B.005 ELECTROLYTIC HYDROGENATION TECHNIQUE: NEW APPROACH FOR THE MODIFICATION OF TI-FILM MECHANICAL PROPERTIES AND MEMS APPLICATIONS**  
Chao-Lin Cheng<sup>1</sup>, Wang-Shen Su<sup>2</sup>, Yu-Tsung Tuan<sup>2</sup>, Ming-Hao Shih<sup>3</sup>, Tair-I Wu<sup>3</sup> and Weileun Fang<sup>1,2,4</sup>  
<sup>1</sup>*Power Mechanical Eng. Dept., 4NEMS Inst., National Tsing Hua Univ., Hsinchu, Taiwan*  
<sup>2</sup>*National Nano Device Laboratories, Hsinchu, Taiwan*  
<sup>3</sup>*Department of Materials Engineering, Tatung University, Taipei, Taiwan*  
.....2702

**W4B.006 NEGATIVE-PHOTORESIST MECHANICAL PROPERTY FOR NANO-FILTRATION MEMBRANE EMBEDDED IN MICROFLUIDICS**  
Y. Hirai<sup>1</sup>, A. Uesugi<sup>1</sup>, Y. Makino<sup>1</sup>, H. Yagyu<sup>2</sup>, K. Sugano<sup>1</sup>, T. Tsuchiya<sup>1</sup>, and O. Tabata<sup>1</sup>  
<sup>1</sup>*Department of Micro Engineering, Kyoto University, Kyoto, JAPAN*  
<sup>2</sup>*Mitsuboshi Belting Ltd., Kobe, JAPAN*  
.....2706

**W4B.007 OXYGEN PLASMA FUNCTIONALIZED PEDOT/PSS-SWCNTS THIN FILM DEPOSITED BY ELECTROPHORESIS FOR GAS SENSING**  
J.M. Jian<sup>1</sup>, X.S. Guo<sup>1\*</sup>, Q. Cai<sup>2</sup>, and L.W. Lin<sup>3</sup>  
<sup>1</sup>*Biosensors National Special Laboratory, Department of Biosystems Engineering, Zhejiang University, Hangzhou, Zhejiang, China*  
<sup>2</sup>*Institute of Ecology and Environment, Yangtze Delta Region Institute of Tsinghua University, Jiaying, Zhejiang, China*  
<sup>3</sup>*Berkeley Sensor and Actuator Center, University of California, Berkeley, California, U.S.A*  
.....2710

### SESSION VII(3) –Nanotubes & Nanowires

**W4C.001 “PICKUP AND PLACE” INTEGRATION METHOD OF BRIDGING CARBON NANOTUBES BY STAMPING TRANSFER**  
Yusuke Takei, Kiyoshi Matsumoto, and Isao Shimoyama,  
*The University of Tokyo, Japan*  
.....2714

**W4C.002 PROGRAMMABLE TRANSFORMATION OF VERTICALLY ALIGNED CARBON NANOTUBES INTO 3D MICROSTRUCTURES**  
M. De Volder<sup>1,2</sup>, S. Tawfick<sup>1</sup>, S.J. Park<sup>1</sup>, D. Copic<sup>1</sup>, A.J. Hart<sup>1</sup>  
<sup>1</sup>*University of Michigan, Ann Arbor, MI – USA*  
<sup>2</sup>*IMEC KULeuven, Heverlee, Belgium*  
.....2718

**W4C.003 DENSELY PACKED CARBON NANOTUBE FOREST ON SILICON SUBSTRATE FOR MEMS SUPERCAPACITOR APPLICATIONS**

- Y. Jiang and L. Lin\*  
*Mechanical Engineering Department, Berkeley  
 Sensor and Actuator Center  
 University of California at Berkeley, USA*  
 .....2722
- W4C.004 AUTONOMOUS PASSIVE LIGHT TRACKING  
 UTILIZING SINGLE-WALL CARBON NANOTUBE  
 ENHANCED OPTO-THERMO-MECHANICAL  
 ELASTOMER ACTUATORS**  
 Ye Liu<sup>1</sup>, Chensha Li<sup>1</sup>, Chi-Wei Lo<sup>2</sup>, and Hongrui  
 Jiang<sup>1,2</sup>  
<sup>1</sup>*Electrical and Computer Engineering Department,  
 University of Wisconsin - Madison, Madison, WI, USA*  
<sup>2</sup>*Materials Science Program, University of Wisconsin -  
 Madison, Madison, WI, USA*  
 .....2726
- W4C.005 SELF-ALIGNED DOUBLE-GATE  
 SUSPENDED-BODY CARBON NANOTUBE  
 FIELD-EFFECT TRANSISTORS FOR RF  
 APPLICATIONS**  
 Ji Cao, Adrian M. Ionescu  
*Nanoelectronic Devices Laboratory (Nanolab), Ecole  
 Polytechnique Fédérale de Lausanne, Switzerland*  
 .....2730
- W4C.006 ULTRASENSITIVE PRESSURE SENSOR BASED ON  
 GATE-ALL-AROUND NANOWIRE FET**  
 Pushpapraj Singh<sup>1,2</sup>, Jianmin Miao<sup>1,2</sup>, Woo-Tae  
 Park<sup>2</sup>, Dim-Lee Kwong<sup>2</sup>  
<sup>1</sup>*School of mechanical and Aerospace Engineering,  
 Nanyang Technology University, Singapore*  
<sup>2</sup>*Institute of Microelectronics, A\*STAR (Agency for  
 Science, Technology and Research), Singapore*  
 .....2734
- W4C.007 HIGHLY SENSITIVE BILAYER STRUCTURED  
 GRAPHENE SENSOR**  
 F.B. Rao, H. Almumen, L.X. Dong, and W. Li|  
*Electrical & Computer Engineering, Michigan State  
 University, East Lansing, MI 48824, USA*  
 .....2738

### SESSION VII(4) –Devices for Cells & Microorganisms

- W4D.001 MAGNETOPHORETIC LABELFREE CELL  
 SEPARATION USING PARAMAGNETIC  
 SOLUTION**  
 F. Shen, H. Hwang, Y.K. Hahn and J.-K. Park  
*Department of Bio and Brain Engineering, KAIST,  
 Daejeon, REPUBLIC OF KOREA*  
 .....2742
- W4D.002 AMPLIFICATION OF CHEMOTACTIC  
 RESPONSES OF MOTILE BACTERIAL CELLS  
 FOR CHARACTERIZING PREFERENTIAL  
 CHEMOTAXIS TOWARD CARBON SOURCES**  
 M. Kim<sup>1</sup>, S.H. Kim<sup>1</sup>, S.K. Lee<sup>1</sup> and T. Kim<sup>1</sup>  
<sup>1</sup>*Ulsan National Institute of Science and Technology,  
 Ulsan, Korea*  
 .....2746

- W4D.003 A GLUCOSE-RESPONSIVE INSULIN DELIVERY  
 MICRO DEVICE EMBEDDED  
 WITH NANOHYDROGEL PARTICLES AS “SMART  
 VALVES”**  
 Jian Chen<sup>1\*</sup>, Claudia R. Gordijo<sup>2\*</sup>, Michael  
 Chu<sup>2</sup>, Xiao Yu Wu<sup>2\*\*</sup>, and Yu Sun<sup>1\*\*</sup>  
<sup>1</sup>*Advanced Micro and Nanosystems Lab, University of  
 Toronto, Canada*  
<sup>2</sup>*Department of Pharmaceutical Sciences, University  
 of Toronto, Canada*  
 .....2750
- W4D.004 SI NANO-PILLARS FOR MEASURING TRACTION  
 FORCE EXERTED BY FILOPODIA**  
 Uijin Jung, Tetsuo Kan, Kenta Kuwana, Kiyoshi  
 Matsumoto and Isao Shimoyama  
*The University of Tokyo, Tokyo, JAPAN*  
 .....2754
- W4D.005 GOLD NANOPARTICLE-BASED REDOX SIGNAL  
 ENHANCEMENT TOWARDS THE DETECTION OF  
 SINGLE BACTERIUM**  
 Jen-Kuei Wu<sup>1</sup>, Hwan-You Chang<sup>2</sup> and Fan-Gang  
 Tseng<sup>1,3\*</sup>  
<sup>1</sup>*Department of Engineering and System Science,  
 National Tsing Hua University, Taiwan (R.O.C.)*  
<sup>2</sup>*Department of Life Science, National Tsing Hua  
 University (R.O.C.)*  
<sup>3</sup>*Division of Mechanics, Research Center for Applied  
 Sciences, Taiwan (R.O.C.)*  
 .....2758
- W4D.006 BIOFUEL CELLS WITH TREHALOSE LEADING  
 TO AN INSECT-IMPLANTED POWER SOURCE**  
 K. Shoji, M. Suzuki, Y. Akiyama, T. Hoshino, N.  
 Nakamura, H. Ohno and K. Morishima,  
*Tokyo University of Agriculture and Technology,  
 Tokyo, JAPAN*  
 .....2762
- W4D.007 SEPARATION OF CAENORHABDITIS ELEGANS  
 BY ELECTROTAXIS IN A MICRODEVICE**  
 P. Rezaei<sup>1</sup>, S. Salam<sup>2</sup>, P. R. Selvaganapathy<sup>1,\*</sup> and  
 B. P. Gupta<sup>2</sup>  
<sup>1</sup>*Department of Mechanical Engineering, McMaster  
 University, Hamilton, ON, CANADA*  
<sup>2</sup>*Department of Biology, McMaster University,  
 Hamilton, ON, CANADA*  
 .....2766

## THURSDAY, JUNE 9, 2011

**ORAL SESSIONS** 08:30 - 10:00

### SESSION VIII(1) –Polymers in MEMS

- Th1A.001 Invited Speaker  
 ELASTOMERIC CAPACITIVE SENSORS**  
 S.P. Lacour<sup>1</sup>, D.P.J. Cotton<sup>2</sup>

<sup>1</sup>Ecole Polytechnique Fédérale de Lausanne,  
Laboratory for Soft Bioelectronic Interfaces,  
Lausanne, Switzerland  
<sup>2</sup>University of Cambridge, Nanoscience Centre,  
Cambridge, UK  
.....2770

**Th1A.002** **A DESIGN OF LONGITUDINALLY-DIVIDED  
BALLOON STRUCTURE IN PDMS PNEUMATIC  
BALLOON ACTUATOR BASED ON FEM  
SIMULATIONS**  
K. Morimoto, A. Utsumi and S. Konishi  
Ritsumeikan University, Shiga, JAPAN  
.....2774

**Th1A.003** **ONE STEP INTEGRATION OF GOLD COATED  
SENSORS WITH OSTEO POLYMER CARTRIDGES  
BY LOW TEMPERATURE DRY BONDING**  
N. Sandström, R. Z. Shafagh, C.F. Carlborg, T.  
Haraldsson, G. Stemme and W. van der  
Wijngaart  
KTH Royal Institute of Technology, Microsystem  
Technology Lab, Stockholm, Sweden  
.....2778

**Th1A.004** **SINGLE-STEP FABRICATION OF ORGANIC  
NANOFIBROUS MEMBRANE FOR  
PIEZOELECTRIC VIBRATION SENSOR**  
G.F. Zheng<sup>1</sup>, X. Wang<sup>1</sup>, W.W. Li<sup>1,2</sup>, T.P. Lei<sup>1</sup>, W.  
Tao<sup>1</sup>, J. Du<sup>1</sup>, Q.Y. Qiu<sup>1</sup>, X.G. Chi<sup>1</sup>, and D.H.  
Sun<sup>1\*</sup>  
<sup>1</sup>Department of Mechanical and Electrical Engineering,  
Xiamen University, Xiamen, Fujian, China  
<sup>2</sup>Department of Mechanical Engineering, Xiamen  
University of Technology, Xiamen, Fujian, China  
.....2782

**Th1A.005** **MECHANICAL REGULATION OF COLLECTIVE  
CELL BEHAVIOR VIA MICROTOPOGRAPHIC  
SUBSTRATES**  
Adrienne T. Higa<sup>1\*</sup>, Ryan D. Sochol<sup>1</sup>, Kosuke  
Iwai<sup>1</sup>, Song Li<sup>2</sup>, and Liwei Lin<sup>1</sup>  
<sup>1</sup>Berkeley Sensor and Actuator Center, University of  
California, Berkeley, USA  
<sup>2</sup>Department of Bioengineering, University of  
California, Berkeley, USA  
.....2786

**SESSION VIII(2) –Wireless Systems &  
Components**

**Th1B.001** **Invited Speaker**  
**Th1B.002** **BATTERY-FREE WIRELESS TOUCH DRIVEN  
TRANSMITTER WITH ON-CHIP ANTENNAS FOR  
WIRELESS SENSOR SYSTEMS**  
Makoto Niino<sup>1</sup>, Tuan-Anh Nguyen<sup>1</sup>,  
Wang-Hoon Lee<sup>1,2</sup>, Kazuaki Sawada<sup>1,2</sup>, Makoto  
Ishida<sup>1,2</sup>  
<sup>1</sup>Toyohashi University of Technology, Toyohashi,  
Japan  
<sup>2</sup>JST-CREST Advance Integrated Sensing Technology,  
Tokyo, Japan

.....2790  
**Th1B.003** **NOVEL FREQUENCY AGILE  
ELECTROMAGNETIC DECOUPLING MEMS  
DEVICE**  
Yun-Ho Jang<sup>1</sup>, Ignacio Llamas-Garro<sup>2</sup>, Jung-Mu  
Kim<sup>3</sup>, and Yong-Kweon Kim<sup>1</sup>  
<sup>1</sup>Seoul National University, Seoul, KOREA  
<sup>2</sup>Centre Tecnologic de Telecomunicacions de  
Catalunya, Barcelona, SPAIN  
<sup>3</sup>Chonbuk National University, Jeonju, KOREA  
.....2794

**Th1B.004** **INDUCTIVELY COUPLED WIREBONDED  
MICROCOILS FOR WIRELESS ON-CHIP NMR**  
V. Badilita<sup>1,\*</sup>, B. Fassbender<sup>2</sup>, O. Gruschke<sup>3</sup>, K.  
Kratt<sup>1</sup>, R. Meier<sup>3</sup>, D. Sakellariou<sup>2</sup>, J.G. Korvink<sup>3,4</sup>  
and U. Wallrabe<sup>1</sup>  
<sup>1</sup>Lab. for Microactuators, Dept. of Microsystems  
Engineering – IMTEK, University of Freiburg,  
Germany  
<sup>2</sup>CEA Saclay, IRAMIS, SIS2M, F-91191, Gif-sur-Yvette,  
France  
<sup>3</sup>Lab. for Simulation, Dept. of Microsystems  
Engineering. – IMTEK, University of Freiburg,  
Germany  
<sup>4</sup>Freiburg Institute for Advanced Studies. – FRIAS,  
University of Freiburg, Germany  
.....2798

**Th1B.005** **ON-CHIP RF INDUCTORS WITH MAGNETIC  
NANO PARTICLES MEDIUM**  
C. Yang<sup>1</sup>, K. Koh<sup>1</sup>, X. Zhu<sup>2</sup>, and L. Lin<sup>1</sup>  
<sup>1</sup>University of California, Berkeley, CA, USA  
<sup>2</sup>Samsung Electronics, Dallas, TX, USA  
.....2801

**SESSION VIII(3) –MEMS Gyroscopes**

**Th1C.001** **Invited Speaker**  
**MULTI-DOF INERTIAL MEMS:FROM GAMING TO  
DEAD RECKONING**  
**Farrokh Ayazi**  
Georgia Institute of Technology, Atlanta, GA, USA  
Qualtré Inc., Marlborough, MA, USA  
.....2805

**Th1C.002** **SUB-DEGREE-PER-HOUR SILICON MEMS RATE  
SENSOR WITH 1 MILLION Q-FACTOR**  
I.P. Prikhodko, S.A. Zotov, A.A. Trusov, and  
A.M. Shkel  
Microsystems Laboratory, University of California,  
Irvine, CA, USA  
.....2809

**Th1C.003** **SINGLE-CRYSTAL-SILICON VIBRATORY  
CYLINDRICAL RATE INTEGRATING  
GYROSCOPE (CING)**  
J. Cho, J.A. Gregory, and K. Najafi  
Center for Wireless Integrated Microsystems (WIMS)  
University of Michigan, USA  
.....2813

- Th1C.004 EXPERIMENTAL EVALUATION OF ALTERNATIVE DRIVE-MODE CONTROL ELECTRONICS DEVELOPED FOR HIGH-PERFORMANCE MEMS GYROSCOPES**  
E. Sahin<sup>1</sup>, S. E. Alper<sup>1</sup>, and T. Akin<sup>1,2</sup>  
<sup>1</sup>Middle East Technical University, MEMS Research and Applications Center, Ankara, TURKEY  
<sup>2</sup>Middle East Technical University, Department of Electrical and Electronics Eng., Ankara, TURKEY  
.....2817
- Th1C.005 A MODE-MATCHED 0.9 MHZ SINGLE PROOF-MASS DUAL-AXIS GYROSCOPE**  
W.K. Sung, M. Dalal and F. Ayazi  
School of Electrical and Computer Engineering, Georgia Institute of Technology, Atlanta, GA 30308-0250, USA  
.....2821

#### SESSION VIII(4) –Medical Devices & Systems

- Th1D.001 Invited Speaker RETINAL IMPLANTS TO RESTORE VISION IN BLIND PEOPLE**  
Wilfried Mokwa  
Institute of Materials in Electrical Engineering I, RWTH Aachen University, Aachen, Germany  
.....2825
- Th1D.002 DELIVERY OF AN ANTI-CANCER DRUG FROM A MAGNETICALLY CONTROLLED MEMS DEVICE SHOW CYTOTOXICITY IN PC3 AND HUVEC CELLS**  
F. N. Pirmoradi<sup>1</sup>, J. Jackson<sup>2</sup>, H. Burt<sup>2</sup>, and M. Chiao<sup>1</sup>  
<sup>1</sup>Department of Mechanical Engineering, University of British Columbia, Vancouver, BC, Canada  
<sup>2</sup>Faculty of Pharmaceutical Sciences, University of British Columbia, Vancouver, BC, Canada  
.....2831
- Th1D.003 CAPSULE MICROROBOT FOR TARGETTING IN MEDICAL DIAGNOSTIC TREATMENT**  
H. KOGA, Y. SAKATA, S. HIROSE and S.KONISHI  
Ritsumeikan University, Shiga, JAPAN  
.....2835
- Th1D.004 ELECTROCHEMICALLY-BASED DOSE MEASUREMENT FOR CLOSED-LOOP DRUG DELIVERY APPLICATIONS**  
Christian A. Gutierrez, Roya Sheybani and Ellis Meng  
University of Southern California, Department of Biomedical Engineering, Los Angeles, CA, USA  
.....2839
- Th1D.005 A MEDICAL TACTILE SENSOR FOR MEASURING TISSUE HARDNESS IN ROBOTIC SURGICAL TOOLS**  
Shenshen Zhao, David Parks, and Chang Liu  
MedX Lab, Northwestern University, Evanston, IL,  
.....

60208, USA  
.....2843

#### ORAL SESSIONS 10:30 - 12:15

#### SESSION IX(1) –Physical Sensors II

- Th2A.001 A MEMS MICRO-REED SWITCH DESIGNED FOR PORTABLE APPLICATIONS**  
Min Tang<sup>1</sup>, Yong Hean Lee<sup>1</sup>, Rakesh Kumar<sup>1</sup>, Ravi Shankar<sup>2</sup>, Olivier Le Neel<sup>2</sup>  
<sup>1</sup>Institute of Microelectronics, A\*STAR (Agency for Science, Technology and Research), Singapore  
<sup>2</sup>ST Microelectronics Asia Pacific Pte Ltd, Singapore  
.....2847
- Th2A.002 MICROMECHANICAL MAGNETOMETERS BASED ON CLAMPED-CLAMPED HIGH-Q NONLINEAR RESONATORS**  
D. Antonio and D. López  
Center for Nanoscale Materials, Argonne National Laboratory, Argonne, IL, USA  
.....2851
- Th2A.003 NOVEL COUPLING CONCEPT FOR FIVE-CONTACT VERTICAL HALL DEVICES**  
T. Kaufmann, F. Purkl, P. Ruther and O. Paul  
Department of Microsystems Engineering (IMTEK), University of Freiburg, Germany  
.....2855
- Th2A.004 LOCALIZED STRAIN SENSING USING HIGH SPATIAL RESOLUTION, HIGHLY-SENSITIVE MEMS RESONANT STRAIN GAUGES FOR FAILURE PREVENTION**  
Matthew W. Chan, David R. Myers, Brian D. Sosnowchik, Liwei Lin, and Albert P. Pisano  
University of California, Berkeley, Berkeley, CA, United States  
.....2859
- Th2A.005 DETECTION SYSTEM OF INCIDENT SLIPPAGE AND FRICTION COEFFICIENT BASED ON A FLEXIBLE TACTILE SENSOR WITH STRUCTURAL ELECTRODES**  
C.H. Chuang\*, Y.R. Liou and C.W. Chen  
Department of Mechanical Engineering, Southern Taiwan University, Tainan, TAIWAN  
.....2863
- Th2A.006 IR THERMOCYCLER FOR CENTRIFUGAL MICROFLUIDIC PLATFORM WITH DIRECT ON-DISK WIRELESS TEMPERATURE MEASUREMENT SYSTEM**  
J. Burger<sup>1</sup>, André Gross<sup>1</sup>, Daniel Mark<sup>3</sup>, Felix von Stetten<sup>1,3</sup>, Roland Zengerle<sup>1,2,3</sup> and Günter Roth<sup>1,2,3</sup>  
<sup>1</sup>Laboratory for MEMS Applications, Department of Microsystems Engineering - IMTEK, University of Freiburg, Georges-Koehler-Allee 106, D-79110 Freiburg, Germany  
<sup>2</sup>Centre for Biological Signalling Studies – BIOS,  
.....

University of Freiburg, Germany  
<sup>3</sup>HSG-IMIT, Wilhelm-Schickard-Straße 10, D-78052  
Villingen-Schwenningen, Germany  
.....2867

- Th2A.007 A CONTOUR-MODE FILM BULK ACOUSTIC RESONATOR FOR MONITORING BLOOD COAGULATION IN REAL-TIME**  
W. Xu<sup>1\*</sup>, J. Appel<sup>2</sup>, and J. Chae<sup>1</sup>  
<sup>1</sup>Arizona State University, Tempe, Arizona, USA  
<sup>2</sup>Auburn University, Auburn, Alabama, USA  
.....2871

### SESSION IX(2) –Harsh Environmental Reliability

- Th2B.001 IMPROVED RELIABILITY OF SIC PRESSURE SENSORS FOR LONG TERM HIGH TEMPERATURE APPLICATIONS**  
R.S. Okojie<sup>1</sup>, V. Nguyen<sup>2</sup>, E. Savrun<sup>2</sup>, and D. Lukco<sup>3</sup>  
<sup>1</sup>NASA Glenn Research Center, Cleveland, OH, USA  
<sup>2</sup>Sienna Technologies, Inc. Woodingville, WA, USA  
<sup>3</sup>ASRC Research Corp., NASA Glenn Research Center, Cleveland, OH, USA  
.....2875

- Th2B.002 VERY HIGH TEMPERATURE (800°C) OHMIC CONTACT OF AU/NI2SI ON N-TYPE POLYCRYSTALLINE SILICON CARBIDE AGED IN AIR**  
R. Larger and L. G. Fréchette  
Department of Mechanical Engineering, Université de Sherbrooke, Sherbrooke, CANADA  
.....2879

- Th2B.003 IMPACT OF ENCAPSULATION MATERIALS ON THE PERFORMANCE OF SILICON-BASED SOLID STATE HIGH PRESSURE SENSORS WITH SURFACE TRENCHES**  
M. Baumann, C. Sander, P. Ruther, and O. Paul  
Department of Microsystems Engineering (IMTEK), University of Freiburg, Germany  
.....2883

- Th2B.004 AN SOI THERMAL-DIFFUSIVITY-BASED TEMPERATURE SENSOR WITH ±0.6°C (3 $\Sigma$ ) UNTRIMMED INACCURACY FROM -70°C TO 170°C**  
C.P.L. van Vroonhoven and K.A.A. Makinwa  
Delft University of Technology, Delft, The Netherlands  
.....2887

- Th2B.005 DESIGN EVALUATION OF SHOCK INDUCED FAILURE MECHANISMS OF MEMS BY CORRELATION OF NUMERICAL AND EXPERIMENTAL RESULTS**  
M. Naumann<sup>1</sup>, D. Lin<sup>2</sup>, J. Mehner<sup>1</sup>, A. McNeil<sup>2</sup> and T. F. Miller<sup>2</sup>  
<sup>1</sup>Chemnitz University of Technology, Department of Microsystems and Precision Engineering, Chemnitz, Germany  
<sup>2</sup>Freescale Semiconductor Inc., Tempe, Arizona,  
.....2891

United States  
.....2891

- Th2B.006 EFM STUDY OF THE INFLUENCE OF HUMIDITY ON CHARGE INJECTION AND CHARGE RELAXATION IN SILICON NITRIDE USED IN ELECTROSTATICALLY ACTUATED MEMS**  
A. Nowodzinski<sup>1</sup>, T. Toussaint<sup>1</sup>, A. Koszewski<sup>1</sup>, F.Souchon<sup>1</sup>  
<sup>1</sup>CEA-Leti LCFM, Grenoble, France  
.....2895

- Th2B.007 TIME PREDICTIVE MODEL OF CHARGE ACCUMULATION IN BULK PECVD DIELECTRIC MATERIALS USED FOR ELECTROSTATIC RF MEMS SWITCHES**  
F. Souchon<sup>1</sup>, A. Koszewski<sup>1</sup>, C. Dieppedale<sup>1</sup> and T. Ouisse<sup>2</sup>  
<sup>1</sup>CEA-LETI-MINATEC-CAMPUS, Grenoble, FRANCE  
<sup>2</sup>Grenoble INP and LMGP-UMRCNRS5628, Grenoble, FRANCE  
.....2899

### SESSION IX(3) –Displays, Scanners and Modulators

- Th2C.001 LENS SCANNING BASED MEMS CATHETER FOR FORWARD ENDOSCOPIC OPTICAL COHERENCE TOMOGRAPHY**  
H. C. Park<sup>†</sup>, C. Song<sup>†</sup>, and K. H. Jeong<sup>\*</sup>  
Department of Bio and Brain Engineering, Korea Advanced Institute of Science and Technology (KAIST), Daejeon, Republic of Korea  
.....2904

- Th2C.002 FRONTSIDE-ONLY PROCESSING OF 2-D MEMS SCANNER FOR MINIATURE DUAL-AXIS CONFOCAL MICROENDOSCOPES**  
J.W. Jeong<sup>\*</sup>, S. Vaithilingam, and O. Solgaard  
E. L. Ginzton Laboratory, Department of Electrical Engineering, Stanford University, Stanford, CA, USA  
.....2908

- Th2C.003 DEVELOPMENT OF THE MICRO-MIRROR WITH LARGE SCANNING ANGLE USING FE-BASED METALLIC GLASS THIN FILM**  
Jae-Wung Lee<sup>1</sup>, Yu-Ching Lin<sup>1</sup>, Neelam Kaushik<sup>1</sup>, Parmanand Sharma<sup>2</sup>, Akihisa Inoue<sup>2</sup>, Masayoshi Esashi<sup>1</sup> and Thomas Gessner<sup>3,4</sup>  
<sup>1</sup>WPI Advanced Institute for Materials Research Tohoku University, Sendai, Tohoku, Japan  
<sup>2</sup>Institute for Materials Research, Tohoku University, Sendai 980-8577, Japan  
<sup>3</sup>Fraunhofer ENAS, Chemnitz 09126, Germany  
<sup>4</sup>Chemnitz University of Technology, Chemnitz, Germany  
.....2912

- Th2C.004 INTERFEROMETRIC MODULATORS USING MECHANICALLY COUPLED MIRROR ACTUATORS FOR COLOR REPRODUCTION**  
W. Han and Y.-H. Cho  
Digital Nanolocomotion Center, Department of Bio  
.....2916

and Brain Engineering, KAIST, Korea

.....2916

**Th2C.005 OPTO-ACOUSTIC OSCILLATOR USING SILICON MEMS OPTICAL MODULATOR**

Suresh Sridaran and Sunil A. Bhawe  
*OxideMEMS Lab, Cornell University, Ithaca, NY, USA*

.....2920

**Th2C.006 ELECTROSTATIC TORSIONAL VERTICAL FLAPS FOR REFLECTIVE MEMS DISPLAY**

F. Jutzi, W. Noell, N. F. de Rooij  
*Ecole Polytechnique Fédérale de Lausanne (EPFL),  
Institute of Microengineering (IMT), Sensors,  
Actuators and Microsystems Laboratory (SAMLAB),  
Neuchâtel, SWITZERLAND*

.....2924

**Th2C.007 MONOLITHIC INTEGRATION OF NEMS TUNABLE COLOR FILTER AND LSI DRIVER CIRCUITS**

H. Honma<sup>1</sup>, H. Miyao<sup>1</sup>, K. Takahashi<sup>1,2</sup>, M. Futagawa<sup>1</sup>, F. Dasai<sup>1</sup>, M. Ishida<sup>1,2</sup>, and K. Sawada<sup>1,2</sup>  
<sup>1</sup>*Toyohashi University of Technology, Toyohashi, Aichi, JAPAN*  
<sup>2</sup>*JST CREST, Tokyo, JAPAN*

.....2928

**SESSION IX(4) –Microfluidics II**

**Th2D.001 HIGH PRESSURE EWOD DIGITAL MICROFLUIDICS**

W. C. Nelson<sup>1</sup>, M. Yen<sup>1</sup>, P. Y. Keng<sup>2,3</sup>, R. M. van Dam<sup>2,3</sup> and C.-J. Kim<sup>1</sup>  
<sup>1</sup>*Mechanical and Aerospace Engineering Department*  
<sup>2</sup>*Department of Molecular and Medical Pharmacology*  
<sup>3</sup>*Crump Institute for Molecular Imaging University of California, Los Angeles (UCLA), USA*

.....2932

**Th2D.002 ENHANCED MICRO-DROPLET SPLITTING, CONCENTRATION, SENSING AND EJECTION BY INTEGRATING**

**ELECTROWETTING-ON-DIELECTRICS AND SURFACE ACOUSTIC WAVE TECHNOLOGIES**  
Y. Li<sup>1</sup>, Y.Q. Fu<sup>2,3</sup>, S.D. Brodie<sup>2</sup>, M. Alghane<sup>2</sup> and A.J. Walton<sup>1</sup>

<sup>1</sup>*Institute for Integrated Micro and Nano Systems, School of Engineering, Institute for Integrated Systems-Part of ERPem, University of Edinburgh, Edinburgh, EH9 3JF, UK*

<sup>2</sup>*Department of Mechanical Engineering, School of Engineering and Physical Sciences, Institute for Integrated Systems - Part of ERPem, Heriot-Watt University, Edinburgh, UK*

<sup>3</sup>*Thin Film Centre, Scottish Union of Physics Alliance*

(SUPA), University of West of Scotland, Paisley, PA1 2BE, Scotland

.....2936

**Th2D.003 ON-CHIP SYNTHESIS OF SILICA NANOPARTICLE ASSEMBLIES WITH CONTROLLED SHAPE AND SIZE**

J.B. Wacker, V.K. Parashar, and M.A.M. Gijs  
*Laboratory of Microsystems, Ecole Polytechnique Fédérale de Lausanne (EPFL), Lausanne, Switzerland*

.....2940

**Th2D.004 STAND-ALONE MICRO FLUIDIC SYSTEM USING PARTLY DISPOSABLE PDMS MICROWELL ARRAY FOR HIGH THROUGHPUT CELL ANALYSIS**

Kasumi Miyamoto<sup>1</sup>, Ryo Yamamoto<sup>1</sup>, Kentaro Kawai<sup>2</sup>, and Shuichi Shoji<sup>1</sup>

<sup>1</sup>*Major in Nano-Science and Nano-Engineering, Waseda University, Japan*

<sup>2</sup>*Department of Precision Science and Technology, Osaka University, Japan*

.....2944

**Th2D.005 ON-CHIP INTEGRATION OF EIGHT DIRECTIONAL DROPLET EJECTORS FOR INKING A SPOT WITH EIGHT DROPLETS WITHOUT EJECTOR MOVEMENT**

Youngki Choe, Lingtao Wang, and Eun Sok Kim  
*Department of EE-Electrophysics, University of Southern California, Los Angeles, CA, USA*

.....2948

**Th2D.006 FULLY INTEGRATED DILUTION SERIES GENERATION ON A LABORATORY CENTRIFUGE**

O. Strohmeier<sup>1,\*</sup>, M. Rombach<sup>1</sup>, D. Mark<sup>2</sup>, R. Zengerle<sup>1,2,3</sup>, G. Roth<sup>1,2,3</sup> and F. von Stetten<sup>1,2</sup>

<sup>1</sup>*Laboratory for MEMS Applications, Department of Microsystems Engineering - IMTEK, University of Freiburg, Georges-Koehler-Allee 106, 79110 Freiburg, GERMANY*

<sup>2</sup>*HSG-IMIT, Wilhelm-Schickard-Straße 10, 78052 Villingen-Schwenningen, GERMANY*

<sup>3</sup>*Center for Biological Signalling Studies – BIOSS, University of Freiburg, GERMANY*

.....2952

**Th2D.007 LEUKOCYTE 5-PART DIFFERENTIAL COUNT USING A MICROFLUIDIC CYTOMETER**

W. Shi<sup>1</sup>, L.W. Guo<sup>1</sup>, H. Kasdan<sup>2</sup>, A. Fridge<sup>2</sup>, and YC. Tai<sup>1</sup>

<sup>1</sup>*California Institute of Technology, Pasadena, CA, USA*

<sup>2</sup>*IRIS Diagnostics Division, IRIS International Inc., Chatsworth, CA, USA*

.....2956